

# MC9S08QE128 MC9S08QE96 MC9S08QE64 Reference Manual



## *HCS08 Microcontrollers*

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Rev. 2  
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# MC9S08QE128 Series Features

## 8-Bit HCS08 Central Processor Unit (CPU)

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- Up to 50.33-MHz HCS08 CPU from 3.6 V to 2.1 V, and 20-MHz CPU at 2.1 V to 1.8 V across temperature range of  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$
- HCS08 instruction set with added BGND instruction
- Support for up to 32 interrupt/reset sources

## On-Chip Memory

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- Flash read/program/erase over full operating voltage and temperature
- Random-access memory (RAM)
- Security circuitry to prevent unauthorized access to RAM and flash contents

## Power-Saving Modes

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- Two very low power stop modes, one of which allows limited use of peripherals
- Reduced power wait mode
- Peripheral clock enable register can disable clocks to unused modules, thereby reducing currents; allows clocks to remain enabled to specific peripherals in stop3 mode
- Very low power external oscillator that can be used in stop3 mode to provide accurate clock source to active peripherals
- Very low power real time counter for use in run, wait, and stop modes with internal and external clock sources
- 6  $\mu\text{s}$  typical wake up time from stop3 mode

## Clock Source Options

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- Oscillator (XOSC) — Loop-control Pierce oscillator; crystal or ceramic resonator range of 31.25 kHz to 38.4 kHz or 1 MHz to 16 MHz
- Internal Clock Source (ICS) — Internal clock source module containing a frequency-locked-loop (FLL) controlled by internal or external reference; precision trimming of internal reference allows 0.2% resolution and 2% deviation over temperature and voltage; supports CPU frequencies from 2 MHz to 50.33 MHz

## System Protection

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- Watchdog computer operating properly (COP) reset with option to run from dedicated 1-kHz internal clock source or bus clock
- Low-voltage detection with reset or interrupt; selectable trip points
- Illegal opcode detection with reset
- Flash block protection

## Development Support

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- Single-wire background debug interface
- Breakpoint capability to allow single breakpoint setting during in-circuit debugging (plus two more breakpoints in on-chip debug module)
- On-chip in-circuit emulator (ICE) debug module containing three comparators and nine trigger modes. Eight deep FIFO for storing change-of-flow addresses and event-only data. Debug module supports both tag and force breakpoints.

## Peripherals

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- **ADC** — 24-channel, 12-bit resolution; 2.5  $\mu\text{s}$  conversion time; automatic compare function; 1.7 mV/ $^{\circ}\text{C}$  temperature sensor; internal bandgap reference channel; operation in stop3; fully functional from 3.6 V to 1.8 V
- **ACMPx** — Two analog comparators with selectable interrupt on rising, falling, or either edge of comparator output; compare option to fixed internal bandgap reference voltage; outputs can be optionally routed to TPM module; operation in stop3
- **SCIx** — Two full duplex non-return to zero (NRZ); LIN master extended break generation; LIN slave extended break detection; wake up on active edge
- **SPIx** — Two serial peripheral interfaces with full-duplex or single-wire bidirectional; double-buffered transmit and receive; master or slave mode; MSB-first or LSB-first shifting
- **IICx** — Two IICs with; up to 100 kbps with maximum bus loading; multi-master operation; programmable slave address; interrupt driven byte-by-byte data transfer; supports broadcast mode and 10 bit addressing
- **TPMx** — One 6-channel (TPM3) and two 3-channel (TPM1 and TPM2); Selectable input capture, output compare, or buffered edge- or center-aligned PWM on each channel
- **RTC** — (Real-time counter) 8-bit modulus counter with binary or decimal based prescaler; external clock source for precise time base, time-of-day, calendar or task scheduling functions; free running on-chip low power oscillator (1 kHz) for cyclic wake-up without external components; runs in all MCU modes

## Input/Output

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- 70 GPIOs and 1 input-only and 1 output only pin
- 16 KBI interrupts with selectable polarity
- Hysteresis and configurable pull up device on all input pins; configurable slew rate and drive strength on all output pins.
- SET/CLR registers on 16 pins (PTC and PTE)

## Package Options

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- 80-LQFP, 64-LQFP, 48-QFN, 44-QFP, 32-LQFP



# MC9S08QE128 Reference Manual

Covers MC9S08QE128  
MC9S08QE96  
MC9S08QE64

MC9S08QE128RM  
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## Revision History

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# Chapter 1

## Device Overview

The MC9S08QE128, MC9S08QE96, and MC9S08QE64 are members of the low-cost, low-power, high-performance HCS08 Family of 8-bit microcontroller units (MCUs). All MCUs in the family use the enhanced HCS08 core and are available with a variety of modules, memory sizes, memory types, and package types.

### 1.1 Devices in the MC9S08QE128 Series

Table 1-1 summarizes the feature set available in the MC9S08QE128 Series of MCUs.

**Table 1-1. MC9S08QE128 Series Features by MCU and Package**

Feature	MC9S08QE128				MC9S08QE96				MC9S08QE64			
Flash size (bytes)	131,072				98,304				65,536			
RAM size (bytes)	8064				6016				4096			
Pin quantity	80	64	48	44	80	64	48	44	64	48	44	32
ACMP1	yes											
ACMP2	yes											
ADC channels	24	22	10	10	24	22	10	10	22	10	10	10
DBG	yes											
ICS	yes											
IIC1	yes											
IIC2	yes	yes	no	no	yes	yes	no	no	yes	no	no	no
IRQ	yes											
KBI	16	16	16	16	16	16	16	16	16	16	16	12
Port I/O <sup>1</sup>	70	54	38	34	70	54	38	34	54	38	34	26
RTC	yes											
SCI1	yes											
SCI2	yes											
SPI1	yes											
SPI2	yes											
TPM1 channels	3											
TPM2 channels	3											
TPM3 channels	6											
XOSC	yes											

<sup>1</sup> Port I/O count does not include the input only PTA5/IRQ/TPM1CLK/RESET or the output only PTA4/ACMP1O/BKGD/MS.

## 1.2 MCU Block Diagram

The block diagram in [Figure 1-1](#) shows the structure of the MC9S08QE128 Series MCU.

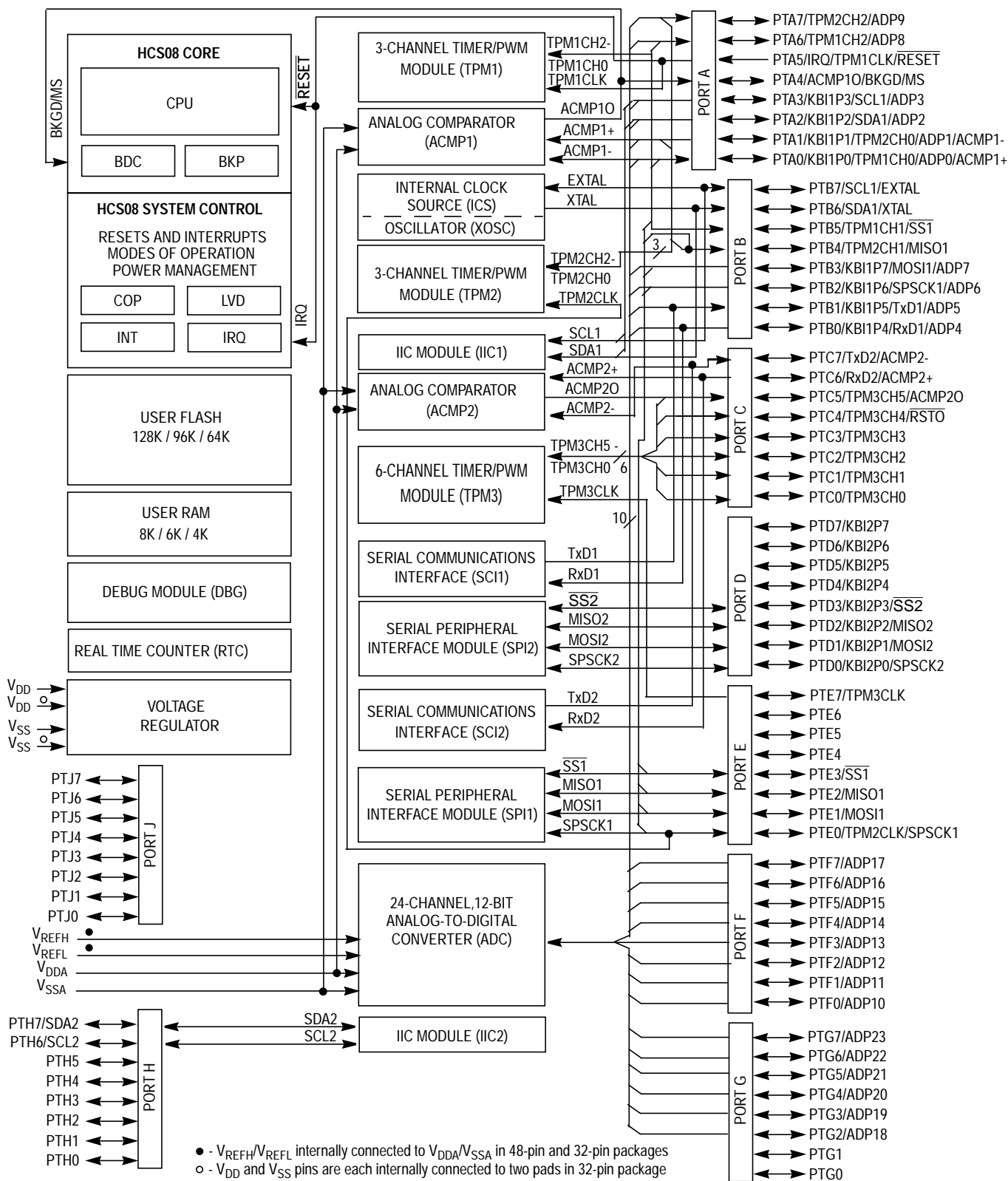


Figure 1-1. MC9S08QE128 Series Block Diagram

Table 1-2 provides the functional version of the on-chip modules.

**Table 1-2. Module Versions**

Module	Version
Very Low Power Analog Comparator (ACMPVLP)	1
12-bit Analog-to-Digital Converter (ADC12)	1
Central Processor Unit (CPU)	4
General-Purpose I/O (GPIO)	2
Inter-Integrated Circuit (IIC)	2
Internal Clock Source (ICS)	3
Keyboard Interrupt (KBI)	2
Low Power Oscillator (XOSCVLP)	1
On-Chip In-Circuit Debug/Emulator (DBG)	3
Port Set/Clear (PSC)	1
Real-Time Counter (RTC)	1
Serial Communications Interface (SCI)	4
Serial Peripheral Interface (SPI)	3
Timer Pulse Width Modulator (TPM)	3

## 1.3 System Clock Distribution

Figure 1-2 shows a simplified clock connection diagram. Some modules in the MCU have selectable clock inputs as shown. The clock inputs to the modules indicate the clock(s) that are used to drive the module function. All memory mapped registers associated with the modules are clocked with BUSCLK. The ICS supplies the clock sources:

- ICSOUT — This clock source is used as the CPU clock and is divided by 2 to generate the peripheral bus clock. Control bits in the ICS control registers determine which of three clock sources is connected:
  - Internal reference clock
  - External reference clock
  - Frequency-locked loop (FLL) outputSee Chapter 11, “Internal Clock Source (S08ICSV3)” for details on configuring the ICSOUT clock.
- ICSLCLK — This clock source is derived from the digitally controlled oscillator (DCO) of the ICS when the ICS is configured to run off of the internal or external reference clock. Development tools can select this internal self-clocked source (~ 8 MHz) to speed up BDC communications in systems where the bus clock is slow. See Chapter 11, “Internal Clock Source (S08ICSV3)” for details.
- ICSECLK — This is the external reference clock and can be selected as the alternate clock for the ADC module. The Optional External Reference Clock section in Chapter 11, “Internal Clock Source (S08ICSV3)” explains the ICSECLK in more detail. See Chapter 10, “Analog-to-Digital Converter (S08ADC12V1)” for more information regarding the use of ICSECLK with these modules.
- ICSIRCLK — This is the internal reference clock and can be selected as the real-time counter clock source. The Internal Reference Clock section in Chapter 11, “Internal Clock Source (S08ICSV3)” explains the ICSECLK in more detail. See Chapter 13, “Real-Time Counter (S08RTCV1)” for more information regarding the use of ICSIRCLK.
- ICSFFCLK — This generates the fixed frequency clock (FFCLK) after being synchronized to the bus clock. It can be selected as clock source for the TPM modules. The frequency of the ICSFFCLK is determined by the settings of the ICS. See the Fixed Frequency Clock section in Chapter 11, “Internal Clock Source (S08ICSV3)” for details.
- LPOCLK — This clock is generated from an internal low power oscillator that is completely independent of the ICS module. The LPOCLK can be selected as the clock source to the RTC or COP modules. See Chapter 13, “Real-Time Counter (S08RTCV1)” and Section 5.4, “Computer Operating Properly (COP) Watchdog” for details on using the LPOCLK with these modules.
- OSCOUT — This is the direct output of the external oscillator module and can be selected as the real-time counter clock source. See Chapter 13, “Real-Time Counter (S08RTCV1)” for details.
- TPMxCLK — TPMxCLKs are optional external clock sources for the TPM modules. The TPMxCLK must be limited to 1/4th the frequency of the bus clock for synchronization. See the External TPM Clock Sources section in Chapter 16, “Timer/Pulse-Width Modulator (S08TPMV3)” for more details.

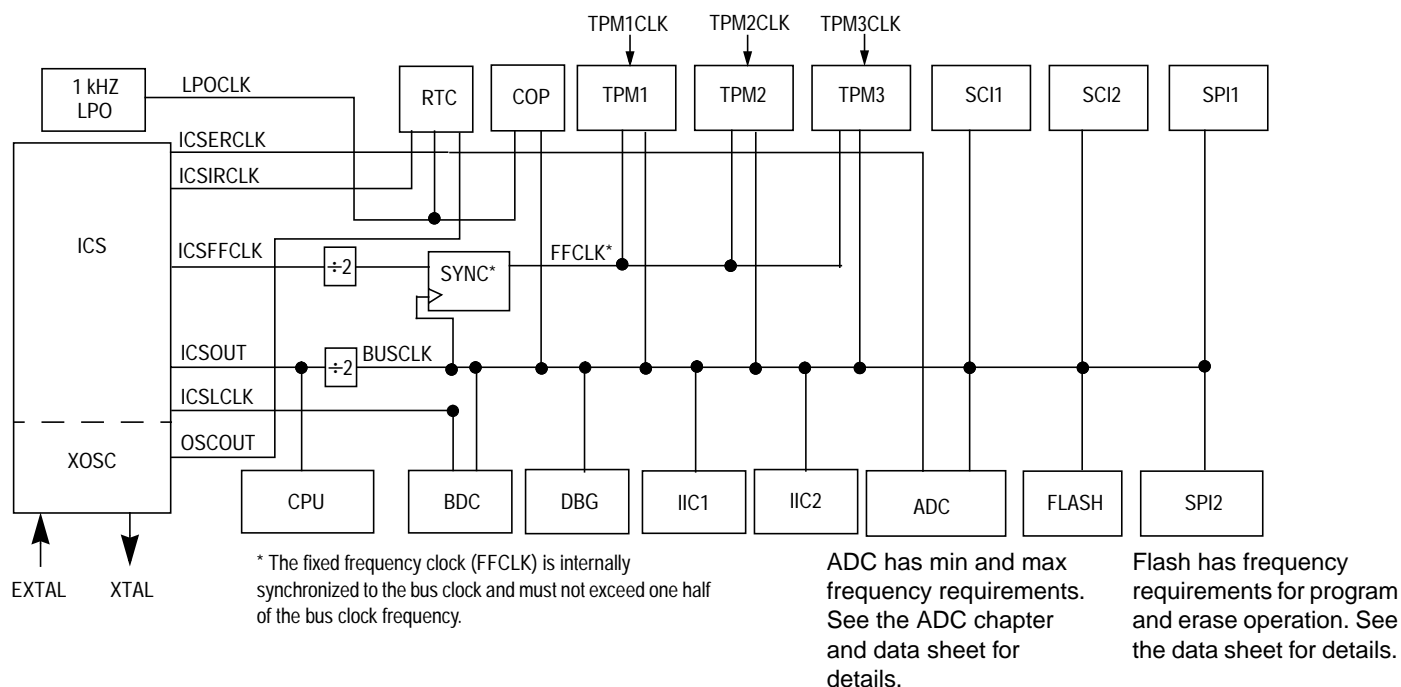


Figure 1-2. System Clock Distribution Diagram



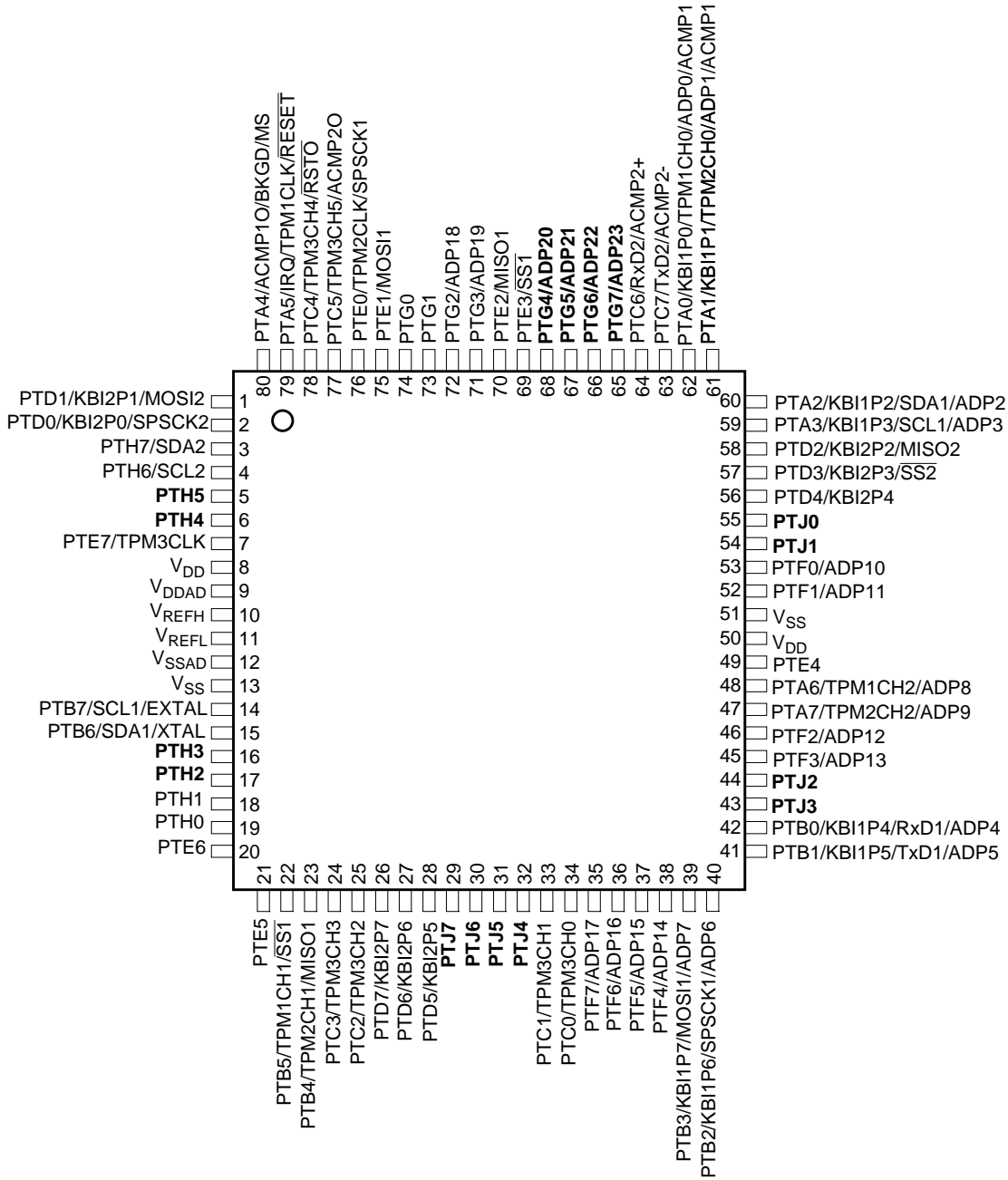
## Chapter 2

# Pins and Connections

This section describes signals that connect to package pins. It includes pinout diagrams, recommended system connections, and detailed discussions of signals.

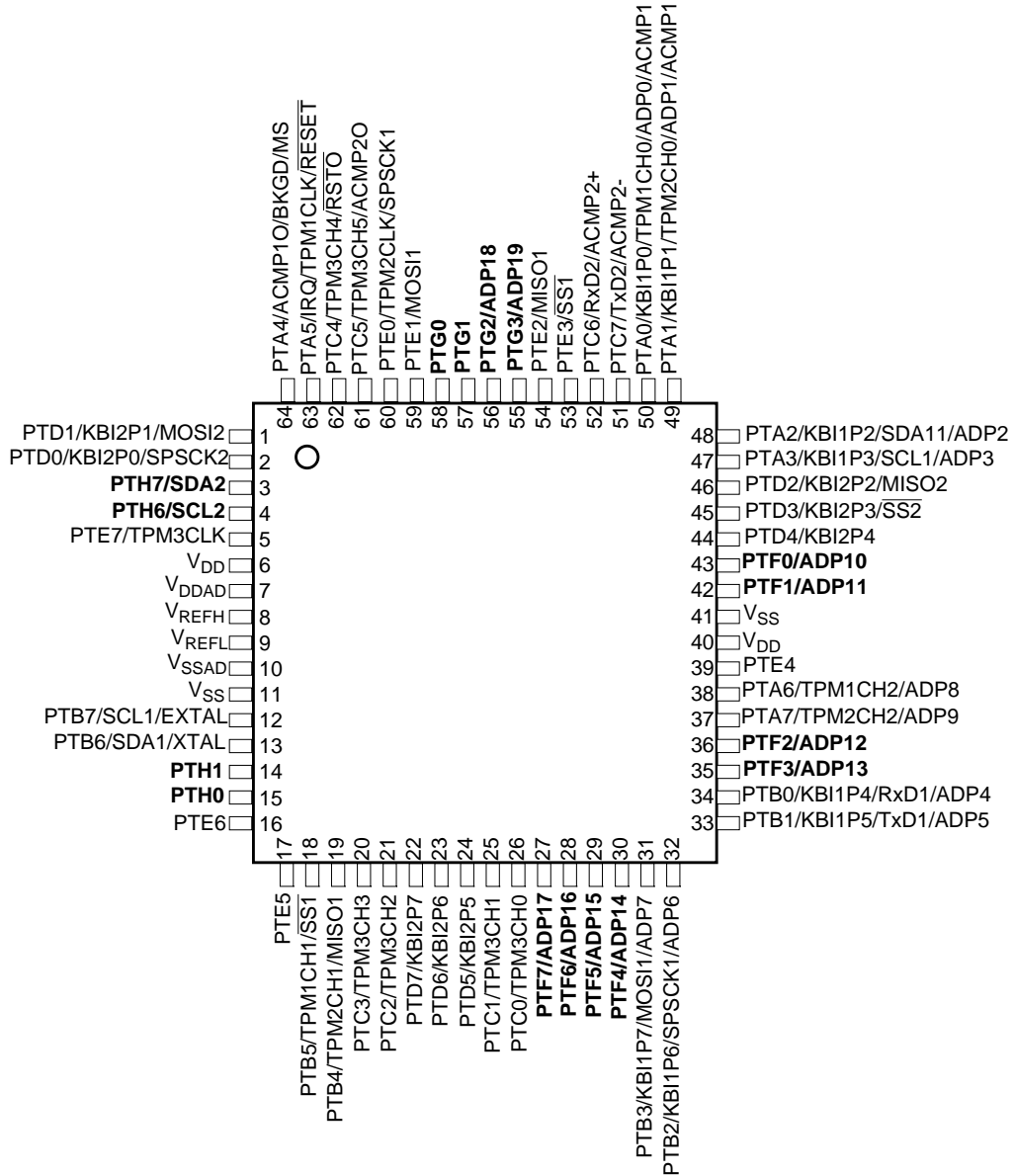
### 2.1 Device Pin Assignment

This section shows the pin assignments for MC9S08QE128 Series devices in the available packages.



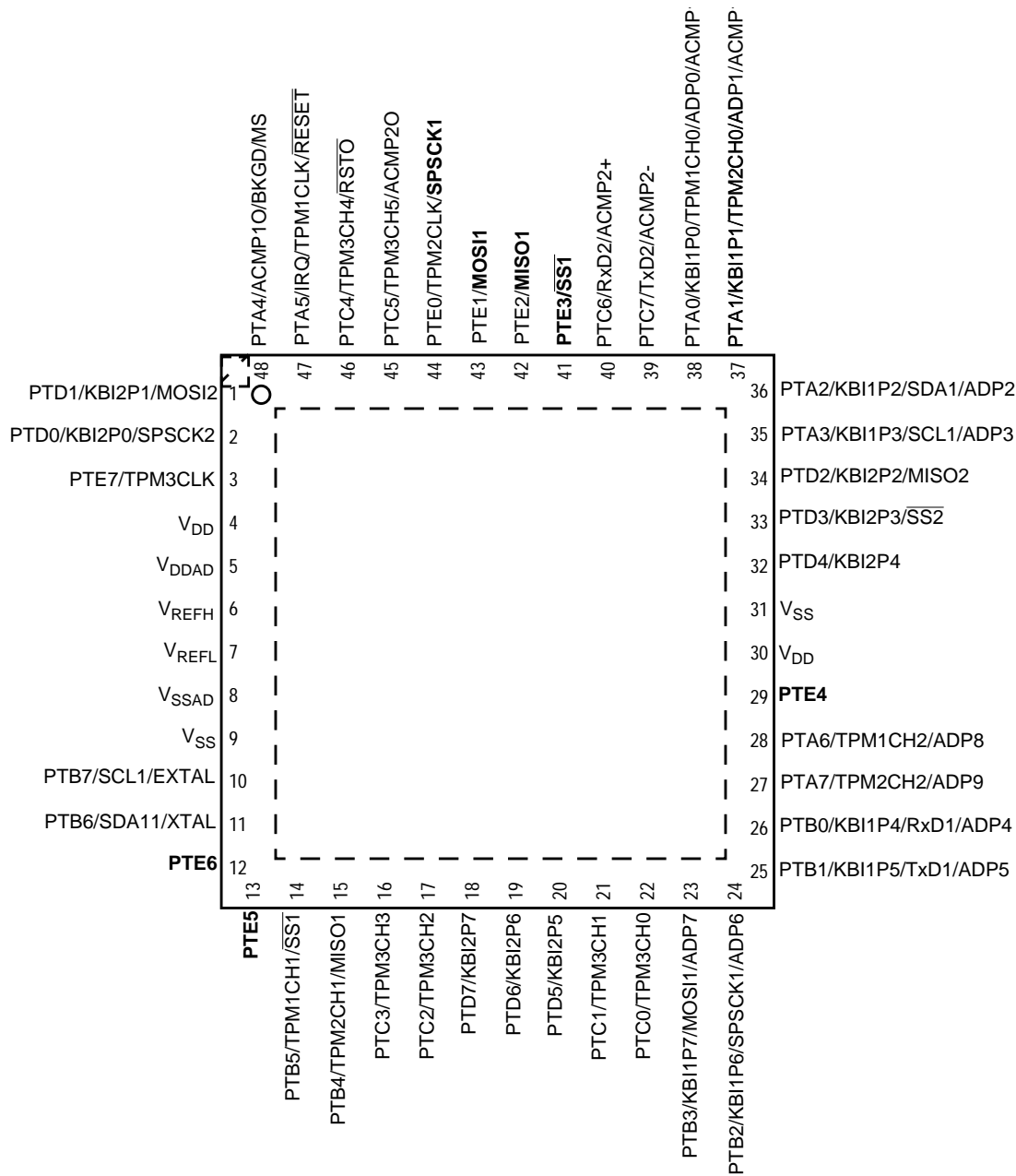
Pins in **bold** are added from the next smaller package.

Figure 2-1. 80-Pin LQFP



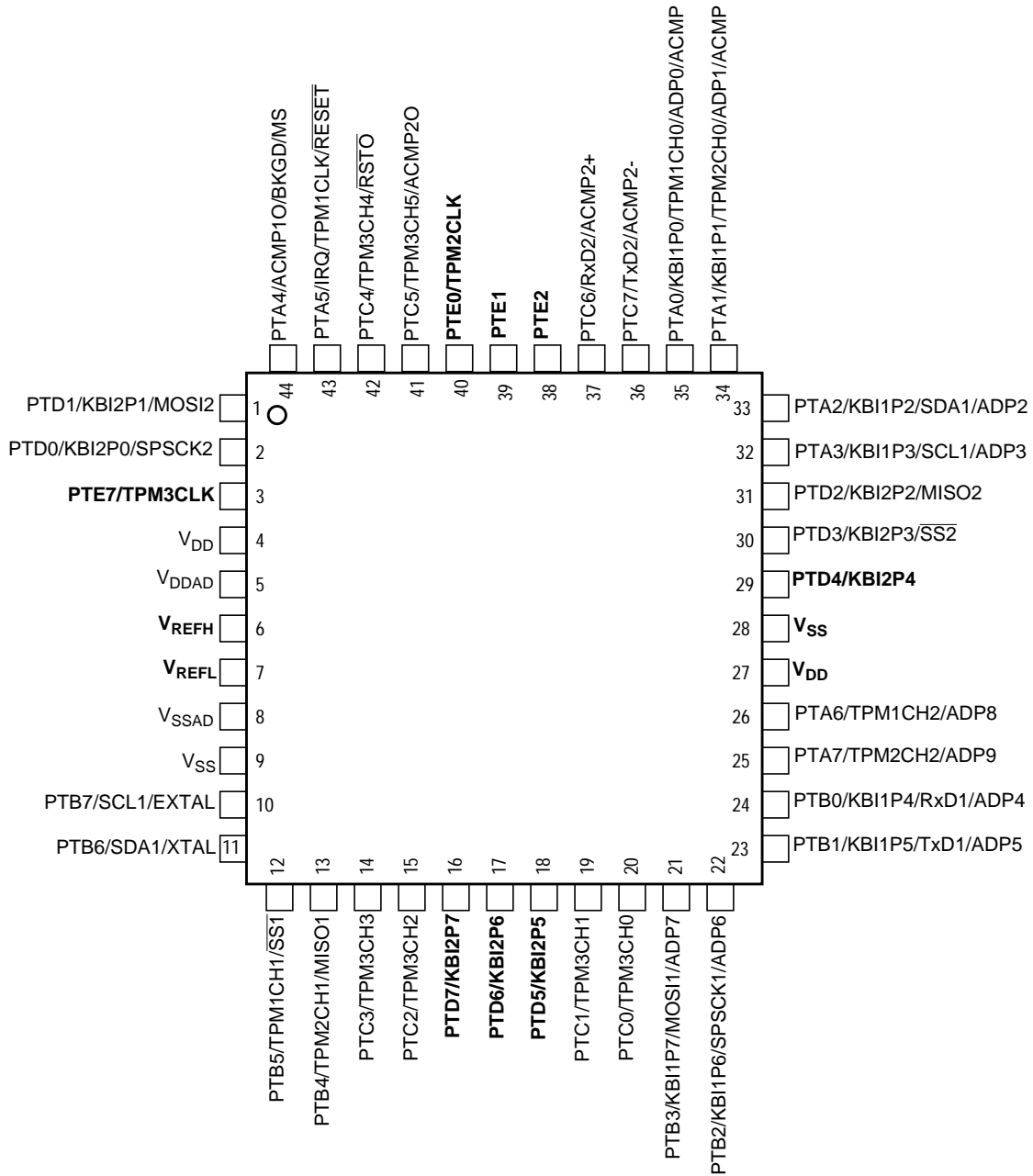
Pins in **bold** are added from the next smaller package.

Figure 2-2. 64-Pin LQFP



Pins in **bold** are added from the next smaller package.

**Figure 2-3. 48-Pin QFN**



Pins in **bold** are added from the next smaller package.

Figure 2-4. 44-Pin QFP

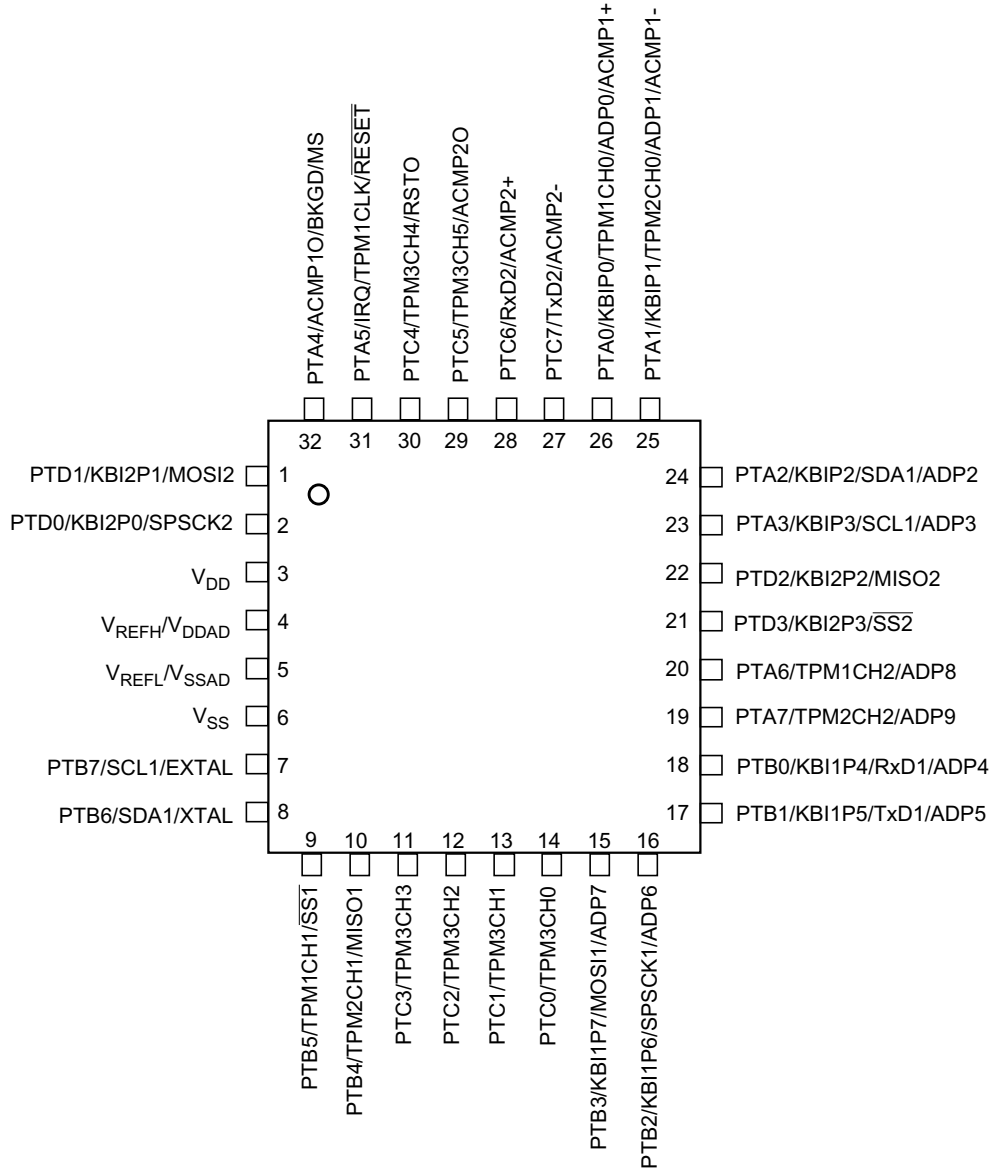


Figure 2-5. 32-Pin LQFP

## 2.2 Recommended System Connections

Figure 2-6 shows pin connections that are common to MC9S08QE128 Series application systems.

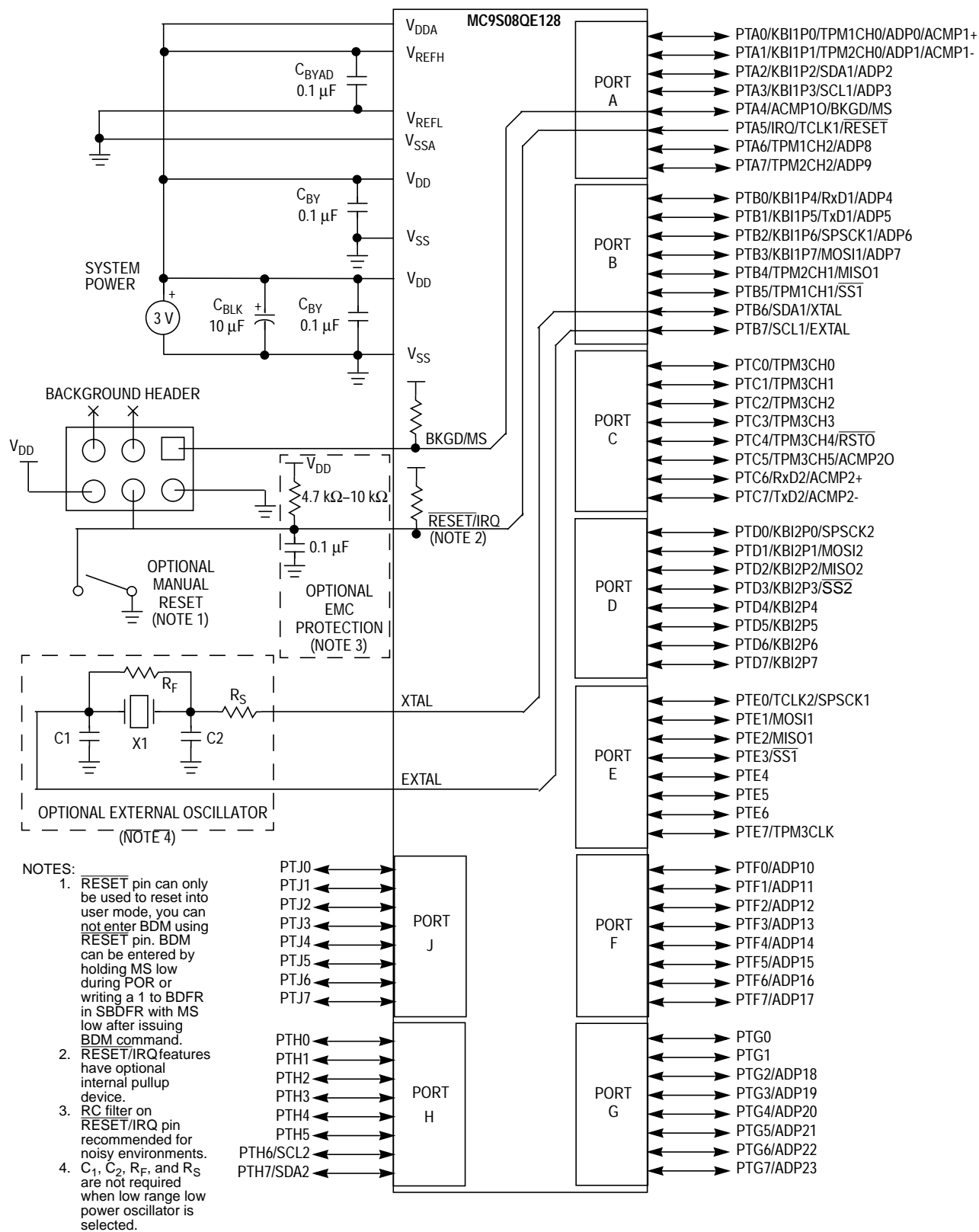


Figure 2-6. Basic System Connections



## 2.2.1 Power

$V_{DD}$  and  $V_{SS}$  are the primary power supply pins for the MCU. This voltage source supplies power to all I/O buffer circuitry and to an internal voltage regulator. The internal voltage regulator provides regulated lower-voltage source to the CPU and other internal circuitry of the MCU.

Typically, application systems have two separate capacitors across the power pins. In this case, there should be a bulk electrolytic capacitor, such as a 10- $\mu$ F tantalum capacitor, to provide bulk charge storage for the overall system and a 0.1- $\mu$ F ceramic bypass capacitor located as near to the MCU power pins as practical to suppress high-frequency noise. Actual decoupling capacitor values and number will vary according to layout and application. The MC9S08QE128 Series has two  $V_{DD}$  pins except on the 32-pin package. Each pin must have a bypass capacitor for best noise suppression.

$V_{DDA}$  and  $V_{SSA}$  are the analog power supply pins for the MCU. This voltage source supplies power to the ADC module. A 0.1- $\mu$ F ceramic bypass capacitor should be located as near to the MCU power pins as practical to suppress high-frequency noise.

## 2.2.2 Oscillator

Immediately after reset, the MCU uses an internally generated clock provided by the internal clock source (ICS) module. For more information on the ICS, see Chapter 11, “Internal Clock Source (S08ICSV3).”

The oscillator (XOSCVLP) in this MCU is a Pierce oscillator that can accommodate a crystal or ceramic resonator. Optionally, an external clock source can be connected to the EXTAL input pin. The oscillator can be configured to run in stop2 or stop3 modes.

Refer to Figure 2-6 for the following discussion.  $R_S$  (when used) and  $R_F$  should be low-inductance resistors such as carbon composition resistors. Wire-wound resistors, and some metal film resistors, have too much inductance. C1 and C2 normally should be high-quality ceramic capacitors that are specifically designed for high-frequency applications.

$R_F$  is used to provide a bias path to keep the EXTAL input in its linear range during crystal startup; its value is not generally critical. Typical systems use 1 M $\Omega$  to 10 M $\Omega$ . Higher values are sensitive to humidity and lower values reduce gain and (in extreme cases) could prevent startup.

C1 and C2 are typically in the 5-pF to 25-pF range and are chosen to match the requirements of a specific crystal or resonator. Be sure to take into account printed circuit board (PCB) capacitance and MCU pin capacitance when selecting C1 and C2. The crystal manufacturer typically specifies a load capacitance which is the series combination of C1 and C2 (which are usually the same size). As a first-order approximation, use 10 pF as an estimate of combined pin and PCB capacitance for each oscillator pin (EXTAL and XTAL).

When using the oscillator in low range and low gain mode, the external components  $R_S$ ,  $R_F$ , C1 and C2 are not required.

## 2.2.3 $\overline{\text{RESET}}$ and $\overline{\text{RSTO}}$

After a power-on reset (POR), the PTA5/IRQ/TCLK/ $\overline{\text{RESET}}$  pin defaults to a general-purpose input port pin, PTA5. Setting RSTPE in SOPT1 configures the pin to be the  $\overline{\text{RESET}}$  pin. After configured as  $\overline{\text{RESET}}$ ,

the pin will remain  $\overline{\text{RESET}}$  until the next POR. The  $\overline{\text{RESET}}$  pin can be used to reset the MCU from an external source when the pin is driven low. When enabled as the  $\overline{\text{RESET}}$  pin ( $\text{RSTPE} = 1$ ), the pin is configured as an input only with an internal pullup device automatically enabled.

#### NOTE

This pin does not contain a clamp diode to  $V_{DD}$  and should not be driven above  $V_{DD}$ .

#### NOTE

The  $\overline{\text{RESET}}$  pin is pulled to  $V_{DD}$  internally. The external voltage measured on the  $\overline{\text{RESET}}$  pin will be less than  $V_{DD}$ . Therefore, the  $\overline{\text{RESET}}$  pullup should not be used to pullup components external to the MCU.

#### NOTE

In EMC-sensitive applications, an external RC filter is recommended on the  $\overline{\text{RESET}}$  pin, if enabled. See [Figure 2-6](#) for an example.

After a power-on reset (POR), the PTC4/TPM3CH4/ $\overline{\text{RSTO}}$  pin defaults to a general-purpose port pin, PTC4. Setting  $\text{RSTOPE}$  in  $\text{SOPT1}$  configures the pin to be the  $\overline{\text{RSTO}}$  pin. After configured as  $\overline{\text{RSTO}}$ , the pin will remain  $\overline{\text{RSTO}}$  until the next POR. The  $\overline{\text{RSTO}}$  pin will reflect the current state of the internal MCU reset signal. As long as the MCU is not in a reset state, the  $\overline{\text{RSTO}}$  pin will drive high. Whenever the MCU is in a reset state, this pin will drive low until the internal reset signal is released. When enabled as the  $\overline{\text{RSTO}}$  pin ( $\text{RSTOPE} = 1$ ), the pin is automatically configured as an output only. The  $\overline{\text{RSTO}}$  pin can be enabled independently of the  $\overline{\text{RESET}}$  pin.

## 2.2.4 Background / Mode Select (BKGD/MS)

During a power-on-reset (POR) or background debug force reset (see [Section 5.8.3, “System Background Debug Force Reset Register \(SBD FR\)”](#) for more information), the PTA4/ACMPO/BKGD/MS pin functions as a mode select pin. Immediately after any reset, the pin functions as the background pin and can be used for background debug communication. When enabled as the BKGD/MS pin ( $\text{BKGDPE} = 1$ ), an internal pullup device is automatically enabled.

The background debug communication function is enabled when  $\text{BKGDPE}$  in  $\text{SOPT1}$  is set.  $\text{BKGDPE}$  is set following any reset of the MCU and must be cleared to use the PTA4/ACMPO/BKGD/MS pin’s alternative pin functions.

If nothing is connected to this pin, the MCU will enter normal operating mode at the rising edge of the internal reset after a POR or force BDC reset. If a debug system is connected to the 6-pin standard background debug header, it can hold BKGD/MS low during a POR or immediately after issuing a background debug force reset, which will force the MCU to active background mode.

The BKGD/MS pin is used primarily for background debug controller (BDC) communications using a custom protocol that uses 16 clock cycles of the target MCU’s BDC clock per bit time. The target MCU’s BDC clock could be as fast as the bus clock rate, so there should never be any significant capacitance connected to the BKGD/MS pin that could interfere with background serial communications.

Although the BKGD/MS pin is a pseudo open-drain pin, the background debug communication protocol provides brief, actively driven, high speedup pulses to ensure fast rise times. Small capacitances from cables and the absolute value of the internal pull-up device play almost no role in determining rise and fall times on the BKGD/MS pin.

### 2.2.5 ADC Reference Pins ( $V_{REFH}$ , $V_{REFL}$ )

The  $V_{REFH}$  and  $V_{REFL}$  pins are the voltage reference high and voltage reference low inputs, respectively, for the ADC module. In the 32-pin package,  $V_{REFH}$  and  $V_{REFL}$  are shared with  $V_{DDA}$  and  $V_{SSA}$ , respectively.

### 2.2.6 General-Purpose I/O and Peripheral Ports

The MC9S08QE128 Series of MCUs support up to 70 general-purpose I/O pins 1 input-only pin, and 1 output-only pin, which are shared with on-chip peripheral functions (timers, serial I/O, ADC, ACMP, etc.).

When a port pin is configured as a general-purpose output or a peripheral uses the port pin as an output, software can select one of two drive strengths and enable or disable slew rate control. When a port pin is configured as a general-purpose input or a peripheral uses the port pin as an input, software can enable a pull-up device. Immediately after reset, all of these pins are configured as high-impedance general-purpose inputs with internal pull-up devices disabled.

PTA5 is a special-case input pin. When the PTA5/IRQ/TCLK/ $\overline{\text{RESET}}$  pin is configured as PTA5 with the pullup enabled, the voltage observed on the pin will not be pulled to  $V_{DD}$ . However, the internal voltage on the PTA5 node will be at  $V_{DD}$ .

When an on-chip peripheral system is controlling a pin, data direction control bits still determine what is read from port data registers even though the peripheral module controls the pin direction by controlling the enable for the pin's output buffer. For information about controlling these pins as general-purpose I/O pins, see [Chapter 6, "Parallel Input/Output Control."](#)

#### NOTE

To avoid extra current drain from floating input pins, the reset initialization routine in the application program should either enable on-chip pull-up devices or change the direction of unused or non-bonded pins to outputs so they do not float.

**Table 2-1. Pin Assignment by Package and Pin Sharing Priority**

Pin Number					<-- Lowest Priority --> Highest				
80	64	48	44	32	Port Pin	Alt 1	Alt 2	Alt 3	Alt 4
1	1	1	1	1	PTD1	KBI2P1	MOSI2		
2	2	2	2	2	PTD0	KBI2P0	SPSCK2		
3	3	—	—	—	PTH7	SDA2			
4	4	—	—	—	PTH6	SCL2			
5	—	—	—	—	PTH5				
6	—	—	—	—	PTH4				
7	5	3	3	—	PTE7	TPM3CLK			
8	6	4	4	3					V <sub>DD</sub>
9	7	5	5	4					V <sub>DDA</sub>
10	8	6	6	4					V <sub>REFH</sub>
11	9	7	7	5					V <sub>REFL</sub>
12	10	8	8	5					V <sub>SSA</sub>
13	11	9	9	6					V <sub>SS</sub>
14	12	10	10	7	PTB7	SCL1 <sup>1</sup>			EXTAL
15	13	11	11	8	PTB6	SDA1 <sup>1</sup>			XTAL
16	—	—	—	—	PTH3				
17	—	—	—	—	PTH2				
18	14	—	—	—	PTH1				
19	15	—	—	—	PTH0				
20	16	12	—	—	PTE6				
21	17	13	—	—	PTE5				
22	18	14	12	9	PTB5	TPM1CH1	SS1 <sup>2</sup>		
23	19	15	13	10	PTB4	TPM2CH1	MISO1 <sup>2</sup>		
24	20	16	14	11	PTC3	TPM3CH3			
25	21	17	15	12	PTC2	TPM3CH2			
26	22	18	16	—	PTD7	KBI2P7			
27	23	19	17	—	PTD6	KBI2P6			
28	24	20	18	—	PTD5	KBI2P5			
29	—	—	—	—	PTJ7				
30	—	—	—	—	PTJ6				
31	—	—	—	—	PTJ5				
32	—	—	—	—	PTJ4				
33	25	21	19	13	PTC1	TPM3CH1			
34	26	22	20	14	PTC0	TPM3CH0			
35	27	—	—	—	PTF7				ADP17
36	28	—	—	—	PTF6				ADP16
37	29	—	—	—	PTF5				ADP15
38	30	—	—	—	PTF4				ADP14
39	31	23	21	15	PTB3	KBI1P7	MOSI1 <sup>2</sup>		ADP7
40	32	24	22	16	PTB2	KBI1P6	SPSCK1 <sup>2</sup>		ADP6

**Table 2-1. Pin Assignment by Package and Pin Sharing Priority (continued)**

Pin Number					<-- Lowest Priority --> Highest				
80	64	48	44	32	Port Pin	Alt 1	Alt 2	Alt 3	Alt 4
41	33	25	23	17	PTB1	KBI1P5	TxD1		ADP5
42	34	26	24	18	PTB0	KBI1P4	RxD1		ADP4
43	—	—	—	—	PTJ3				
44	—	—	—	—	PTJ2				
45	35	—	—	—	PTF3				ADP13
46	36	—	—	—	PTF2				ADP12
47	37	27	25	19	PTA7	TPM2CH2			ADP9
48	38	28	26	20	PTA6	TPM1CH2			ADP8
49	39	29	—	—	PTE4				
50	40	30	27	—					V <sub>DD</sub>
51	41	31	28	—					V <sub>SS</sub>
52	42	—	—	—	PTF1				ADP11
53	43	—	—	—	PTF0				ADP10
54	—	—	—	—	PTJ1				
55	—	—	—	—	PTJ0				
56	44	32	29	—	PTD4	KBI2P4			
57	45	33	30	21	PTD3	KBI2P3	SS2		
58	46	34	31	22	PTD2	KBI2P2	MISO2		
59	47	35	32	23	PTA3	KBI1P3	SCL1 <sup>1</sup>		ADP3
60	48	36	33	24	PTA2	KBI1P2	SDA1 <sup>1</sup>		ADP2
61	49	37	34	25	PTA1	KBI1P1	TPM2CH0	ADP1 <sup>3</sup>	ACMP1- <sup>3</sup>
62	50	38	35	26	PTA0	KBI1P0	TPM1CH0	ADP0 <sup>3</sup>	ACMP1+ <sup>3</sup>
63	51	39	36	27	PTC7	TxD2			ACMP2-
64	52	40	37	28	PTC6	RxD2			ACMP2+
65	—	—	—	—	PTG7				ADP23
66	—	—	—	—	PTG6				ADP22
67	—	—	—	—	PTG5				ADP21
68	—	—	—	—	PTG4				ADP20
69	53	41	—	—	PTE3	SS1 <sup>2</sup>			
70	54	42	38	—	PTE2	MISO1 <sup>2</sup>			
71	55	—	—	—	PTG3				ADP19
72	56	—	—	—	PTG2				ADP18
73	57	—	—	—	PTG1				
74	58	—	—	—	PTG0				
75	59	43	39	—	PTE1	MOSI1 <sup>2</sup>			
76	60	44	40	—	PTE0	TPM2CLK	SPSCK1 <sup>2</sup>		
77	61	45	41	29	PTC5	TPM3CH5			ACMP20
78	62	46	42	30	PTC4	TPM3CH4	RSTO		
79	63	47	43	31	PTA5	IRQ	TPM1CLK	RESET	
80	64	48	44	32	PTA4	ACMP1O	BKGD	MS	

- <sup>1</sup> IIC1 pins (SCL1 and SDA1) can be repositioned using IIC1PS in SOPT2. Default locations are PTA3 and PTA, respectively.
- <sup>2</sup> SPI1 pins ( $\overline{SS1}$ , MISO1, MOSI1, and SPCK1) can be repositioned using SPI1PS in SOPT2. Default locations are PTB5, PTB4, PTB3, and PTB2.
- <sup>3</sup> If ADC and ACMP1 are enabled, both modules will have access to the pin.

## Chapter 3

# Modes of Operation

### 3.1 Introduction

The operating modes of the MC9S08QE128 Series are described in this chapter. Entry into each mode, exit from each mode, and functionality while in each of the modes are described.

### 3.2 Features

- Active background mode for code development
- Run mode — CPU clocks can be run at full speed and the internal supply is fully regulated.
- LPRUN mode — CPU clocks are restricted to a maximum of 250 kHz, peripheral clocks are restricted to a maximum of 125 kHz, and the internal voltage regulator is in standby
- Wait mode — CPU shuts down to conserve power; system clocks are running and full regulation is maintained
- LPWAIT mode — CPU shuts down to conserve power; peripheral clocks are restricted to 125 kHz maximum and the internal voltage regulator is in standby
- Stop modes — System clocks are stopped and voltage regulator is in standby
  - Stop3 — All internal circuits are powered for fast recovery
  - Stop2 — Partial power down of internal circuits, RAM content is retained; I/O states are held

### 3.3 Run Mode

This is the normal operating mode for the MC9S08QE128 Series. In this mode, the CPU executes code from internal memory with execution beginning at the address fetched from memory at 0xFFFFE–0xFFFF after reset.

#### 3.3.1 Low Power Run Mode (LPRun)

In the low power run mode, the on-chip voltage regulator is put into its standby state. In this state, the power consumption is reduced to a minimum that still allows CPU functionality. Power consumption is reduced the most by disabling the clocks to all unused peripherals by clearing the corresponding bits in the SCGC1 and SCGC2 registers.

Before entering this mode, the following conditions must be met:

- FBELP is the selected clock mode for the ICS (See the FBELP section in Chapter 11, “Internal Clock Source (S08ICSV3).”)
- The HGO bit in the ICSC2 register is clear.

- The bus frequency is 125 kHz or less.
- The ADC if enabled must be configured to use the asynchronous clock source, ADACK, to meet the ADC minimum frequency requirements. The bandgap channel cannot be converted in low power run mode.
- The LVDE or LVDSE bit in SPMSC1 register must be clear. LVD and LVW will automatically be disabled.
- Flash programming/erasing is not allowed.
- ACMP option to compare to internal bandgap reference is not allowed.
- The MCU cannot be in active background mode.

Once these conditions are met, low power run mode can be entered by setting the LPR bit in the SPMSC2 register.

To re-enter standard run mode, simply clear the LPR bit. The LPRS bit in the SPMSC2 register is a read-only status bit that can be used to determine if the regulator is in full regulation mode or not. When LPRS is '0', the regulator is in full regulation mode and the MCU can run at full speed in any clock mode.

### 3.3.1.1 Interrupts in Low Power Run Mode

Low power run mode provides the option to return to full regulation if any interrupt occurs. This is done by setting the LPWUI bit in the SPMSC2 register. The ICS can then be set for full speed immediately in the interrupt service routine.

If the LPWUI bit is clear, interrupts will be serviced in low power run mode.

If the LPWUI bit is set, LPR and LPRS bits will be cleared and interrupts will be serviced with the regulator in full regulation.

### 3.3.1.2 Resets in Low Power Run Mode

Any reset will exit low power run mode, clear the LPR and LPRS bits and return the device to normal run mode.

### 3.3.1.3 BDM in Low Power Run Mode

Low power run mode cannot be entered when the MCU is in active background debug mode.

If a device is in low power run mode, a falling edge on an active BKGD/MS pin exits low power run mode, clears the LPR and LPRS bits, and returns the device to normal run mode.

### 3.3.1.4 BDM in Low Power Wait Mode

If a device is in low power wait mode, a falling edge on an active BKGD/MS pin exits low power wait mode, clears the LPR and LPRS bits, and returns the device to normal run mode.



## 3.4 Active Background Mode

The active background mode functions are managed through the background debug controller (BDC) in the HCS08 core. The BDC, together with the on-chip debug module (DBG), provide the means for analyzing MCU operation during software development.

Active background mode is entered in any of six ways:

- When the BKGD/MS pin is low during POR
- When the BKGD/MS pin is low immediately after issuing a background debug force reset (see [Section 5.8.3, “System Background Debug Force Reset Register \(SBD FR\)”](#))
- When a BACKGROUND command is received through the BKGD/MS pin
- When a BGND instruction is executed
- When encountering a BDC breakpoint
- When encountering a DBG breakpoint

After entering active background mode, the CPU is held in a suspended state waiting for serial background commands rather than executing instructions from the user application program.

Background commands are of two types:

- Non-intrusive commands, defined as commands that can be issued while the user program is running. Non-intrusive commands can be issued through the BKGD pin while the MCU is in run mode; non-intrusive commands can also be executed when the MCU is in the active background mode. Non-intrusive commands include:
  - Memory access commands
  - Memory-access-with-status commands
  - BDC register access commands
  - The BACKGROUND command
- Active background commands, which can only be executed while the MCU is in active background mode. Active background commands include commands to:
  - Read or write CPU registers
  - Trace one user program instruction at a time
  - Leave active background mode to return to the user application program (GO)

The active background mode is used to program a bootloader or user application program into the flash program memory before the MCU is operated in run mode for the first time. When the MC9S08QE128 Series is shipped from the Freescale Semiconductor factory, the flash program memory is erased by default unless specifically noted, so there is no program that could be executed in run mode until the flash memory is initially programmed. The active background mode can also be used to erase and reprogram the flash memory after it has been previously programmed.

For additional information about the active background mode, refer to the [Development Support](#) chapter.

## 3.5 Wait Mode

Wait mode is entered by executing a WAIT instruction. Upon execution of the WAIT instruction, the CPU enters a low-power state in which it is not clocked. The I bit in CCR is cleared when the CPU enters the wait mode, enabling interrupts. When an interrupt request occurs, the CPU exits the wait mode and resumes processing, beginning with the stacking operations leading to the interrupt service routine.

While the MCU is in wait mode, there are some restrictions on which background debug commands can be used. Only the BACKGROUND command and memory-access-with-status commands are available when the MCU is in wait mode. The memory-access-with-status commands do not allow memory access, but they report an error indicating that the MCU is in either stop or wait mode. The BACKGROUND command can be used to wake the MCU from wait mode and enter active background mode.

### 3.5.1 Low Power Wait Mode (LPWait)

Low power wait mode is entered by executing a WAIT instruction while the MCU is in low power run mode. In the low power wait mode, the on-chip voltage regulator remains in its standby state as in the low power run mode. In this state, the power consumption is reduced to a minimum that still allows most modules to maintain functionality. Power consumption is reduced the most by disabling the clocks to all unused peripherals by clearing the corresponding bits in the SCGC register.

The same restrictions from the low power run mode apply to low power wait mode.

#### 3.5.1.1 Interrupts in Low Power Wait Mode

If the LPWUI bit is set when the WAIT instruction is executed, then the voltage regulator will return to full regulation when wait mode is exited. The ICS can be set for full speed immediately in the interrupt service routine.

If the LPWUI bit is clear when the WAIT instruction is executed, an interrupt will return the device to low power run mode.

If the LPWUI bit is set when the WAIT instruction is executed, an interrupt will return the device to normal run mode with full regulation and the LPR and LPRS bits will be cleared.

#### 3.5.1.2 Resets in Low Power Wait Mode

Any reset will exit low power wait mode, clear LPR and LPRS bit, and return the device to normal run mode.

## 3.6 Stop Modes

Either stop2 or stop3 is entered upon execution of a STOP instruction when the STOPE bit in the system option 1 register (SOPT1) is set. In both stop modes, the bus and CPU clocks are halted. In stop3 the regulator is in standby. In stop2 the regulator is in partial powerdown. The ICS module can be configured to leave the reference clocks running. See [Chapter 11, “Internal Clock Source \(S08ICSV3\)”](#) for more information.

If the STOPE bit is not set when the CPU executes a STOP instruction, the MCU will not enter either of the stop modes and an illegal opcode reset is forced. The stop modes are selected by setting the appropriate bits in the Section 5.8.10, “System Clock Gating Control 1 Register (SCGC1).”

Table 3-1 shows all of the control bits that affect stop mode selection and the mode selected under various conditions. The selected mode is entered following the execution of a STOP instruction.

**Table 3-1. Stop Mode Selection**

Register	SOPT1	BDCSCR	SPMSC1		SPMSC2	Stop Mode
Bit name	STOPE	ENBDM <sup>1</sup>	LVDE	LVDSE	PPDC	
	0	x	x		x	Stop modes disabled; illegal opcode reset if STOP instruction executed
	1	1	x		x	Stop3 with BDM enabled <sup>2</sup>
	1	0	Both bits must be 1		x	Stop3 with voltage regulator active
	1	0	Either bit a 0		0	Stop3
	1	0	Either bit a 0		1	Stop2

<sup>1</sup> ENBDM is located in the BDCSCR, which is only accessible through BDC commands; see the “BDC Status and Control Register (BDCSCR)” section in Chapter 17, “Development Support.”

<sup>2</sup> When in Stop3 mode with BDM enabled, The  $S_{IDD}$  will be near  $R_{IDD}$  levels because internal clocks are enabled.

## 3.6.1 Stop2 Mode

### 3.6.1.1 Stop2 Entry

Stop2 mode is entered by executing a STOP instruction under the conditions as shown in Table 3-1.

### 3.6.1.2 Behavior in Stop2

Most of the internal circuitry of the MCU is powered off in stop2 with the exception of the RAM and optionally the RTC and low power oscillator (LPO), and the low-range low-gain oscillator (XOSCVLP). Upon entering stop2, all I/O pin control signals are latched so that the pins retain their states during stop2.

### 3.6.1.3 Exit from Stop2

Exit from stop2 is performed by asserting the wake-up pin (PTA5/IRQ/TCLK/ $\overline{\text{RESET}}$ ) on the MCU.

#### NOTE

PTA5/IRQ/TPM1CLK/ $\overline{\text{RESET}}$  functions as an active-low wakeup input when the MCU is in stop2. The pullup on this pin is not automatically enabled in stop2. To enable the internal pullup, set the PTAPE5 bit in the port A pull enable register (PTAPE).

### 3.6.1.4 RTC Considerations for Stop2

In addition, the real-time counter (RTC) can wake the MCU from stop2, if enabled.

Upon wake-up from stop2 mode, the MCU starts up as from a power-on reset (POR):

- All module control and status registers are reset, except for SPMSC1–SPMSC3, DBG trace buffer, and RTC registers
- The CPU takes the reset vector

### 3.6.1.5 I/O Considerations for Stop2

In addition to the above, upon waking up from stop2, the PPDF bit in SPMSC2 is set. This flag is used to direct user code to go to a stop2 recovery routine. PPDF remains set and the I/O pin states remain latched until a 1 is written to PPDACK in SPMSC2.

**GPIO** — To maintain I/O states for pins that were configured as general-purpose I/O, the user must:

1. Before entering stop2, save the contents of the I/O registers into RAM before entering stop2.
2. Restore the contents of the I/O port registers, which have been saved in RAM, to the port registers before writing to the PPDACK bit.

If the port registers are not restored from RAM before writing to PPDACK, then the pins will switch to their reset states when PPDACK is written.

**Peripheral I/O** — For pins that were configured as peripheral I/O, the user must reconfigure the peripheral module that interfaces to the pin before writing to the PPDACK bit.

If the peripheral module is not enabled before writing to PPDACK, the pins will be controlled by their associated port control registers when the I/O latches are opened.

#### NOTE

The RSTPE bit will be cleared by the stop2 recovery and should not be set before writing to the PPDACK bit. Doing so will cause a second reset event and the PPDF bit will be cleared at the end of the second reset.

### 3.6.1.6 Low-Power Oscillator Considerations for Stop2

If using the low power oscillator during stop2, the user must reconfigure the ICSC2 register which contains oscillator control bits before PPDACK is written.

The low power (HGO=0), low range (RANGE=0) oscillator can operate in stop2 to be the clock source for the RTC module. If the low power low range oscillator is active upon entering stop2, it will remain active in stop2 regardless of the value of EREFSTEN. To disable the oscillator in stop2, the ICS must be switched into FBI or FEI mode before executing the STOP instruction.

## 3.6.2 Stop3 Mode

Stop3 mode is entered by executing a STOP instruction under the conditions as shown in [Table 3-1](#). The states of all of the internal registers and logic, RAM contents, and I/O pin states are maintained.

Stop3 can be exited by asserting  $\overline{\text{RESET}}$ , or by an interrupt from one of the following sources: the RTC, LVD, LVW, ADC, ACMPx, IRQ, SCI, or the KBI.

If stop3 is exited by means of the  $\overline{\text{RESET}}$  pin, then the MCU is reset and operation will resume after taking the reset vector. Exit by means of one of the internal interrupt sources results in the MCU taking the appropriate interrupt vector.

### 3.6.3 Active BDM Enabled in Stop Mode

Entry into the active background mode from run mode is enabled if the ENBDM bit in BDCSCR is set. This register is described in [Chapter 17, “Development Support.”](#) If ENBDM is set when the CPU executes a STOP instruction, the system clocks to the background debug logic remain active when the MCU enters stop mode. Because of this, background debug communication remains possible. In addition, the voltage regulator does not enter its low-power standby state but maintains full internal regulation. If the user attempts to enter stop2 with ENBDM set, the MCU will instead enter stop3.

Most background commands are not available in stop mode. The memory-access-with-status commands do not allow memory access, but they report an error indicating that the MCU is in either stop or wait mode. The BACKGROUND command can be used to wake the MCU from stop and enter active background mode if the ENBDM bit is set. After entering background debug mode, all background commands are available.

### 3.6.4 LVD Enabled in Stop Mode

The LVD system is capable of generating either an interrupt or a reset when the supply voltage drops below the LVD voltage. If the LVD is enabled in stop (LVDE and LVDSE bits in SPMSC1 both set) the voltage regulator remains active during stop mode. If the user attempts to enter stop2 with the LVD enabled for stop, the MCU will instead enter stop3.

### 3.6.5 Stop modes in Low Power Run Mode

Stop2 mode cannot be entered from low power run mode. If the PPDC bit is set, then the LPR bit cannot be set. Likewise, if the LPR bit is set, the PPDC bit cannot be set.

Stop3 mode can be entered from low power run mode by executing the STOP instruction while in low power run. Existing stop3 with a reset will put the device back into normal run mode. If LPWUI is clear, interrupts will exit stop3 mode, return the device to low power run mode, and then service the interrupt. If LPWUI is set, interrupts will exit stop3 mode, put the device into normal run mode, clear LPR and LPRS bits, and then service the interrupt.

## 3.7 Mode Selection

Several control signals are used to determine the current operating mode of the device. [Table 3-2](#) shows the conditions for each of the device’s operating modes.

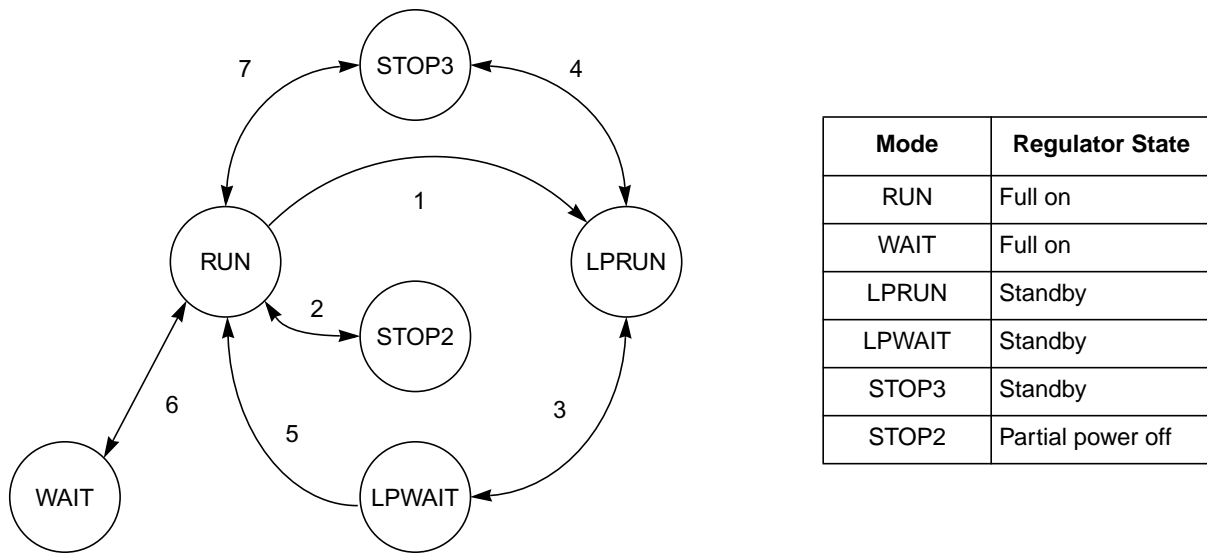
**Table 3-2. Power Mode Selections**

Mode of Operation	BDCSCR BDM	SPMSC1 PMC		SPMSC2 PMC		CPU & Periph CLKs	Effects on Sub-System	
	ENBDM <sup>1</sup>	LVDE	LVDSE	LPR	PPDC		BDM Clock	Voltage Regulator
RUN mode	0	x	x	0	x	on. ICS in any mode.	off	on
		1	1	1				
	1	x	x	x				
LPRUN mode	0	0	x	1	0	low freq required. ICS in FBELP mode only.	off	standby
		1	0					
WAIT mode - (Assumes WAIT instruction executed.)	0	x	x	0	x	CPU clock is off; peripheral clocks on. ICS state same as RUN mode.	off	on
		1	1	1				
	1	x	x	x				
LPWAIT mode - (Assumes WAIT instruction executed.)	0	0	x	1	0	CPU clock is off; peripheral clocks at low speed. ICS in FBELP mode.	off	standby
		1	0					
STOP3 - (Assumes STOPE bit is set and STOP instruction executed.) Note that STOP3 is used in place of STOP2 if the BDM or LVD is enabled.	0	0	x	x	0	ICS in STOP. LPO, OSCOUT, IC SERCLK and IC SIRCLK optionally on <sup>2</sup>	off	standby
	0	1	0	x	0		off	
	0	1	1	x	x		off	
	1	x	x	x	x	ICS LCLK still active.	on	on - stop currents will be increased
STOP2 - (Assumes STOPE bit is set and STOP instruction executed.) If BDM or LVD is enabled, STOP3 will be invoked rather than STOP2.	0	0	x	0	1	LPO and OSCOUT optionally on <sup>2,3</sup>	off	partial powerdown
	1	0						

<sup>1</sup> ENBDM is located in the BDC status and control register (BDCSCR) which is write accessible only through BDC commands, see [Chapter 17, "Development Support."](#)

<sup>2</sup> Configured within the ICS module based on the settings of IREFSTEN, EFRESTEN, IRCLKEN, and ERCLKEN.

<sup>3</sup> In stop2, CPU, flash, ICS and all peripheral modules are powered down except for the RTC.



**Figure 3-1. Allowable Power Mode Transitions for the MC9S08QE128 Series**

Figure 3-1 illustrates mode state transitions allowed between the legal states shown in Table 3-1. PTA5/IRQ/TPM1CLK/ $\overline{\text{RESET}}$  must be asserted low (or an RTC interrupt must occur) in order to exit stop2. Interrupts suffice for the other stop and wait modes.

Table 3-3 defines triggers for the various state transitions shown in Figure 3-1.

**Table 3-3. Triggers for Transitions Shown in Figure 3-1.**

Transition #	From	To	Trigger
1	RUN	LPRUN	Configure settings shown in Table 3-1, <b>switch LPR=1 last</b>
	LPRUN	RUN	Clear LPR <b>Interrupt</b> when LPWUI=1
2	RUN	STOP2	Pre-configure settings shown in Table 3-1, issue <b>STOP instruction</b>
	STOP2	RUN	<b>Assert zero on PTA5/IRQ/TPM1CLK/<math>\overline{\text{RESET}}</math><sup>1</sup></b> , reload environment from RAM
3	LPRUN	LPWAIT	<b>WAIT</b> instruction
	LPWAIT	LPRUN	<b>Interrupt</b> when LPWUI=0
4	LPRUN	STOP3	<b>STOP</b> instruction
	STOP3	LPRUN	<b>Interrupt</b> when LPWUI=0

**Table 3-3. Triggers for Transitions Shown in Figure 3-1. (continued)**

Transition #	From	To	Trigger
5	LPWAIT	RUN	Interrupt when LPWUI=1
	RUN	LPWAIT	NOT SUPPORTED
6	RUN	WAIT	WAIT instruction
	WAIT	RUN	Interrupt or reset
7	STOP3	RUN	Interrupt (if LPR = 0, or LPR = 1 and LPWUI =1) or reset
	RUN	STOP3	STOP instruction

<sup>1</sup> An analog connection from this pin to the on-chip regulator will wake up the regulator, which will then initiate a power-on-reset sequence.

### 3.7.1 On-Chip Peripheral Modules in Stop and Low Power Modes

When the MCU enters any stop mode, system clocks to the internal peripheral modules are stopped. Even in the exception case (ENBDM = 1), where clocks to the background debug logic continue to operate, clocks to the peripheral systems are halted to reduce power consumption. Refer to Section 3.6.1, “Stop2 Mode,” and Section 3.6.2, “Stop3 Mode,” for specific information on system behavior in stop modes.

When the MCU enters LPWait or LPRun modes, system clocks to the internal peripheral modules continue based on the settings of the clock gating control registers (SCGC1 and SCGC2).

**Table 3-4. Stop and Low Power Mode Behavior**

Peripheral	Mode			
	Stop2	Stop3	LPWait	LPRun
CPU	Off	Standby	Standby	On
RAM	Standby	Standby	Standby	On
Flash	Off	Standby	Standby	On
Port I/O Registers	Off	Standby	Standby	On
Port I/O Pins	States Held	Peripheral Control	Peripheral Control	On
ADC	Off	Optionally On <sup>1</sup>	Optionally On <sup>1</sup>	Optionally On <sup>1</sup>
ACMPx	Off	Optionally On <sup>2</sup>	Optionally On	Optionally On
BDM	Off <sup>3</sup>	Optionally On	Off <sup>4</sup>	Off <sup>4</sup>
COP	Off	Off	Optionally On	Optionally On
ICS	Off	Optionally On <sup>5</sup>	On <sup>6</sup>	On <sup>6</sup>
IICx	Off	Standby	Optionally On	Optionally On
IRQ	Wake Up	Optionally On	Optionally On	Optionally On
KBIX	Off	Optionally On	Optionally On	Optionally On
LVD/LVW	Off <sup>7</sup>	Optionally On	Off <sup>8</sup>	Off <sup>8</sup>
RTC	Optionally On	Optionally On	Optionally On	Optionally On



**Table 3-4. Stop and Low Power Mode Behavior (continued)**

Peripheral	Mode			
	Stop2	Stop3	LPWait	LPRun
SCIx	Off	Standby	Optionally On	Optionally On
SPIx	Off	Standby	Optionally On	Optionally On
TPMx	Off	Standby	Optionally On	Optionally On
Voltage Regulator	Partial Powerdown	Optionally On <sup>9</sup>	Standby	Standby
XOSC	Optionally On	Optionally On <sup>10</sup>	Optionally On	Optionally On

<sup>1</sup> Requires the asynchronous ADC clock. For stop3, LVD must be enabled to run in stop if converting the bandgap channel.

<sup>2</sup> LVD must be enabled to run in stop if using the bandgap as a reference.

<sup>3</sup> If ENBDM is set when entering stop2, the MCU will actually enter stop3.

<sup>4</sup> If ENBDM is set when entering LPRun or LPWait, the MCU will actually stay in run mode or enter wait mode, respectively.

<sup>5</sup> IRCLKEN and IREFSTEN set in ICSC1, else in standby.

<sup>6</sup> ICS must be configured for FBELP, bus frequency limited to 125kHz in LPRUN or LPWAIT.

<sup>7</sup> If LVDSE is set when entering stop2, the MCU will actually enter stop3.

<sup>8</sup> If LVDSE is set when entering LPRun or LPWait, the MCU will actually enter run or wait mode, respectively.

<sup>9</sup> Requires the LVD to be enabled, else in standby. See [Section 3.6.4, "LVD Enabled in Stop Mode"](#).

<sup>10</sup> ERCLKEN and EREFSTEN set in ICSC2, else in standby.



# Chapter 4 Memory

## 4.1 MC9S08QE128 Series Memory Map

As shown in Figure 4-1, Figure 4-2, and Figure 4-3, on-chip memory in the MC9S08QE128 Series of MCUs consists of RAM, flash program memory for nonvolatile data storage, and I/O and control/status registers. The registers are divided into three groups:

- Direct-page registers (0x0000 through 0x007F)
- High-page registers (0x1800 through 0x187F)
- Nonvolatile registers (0xFFB0 through 0xFFBF)

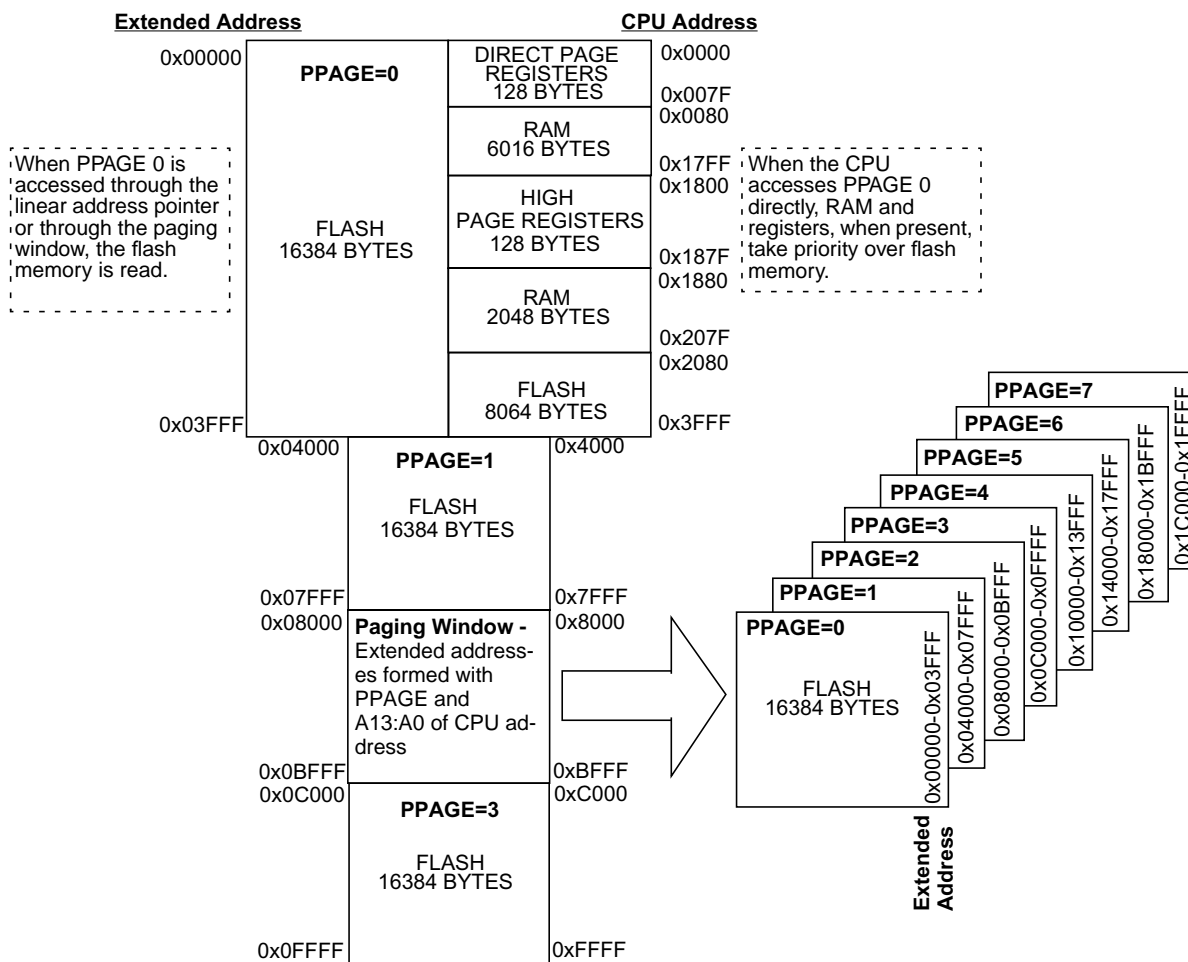


Figure 4-1. MC9S08QE128 Memory Map

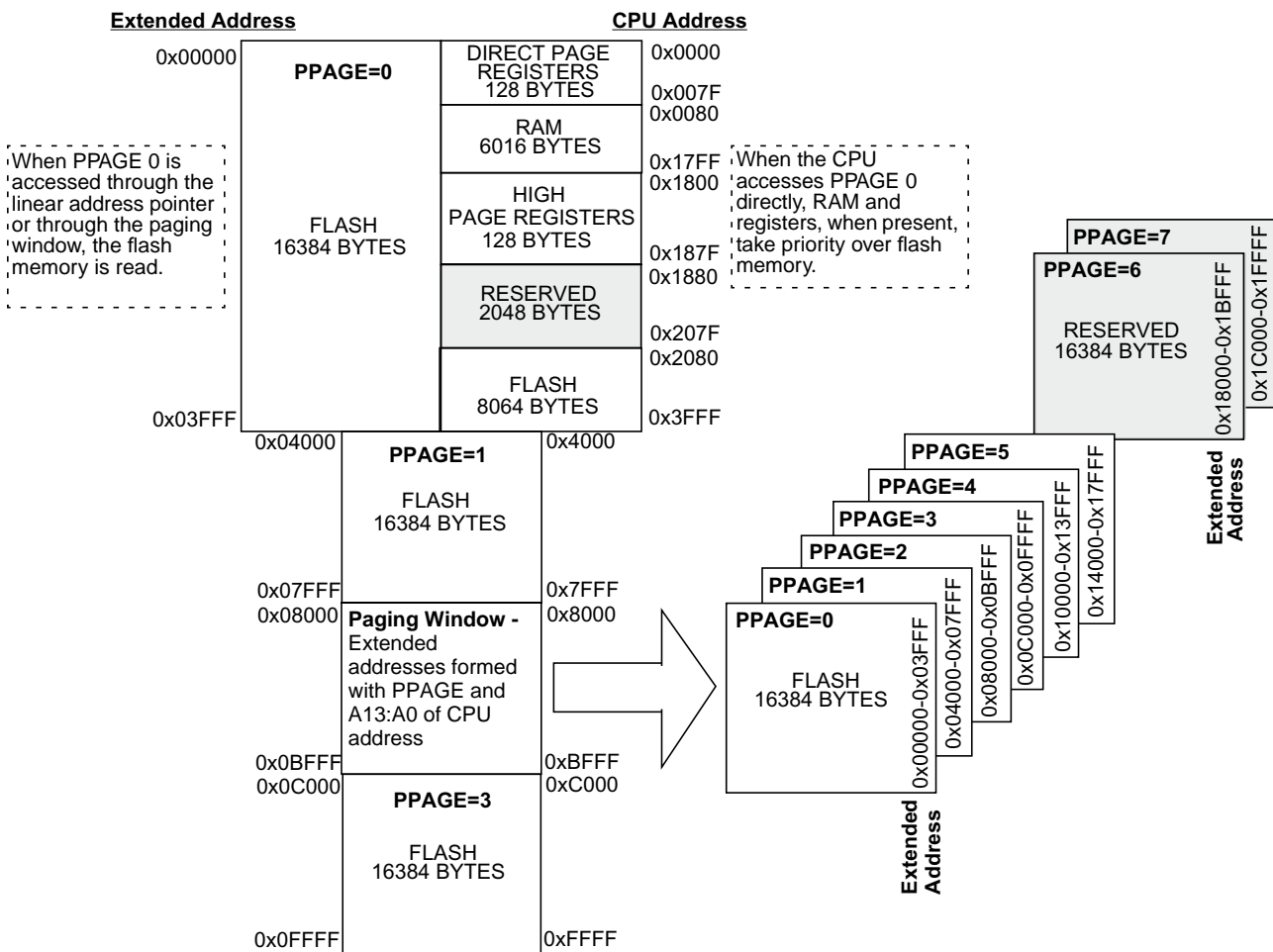


Figure 4-2. MC9S08QE96 Memory Map

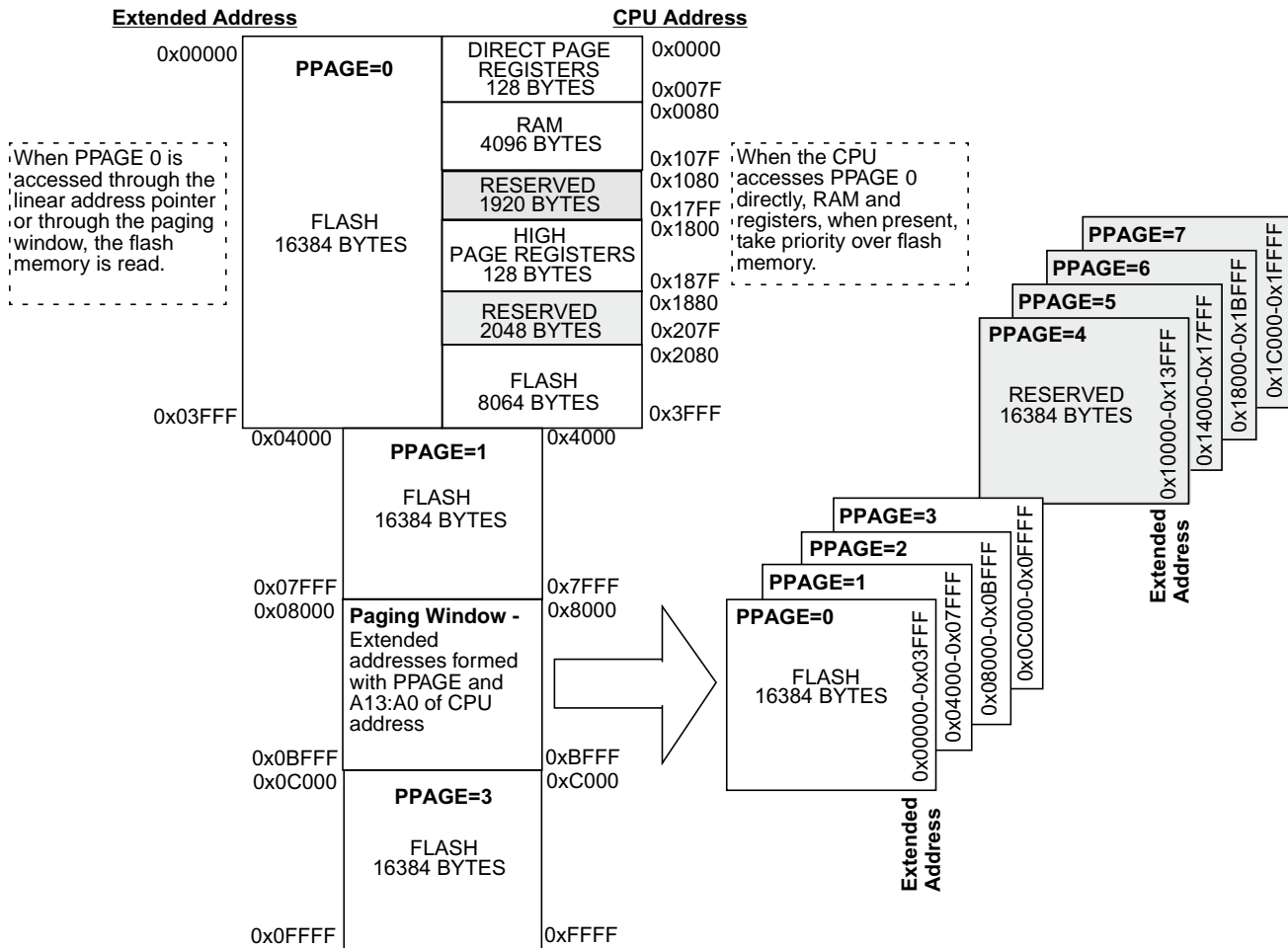


Figure 4-3. MC9S08QE64 Memory Map

## 4.2 Reset and Interrupt Vector Assignments

Table 4-1 shows address assignments for reset and interrupt vectors. The vector names shown in this table are the labels used in the Freescale Semiconductor provided equate file for the MC9S08QE128 Series.

Table 4-1. Reset and Interrupt Vectors

Address (High/Low)	Vector	Vector Name
0xFFC0:0xFFC1	TPM3 Overflow	Vtpm3ovf
0xFFC2:0xFFC3	TPM3 Channel 5	Vtpm3ch5
0xFFC4:0xFFC5	TPM3 Channel 4	Vtpm3ch4
0xFFC6:0xFFC7	TPM3 Channel 3	Vtpm3ch3
0xFFC8:0xFFC9	TPM3 Channel 2	Vtpm3ch2
0xFFCA:0xFFCB	TPM3 Channel 1	Vtpm3ch1
0xFFCC:0xFFCD	TPM3 Channel 0	Vtpm3ch0

**Table 4-1. Reset and Interrupt Vectors (continued)**

Address (High/Low)	Vector	Vector Name
0xFFCE:0xFFCF	RTC	Vrtc
0xFFD0:0xFFD1	SCI2 Transmit	Vsci2tx
0xFFD2:0xFFD3	SCI2 Receive	Vsci2rx
0xFFD4:0xFFD5	SCI2 Error	Vsci2err
0xFFD6:0xFFD7	ACMPx <sup>1</sup>	Vacmpx
0xFFD8:0xFFD9	ADC Conversion	Vadc
0xFFDA:0xFFDB	KBlx Interrupt <sup>2</sup>	Vkeyboard
0xFFDC:0xFFDD	IICx <sup>3</sup>	Viicx
0xFFDE:0xFFDF	SCI1 Transmit	Vsci1tx
0xFFE0:0xFFE1	SCI1 Receive	Vsci1rx
0xFFE2:0xFFE3	SCI1 Error	Vsci1err
0xFFE4:0xFFE5	SPI1	Vspi1
0xFFE6:0xFFE7	SPI2	Vspi2
0xFFE8:0xFFE9	TPM2 Overflow	Vtpm2ovf
0xFFEA:0xFFEB	TPM2 Channel 2	Vtpm2ch2
0xFFEC:0xFFED	TPM2 Channel 1	Vtpm2ch1
0xFFEE:0xFFEF	TPM2 Channel 0	Vtpm2ch0
0xFFFF0:0xFFFF1	TPM1 Overflow	Vtpm1ovf
0xFFFF2:0xFFFF3	TPM1 Channel 2	Vtpm1ch2
0xFFFF4:0xFFFF5	TPM1 Channel 1	Vtpm1ch1
0xFFFF6:0xFFFF7	TPM1 Channel 0	Vtpm1ch0
0xFFFF8:0xFFFF9	Low Voltage Detect or Low Voltage Warning	Vlvd
0xFFFFA:0xFFFFB	IRQ	Virq
0xFFFFC:0xFFFFD	SWI	Vswi
0xFFFFE:0xFFFFF	Reset	Vreset

<sup>1</sup> ACMP1 and ACMP2 share this vector, if both modules are enabled user should poll each flag to determine pending interrupt.

<sup>2</sup> KBI1 and KBI2 share this vector, if both modules are enabled user should poll each flag to determine pending interrupt.

<sup>3</sup> IIC1 and IIC2 share this vector, if both modules are enabled user should poll each flag to determine pending interrupt.

### 4.3 Register Addresses and Bit Assignments

The registers in the MC9S08QE128 Series are divided into these groups:

- Direct-page registers are located in the first 128 locations in the memory map; these are accessible with efficient direct addressing mode instructions.
- High-page registers are used much less often, so they are located above 0x1800 in the memory map. This leaves more room in the direct page for more frequently used registers and RAM.
- The nonvolatile register area consists of a block of 16 locations in flash memory at 0xFFB0–0xFFBF. Nonvolatile register locations include:
  - NVPROT and NVOPT are loaded into working registers at reset
  - An 8-byte backdoor comparison key that optionally allows a user to gain controlled access to secure memory

Because the nonvolatile register locations are flash memory, they must be erased and programmed like other flash memory locations.

Direct-page registers can be accessed with efficient direct addressing mode instructions. Bit manipulation instructions can be used to access any bit in any direct-page register. [Table 4-2](#) is a summary of all user-accessible direct-page registers and control bits.

The direct page registers in [Table 4-2](#) can use the more efficient direct addressing mode, which requires only the lower byte of the address. Because of this, the lower byte of the address in column one is shown in bold text. In [Table 4-3](#) and [Table 4-4](#), the whole address in column one is shown in bold. In [Table 4-2](#), [Table 4-3](#), and [Table 4-4](#), the register names in column two are shown in bold to set them apart from the bit names to the right. Cells that are not associated with named bits are shaded. A shaded cell with a 0 indicates this unused bit always reads as a 0. Shaded cells with dashes indicate unused or reserved bit locations that could read as 1s or 0s. When writing to these bits, write a 0 unless otherwise specified.

Table 4-2. Direct-Page Register Summary (Sheet 1 of 4)

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0	
0x0000	PTAD	PTAD7	PTAD6	PTAD5	PTAD4	PTAD3	PTAD2	PTAD1	PTAD0	
0x0001	PTADD	PTADD7	PTADD6	PTADD5	PTADD4	PTADD3	PTADD2	PTADD1	PTADD0	
0x0002	PTBD	PTBD7	PTBD6	PTBD5	PTBD4	PTBD3	PTBD2	PTBD1	PTBD0	
0x0003	PTBDD	PTBDD7	PTBDD6	PTBDD5	PTBDD4	PTBDD3	PTBDD2	PTBDD1	PTBDD0	
0x0004	PTCD	PTCD7	PTCD6	PTCD5	PTCD4	PTCD3	PTCD2	PTCD1	PTCD0	
0x0005	PTCDD	PTCDD7	PTCDD6	PTCDD5	PTCDD4	PTCDD3	PTCDD2	PTCDD1	PTCDD0	
0x0006	PTDD	PTDD7	PTDD6	PTDD5	PTDD4	PTDD3	PTDD2	PTDD1	PTDD0	
0x0007	PTDDD	PTDDD7	PTDDD6	PTDDD5	PTDDD4	PTDDD3	PTDDD2	PTDDD1	PTDDD0	
0x0008	PTED	PTED7	PTED6	PTED5	PTED4	PTED3	PTED2	PTED1	PTED0	
0x0009	PTEDD	PTEDD7	PTEDD6	PTEDD5	PTEDD4	PTEDD3	PTEDD2	PTEDD1	PTEDD0	
0x000A	PTFD	PTFD7	PTFD6	PTFD5	PTFD4	PTFD3	PTFD2	PTFD1	PTFD0	
0x000B	PTFDD	PTFDD7	PTFDD6	PTFDD5	PTFDD4	PTFDD3	PTFDD2	PTFDD1	PTFDD0	
0x000C	KBI1SC	0	0	0	0	KBF	KBACK	KBIE	KBIMOD	
0x000D	KBI1PE	KBIPE7	KBIPE6	KBIPE5	KBIPE4	KBIPE3	KBIPE2	KBIPE1	KBIPE0	
0x000E	KBI1ES	KBEDG7	KBEDG6	KBEDG5	KBEDG4	KBEDG3	KBEDG2	KBEDG1	KBEDG0	
0x000F	IRQSC	0	IRQPDD	IRQEDG	IRQPE	IRQF	IRQACK	IRQIE	IRQMOD	
0x0010	ADCSC1	COCO	AIEN	ADCO	ADCH					
0x0011	ADCSC2	ADACT	ADTRG	ACFE	ACFGT	—	—	Reserved	Reserved	
0x0012	ADCRH	0	0	0	0	ADR11	ADR10	ADR9	ADR8	
0x0013	ADCRL	ADR7	ADR6	ADR5	ADR4	ADR3	ADR2	ADR1	ADR0	
0x0014	ADCCVH	0	0	0	0	ADCV11	ADCV10	ADCV9	ADCV8	
0x0015	ADCCVL	ADCV7	ADCV6	ADCV5	ADCV4	ADCV3	ADCV2	ADCV1	ADCV0	
0x0016	ADCCFG	ADLPC	ADIV		ADLSMP	MODE		ADICLK		
0x0017	APCTL1	ADPC7	ADPC6	ADPC5	ADPC4	ADPC3	ADPC2	ADPC1	ADPC0	
0x0018	APCTL2	ADPC15	ADPC14	ADPC13	ADPC12	ADPC11	ADPC10	ADPC9	ADPC8	
0x0019	APCTL3	ADPC23	ADPC22	ADPC21	ADPC20	ADPC19	ADPC18	ADPC17	ADPC16	
0x001A	ACMP1SC	ACME	ACBGS	ACF	ACIE	ACO	ACOPE	ACMOD		
0x001B	ACMP2SC	ACME	ACBGS	ACF	ACIE	ACO	ACOPE	ACMOD		
0x001C	PTGD	PTGD7	PTGD6	PTGD5	PTGD4	PTGD3	PTGD2	PTGD1	PTGD0	
0x001D	PTGDD	PTGDD7	PTGDD6	PTGDD5	PTGDD4	PTGDD3	PTGDD2	PTGDD1	PTGDD0	
0x001E	PTHD	PTHD7	PTHD6	PTHD5	PTHD4	PTHD3	PTHD2	PTHD1	PTHD0	
0x001F	PTHDD	PTHDD7	PTHDD6	PTHDD5	PTHDD4	PTHDD3	PTHDD2	PTHDD1	PTHDD0	
0x0020	SCI1BDH	LBKDIE	RXEDGIE	0	SBR12	SBR11	SBR10	SBR9	SBR8	
0x0021	SCI1BDL	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0	
0x0022	SCI1C1	LOOPS	SCISWAI	RSRC	M	WAKE	ILT	PE	PT	
0x0023	SCI1C2	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK	
0x0024	SCI1S1	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF	
0x0025	SCI1S2	LBKDIF	RXEDGIF	0	RXINV	RWUID	BRK13	LBKDE	RAF	
0x0026	SCI1C3	R8	T8	TXDIR	TXINV	ORIE	NEIE	FEIE	PEIE	
0x0027	SCI1D	Bit 7	6	5	4	3	2	1	Bit 0	
0x0028	SPI1C1	SPIE	SPE	SPTIE	MSTR	CPOL	CPHA	SSOE	LSBFE	
0x0029	SPI1C2	0	0	0	MODFEN	BIDIROE	0	SPISWAI	SPC0	



Table 4-2. Direct-Page Register Summary (Sheet 2 of 4)

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x002A	SPI1BR	0	SPPR2	SPPR1	SPPR0	0	SPR2	SPR1	SPR0
0x002B	SPI1S	SPRF	0	SPTEF	MODF	0	0	0	0
0x002C	Reserved	0	0	0	0	0	0	0	0
0x002D	SPI1D	Bit 7	6	5	4	3	2	1	Bit 0
0x002E	PTJD	PTJD7	PTJD6	PTJD5	PTJD4	PTJD3	PTJD2	PTJD1	PTJD0
0x002F	PTJDD	PTJDD7	PTJDD6	PTJDD5	PTJDD4	PTJDD3	PTJDD2	PTJDD1	PTJDD0
0x0030	IIC1A	AD7	AD6	AD5	AD4	AD3	AD2	AD1	0
0x0031	IIC1F	MULT			ICR				
0x0032	IIC1C1	IICEN	IICIE	MST	TX	TXAK	RSTA	0	0
0x0033	IIC1S	TCF	IAAS	BUSY	ARBL	0	SRW	IICIF	RXAK
0x0034	IIC1D	DATA							
0x0035	IIC1C2	GCAEN	ADEXT	0	0	0	AD10	AD9	AD8
0x0036	Reserved	—	—	—	—	—	—	—	—
0x0037	Reserved	—	—	—	—	—	—	—	—
0x0038	ICSC1	CLKS		RDIV			IREFS	IRCLKEN	IREFSTEN
0x0039	ICSC2	BDIV		RANGE	HGO	LP	EREFS	ERCLKEN	EREFSTEN
0x003A	ICSTRM	TRIM							
0x003B	ICSSC	DRS/DRST		DMX32	IREFST	CLKST		OSCINIT	FTRIM
0x003C	KBI2SC	0	0	0	0	KBF	KBACK	KBIE	KBIMOD
0x003D	KBI2PE	KBIPE7	KBIPE6	KBIPE5	KBIPE4	KBIPE3	KBIPE2	KBIPE1	KBIPE0
0x003E	KBI2ES	KBEDG7	KBEDG6	KBEDG5	KBEDG4	KBEDG3	KBEDG2	KBEDG1	KBEDG0
0x003F	Reserved	—	—	—	—	—	—	—	—
0x0040	TPM1SC	TOF	TOIE	CPWMS	CLKSB	CLKSA	PS2	PS1	PS0
0x0041	TPM1CNTH	Bit 15	14	13	12	11	10	9	Bit 8
0x0042	TPM1CNTL	Bit 7	6	5	4	3	2	1	Bit 0
0x0043	TPM1MODH	Bit 15	14	13	12	11	10	9	Bit 8
0x0044	TPM1MODL	Bit 7	6	5	4	3	2	1	Bit 0
0x0045	TPM1C0SC	CH0F	CH0IE	MS0B	MS0A	ELS0B	ELS0A	0	0
0x0046	TPM1C0VH	Bit 15	14	13	12	11	10	9	Bit 8
0x0047	TPM1C0VL	Bit 7	6	5	4	3	2	1	Bit 0
0x0048	TPM1C1SC	CH1F	CH1IE	MS1B	MS1A	ELS1B	ELS1A	0	0
0x0049	TPM1C1VH	Bit 15	14	13	12	11	10	9	Bit 8
0x004A	TPM1C1VL	Bit 7	6	5	4	3	2	1	Bit 0
0x004B	TPM1C2SC	CH2F	CH2IE	MS2B	MS2A	ELS2B	ELS2A	0	0
0x004C	TPM1C2VH	Bit 15	14	13	12	11	10	9	Bit 8
0x004D	TPM1C2VL	Bit 7	6	5	4	3	2	1	Bit 0
0x004E- 0x004F	Reserved	—	—	—	—	—	—	—	—
0x0050	TPM2SC	TOF	TOIE	CPWMS	CLKSB	CLKSA	PS2	PS1	PS0
0x0051	TPM2CNTH	Bit 15	14	13	12	11	10	9	Bit 8
0x0052	TPM2CNTL	Bit 7	6	5	4	3	2	1	Bit 0
0x0053	TPM2MODH	Bit 15	14	13	12	11	10	9	Bit 8

Table 4-2. Direct-Page Register Summary (Sheet 3 of 4)

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x0054	TPM2MODL	Bit 7	6	5	4	3	2	1	Bit 0
0x0055	TPM2C0SC	CH0F	CH0IE	MS0B	MS0A	ELS0B	ELS0A	0	0
0x0056	TPM2C0VH	Bit 15	14	13	12	11	10	9	Bit 8
0x0057	TPM2C0VL	Bit 7	6	5	4	3	2	1	Bit 0
0x0058	TPM2C1SC	CH1F	CH1IE	MS1B	MS1A	ELS1B	ELS1A	0	0
0x0059	TPM2C1VH	Bit 15	14	13	12	11	10	9	Bit 8
0x005A	TPM2C1VL	Bit 7	6	5	4	3	2	1	Bit 0
0x005B	TPM2C2SC	CH2F	CH2IE	MS2B	MS2A	ELS2B	ELS2A	0	0
0x005C	TPM2C2VH	Bit 15	14	13	12	11	10	9	Bit 8
0x005D	TPM2C2VL	Bit 7	6	5	4	3	2	1	Bit 0
0x005E- 0x005F	Reserved	—	—	—	—	—	—	—	—
0x0060	TPM3SC	TOF	TOIE	CPWMS	CLKSB	CLKSA	PS2	PS1	PS0
0x0061	TPM3CNTH	Bit 15	14	13	12	11	10	9	Bit 8
0x0062	TPM3CNTL	Bit 7	6	5	4	3	2	1	Bit 0
0x0063	TPM3MODH	Bit 15	14	13	12	11	10	9	Bit 8
0x0064	TPM3MODL	Bit 7	6	5	4	3	2	1	Bit 0
0x0065	TPM3C0SC	CH0F	CH0IE	MS0B	MS0A	ELS0B	ELS0A	0	0
0x0066	TPM3C0VH	Bit 15	14	13	12	11	10	9	Bit 8
0x0067	TPM3C0VL	Bit 7	6	5	4	3	2	1	Bit 0
0x0068	TPM3C1SC	CH1F	CH1IE	MS1B	MS1A	ELS1B	ELS1A	0	0
0x0069	TPM3C1VH	Bit 15	14	13	12	11	10	9	Bit 8
0x006A	TPM3C1VL	Bit 7	6	5	4	3	2	1	Bit 0
0x006B	TPM3C2SC	CH2F	CH2IE	MS2B	MS2A	ELS2B	ELS2A	0	0
0x006C	TPM3C2VH	Bit 15	14	13	12	11	10	9	Bit 8
0x006D	TPM3C2VL	Bit 7	6	5	4	3	2	1	Bit 0
0x006E	TPM3C3SC	CH3F	CH3IE	MS3B	MS3A	ELS3B	ELS3A	0	0
0x006F	TPM3C3VH	Bit 15	14	13	12	11	10	9	Bit 8
0x0070	TPM3C3VL	Bit 7	6	5	4	3	2	1	Bit 0
0x0071	TPM3C4SC	CH4F	CH4IE	MS4B	MS4A	ELS4B	ELS4A	0	0
0x0072	TPM3C4VH	Bit 15	14	13	12	11	10	9	Bit 8
0x0073	TPM3C4VL	Bit 7	6	5	4	3	2	1	Bit 0
0x0074	TPM3C5SC	CH5F	CH5IE	MS5B	MS5A	ELS5B	ELS5A	0	0
0x0075	TPM3C5VH	Bit 15	14	13	12	11	10	9	Bit 8
0x0076	TPM3C5VL	Bit 7	6	5	4	3	2	1	Bit 0
0x0077	Reserved	—	—	—	—	—	—	—	—
0x0078	PPAGE	0	0	0	0	0	XA16	XA15	XA14
0x0079	LAP2	0	0	0	0	0	0	0	LA16

**Table 4-2. Direct-Page Register Summary (Sheet 4 of 4)**

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x007A	LAP1	LA15	LA14	LA13	LA12	LA11	LA10	LA9	LA8
0x007B	LAP0	LA7	LA6	LA5	LA4	LA3	LA2	LA1	LA0
0x007C	LWP	D7	D6	D5	D4	D3	D2	D1	D0
0x007D	LBP	D7	D6	D5	D4	D3	D2	D1	D0
0x007E	LB	D7	D6	D5	D4	D3	D2	D1	D0
0x007F	LAPAB	D7	D6	D5	D4	D3	D2	D1	D0

High-page registers, shown in Table 4-3, are accessed much less often than other I/O and control registers so they have been located outside the direct addressable memory space, starting at 0x1800.

**Table 4-3. High-Page Register Summary (Sheet 1 of 4)**

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x1800	SRS	POR	PIN	COP	ILOP	0	0	LVD	0
0x1801	SBDFR	0	0	0	0	0	0	0	BDFR
0x1802	SOPT1	COPE	COPT	STOPE	—	0	RSTPOE	BKGDPE	RSTPE
0x1803	SOPT2	COPCLKS	0	0	0	SPI1PS	ACIC2	IIC1PS	ACIC1
0x1804 – 0x1805	Reserved	—	—	—	—	—	—	—	—
0x1806	SDIDH	—	—	—	—	ID11	ID10	ID9	ID8
0x1807	SDIDL	ID7	ID6	ID5	ID4	ID3	ID2	ID1	ID0
0x1808	SPMSC1	LVDF	LVDACK	LVDIE	LVDRE	LVDSE	LVDE	0	BGBE
0x1809	SPMSC2	LPR	LPRS	LPWUI	0	PPDF	PPDACK	PPDE	PPDC
0x180A	Reserved	—	—	—	—	—	—	—	—
0x180B	SPMSC3	LVWF	LVWACK	LVDV	LVWV	LVWIE	—	—	—
0x180C	Reserved	—	—	—	—	—	—	—	—
0x180D	Reserved	—	—	—	—	—	—	—	—
0x180E	SCGC1	TPM3	TPM2	TPM1	ADC	IIC2	IIC1	SCI2	SCI1
0x180F	SCGC2	DBG	FLS	IRQ	KBI	ACMP	RTC	SPI2	SPI1
0x1810	DBGCAH	Bit 15	14	13	12	11	10	9	Bit 8
0x1811	DBGCAL	Bit 7	6	5	4	3	2	1	Bit 0
0x1812	DBGCBH	Bit 15	14	13	12	11	10	9	Bit 8
0x1813	DBGCBL	Bit 7	6	5	4	3	2	1	Bit 0
0x1814	DBGCCH	Bit 15	14	13	12	11	10	9	Bit 8
0x1815	DBGCCL	Bit 7	6	5	4	3	2	1	Bit 0
0x1816	DBGFHH	Bit 15	14	13	12	11	10	9	Bit 8
0x1817	DBGFHL	Bit 7	6	5	4	3	2	1	Bit 0
0x1818	DBGCAH	RWAEN	RWA	PAGSEL	0	0	0	0	Bit 16
0x1819	DBGCBH	RWBEN	RWB	PAGSEL	0	0	0	0	Bit 16
0x181A	DBGCHH	RWCEN	RWC	PAGSEL	0	0	0	0	Bit 16
0x181B	DBGCHL	PPACC	0	0	0	0	0	0	Bit 16
0x181C	DBGCH	DBGGEN	ARM	TAG	BRKEN	0	0	0	LOOP1
0x181D	DBGCH	TRGSEL	BEGIN	0	0	TRG			
0x181E	DBGCH	AF	BF	CF	0	0	0	0	ARMF

**Table 4-3. High-Page Register Summary (Sheet 2 of 4)**

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x181F	<b>DBGCNT</b>	0	0	0	0	CNT			
0x1820	<b>FCDIV</b>	FDIVLD	PRDIV8	FDIV					
0x1821	<b>FOPT</b>	KEYEN		0	0	0	0	SEC	
0x1822	Reserved	—	—	—	—	—	—	—	—
0x1823	<b>FCNFG</b>	0	0	KEYACC	0	0	0	0	0
0x1824	<b>FPROT</b>	FPS							FPOPEN
0x1825	<b>FSTAT</b>	FCBEF	FCCF	FPVIOL	FACCERR	0	FBLANK	0	0
0x1826	<b>FCMD</b>	0	FCMD						
0x1827-	Reserved	—	—	—	—	—	—	—	—
0x1829		—	—	—	—	—	—	—	—
0x182A	Reserved								
0x182B-	Reserved	—	—	—	—	—	—	—	—
0x182F									
0x1830	<b>RTCSC</b>	RTIF	RTCLKS		RTIE	RTCPS			
0x1831	<b>RTCCNT</b>	RTCCNT							
0x1832	<b>RTCMOD</b>	RTCMOD							
0x1833-	Reserved	—	—	—	—	—	—	—	—
0x1837		—	—	—	—	—	—	—	—
0x1838	<b>SPI2C1</b>	SPIE	SPE	SPTIE	MSTR	CPOL	CPHA	SSOE	LSBFE
0x1839	<b>SPI2C2</b>	0	0	0	MODFEN	BIDIROE	0	SPISWAI	SPC0
0x183A	<b>SPI2BR</b>	0	SPPR2	SPPR1	SPPR0	0	SPR2	SPR1	SPR0
0x183B	<b>SPI2S</b>	SPRF	0	SPTEF	MODF	0	0	0	0
0x183C	Reserved	0	0	0	0	0	0	0	0
0x183D	<b>SPI2D</b>	Bit 7	6	5	4	3	2	1	Bit 0
0x183E-	Reserved	—	—	—	—	—	—	—	—
0x183F		—	—	—	—	—	—	—	—
0x1840	<b>PTAPE</b>	PTAPE7	PTAPE6	PTAPE5	PTAPE4	PTAPE3	PTAPE2	PTAPE1	PTAPE0
0x1841	<b>PTASE</b>	PTASE7	PTASE6	PTASE5	PTASE4	PTASE3	PTASE2	PTASE1	PTASE0
0x1842	<b>PTADS</b>	PTADS7	PTADS6	PTADS5	PTADS4	PTADS3	PTADS2	PTADS1	PTADS0
0x1843	Reserved	—	—	—	—	—	—	—	—
0x1844	<b>PTBPE</b>	PTBPE7	PTBPE6	PTBPE5	PTBPE4	PTBPE3	PTBPE2	PTBPE1	PTBPE0
0x1845	<b>PTBSE</b>	PTBSE7	PTBSE6	PTBSE5	PTBSE4	PTBSE3	PTBSE2	PTBSE1	PTBSE0
0x1846	<b>PTBDS</b>	PTBDS7	PTBDS6	PTBDS5	PTBDS4	PTBDS3	PTBDS2	PTBDS1	PTBDS0
0x1847	Reserved	—	—	—	—	—	—	—	—
0x1848	<b>PTCPE</b>	PTCPE7	PTCPE6	PTCPE5	PTCPE4	PTCPE3	PTCPE2	PTCPE1	PTCPE0
0x1849	<b>PTCSE</b>	PTCSE7	PTCSE6	PTCSE5	PTCSE4	PTCSE3	PTCSE2	PTCSE1	PTCSE0
0x184A	<b>PTCDS</b>	PTCDS7	PTCDS6	PTCDS5	PTCDS4	PTCDS3	PTCDS2	PTCDS1	PTCDS0
0x184B	Reserved	—	—	—	—	—	—	—	—
0x184C	<b>PTDPE</b>	PTDPE7	PTDPE6	PTDPE5	PTDPE4	PTDPE3	PTDPE2	PTDPE1	PTDPE0
0x184D	<b>PTDSE</b>	PTDSE7	PTDSE6	PTDSE5	PTDSE4	PTDSE3	PTDSE2	PTDSE1	PTDSE0
0x184E	<b>PTDDS</b>	PTDDS7	PTDDS6	PTDDS5	PTDDS4	PTDDS3	PTDDS2	PTDDS1	PTDDS0
0x184F	Reserved	—	—	—	—	—	—	—	—
0x1850	<b>PTEPE</b>	PTEPE7	PTEPE6	PTEPE5	PTEPE4	PTEPE3	PTEPE2	PTEPE1	PTEPE0

Table 4-3. High-Page Register Summary (Sheet 3 of 4)

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x1851	<b>PTESE</b>	PTESE7	PTESE6	PTESE5	PTESE4	PTESE3	PTESE2	PTESE1	PTESE0
0x1852	<b>PTEDS</b>	PTEDS7	PTEDS6	PTEDS5	PTEDS4	PTEDS3	PTEDS2	PTEDS1	PTEDS0
0x1853	<b>Reserved</b>	—	—	—	—	—	—	—	—
0x1854	<b>PTFPE</b>	PTFPE7	PTFPE6	PTFPE5	PTFPE4	PTFPE3	PTFPE2	PTFPE1	PTFPE0
0x1855	<b>PTFSE</b>	PTFSE7	PTFSE6	PTFSE5	PTFSE4	PTFSE3	PTFSE2	PTFSE1	PTFSE0
0x1856	<b>PTFDS</b>	PTFDS7	PTFDS6	PTFDS5	PTFDS4	PTFDS3	PTFDS2	PTFDS1	PTFDS0
0x1857	<b>Reserved</b>	—	—	—	—	—	—	—	—
0x1858	<b>PTGPE</b>	PTGPE7	PTGPE6	PTGPE5	PTGPE4	PTGPE3	PTGPE2	PTGPE1	PTGPE0
0x1859	<b>PTGSE</b>	PTGSE7	PTGSE6	PTGSE5	PTGSE4	PTGSE3	PTGSE2	PTGSE1	PTGSE0
0x185A	<b>PTGDS</b>	PTGDS7	PTGDS6	PTGDS5	PTGDS4	PTGDS3	PTGDS2	PTGDS1	PTGDS0
0x185B	<b>Reserved</b>	—	—	—	—	—	—	—	—
0x185C	<b>PTHPE</b>	PTHPE7	PTHPE6	PTHPE5	PTHPE4	PTHPE3	PTHPE2	PTHPE1	PTHPE0
0x185D	<b>PTHSE</b>	PTHSE7	PTHSE6	PTHSE5	PTHSE4	PTHSE3	PTHSE2	PTHSE1	PTHSE0
0x185E	<b>PTHDS</b>	PTHDS7	PTHDS6	PTHDS5	PTHDS4	PTHDS3	PTHDS2	PTHDS1	PTHDS0
0x185F	<b>Reserved</b>	—	—	—	—	—	—	—	—
0x1860	<b>PTJPE</b>	PTJPE7	PTJPE6	PTJPE5	PTJPE4	PTJPE3	PTJPE2	PTJPE1	PTJPE0
0x1861	<b>PTJSE</b>	PTJSE7	PTJSE6	PTJSE5	PTJSE4	PTJSE3	PTJSE2	PTJSE1	PTJSE0
0x1862	<b>PTJDS</b>	PTJDS7	PTJDS6	PTJDS5	PTJDS4	PTJDS3	PTJDS2	PTJDS1	PTJDS0
0x1863– 0x1867	<b>Reserved</b>	—	—	—	—	—	—	—	—
0x1868	<b>IIC2A</b>	AD7	AD6	AD5	AD4	AD3	AD2	AD1	0
0x1869	<b>IIC2F</b>	MULT			ICR				
0x186A	<b>IIC2C1</b>	IICEN	IICIE	MST	TX	TXAK	RSTA	0	0
0x186B	<b>IIC2S</b>	TCF	IAAS	BUSY	ARBL	0	SRW	IICIF	RXAK
0x186C	<b>IIC2D</b>	DATA							
0x186D	<b>IIC2C2</b>	GCAEN	ADEXT	0	0	0	AD10	AD9	AD8
0x186E– 0x186F	<b>Reserved</b>	—	—	—	—	—	—	—	—
0x1870	<b>SCI2BDH</b>	LBKDIE	RXEDGIE	0	SBR12	SBR11	SBR10	SBR9	SBR8
0x1871	<b>SCI2BDL</b>	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0
0x1872	<b>SCI2C1</b>	LOOPS	SCISWAI	RSRC	M	WAKE	ILT	PE	PT
0x1873	<b>SCI2C2</b>	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
0x1874	<b>SCI2S1</b>	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
0x1875	<b>SCI2S2</b>	LBKDIF	RXEDGIF	0	RXINV	RWUID	BRK13	LBKDE	RAF
0x1876	<b>SCI2C3</b>	R8	T8	TXDIR	TXINV	ORIE	NEIE	FEIE	PEIE
0x1877	<b>SCI2D</b>	Bit 7	6	5	4	3	2	1	Bit 0
0x1878	<b>PTCSET</b>	PTCSET7	PTCSET6	PTCSET5	PTCSET4	PTCSET3	PTCSET2	PTCSET1	PTCSET0
0x1879	<b>PTESET</b>	PTESET7	PTESET6	PTESET5	PTESET4	PTESET3	PTESET2	PTESET1	PTESET0
0x187A	<b>PTCCLR</b>	PTCCLR7	PTCCLR6	PTCCLR5	PTCCLR4	PTCCLR3	PTCCLR2	PTCCLR1	PTCCLR0
0x187B	<b>PTECLR</b>	PTECLR7	PTECLR6	PTECLR5	PTECLR4	PTECLR3	PTECLR2	PTECLR1	PTECLR0
0x187C	<b>PTCTOG</b>	PTCTOG7	PTCTOG6	PTCTOG5	PTCTOG4	PTCTOG3	PTCTOG2	PTCTOG1	PTCTOG0

**Table 4-3. High-Page Register Summary (Sheet 4 of 4)**

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x187D	<b>PTETOG</b>	PTETOG7	PTETOG6	PTETOG5	PTETOG4	PTETOG3	PTETOG2	PTETOG1	PTETOG0
0x187E– 0x187F	<b>Reserved</b>	—	—	—	—	—	—	—	—

Several reserved flash memory locations, shown in Table 4-4, are used for storing values used by several registers. These registers include an 8-byte backdoor key, NVBACKKEY, which can be used to gain access to secure memory resources. During reset events, the contents of NVPROT and NVOPT in the reserved flash memory are transferred into corresponding FPROT and FOPT registers in the high-page registers area to control security and block protection options.

The factory ICS trim value is stored in the flash information row (IFR<sup>1</sup>) and will be loaded into the ICSTRM and ICSSC registers after any reset. The internal reference trim values stored in flash, TRIM and FTRIM, can be programmed by third party programmers and must be copied into the corresponding ICS registers by user code to override the factory trim.

**NOTE**

When the MCU is in active BDM, the trim value in the IFR will not be loaded. Instead, the ICSTRM register will reset to 0x80 and the FTRIM bit in the ICSSC register will be reset to 0.

**Table 4-4. Reserved Flash Memory Addresses**

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0xFFAE	Reserved for Storage of FTRIM	0	0	0	0	0	0	0	FTRIM
0xFFAF	Reserved for Storage of ICSTRM	TRIM							
0xFFB0 – 0xFFB7	<b>NVBACKKEY</b>	8-Byte Comparison Key							
0xFFB8 – 0xFFBC	Reserved	—	—	—	—	—	—	—	—
0xFFBD	<b>NVPROT</b>	FPS							FPOPEN
0xFFBE	Reserved	—	—	—	—	—	—	—	—
0xFFBF	<b>NVOPT</b>	KEYEN		0	0	0	0	SEC	

Provided the key enable (KEYEN) bit is 1, the 8-byte comparison key can be used to temporarily disengage memory security. This key mechanism can be accessed only through user code running in secure memory. (A security key cannot be entered directly through background debug commands.) This security key can be disabled completely by programming the KEYEN bit to 0. If the security key is disabled, the only way to disengage security is by mass erasing the flash if needed (normally through the background

1. IFR — Nonvolatile information memory that can be only accessed during production test. During production test, system initialization, configuration and test information is stored in the IFR. This information cannot be read or modified in normal user or background debug modes.

debug interface) and verifying that flash is blank. To avoid returning to secure mode after the next reset, program the security bits (SEC) to the unsecured state (1:0).

## 4.4 Memory Management Unit

The memory management unit (MMU) allows the program and data space for the HCS08 Family of microcontrollers to be extended beyond the 64K byte CPU addressable memory map. The MMU uses a paging scheme similar to that seen on other MCU architectures, such as HCS12. The extended memory when used for data can also be accessed linearly using a linear address pointer and data access registers.

### 4.4.1 Features

Key features of the MMU module are:

- Memory Management Unit extends the HCS08 memory space
  - up to 4 MB for program and data space
- Extended program space using paging scheme
  - PPAGE register used for page selection
  - fixed 16K byte memory window
  - architecture supports up to 256, 16K pages
- Extended data space using linear address pointer
  - up to 22-bit linear address pointer
  - linear address pointer and data register provided in direct page allows access of complete flash memory map using direct page instructions
  - optional auto increment of pointer when data accessed
  - supports an 2s compliment addition/subtraction to address pointer without using any math instructions or memory resources
  - supports word accesses to any address specified by the linear address pointer when using LDHX, STHX instructions

### 4.4.2 Register Definition

#### 4.4.2.1 Program Page Register (PPAGE)

The HCS08 Core architecture limits the CPU addressable space available to 64K bytes. The address space can be extended to 128K bytes using a paging window scheme. The Program Page (PPAGE) allows for selecting one of the 16K byte blocks to be accessed through the Program Page Window located at 0x8000-0xBFFF. The CALL and RTC instructions can load or store the value of PPAGE onto or from the stack during program execution. After any reset, PPAGE is set to PAGE 2.

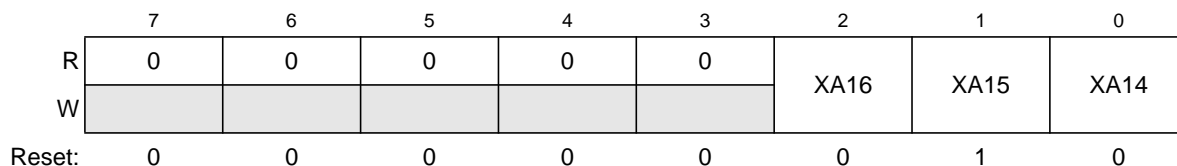


Figure 4-4. Program Page Register (PPAGE)

Table 4-5. Program Page Register Field Descriptions

Field	Description
2:0 XA16:XA14	When the CPU addresses the paging window, 0x8000-0xBFFF, the value in the PPAGE register along with the CPU addresses A13:A0 are used to create a 17-bit extended address.

### 4.4.2.2 Linear Address Pointer Registers 2:0 (LAP2:LAP0)

The three registers, LAP2:LAP0 contain the 17-bit linear address that allows the user to access any flash location in the extended address map. This register is used in conjunction with the data registers, linear byte (LB), linear byte post increment (LBP) and linear word post increment (LWP). The contents of LAP2:LAP0 will auto-increment when accessing data using the LBP and LWP registers. The contents of LAP2:LAP0 can be increased by writing an 8-bit value to LAPAB.

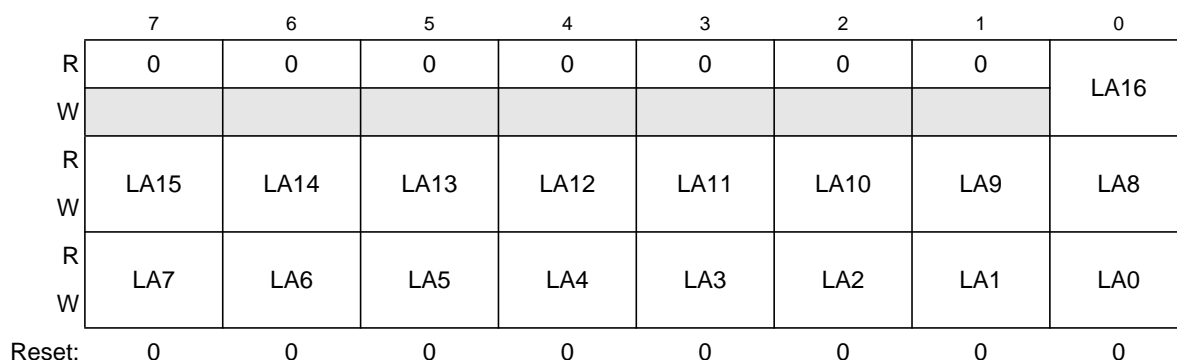


Figure 4-5. Linear Address Pointer Registers 2:0 (LAP2:LAP0)

Table 4-6. Linear Address Pointer Registers 2:0 Field Descriptions

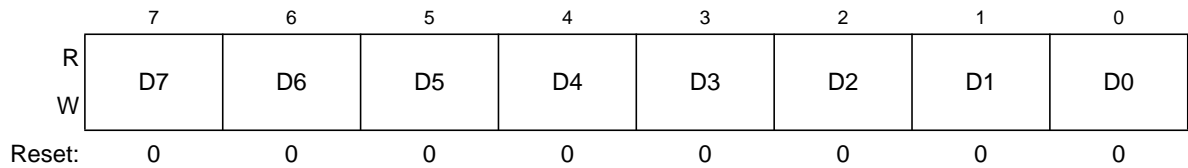
Field	Description
16:0 LA21:LA0	The values in LAP2:LAP0 are used to create a 17-bit linear address pointer. The value in these registers are used as the extended address when accessing any of the data registers LB, LBP and LWP.

### 4.4.2.3 Linear Word Post Increment Register (LWP)

This register is one of three data registers that the user can use to access any flash memory location in the extended address map. When LWP is accessed the contents of LAP2:LAP0 make up the extended address of the flash memory location to be addressed. When accessing data using LWP, the contents of LAP2:LAP0 will increment after the read or write is complete.



Accessing LWP does the same thing as accessing LBP. The MMU register ordering of LWP followed by LBP, allow the user to access data by words using the LDHX or STHX instructions of the LWP register.



**Figure 4-6. Linear Word Post Increment Register (LWP)**

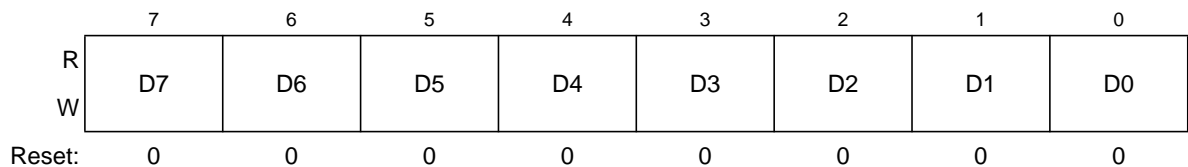
**Table 4-7. Linear Word Post Increment Register Field Descriptions**

Field	Description
7:0 D7:D0	Reads of this register will first return the data value pointed to by the linear address pointer, LAP2:LAP0 and then will increment LAP2:LAP0. Writes to this register will first write the data value to the memory location specified by the linear address pointer and then will increment LAP2:LAP0. Writes to this register are most commonly used when writing to the flash block(s) during programming.

#### 4.4.2.4 Linear Byte Post Increment Register (LBP)

This register is one of three data registers that the user can use to access any flash memory location in the extended address map. When LBP is accessed the contents of LAP2:LAP0 make up the extended address of the flash memory location to be addressed. When accessing data using LBP, the contents of LAP2:LAP0 will increment after the read or write is complete.

Accessing LBP does the same thing as accessing LWP. The MMU register ordering of LWP followed by LBP, allow the user to access data by words using the LDHX or STHX instructions with the address of the LWP register.



**Figure 4-7. Linear Byte Post Increment Register (LBP)**

**Table 4-8. Linear Byte Post Increment Register Field Descriptions**

Field	Description
7:0 D7:D0	Reads of this register will first return the data value pointed to by the linear address pointer, LAP2:LAP0 and then will increment LAP2:LAP0. Writes to this register will first write the data value to the memory location specified by the linear address pointer and then will increment LAP2:LAP0. Writes to this register are most commonly used when writing to the flash block(s) during programming.

### 4.4.2.5 Linear Byte Register (LB)

This register is one of three data registers that the user can use to access any flash memory location in the extended address map. When LB is accessed the contents of LAP2:LAP0 make up the extended address of the flash memory location to be addressed.



Figure 4-8. Linear Byte Register (LB)

Table 4-9. Linear Data Register Field Descriptions

Field	Description
7:0 D7:D0	Reads of this register returns the data value pointed to by the linear address pointer, LAP2:LAP0. Writes to this register will write the data value to the memory location specified by the linear address pointer. Writes to this register are most commonly used when writing to the flash block(s) during programming.

### 4.4.2.6 Linear Address Pointer Add Byte Register (LAPAB)

The user can increase or decrease the contents of LAP2:LAP0 by writing a 2s compliment value to LAPAB. The value written will be added to the current contents of LAP2:LAP0.

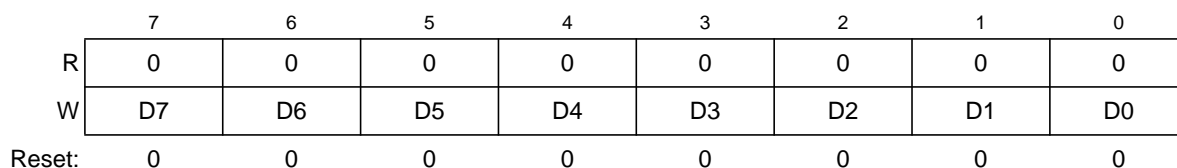


Figure 4-9. Linear Address Pointer Add Byte Register (LAPAB)

Table 4-10. Linear Address Pointer Add Byte Register Field Descriptions

Field	Description
7:0 D7:D0	The 2s compliment value written to LAPAB will be added to contents of the linear address pointer register, LAP2:LAP0. Writing a value of 0x7f to LAPAB will increase LAP by 127, a value of 0xff will decrease LAP by 1, and a value of 0x80 will decrease LAP by 128.

## 4.4.3 Functional Description

### 4.4.3.1 Memory Expansion

The HCS08 Core architecture limits the CPU addressable space available to 64K bytes. The Program Page (PPAGE) allows for integrating up to 4M byte of flash into the system by selecting one of the 16K byte blocks to be accessed through the paging window located at 0x8000-0xBFFF. The MMU module also provides a linear address pointer that allows extension of data access up to 4M bytes.

#### 4.4.3.1.1 Program Space

The PPAGE register holds the page select value for the paging window. The value in PPAGE can be manipulated by using normal read and write instructions as well as the CALL and RTC instructions. The user should not change PPAGE directly when running from paged memory, only CALL and RTC should be used.

When the MMU detects that the CPU is addressing the paging window, the value currently in PPAGE will be used to create an extended address that the MCU's decode logic will use to select the desired flash location.

As seen in [Figure 4-1](#), the flash blocks in the CPU addressable memory can be accessed directly or using the paging window and PPAGE register. For example, the flash from location 0x4000-0x7FFF can be accessed directly or using the paging window, PPAGE = 1, address 0x8000-0xBFFF.

#### 4.4.3.1.2 CALL and RTC (Return from Call) Instructions

CALL and RTC are instructions that perform automated page switching when executed in the user program. CALL is similar to a JSR instruction, but the subroutine that is called can be located anywhere in the normal 64K byte address space or on any page of program memory.

During the execution of a CALL instruction, the CPU:

- Stacks the return address.
- Pushes the current PPAGE value onto the stack.
- Writes the new instruction-supplied PPAGE value into the PPAGE register.
- Transfers control to the subroutine of the new instruction-supplied address.

This sequence is not interruptible; there is no need to inhibit interrupts during CALL execution. A CALL can be executed from any address in memory to any other address.

The new PPAGE value is provided by an immediate operand in the instruction along with the address within the paging window, 0x8000-0xBFFF.

RTC is similar to an RTS instruction.

The RTC instruction terminates subroutines invoked by a CALL instruction.

During the execution of an RTC instruction, the CPU:

- Pulls the old PPAGE value from the stack and loads it into the PPAGE register
- Pulls the 16-bit return address from the stack and loads it into the PC
- Resumes execution at the return address

This sequence is not interruptible; there is no need to inhibit interrupts during RTC execution. An RTC can be executed from any address in memory.

#### 4.4.3.1.3 Data Space

The linear address pointer registers, LAP2:LAP0 along with the linear data register allow the CPU to read or write any address in the extended flash memory space. This linear address pointer may be used to access data from any memory location while executing code from any location in extended memory, including accessing data from a different PPAGE than the currently executing program.

To access data using the linear address pointer, the user would first setup the extended address in the 22-bit address pointer, LAP2:LAP0. Accessing one of the three linear data registers LB, LBP and LWP will access the extended memory location specified by LAP2:LAP0. The three linear data registers access the memory locations in the same way, however the LBP and LWP will also increment LAP2:LAP0.

Accessing either the LBP or LWP registers allows a user program to read successive memory locations without re-writing the linear address pointer. Accessing LBP or LWP does the exact same function. However, because of the address mapping of the registers with LBP following LWP, a user can do word accesses in the extended address space using the LDHX or STHX instructions to access location LWP.

The MMU supports the addition of a 2s compliment value to the linear address pointer without using any math instructions or memory resources. Writes to LAPAB with a 2s compliment value will cause the MMU to add that value to the existing value in LAP2:LAP0.

#### 4.4.3.1.4 PPAGE and Linear Address Pointer to Extended Address

See [Figure 4-1](#), on how the program PPAGE memory pages and the Linear Address Pointer are mapped to extended address space.

## 4.5 RAM

The MC9S08QE128 Series includes static RAM. The locations in RAM below 0x0100 can be accessed using the more efficient direct addressing mode, and any single bit in this area can be accessed with the bit manipulation instructions (BCLR, BSET, BRCLR, and BRSET). Locating the most frequently accessed program variables in this area of RAM is preferred.

At power-on, the contents of RAM are uninitialized. RAM data is unaffected by any reset provided that the supply voltage does not drop below the minimum value for RAM retention ( $V_{RAM}$ ).

For compatibility with M68HC05 MCUs, the HCS08 resets the stack pointer to 0x00FF. In the MC9S08QE128 Series, it is usually best to reinitialize the stack pointer to the top of the RAM so the direct page RAM can be used for frequently accessed RAM variables and bit-addressable program variables. Include the following 2-instruction sequence in your reset initialization routine (where RamLast is equated to the highest address of the RAM in the Freescale Semiconductor-provided equate file).

```
LDHX    #RamLast+1    ;point one past RAM
TXS                    ;SP<-(H:X-1)
```

When security is enabled, the RAM is considered a secure memory resource and is not accessible through BDM or through code executing from non-secure memory. See [Section 4.6.5, “Flash Module Security,”](#) for a detailed description of the security feature.

## 4.6 Flash

The flash memory is intended primarily for program storage. In-circuit programming allows the operating program to be loaded into the flash memory after final assembly of the application product. It is possible to program the entire array through the single-wire background debug interface. Because no special voltages are needed for flash erase and programming operations, in-application programming is also possible through other software-controlled communication paths.

The flash memory is ideal for single-supply applications allowing for field reprogramming without requiring external high voltage sources for program or erase operations. The flash module includes a memory controller that executes commands to modify flash memory contents.

Array read access time is one bus cycle per byte. For flash memory, an erased bit reads 1 and a programmed bit reads 0. It is not possible to read from a flash block while any command is executing on that specific flash block. It is possible to read from a flash block while a command is executing on a different flash block.

### CAUTION

A flash block address must be in the erased state before being programmed. Cumulative programming of bits within a flash block address is not allowed except for status field updates required in EEPROM emulation applications.

For a more detailed discussion of in-circuit and in-application programming, refer to the *HCS08 Family Reference Manual, Volume I*, Freescale Semiconductor document order number HCS08RMv1.

### 4.6.1 Features

Features of the flash memory include:

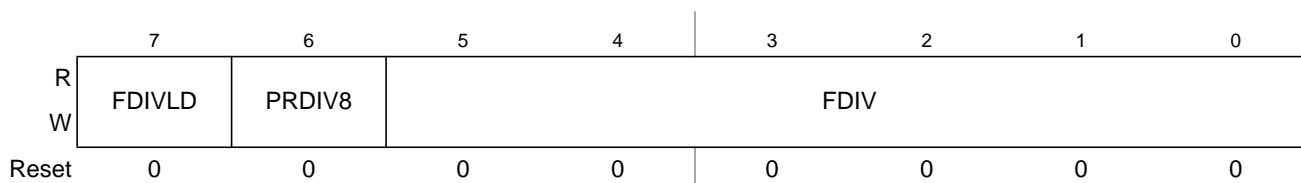
- Flash size
  - MC9S08QE128: 131,072 bytes (256 pages of 512 bytes each)
  - MC9S08QE96: 98,304 bytes (192 pages of 512 bytes each)
  - MC9S08QE64: 65,536 bytes (128 pages of 512 bytes each)
- Single power supply program and erase
- Automated program and erase algorithm
- Fast program and erase operation
- Burst program command for faster flash array program times
- Up to 100,000 program/erase cycles at typical voltage and temperature
- Flexible protection scheme to prevent accidental program or erase
- Security feature to prevent unauthorized access to the flash and RAM
- Auto power-down for low-frequency read accesses

### 4.6.2 Register Descriptions

The flash module contains a set of 16 control and status registers. Detailed descriptions of each register bit are provided in the following sections.

#### 4.6.2.1 Flash Clock Divider Register (FCDIV)

The FCDIV register is used to control the length of timed events in program and erase algorithms executed by the flash memory controller.



**Figure 4-10. Flash Clock Divider Register (FCDIV)**

All bits in the FCDIV register are readable and writable with restrictions as determined by the value of FDIVLD when writing to the FCDIV register (see [Table 4-11](#)).

**Table 4-11. FCDIV Field Descriptions**

Field	Description
7 FDIVLD	<b>Clock Divider Load Control</b> — When writing to the FCDIV register for the first time after a reset, the value of the FDIVLD bit written controls the future ability to write to the FCDIV register: 0 Writing a 0 to FDIVLD locks the FCDIV register contents; all future writes to FCDIV are ignored. 1 Writing a 1 to FDIVLD keeps the FCDIV register writable; next write to FCDIV is allowed. When reading the FCDIV register, the value of the FDIVLD bit read indicates the following: 0 FCDIV register has not been written to since the last reset. 1 FCDIV register has been written to since the last reset.
6 PRDIV8	<b>Enable Prescaler by 8.</b> 0 The bus clock is directly fed into the clock divider. 1 The bus clock is divided by 8 before feeding into the clock divider.
5:0 FDIV[5:0]	<b>Clock Divider Bits</b> — The combination of PRDIV8 and FDIV[5:0] must divide the bus clock down to a frequency of 150 kHz–200 kHz. The minimum divide ratio is 2 and the maximum divide ratio is 512. Please refer to <a href="#">Section 4.6.3.1.1, “Writing the FCDIV Register”</a> for more information.

$$\text{if PRDIV8} = 0 \text{ — } f_{\text{FCLK}} = f_{\text{BUS}} \div (\text{DIV} + 1) \quad \text{Eqn. 4-1}$$

$$\text{if PRDIV8} = 1 \text{ — } f_{\text{FCLK}} = f_{\text{BUS}} \div (8 \times (\text{DIV} + 1)) \quad \text{Eqn. 4-2}$$

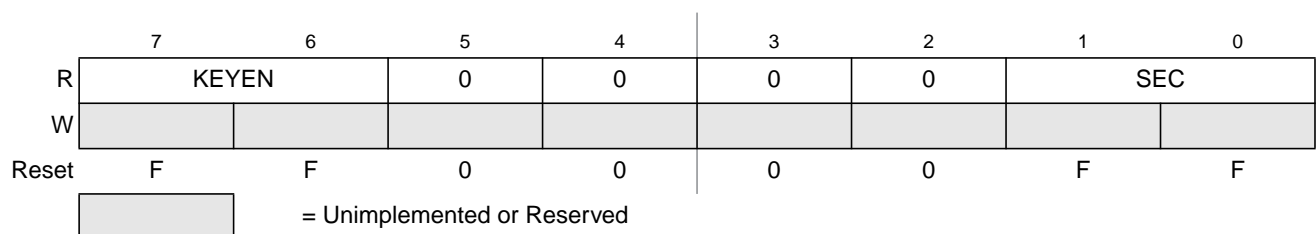
Table 4-12 shows the appropriate values for PRDIV8 and DIV for selected bus frequencies.

**Table 4-12. Flash Clock Divider Settings**

$f_{\text{BUS}}$	PRDIV8 (Binary)	DIV (Decimal)	$f_{\text{FCLK}}$	Program/Erase Timing Pulse (5 $\mu\text{s}$ Min, 6.7 $\mu\text{s}$ Max)
20 MHz	1	12	192.3 kHz	5.2 $\mu\text{s}$
10 MHz	0	49	200 kHz	5 $\mu\text{s}$
8 MHz	0	39	200 kHz	5 $\mu\text{s}$
4 MHz	0	19	200 kHz	5 $\mu\text{s}$
2 MHz	0	9	200 kHz	5 $\mu\text{s}$
1 MHz	0	4	200 kHz	5 $\mu\text{s}$
200 kHz	0	0	200 kHz	5 $\mu\text{s}$
150 kHz	0	0	150 kHz	6.7 $\mu\text{s}$

### 4.6.2.2 Flash Options Register (FOPT and NVOPT)

The FOPT register holds all bits associated with the security of the MCU and flash module.


**Figure 4-11. Flash Options Register (FOPT)**

All bits in the FOPT register are readable but are not writable. To change the value in this register, erase and reprogram the NVOPT location in flash memory as usual and then issue an MCU reset.

The FOPT register is loaded from the flash location, NVOPT, during the reset sequence, indicated by F in Figure 4-11.

**Table 4-13. FOPT Field Descriptions**

Field	Description
7:6 KEYEN[1:0]	<b>Backdoor Key Security Enable Bits</b> — The KEYEN[1:0] bits define the enabling of backdoor key access to the flash module as shown in Table 4-14.
1:0 SEC[1:0]	<b>Flash Security Bits</b> — The SEC[1:0] bits define the security state of the MCU as shown in Table 4-15. If the flash module is unsecured using backdoor key access, the SEC[1:0] bits are forced to the unsecured state.

**Table 4-14. Flash KEYEN States**

KEYEN[1:0]	Status of Backdoor Key Access
00	DISABLED
01 <sup>1</sup>	DISABLED
10	ENABLED
11	DISABLED

<sup>1</sup> Preferred KEYEN state to disable Backdoor Key Access.

**Table 4-15. Flash Security States**

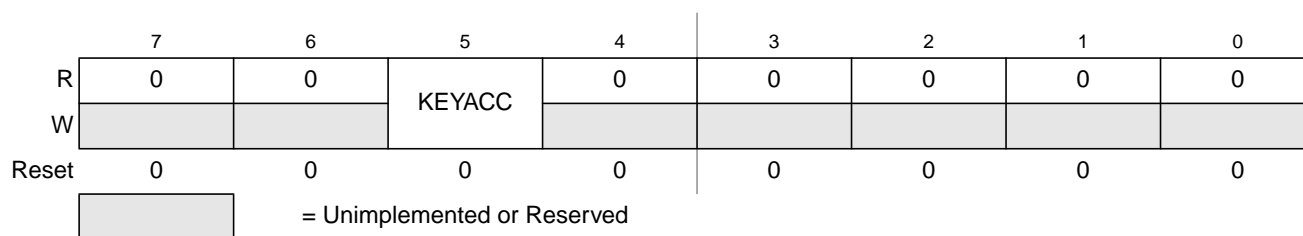
SEC[1:0]	Status of Security
00	SECURED
01 <sup>1</sup>	SECURED
10	UNSECURED
11	SECURED

<sup>1</sup> Preferred SEC state to set MCU to secured state.

The security feature in the flash module is described in Section 4.6.5, “Flash Module Security”.

### 4.6.2.3 Flash Configuration Register (FCNFG)

The FCNFG register enables the flash interrupts and gates the security backdoor writes.



**Figure 4-12. Flash Configuration Register (FCNFG)**



CBEIE, CCIE and KEYACC bits are readable and writable while all remaining bits read 0 and are not writable. KEYACC is only writable if KEYEN is set to the enabled state (see Section 4.6.2.2, “Flash Options Register (FOPT and NVOPT)”).

**Table 4-16. FCNFG Field Descriptions**

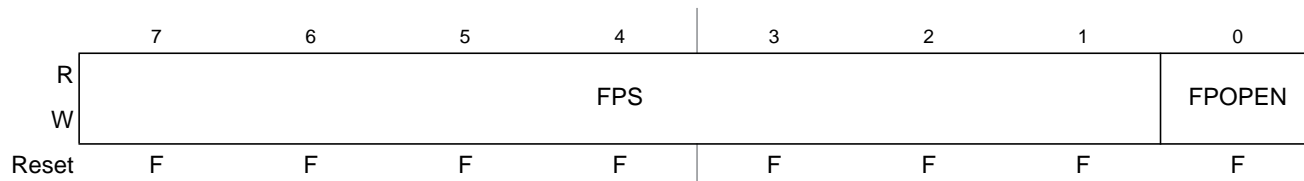
Field	Description
5 KEYACC	<b>Enable Security Key Writing</b> 0 Writes to the flash block are interpreted as the start of a command write sequence. 1 Writes to the flash block are interpreted as keys to open the backdoor.

### NOTE

Flash array reads are allowed while KEYACC is set.

## 4.6.2.4 Flash Protection Register (FPROT and NVPROT)

The FPROT register defines which flash sectors are protected against program or erase operations.


**Figure 4-13. Flash Protection Register (FPROT)**

FPROT bits are readable and writable as long as the size of the protected flash memory is being increased. Any write to FPROT that attempts to decrease the size of the protected flash memory will be ignored.

During the reset sequence, the FPROT register is loaded from the flash protection byte, NVPROT. To change the flash protection that will be loaded during the reset sequence, the flash sector containing NVPROT must be unprotected and erased, then NVPROT can be reprogrammed.

Trying to alter data in any protected area in the flash memory will result in a protection violation error and the FPVIOL flag will be set in the FSTAT register. The mass erase of the flash array is not possible if any of the flash sectors contained in the flash array are protected.

**Table 4-17. FPROT Field Descriptions**

Field	Description
7:1 FPS[6:0]	<b>Flash Protection Size</b> — With FPOPEN set, the FPS bits determine the size of the protected flash address range as shown in Table 4-18.
0 FPOPEN	<b>Flash Protection Open</b> 0 Flash array fully protected. 1 Flash array protected address range determined by FPS bits.

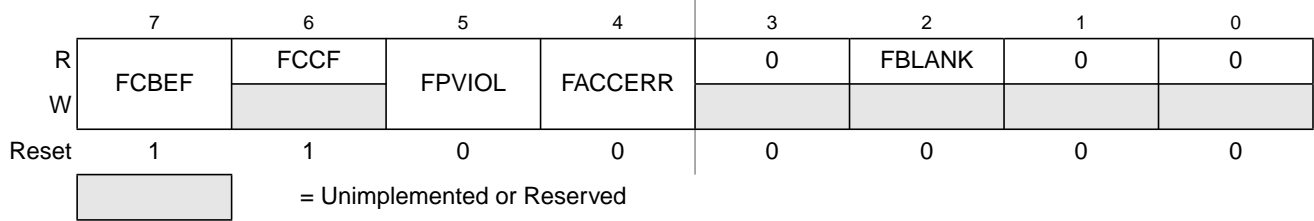
**Table 4-18. Flash Protection Address Range**

FPS[6:0]	FPOPEN	Protected Address Range Relative to Flash Array Base		Protected Size	
		Flash Array 0	Flash Array 1		
-	0	0x0_0000–0x0_FFFF	0x1_0000–0x1_FFFF	128 Kbytes	
0x00	1	0x0_0000–0x0_FFFF	0x1_0400–0x1_FFFF	127 Kbytes	
0x01		0x0_0000–0x0_FFFF	0x1_0800–0x1_FFFF	126 Kbytes	
0x02		0x0_0000–0x0_FFFF	0x1_0C00–0x1_FFFF	125 Kbytes	
0x03		0x0_0000–0x0_FFFF	0x1_1000–0x1_FFFF	124 Kbytes	
0x04		0x0_0000–0x0_FFFF	0x1_1400–0x1_FFFF	123 Kbytes	
0x05		0x0_0000–0x0_FFFF	0x1_1800–0x1_FFFF	122 Kbytes	
0x06		0x0_0000–0x0_FFFF	0x1_1C00–0x1_FFFF	121 Kbytes	
...		...	...	...	...
0x37		0x0_0000–0x0_FFFF	0x1_E000–0x1_FFFF	72 Kbytes	
0x38		0x0_0000–0x0_FFFF	0x1_E400–0x1_FFFF	71 Kbytes	
0x39		0x0_0000–0x0_FFFF	0x1_E800–0x1_FFFF	70 Kbytes	
0x3A		0x0_0000–0x0_FFFF	0x1_EC00–0x1_FFFF	69 Kbytes	
0x3B		0x0_0000–0x0_FFFF	0x1_F000–0x1_FFFF	68 Kbytes	
0x3C		0x0_0000–0x0_FFFF	0x1_F400–0x1_FFFF	67 Kbytes	
0x3D		0x0_0000–0x0_FFFF	0x1_F800–0x1_FFFF	66 Kbytes	
0x3E		0x0_0000–0x0_FFFF	0x1_FC00–0x1_FFFF	65 Kbytes	
0x3F		0x0_0000–0x0_FFFF		64 Kbytes	
0x40		0x0_0400–0x0_FFFF		63 Kbytes	
0x41		0x0_0800–0x0_FFFF		62 Kbytes	
0x42		0x0_0C00–0x0_FFFF		61 Kbytes	
0x43		0x0_1000–0x0_FFFF		60 Kbytes	
0x44		0x0_1400–0x0_FFFF		59 Kbytes	
0x45		0x0_1800–0x0_FFFF		58 Kbytes	
0x46		0x0_1C00–0x0_FFFF		57 Kbytes	
...		...		...	
0x77		0x0_E000–0x0_FFFF		8 Kbytes	
0x78		0x0_E400–0x0_FFFF		7 Kbytes	
0x79	0x0_E800–0x0_FFFF		6 Kbytes		
0x7A	0x0_EC00–0x0_FFFF		5 Kbytes		
0x7B	0x0_F000–0x0_FFFF		4 Kbytes		
0x7C	0x0_F400–0x0_FFFF		3 Kbytes		
0x7D	0x0_F800–0x0_FFFF		2 Kbytes		
0x7E	0x0_FC00–0x0_FFFF		1 Kbyte		
0x7F	No Protection		0 Kbytes		

### 4.6.2.5 Flash Status Register (FSTAT)

The FSTAT register defines the operational status of the flash module.

FCCF, FPVIOL, and FACCERR are readable and writable, FCCF and FBLANK are readable and not



**Figure 4-14. Flash Status Register (FSTAT)**

writable, remaining bits read 0 and are not writable.

**Table 4-19. FSTAT Field Descriptions**

Field	Description
7 FCBEF	<p><b>Flash Command Buffer Empty Flag</b> — The FCBEF flag indicates that the command buffer is empty so that a new command write sequence can be started when performing burst programming. Writing a 0 to the FCBEF flag has no effect on FCBEF. Writing a 0 to FCBEF after writing an aligned address to the flash array memory, but before FCBEF is cleared, will abort a command write sequence and cause the FACCERR flag to be set. Writing a 0 to FCBEF outside of a command write sequence will not set the FACCERR flag. The FCBEF flag is cleared by writing a 1 to FCBEF.</p> <p>0 Command buffers are full. 1 Command buffers are ready to accept a new command.</p>
6 FCCF	<p><b>Flash Command Complete Interrupt Flag</b> — The FCCF flag indicates that there are no more commands pending. The FCCF flag is cleared when FCBEF is cleared and sets automatically upon completion of all active and pending commands. The FCCF flag does not set when an active program command completes and a pending burst program command is fetched from the command buffer. Writing to the FCCF flag has no effect on FCCF.</p> <p>0 Command in progress. 1 All commands are completed.</p>
5 FPVIOL	<p><b>Flash Protection Violation Flag</b> —The FPVIOL flag indicates an attempt was made to program or erase an address in a protected area of the flash memory or flash IFR during a command write sequence. Writing a 0 to the FPVIOL flag has no effect on FPVIOL. The FPVIOL flag is cleared by writing a 1 to FPVIOL. While FPVIOL is set, it is not possible to launch a command or start a command write sequence.</p> <p>0 No protection violation detected. 1 Protection violation has occurred.</p>

**Table 4-19. FSTAT Field Descriptions**

Field	Description
4 FACCERR	<b>Flash Access Error Flag</b> — The FACCERR flag indicates an illegal access has occurred to the flash memory or flash IFR caused by either a violation of the command write sequence (see Section 4.6.3.1.2, “Command Write Sequence”), issuing an illegal flash command (see Table 4-21), or the execution of a CPU STOP instruction while a command is executing (FCCF = 0). Writing a 0 to the FACCERR flag has no effect on FACCERR. The FACCERR flag is cleared by writing a 1 to FACCERR. While FACCERR is set, it is not possible to launch a command or start a command write sequence. 0 No access error detected. 1 Access error has occurred.
2 FBLANK	<b>Flash Flag Indicating the Erase Verify Operation Status</b> — When the FCCF flag is set after completion of an erase verify command, the FBLANK flag indicates the result of the erase verify operation. The FBLANK flag is cleared by the flash module when FCBEF is cleared as part of a new valid command write sequence. Writing to the FBLANK flag has no effect on FBLANK. 0 Flash block verified as not erased. 1 Flash block verified as erased.

### 4.6.2.6 Flash Command Register (FCMD)

The FCMD register is the flash command register.


**Figure 4-15. Flash Command Register (FCMD)**

All FCMD bits are readable and writable during a command write sequence while bit 7 reads 0 and is not writable.

**Table 4-20. FCMD Field Descriptions**

Field	Description
6:0 FCMD[6:0]	<b>Flash Command</b> — Valid flash commands are shown in Table 4-21. Writing any command other than those listed in Table 4-21 sets the FACCERR flag in the FSTAT register.

**Table 4-21. Valid Flash Command List**

FCMD[6:0]	NVM Command
0x05	Erase Verify
0x20	Program
0x25	Burst Program
0x40	Sector Erase
0x41	Mass Erase

## 4.6.3 Functional Description

### 4.6.3.1 Flash Command Operations

Flash command operations are used to execute program, erase, and erase verify algorithms described in this section. The program and erase algorithms are controlled by the flash memory controller whose time base, FCLK, is derived from the bus clock via a programmable divider.

The next sections describe:

1. How to write the FCDIV register to set FCLK
2. Command write sequences to program, erase, and erase verify operations on the flash memory
3. Valid flash commands
4. Effects resulting from illegal flash command write sequences or aborting flash operations

#### 4.6.3.1.1 Writing the FCDIV Register

Prior to issuing any flash command after a reset, the user is required to write the FCDIV register to divide the bus clock down to within the 150 kHz to 200 kHz range. This register can be written only once, so normally this write is done during reset initialization. FCDIV cannot be written if the access error flag, FACCERR in FSTAT, is set. The user must ensure that FACCERR is not set before writing to the FCDIV register. One period of the resulting clock ( $1/f_{FCLK}$ ) is used by the command processor to time program and erase pulses. An integer number of these timing pulses are used by the command processor to complete a program or erase command.

Table 4-22 shows program and erase times. The bus clock frequency and FCDIV determine the frequency of FCLK ( $f_{FCLK}$ ). The time for one cycle of FCLK is  $t_{FCLK} = 1/f_{FCLK}$ . The times are shown as a number of cycles of FCLK and as an absolute time for the case where  $t_{FCLK} = 5 \mu\text{s}$ . Program and erase times shown include overhead for the command state machine and enabling and disabling of program and erase voltages.

**Table 4-22. Program and Erase Times**

Parameter	Cycles of FCLK	Time if FCLK = 200 kHz
Byte program	9	45 $\mu\text{s}$
Byte program (burst)	4	20 $\mu\text{s}$ <sup>1</sup>
Page erase	4000	20 ms
Mass erase	20,000	100 ms

<sup>1</sup> Excluding start/end overhead

#### NOTE

Program and erase command execution time will increase proportionally with the period of FCLK. Programming or erasing the flash memory with  $FCLK < 150 \text{ kHz}$  should be avoided. Setting FCDIV to a value such that  $FCLK < 150 \text{ kHz}$  can destroy the flash memory due to overstress. Setting FCDIV to a value such that  $FCLK > 200 \text{ kHz}$  can result in incomplete programming or erasure of the flash memory cells.

If the FCDIV register is written, the FDIVLD bit is set automatically. If the FDIVLD bit is 0, the FCDIV register has not been written since the last reset. If the FCDIV register has not been written to, the flash command loaded during a command write sequence will not execute and the FACCERR flag in the FSTAT register will set.

### 4.6.3.1.2 Command Write Sequence

The flash command controller is used to supervise the command write sequence to execute program, erase, and erase verify algorithms.

Before starting a command write sequence, the FACCERR and FPVIOL flags in the FSTAT register must be clear and the FCBEF flag must be set (see Section 4.6.2.5).

A command write sequence consists of three steps which must be strictly adhered to with writes to the flash module not permitted between the steps. However, flash register and array reads are allowed during a command write sequence. The basic command write sequence is as follows:

1. Write to a valid address in the flash array memory.
2. Write a valid command to the FCMD register.
3. Clear the FCBEF flag in the FSTAT register by writing a 1 to FCBEF to launch the command.

Once a command is launched, the completion of the command operation is indicated by the setting of the FCCF flag in the FSTAT register. The FCCF flag will set upon completion of all active and buffered burst program commands.

### 4.6.3.2 Flash Commands

Table 4-23 summarizes the valid flash commands along with the effects of the commands on the flash block.

**Table 4-23. Flash Command Description**

FCMDB	NVM Command	Function on Flash Memory
0x05	Erase Verify	Verify all memory bytes in the flash array memory are erased. If the flash array memory is erased, the FBLANK flag in the FSTAT register will set upon command completion.
0x20	Program	Program an address in the flash array.
0x25	Burst Program	Program an address in the flash array with the internal address incrementing after the program operation.
0x40	Sector Erase	Erase all memory bytes in a sector of the flash array.
0x41	Mass Erase	Erase all memory bytes in the flash array. A mass erase of the full flash array is only possible when no protection is enabled prior to launching the command.

### CAUTION

A flash block address must be in the erased state before being programmed. Cumulative programming of bits within a flash block address is not allowed except for status field updates required in EEPROM emulation applications.

### 4.6.3.2.1 Erase Verify Command

The erase verify operation will verify that a flash block is erased.

An example flow to execute the erase verify operation is shown in [Figure 4-16](#). The erase verify command write sequence is as follows:

1. Write to a flash block address to start the command write sequence for the erase verify command. The address and data written will be ignored.
2. Write the erase verify command, 0x05, to the FCMD register.
3. Clear the FCBEF flag in the FSTAT register by writing a 1 to FCBEF to launch the erase verify command.

After launching the erase verify command, the FCCF flag in the FSTAT register will set after the operation has completed. The number of bus cycles required to execute the erase verify operation is equal to the number of addresses in the flash array memory plus several bus cycles as measured from the time the FCBEF flag is cleared until the FCCF flag is set. Upon completion of the erase verify operation, the FBLANK flag in the FSTAT register will be set if all addresses in the flash array memory are verified to be erased. If any address in the flash array memory is not erased, the erase verify operation will terminate and the FBLANK flag in the FSTAT register will remain clear.

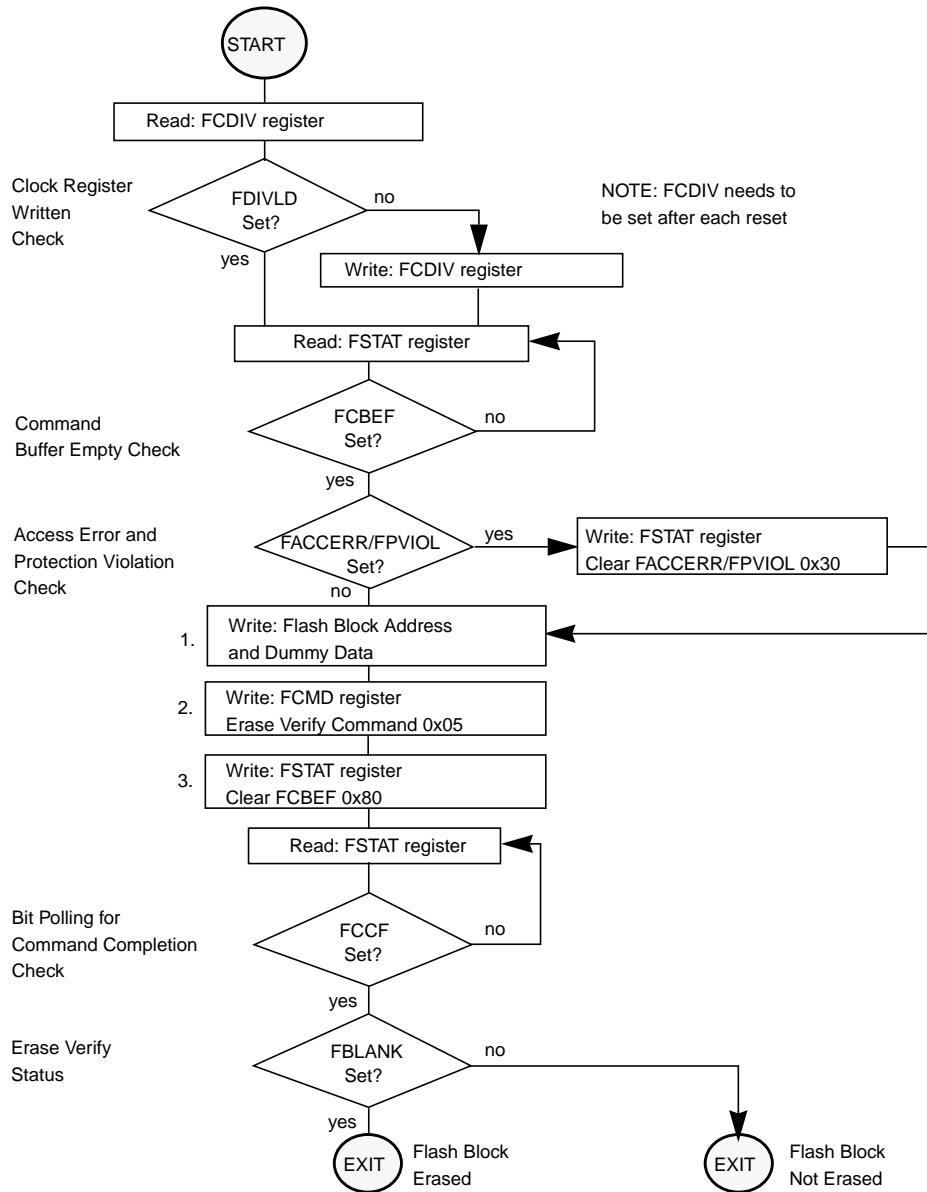


Figure 4-16. Example Erase Verify Command Flow

#### 4.6.3.2.2 Program Command

The program operation will program a previously erased address in the flash memory using an embedded algorithm.

An example flow to execute the program operation is shown in Figure 4-17. The program command write sequence is as follows:

1. Write to a flash block address to start the command write sequence for the program command. The data written will be programmed to the address written.
2. Write the program command, 0x20, to the FCMD register.



- Clear the FCBEF flag in the FSTAT register by writing a 1 to FCBEF to launch the program command.

If an address to be programmed is in a protected area of the flash block, the FPVIOL flag in the FSTAT register will set and the program command will not launch. Once the program command has successfully launched, the FCCF flag in the FSTAT register will set after the program operation has completed.

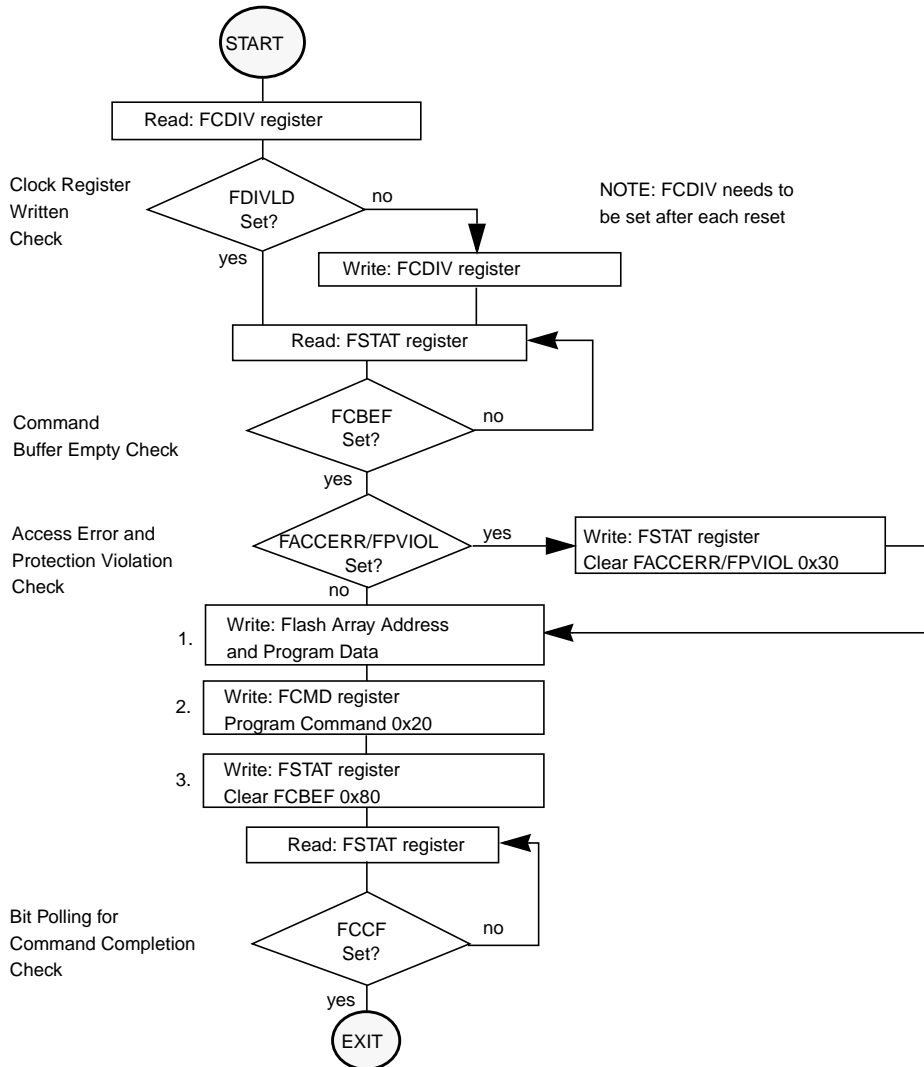


Figure 4-17. Example Program Command Flow

### 4.6.3.2.3 Burst Program Command

The burst program operation will program previously erased data in the flash memory using an embedded algorithm.

While burst programming, two internal data registers operate as a buffer and a register (2-stage FIFO) so that a second burst programming command along with the necessary data can be stored to the buffers while the first burst programming command is still in progress. This pipelined operation allows a time

optimization when programming more than one consecutive address on a specific row in the flash array as the high voltage generation can be kept active in between two programming commands.

An example flow to execute the burst program operation is shown in [Figure 4-18](#). The burst program command write sequence is as follows:

1. Write to a flash block address to start the command write sequence for the burst program command. The data written will be programmed to the address written.
2. Write the program burst command, 0x25, to the FCMD register.
3. Clear the FCBEF flag in the FSTAT register by writing a 1 to FCBEF to launch the program burst command.
4. After the FCBEF flag in the FSTAT register returns to a 1, repeat steps 1 through 3. The address written is ignored but is incremented internally.

The burst program procedure can be used to program an entire flash array even while crossing row boundaries within the flash array. However, the burst program command cannot cross array boundaries. The array boundary for this MCU occurs between extended addresses 0x0FFFF and 0x10000. At least two burst commands are required to program the entire 128K of flash memory.

If data to be burst programmed falls within a protected area of the flash array, the FPVIOL flag in the FSTAT register will set and the burst program command will not launch. Once the burst program command has successfully launched, the FCCF flag in the FSTAT register will set after the burst program operation has completed unless a new burst program command write sequence has been buffered. By executing a new burst program command write sequence on sequential addresses after the FCBEF flag in the FSTAT register has been set, greater than 50% faster programming time for the entire flash array can be effectively achieved when compared to using the basic program command.

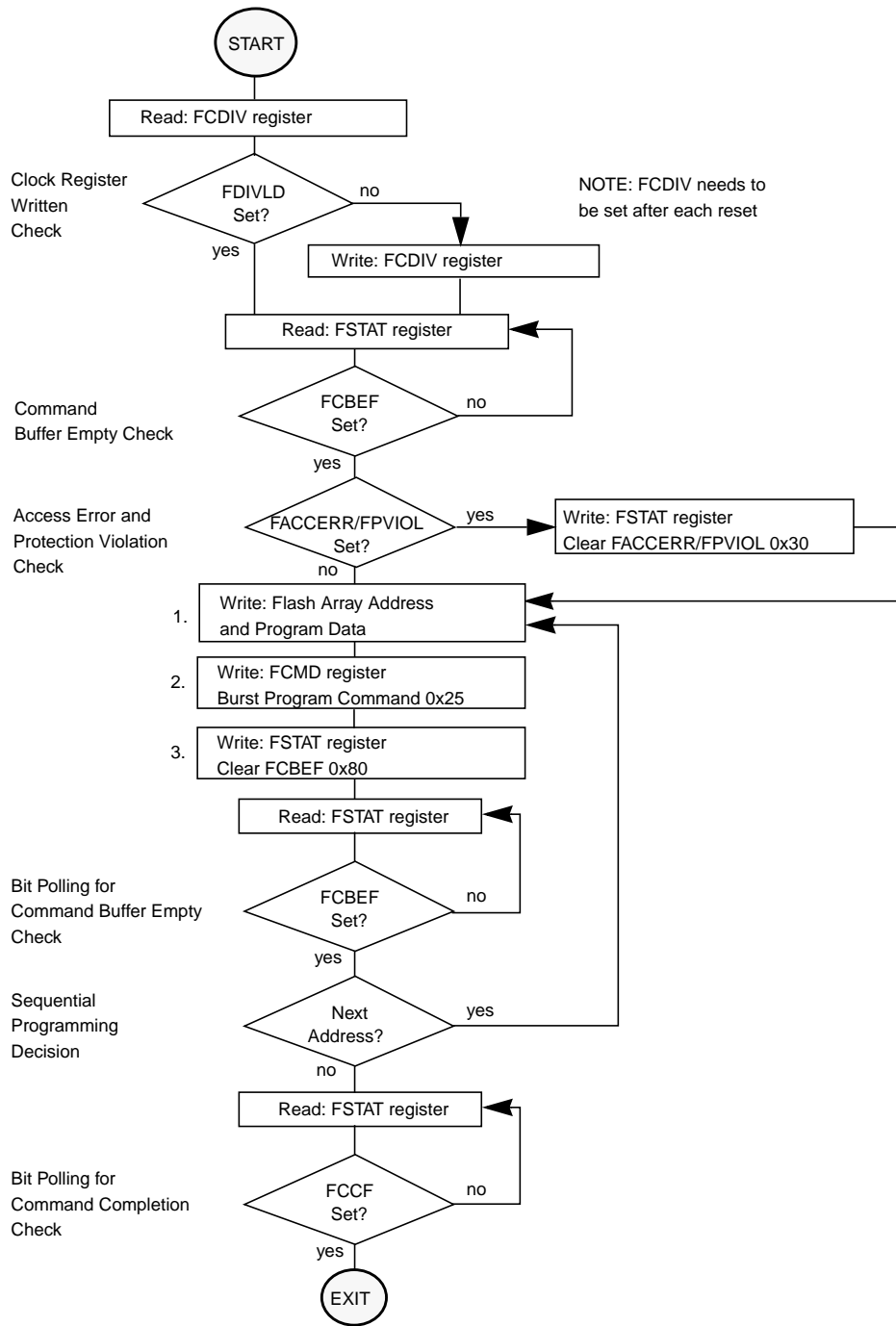


Figure 4-18. Example Burst Program Command Flow

#### 4.6.3.2.4 Sector Erase Command

The sector erase operation will erase all addresses in a 1 Kbyte sector of flash memory using an embedded algorithm.

An example flow to execute the sector erase operation is shown in Figure 4-19. The sector erase command write sequence is as follows:

1. Write to a flash block address to start the command write sequence for the sector erase command. The flash address written determines the sector to be erased while global address bits [8:0] and the data written are ignored.
2. Write the sector erase command, 0x40, to the FCMD register.
3. Clear the FCBEF flag in the FSTAT register by writing a 1 to FCBEF to launch the sector erase command.

If a flash sector to be erased is in a protected area of the flash block, the FPVIOL flag in the FSTAT register will set and the sector erase command will not launch. Once the sector erase command has successfully launched, the FCCF flag in the FSTAT register will set after the sector erase operation has completed.

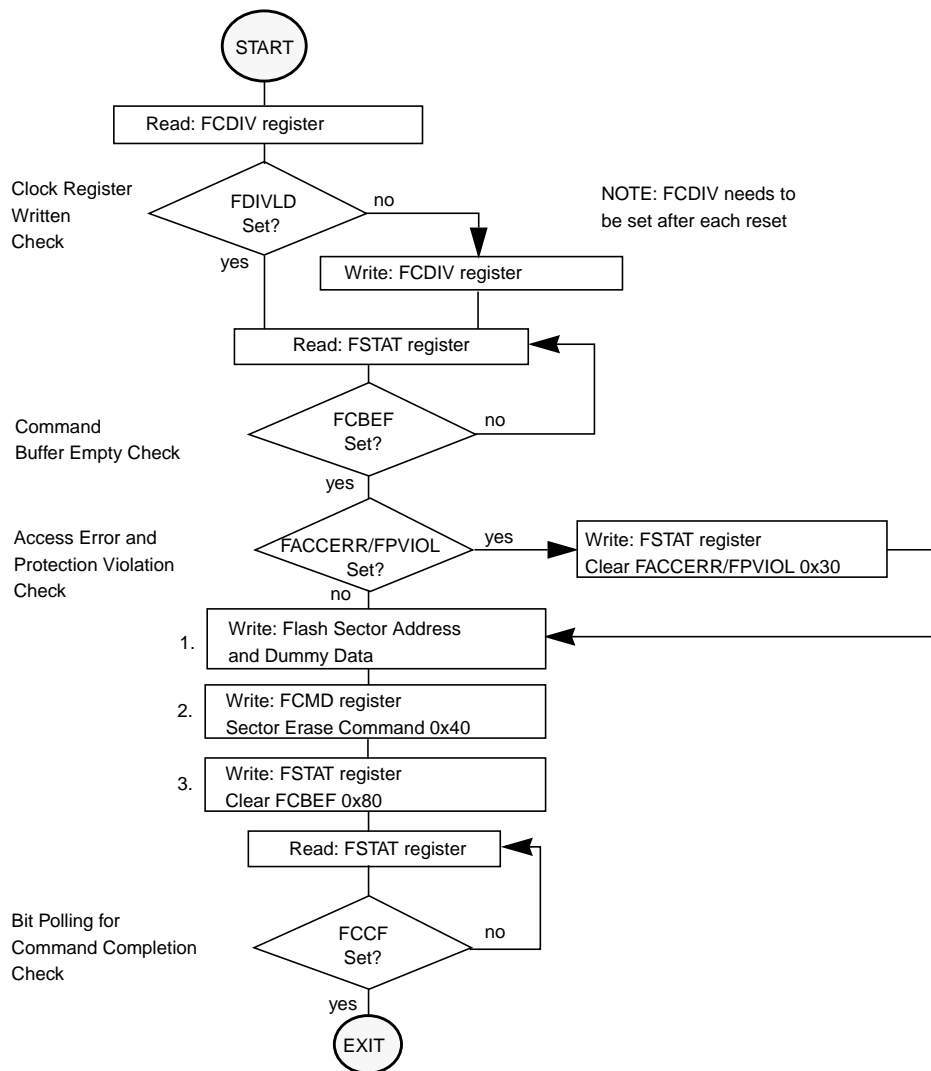


Figure 4-19. Example Sector Erase Command Flow

### 4.6.3.3 Illegal Flash Operations

#### 4.6.3.3.1 Flash Access Violations

The FACCERR flag will be set during the command write sequence if any of the following illegal steps are performed, causing the command write sequence to immediately abort:

1. Writing to a flash address before initializing the FCDIV register.
2. Writing to any flash register other than FCMD after writing to a flash address.
3. Writing to a second flash address in the same command write sequence.
4. Writing an invalid command to the FCMD register unless the address written was in a protected area of the flash array.
5. Writing a command other than burst program while FCBEF is set and FCCF is clear.
6. When security is enabled, writing a command other than mass erase to the FCMD register when the write originates from a non-secure memory location or from the background debug mode.
7. Writing to a flash address after writing to the FCMD register.
8. Writing to any flash register other than FSTAT (to clear FCBEF) after writing to the FCMD register.
9. Writing a 0 to the FCBEF flag in the FSTAT register to abort a command write sequence.

The FACCERR flag will also be set if the MCU enters stop mode while a program or erase operation is active. The operation is aborted immediately and, if burst programming, any pending burst program command is purged (see [Section 4.6.4.2, “Stop Mode”](#)).

The FACCERR flag will not be set if any flash register is read during a valid command write sequence.

If the flash memory is read during execution of an algorithm ( $FCCF = 0$ ), the read operation will return invalid data and the FACCERR flag will not be set.

If the FACCERR flag is set in the FSTAT register, the user must clear the FACCERR flag before starting another command write sequence (see [Section 4.6.2.5, “Flash Status Register \(FSTAT\)”](#)).

#### 4.6.3.3.2 Flash Protection Violations

The FPVIOL flag will be set after the command is written to the FCMD register during a command write sequence if any of the following illegal operations are attempted, causing the command write sequence to immediately abort:

1. Writing the program command if the address written in the command write sequence was in a protected area of the flash array.
2. Writing the sector erase command if the address written in the command write sequence was in a protected area of the flash array.
3. Writing the mass erase command while any flash protection is enabled.
4. Writing an invalid command if the address written in the command write sequence was in a protected area of the flash array.

If the FPVIOL flag is set in the FSTAT register, the user must clear the FPVIOL flag before starting another command write sequence (see [Section 4.6.2.5, “Flash Status Register \(FSTAT\)”](#)).

## 4.6.4 Operating Modes

### 4.6.4.1 Wait Mode

If a command is active (FCCF = 0) when the MCU enters wait mode, the active command and any buffered command will be completed.

### 4.6.4.2 Stop Mode

If a command is active (FCCF = 0) when the MCU enters stop mode, the operation will be aborted and, if the operation is program or erase, the flash array data being programmed or erased may be corrupted and the FCCF and FACCERR flags will be set. If active, the high voltage circuitry to the flash array will immediately be switched off when entering stop mode. Upon exit from stop mode, the FCBEF flag is set and any buffered command will not be launched. The FACCERR flag must be cleared before starting a command write sequence (see [Section 4.6.3.1.2, “Command Write Sequence”](#)).

#### NOTE

As active commands are immediately aborted when the MCU enters stop mode, it is strongly recommended that the user does not use the STOP instruction during program or erase operations.

### 4.6.4.3 Background Debug Mode

In background debug mode (BDM), the FPROT register is writable. If the MCU is unsecured, then all flash commands listed in [Table 4-23](#) can be executed.

## 4.6.5 Flash Module Security

The MC9S08QE128 Series includes circuitry to prevent unauthorized access to the contents of flash and RAM memory. When security is engaged, flash and RAM are considered secure resources. Direct-page registers, high-page registers, and the background debug controller are considered unsecured resources. Programs executing within secure memory have normal access to any MCU memory locations and resources. Attempts to access a secure memory location with a program executing from an unsecured memory space or through the background debug interface are blocked (writes are ignored and reads return all 0s).

The flash module provides the necessary security information to the MCU. During each reset sequence, the flash module determines the security state of the MCU as defined in [Section 4.6.2.2, “Flash Options Register \(FOPT and NVOPT\)”](#).

The contents of the flash security byte in NVOPT must be changed directly by programming the NVOPT location when the MCU is unsecured and the sector containing NVOPT is unprotected. If NVOPT is left in a secured state, any reset will cause the MCU to initialize into a secure operating mode.

The on-chip debug module cannot be enabled while the MCU is secure. The separate background debug controller can still be used for background memory access commands of unsecured resources.

### 4.6.5.1 Unsecuring the MCU using Backdoor Key Access

The MCU may be unsecured by using the backdoor key access feature which requires knowledge of the contents of the backdoor keys (NVBACKKEY through NVBACKKEY+7, see Table 4-4 for specific addresses). If the KEYEN[1:0] bits are in the enabled state (see Section 4.6.2.2) and the KEYACC bit is set, a write to a backdoor key address in the flash memory triggers a comparison between the written data and the backdoor key data stored in the flash memory. If all backdoor keys are written to the correct addresses in the correct order and the data matches the backdoor keys stored in the flash memory, the MCU will be unsecured. The data must be written to the backdoor keys sequentially. Values 0x0000 and 0xFFFF are not permitted as backdoor keys. While the KEYACC bit is set, reads of the flash memory will return invalid data.

The user code stored in the flash memory must have a method of receiving the backdoor keys from an external stimulus. This external stimulus would typically be through one of the on-chip serial ports.

If the KEYEN[1:0] bits are in the enabled state (see Section 4.6.2.2), the MCU can be unsecured by the backdoor key access sequence described below:

1. Set the KEYACC bit in the flash configuration register (FCNFG).
2. Sequentially write the correct eight 8-bit bytes to the flash addresses containing the backdoor keys.
3. Clear the KEYACC bit. Depending on the user code used to write the backdoor keys, a wait cycle (NOP) may be required before clearing the KEYACC bit.
4. If all data written match the backdoor keys, the MCU is unsecured and the SEC[1:0] bits in the FOPT register are forced to the unsecure state of 1:0.

The backdoor key access sequence is monitored by an internal security state machine. An illegal operation during the backdoor key access sequence will cause the security state machine to lock, leaving the MCU in the secured state. A reset of the MCU will cause the security state machine to exit the lock state and allow a new backdoor key access sequence to be attempted. The following operations during the backdoor key access sequence will lock the security state machine:

1. If any of the keys written does not match the backdoor keys programmed in the flash array.
2. If the keys are written in the wrong sequence.
3. If more keys than are required are written.
4. If any of the keys written are all 0s or all 1s.
5. If the KEYACC bit does not remain set while the keys are written.
6. If any of the keys are written on successive MCU clock cycles.
7. Executing a STOP instruction while the KEYACC bit is set.

After the backdoor keys have been correctly matched, the MCU will be unsecured. After the MCU is unsecured, the flash security byte can be programmed to the unsecure state, if desired.

In the unsecure state, the user has full control of the contents of the backdoor keys by programming the associated addresses in NVBACKKEY through NVBACKKEY+7.

The security as defined in the flash security byte is not changed by using the backdoor key access sequence to unsecure. The stored backdoor keys are unaffected by the backdoor key access sequence. After the next reset of the MCU, the security state of the flash module is determined by the flash security byte. The

backdoor key access sequence has no effect on the program and erase protections defined in the flash protection register (FPROT).

It is not possible to unsecure the MCU in special mode by using the backdoor key access sequence in background debug mode (BDM).

#### 4.6.6 Resets

If a reset occurs while any flash command is in progress, that command will be immediately aborted. The state of the flash array address being programmed or the sector/block being erased is not guaranteed.



# Chapter 5

## Resets, Interrupts, and General System Control

### 5.1 Introduction

This section discusses basic reset and interrupt mechanisms and the various sources of reset and interrupt in the MC9S08QE128 Series. Some interrupt sources from peripheral modules are discussed in greater detail within other sections of this reference manual. This section gathers basic information about all reset and interrupt sources in one place for easy reference. A few reset and interrupt sources, including the computer operating properly (COP) watchdog are not part of on-chip peripheral systems with their own chapters.

### 5.2 Features

Reset and interrupt features include:

- Multiple sources of reset for flexible system configuration and reliable operation
- Reset status register (SRS) to indicate source of most recent reset
- Separate interrupt vector for most modules (reduces polling overhead) (see [Table 5-2](#))

### 5.3 MCU Reset

Resetting the MCU provides a way to start processing from a known set of initial conditions. During reset, most control and status registers are forced to initial values and the program counter is loaded from the reset vector (0xFFFF:0xFFFF). On-chip peripheral modules are disabled and I/O pins are initially configured as general-purpose high-impedance inputs with pull-up devices disabled. The I bit in the condition code register (CCR) is set to block maskable interrupts so the user program has a chance to initialize the stack pointer (SP) and system control settings. SP is forced to 0x00FF at reset.

The MC9S08QE128 Series has the following sources for reset:

- Power-on reset (POR)
- External pin reset (PIN)
- Computer operating properly (COP) timer
- Illegal opcode detect (ILOP)
- Low-voltage detect (LVD)
- Background debug forced reset

Each of these sources, with the exception of the background debug forced reset, has an associated bit in the system reset status register (SRS).

## 5.4 Computer Operating Properly (COP) Watchdog

The COP watchdog is intended to force a system reset when the application software fails to execute as expected. To prevent a system reset from the COP timer (when it is enabled), application software must reset the COP counter periodically. If the application program gets lost and fails to reset the COP counter before it times out, a system reset is generated to force the system back to a known starting point.

After any reset, the COPE becomes set in SOPT1 enabling the COP watchdog (see Section 5.8.4, “System Options Register 1 (SOPT1),” for additional information). If the COP watchdog is not used in an application, it can be disabled by clearing COPE. The COP counter is reset by writing any value to the address of SRS. This write does not affect the data in the read-only SRS. Instead, the act of writing to this address is decoded and sends a reset signal to the COP counter.

The COPCLKS bit in SOPT2 (see Section 5.8.5, “System Options Register 2 (SOPT2),” for additional information) selects the clock source used for the COP timer. The clock source options are either the bus clock or an internal 1-kHz clock source. With each clock source, there is an associated short and long time-out controlled by COPT in SOPT1. Table 5-1 summarizes the control functions of the COPCLKS and COPT bits. The COP watchdog defaults to operation from the 1-kHz clock source and the associated long time-out ( $2^8$  cycles).

**Table 5-1. COP Configuration Options**

Control Bits		Clock Source	COP Overflow Count
COPCLKS	COPT		
0	0	~1 kHz	$2^5$ cycles (32 ms) <sup>1</sup>
0	1	~1 kHz	$2^8$ cycles (256 ms) <sup>1</sup>
1	0	Bus	$2^{13}$ cycles
1	1	Bus	$2^{18}$ cycles

<sup>1</sup> Values are shown in this column based on  $t_{LPO} = 1$  ms. See  $t_{LPO}$  in the data sheet for the tolerance of this value.

Even if the application will use the reset default settings of COPE, COPCLKS, and COPT, the user must write to the write-once SOPT1 and SOPT2 registers during reset initialization to lock in the settings. That way, they cannot be changed accidentally if the application program gets lost. The initial writes to SOPT1 and SOPT2 will reset the COP counter.

The write to SRS that services (clears) the COP counter must not be placed in an interrupt service routine (ISR) because the ISR could continue to be executed periodically even if the main application program fails.

In background debug mode, the COP counter will not increment.

When the bus clock source is selected, the COP counter does not increment while the system is in stop mode. The COP counter resumes as soon as the MCU exits stop mode.

When the 1-kHz clock source is selected, the COP counter is re-initialized to zero upon entry to stop mode. The COP counter begins from zero after the MCU exits stop mode.

## 5.5 Interrupts

Interrupts provide a way to save the current CPU status and registers, execute an interrupt service routine (ISR), and then restore the CPU status so processing resumes where it left off before the interrupt. Other than the software interrupt (SWI), which is a program instruction, interrupts are caused by hardware events such as an edge on the IRQ pin or a timer-overflow event. The debug module can also generate an SWI under certain circumstances.

If an event occurs in an enabled interrupt source, an associated read-only status flag will become set. The CPU will not respond unless the local interrupt enable is a 1 to enable the interrupt and the I bit in the CCR is 0 to allow interrupts. The global interrupt mask (I bit) in the CCR is initially set after reset which prevents all maskable interrupt sources. The user program initializes the stack pointer and performs other system setup before clearing the I bit to allow the CPU to respond to interrupts.

When the CPU receives a qualified interrupt request, it completes the current instruction before responding to the interrupt. The interrupt sequence obeys the same cycle-by-cycle sequence as the SWI instruction and consists of:

- Saving the CPU registers on the stack
- Setting the I bit in the CCR to mask further interrupts
- Fetching the interrupt vector for the highest-priority interrupt that is currently pending
- Filling the instruction queue with the first three bytes of program information starting from the address fetched from the interrupt vector locations

While the CPU is responding to the interrupt, the I bit is automatically set to avoid the possibility of another interrupt interrupting the ISR itself (this is called nesting of interrupts). Normally, the I bit is restored to 0 when the CCR is restored from the value stacked on entry to the ISR. In rare cases, the I bit can be cleared inside an ISR (after clearing the status flag that generated the interrupt) so that other interrupts can be serviced without waiting for the first service routine to finish. This practice is not recommended for anyone other than the most experienced programmers because it can lead to subtle program errors that are difficult to debug.

### NOTE

In order for the ISR to be available in the memory map regardless of the PPAGE value, ISRs should be located in pages 0, 1, or 3.

The interrupt service routine ends with a return-from-interrupt (RTI) instruction which restores the CCR, A, X, and PC registers to their pre-interrupt values by reading the previously saved information from the stack.

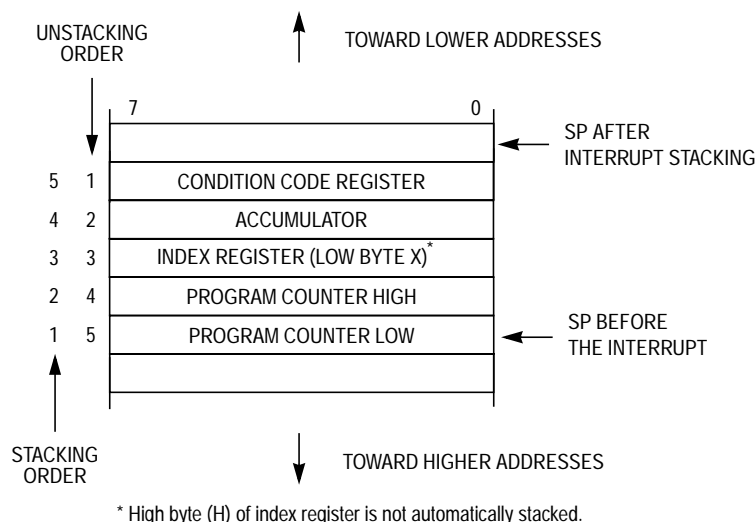
### NOTE

For compatibility with M68HC08 devices, the H register is not automatically saved and restored. It is good programming practice to push H onto the stack at the start of the interrupt service routine (ISR) and restore it immediately before the RTI that is used to return from the ISR.

If more than one interrupt is pending when the I bit is cleared, the highest priority source is serviced first (see Table 5-2).

### 5.5.1 Interrupt Stack Frame

Figure 5-1 shows the contents and organization of a stack frame. Before the interrupt, the stack pointer (SP) points at the next available byte location on the stack. The current values of CPU registers are stored on the stack starting with the low-order byte of the program counter (PCL) and ending with the CCR. After stacking, the SP points at the next available location on the stack which is the address that is one less than the address where the CCR was saved. The PC value that is stacked is the address of the instruction in the main program that would have executed next if the interrupt had not occurred.



**Figure 5-1. Interrupt Stack Frame**

When an RTI instruction is executed, these values are recovered from the stack in reverse order. As part of the RTI sequence, the CPU fills the instruction pipeline by reading three bytes of program information, starting from the PC address recovered from the stack.

The status flag corresponding to the interrupt source must be acknowledged (cleared) before returning from the ISR. Typically, the flag is cleared at the beginning of the ISR so that if another interrupt is generated by this same source, it will be registered so it can be serviced after completion of the current ISR.

### 5.5.2 External Interrupt Request (IRQ) Pin

External interrupts are managed by the IRQ status and control register, IRQSC. When the IRQ function is enabled, synchronous logic monitors the pin for edge-only or edge-and-level events. When the MCU is in stop mode and system clocks are shut down, a separate asynchronous path is used so the IRQ pin (if enabled) can wake the MCU.

### 5.5.2.1 Pin Configuration Options

The IRQ pin enable (IRQPE) control bit in IRQSC must be 1 in order for the IRQ pin to act as the interrupt request (IRQ) input. As an IRQ input, the user can choose the polarity of edges or levels detected (IRQEDG), whether the pin detects edges-only or edges and levels (IRQMOD), and whether an event causes an interrupt or only sets the IRQF flag which can be polled by software (IRQIE).

The IRQ pin, when enabled, defaults to use an internal pull device (IRQPDD = 0), configured as a pull-up or pull-down depending on the polarity chosen. If the user desires to use an external pull-up or pull-down, the IRQPDD can be written to a 1 to turn off the internal device.

BIH and BIL instructions may be used to detect the level on the IRQ pin when the pin is configured to act as the IRQ input.

#### NOTE

This pin does not contain a clamp diode to  $V_{DD}$  and should not be driven above  $V_{DD}$ .

#### NOTE

The voltage measured on the internally pulled up  $\overline{\text{RESET}}$  pin will not be pulled to  $V_{DD}$ . The internal gates connected to this pin are pulled to  $V_{DD}$ . The  $\overline{\text{RESET}}$  pullup should not be used to pullup components external to the MCU.

### 5.5.2.2 Edge and Level Sensitivity

The IRQMOD control bit reconfigures the detection logic so it detects edge events and pin levels. In the edge and level detection mode, the IRQF status flag becomes set when an edge is detected (when the IRQ pin changes from the deasserted to the asserted level), but the flag is continuously set (and cannot be cleared) as long as the IRQ pin remains at the asserted level.

### 5.5.2.3 External Interrupt Initialization

When the IRQ pin is first enabled, it is possible to get a false interrupt flag. To prevent a false interrupt request during IRQ initialization, the user should do the following:

1. Mask interrupts by clearing IRQIE in IRQSC.
2. Select the pin polarity by setting the appropriate IRQEDG bits in IRQSC.
3. If using internal pull-up/pull-down device, clear the IRQPDD bit in IRQSC.
4. Enable the IRQ pin by setting the appropriate IRQPE bit in IRQSC.
5. Write to IRQACK in IRQSC to clear any false interrupts.
6. Set IRQIE in IRQSC to enable interrupts.

## 5.5.3 Interrupt Vectors, Sources, and Local Masks

Table 5-2 provides a summary of all interrupt sources. Higher-priority sources are located toward the bottom of the table. The high-order byte of the address for the interrupt service routine is located at the

first address in the vector address column, and the low-order byte of the address for the interrupt service routine is located at the next higher address.

When an interrupt condition occurs, an associated flag bit becomes set. If the associated local interrupt enable is 1, an interrupt request is sent to the CPU. Within the CPU, if the global interrupt mask (I bit in the CCR) is 0, the CPU will finish the current instruction; stack the PCL, PCH, X, A, and CCR CPU registers; set the I bit; and then fetch the interrupt vector for the highest priority pending interrupt. Processing then continues in the interrupt service routine.

Table 5-2. Vector Summary

Vector Priority	Vector Number	Address (High/Low)	Vector Name	Module	Source	Enable	Description
Lowest  Highest	31	0xFFC0/0xFFC1	Vtpm3ovf	TPM3	TOF	TOIE	TPM3 overflow
	30	0xFFC2/0xFFC3	Vtpm3ch5	TPM3	CH5F	CH5IE	TPM3 channel 5
	29	0xFFC4/0xFFC5	Vtpm3ch4	TPM3	CH4F	CH4IE	TPM3 channel 4
	28	0xFFC6/0xFFC7	Vtpm3ch3	TPM3	CH3F	CH3IE	TPM3 channel 3
	27	0xFFC8/0xFFC9	Vtpm3ch2	TPM3	CH2F	CH2IE	TPM3 channel 2
	26	0xFFCA/0xFFCB	Vtpm3ch1	TPM3	CH1F	CH1IE	TPM3 channel 1
	25	0xFFCC/0xFFCD	Vtpm3ch0	TPM3	CH0F	CH0IE	TPM3 channel 0
	24	0xFFCE/0xFFCF	Vrtc	RTC	RTIF	RTIE	Real-time interrupt
	23	0xFFD0/0xFFD1	Vsci2tx	SCI2	TDRE, TC	TIE, TCIE	SCI2 transmit
	22	0xFFD2/0xFFD3	Vsci2rx	SCI2	IDLE, LBKDIF, RDRF, RXEDGIF	ILIE, LBKDIE, RIE, RXEDGIE	SCI2 receive
	21	0xFFD4/0xFFD5	Vsci2err	SCI2	OR, NF, FE, PF	ORIE, NFIE, FEIE, PFIE	SCI2 error
	20	0xFFD6/0xFFD7	Vacmpx	ACMPx <sup>1</sup>	ACF	ACIE	Analog comparator x
	19	0xFFD8/0xFFD9	Vadc	ADC	COCO	AIEN	ADC
	18	0xFFDA/0xFFDB	Vkeyboard	KBIx <sup>2</sup>	KBF	KBIE	Keyboard x pins
	17	0xFFDC/0xFFDD	Viicx	IICx <sup>3</sup>	IICIS	IICIE	IICx control
	16	0xFFDE/0xFFDF	Vsci1tx	SCI1	TDRE, TC	TIE, TCIE	SCI1 transmit
	15	0xFFE0/0xFFE1	Vsci1rx	SCI1	IDLE, LBKDIF, RDRF, RXEDGIF	ILIE, LBKDIE, RIE, RXEDGIE	SCI1 receive
	14	0xFFE2/0xFFE3	Vsci1err	SCI1	OR, NF, FE, PF	ORIE, NFIE, FEIE, PFIE	SCI1 error
	13	0xFFE4/0xFFE5	Vspi1	SPI1	SPIF, MODF, SPTF	SPIE, SPIE, SPTIE	SPI1
	12	0xFFE6/0xFFE7	Vspi2	SPI2	SPIF, MODF, SPTF	SPIE, SPIE, SPTIE	SPI2
	11	0xFFE8/0xFFE9	Vtpm2ovf	TPM2	TOF	TOIE	TPM2 overflow
	10	0xFFEA/0xFFEB	Vtpm2ch2	TPM2	CH2F	CH2IE	TPM2 channel 2
	9	0xFFEC/0xFFED	Vtpm2ch1	TPM2	CH1F	CH1IE	TPM2 channel 1
	8	0xFFEE/0xFFEF	Vtpm2ch0	TPM2	CH0F	CH0IE	TPM2 channel 0
	7	0xFFFF0/0xFFFF1	Vtpm1ovf	TPM1	TOF	TOIE	TPM1 overflow
	6	0xFFFF2/0xFFFF3	Vtpm1ch2	TPM1	CH2F	CH2IE	TPM1 channel 2
	5	0xFFFF4/0xFFFF5	Vtpm1ch1	TPM1	CH1F	CH1IE	TPM1 channel 1
	4	0xFFFF6/0xFFFF7	Vtpm1ch0	TPM1	CH0F	CH0IE	TPM1 channel 0
	3	0xFFFF8/0xFFFF9	Vlvd	System control	LVDF, LVWF	LVDIE, LVWIE	Low-voltage detect, Low-voltage warning
	2	0xFFFFA/0xFFFFB	Virq	IRQ	IRQF	IRQIE	IRQ pin
	1	0xFFFFC/0xFFFFD	Vswi	Core	SWI Instruction	—	Software interrupt
	0	0xFFFFE/0xFFFFF	Vreset	System control	COP, LVD, RESET pin, Illegal opcode,	COPE, LVDRE, —, —	Watchdog timer, Low-voltage detect, External pin, Illegal opcode

<sup>1</sup> ACMP1 and ACMP2 share this vector, if both modules are enabled user should poll each flag to determine pending interrupt.

<sup>2</sup> KBI1 and KBI2 share this vector, if both modules are enabled user should poll each flag to determine pending interrupt.

<sup>3</sup> IIC1 and IIC2 share this vector, if both modules are enabled user should poll each flag to determine pending interrupt.

## 5.6 Low-Voltage Detect (LVD) System

The MC9S08QE128 Series includes a system to protect against low voltage conditions to protect memory contents and control MCU system states during supply voltage variations. The system is comprised of a power-on reset (POR) circuit and a LVD circuit with a user selectable trip voltage, either high ( $V_{LV\text{DH}}$ ) or low ( $V_{LV\text{DL}}$ ). The LVD circuit is enabled when LVDE in SPMSC1 is set and the trip voltage is selected by LVDV in SPMSC3. The LVD is disabled upon entering either of the stop modes unless LVDSE is set in SPMSC1. If LVDSE and LVDE are both set, then the MCU will enter stop3 instead of stop2, and the current consumption in stop3 with the LVD enabled will be greater.

### 5.6.1 Power-On Reset Operation

When power is initially applied to the MCU, or when the supply voltage drops below the power-on reset rearm voltage level,  $V_{\text{POR}}$ , the POR circuit will cause a reset condition. As the supply voltage rises, the LVD circuit will hold the MCU in reset until the supply has risen above the low voltage detection low threshold,  $V_{LV\text{DL}}$ . Both the POR bit and the LVD bit in SRS are set following a POR.

### 5.6.2 Low-Voltage Detection (LVD) Reset Operation

The LVD can be configured to generate a reset upon detection of a low voltage condition by setting LVDRE to 1. The low voltage detection threshold is determined by the LVDV bit. After an LVD reset has occurred, the LVD system will hold the MCU in reset until the supply voltage has risen above the low voltage detection threshold. The LVD bit in the SRS register is set following either an LVD reset or POR.

### 5.6.3 Low-Voltage Detection (LVD) Interrupt Operation

When a low voltage condition is detected and the LVD circuit is configured using SPMSC1 for interrupt operation (LVDE set, LVDIE set, and LVDRE clear), then LVDF in SPMSC1 will be set and an LVD interrupt request will occur. The LVDF bit is cleared by writing a 1 to the LVDACK bit in SPMSC1.

### 5.6.4 Low-Voltage Warning (LVW) Interrupt Operation

The LVD system has a low voltage warning flag (LVWF) to indicate to the user that the supply voltage is approaching, but is above, the LVD voltage. The LVW also has an interrupt associated with it, enabled by setting the LVWIE bit in the SPMSC3 register. If enabled, an LVW interrupt request will occur when the LVWF is set. LVWF is cleared by writing a 1 to the LVWACK bit in SPMSC3. There are two user selectable trip voltages for the LVW, one high ( $V_{LV\text{WH}}$ ) and one low ( $V_{LV\text{WL}}$ ). The trip voltage is selected by LVWV in SPMSC3.

## 5.7 Peripheral Clock Gating

The MC9S08QE128 Series includes a clock gating system to manage the bus clock sources to the individual peripherals. Using this system, the user can enable or disable the bus clock to each of the peripherals at the clock source, eliminating unnecessary clocks to peripherals which are not in use and thereby reducing the overall run and wait mode currents.



Out of reset, all peripheral clocks will be enabled. For lowest possible run or wait currents, user software should disable the clock source to any peripheral not in use. The actual clock will be enabled or disabled immediately following the write to the Clock Gating Control registers (SCGC1 and SCGC2). Any peripheral with a gated clock can not be used unless its clock is enabled. Writing to the registers of a peripheral with a disabled clock has no effect.

#### **NOTE**

User software should disable the peripheral before disabling the clocks to the peripheral. When clocks are re-enabled to a peripheral, the peripheral registers need to be re-initialized by user software.

In stop modes, the bus clock is disabled for all gated peripherals, regardless of the settings in SCGC1 and SCGC2.

## 5.8 Reset, Interrupt, and System Control Registers and Control Bits

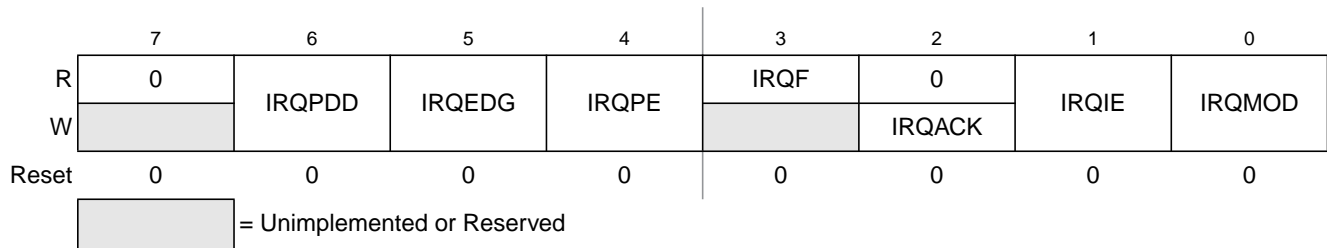
One 8-bit register in the direct page register space and eight 8-bit registers in the high-page register space are related to reset and interrupt systems.

Refer to [Table 4-2](#) and [Table 4-3](#) in [Chapter 4, “Memory,”](#) of this data sheet for the absolute address assignments for all registers. This section refers to registers and control bits only by their names. A Freescale-provided equate or header file is used to translate these names into the appropriate absolute addresses.

Some control bits in the SOPT1 and SPMSC2 registers are related to modes of operation. Although brief descriptions of these bits are provided here, the related functions are discussed in greater detail in [Chapter 3, “Modes of Operation.”](#)

### 5.8.1 Interrupt Pin Request Status and Control Register (IRQSC)

This direct page register includes status and control bits which are used to configure the IRQ function, report status, and acknowledge IRQ events.



**Figure 5-2. Interrupt Request Status and Control Register (IRQSC)**

**Table 5-3. IRQSC Register Field Descriptions**

Field	Description
6 IRQPDD	<b>Interrupt Request (IRQ) Pull Device Disable</b> — This read/write control bit is used to disable the internal pull-up/pull-down device when the IRQ pin is enabled (IRQPE = 1) allowing for an external device to be used. 0 IRQ pull device enabled if IRQPE = 1. 1 IRQ pull device disabled if IRQPE = 1.
5 IRQEDG	<b>Interrupt Request (IRQ) Edge Select</b> — This read/write control bit is used to select the polarity of edges or levels on the IRQ pin that cause IRQF to be set. The IRQMOD control bit determines whether the IRQ pin is sensitive to both edges and levels or only edges. When IRQEDG = 1 and the internal pull device is enabled, the pull-up device is reconfigured as an optional pull-down device. 0 IRQ is falling edge or falling edge/low-level sensitive. 1 IRQ is rising edge or rising edge/high-level sensitive.
4 IRQPE	<b>IRQ Pin Enable</b> — This read/write control bit enables the IRQ pin function. When this bit is set the IRQ pin can be used as an interrupt request. 0 IRQ pin function is disabled. 1 IRQ pin function is enabled.
3 IRQF	<b>IRQ Flag</b> — This read-only status bit indicates when an interrupt request event has occurred. 0 No IRQ request. 1 IRQ event detected.

**Table 5-3. IRQSC Register Field Descriptions**

Field	Description
2 IRQACK	<b>IRQ Acknowledge</b> — This write-only bit is used to acknowledge interrupt request events (write 1 to clear IRQF). Writing 0 has no meaning or effect. Reads always return 0. If edge-and-level detection is selected (IRQMOD = 1), IRQF cannot be cleared while the IRQ pin remains at its asserted level.
1 IRQIE	<b>IRQ Interrupt Enable</b> — This read/write control bit determines whether IRQ events generate an interrupt request. 0 Interrupt request when IRQF set is disabled (use polling). 1 Interrupt requested whenever IRQF = 1.
0 IRQMOD	<b>IRQ Detection Mode</b> — This read/write control bit selects either edge-only detection or edge-and-level detection. The IRQEDG control bit determines the polarity of edges and levels that are detected as interrupt request events. See Section 5.5.2.2, “Edge and Level Sensitivity” for more details. 0 IRQ event on falling edges or rising edges only. 1 IRQ event on falling edges and low levels or on rising edges and high levels.

## 5.8.2 System Reset Status Register (SRS)

This high page register includes read-only status flags to indicate the source of the most recent reset. When a debug host forces reset by writing 1 to BDFR in the SBDFR register, none of the status bits in SRS will be set. Writing any value to this register address clears the COP watchdog timer without affecting the contents of this register. The reset state of these bits depends on what caused the MCU to reset.

	7	6	5	4	3	2	1	0
R	POR	PIN	COP	ILOP	0	0	LVD	0
W	Writing any value to SRS address clears COP watchdog timer.							
POR:	1	0	0	0	0	0	1	0
LVD:	u <sup>1</sup>	0	0	0	0	0	1	0
Any other reset:	0	Note <sup>2</sup>	Note <sup>2</sup>	Note <sup>2</sup>	0	0	0	0

<sup>1</sup> u = unaffected

<sup>2</sup> Any of these reset sources that are active at the time of reset entry will cause the corresponding bit(s) to be set; bits corresponding to sources that are not active at the time of reset entry will be cleared.

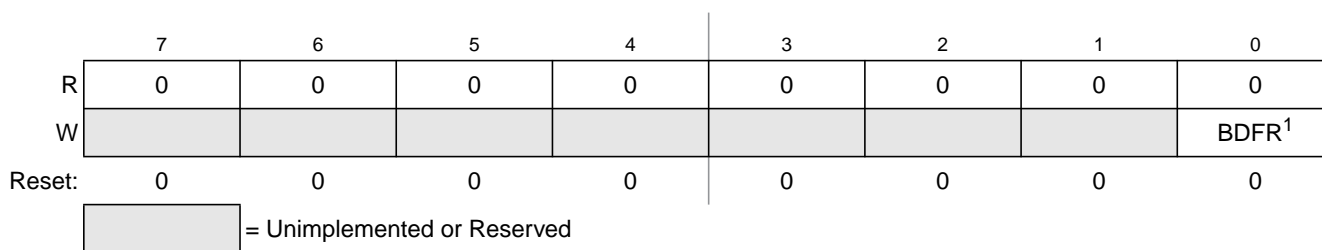
**Figure 5-3. System Reset Status (SRS)**

Table 5-4. SRS Register Field Descriptions

Field	Description
7 POR	<b>Power-On Reset</b> — Reset was caused by the power-on detection logic. Because the internal supply voltage was ramping up at the time, the low-voltage reset (LVD) status bit is also set to indicate that the reset occurred while the internal supply was below the LVD threshold. 0 Reset not caused by POR. 1 POR caused reset.
6 PIN	<b>External Reset Pin</b> — Reset was caused by an active-low level on the external reset pin. 0 Reset not caused by external reset pin. 1 Reset came from external reset pin.
5 COP	<b>Computer Operating Properly (COP) Watchdog</b> — Reset was caused by the COP watchdog timer timing out. This reset source can be blocked by COPE = 0. 0 Reset not caused by COP timeout. 1 Reset caused by COP timeout.
4 ILOP	<b>Illegal Opcode</b> — Reset was caused by an attempt to execute an unimplemented or illegal opcode. The STOP instruction is considered illegal if stop is disabled by STOPE = 0 in the SOPT register. The BGND instruction is considered illegal if active background mode is disabled by ENBDM = 0 in the BDCSC register. 0 Reset not caused by an illegal opcode. 1 Reset caused by an illegal opcode.
1 LVD	<b>Low Voltage Detect</b> — If the LVDRE bit is set and the supply drops below the LVD trip voltage, an LVD reset will occur. This bit is also set by POR. 0 Reset not caused by LVD trip or POR. 1 Reset caused by LVD trip or POR.

### 5.8.3 System Background Debug Force Reset Register (SBDFR)

This high page register contains a single write-only control bit. A serial background command such as WRITE\_BYTE must be used to write to SBDFR. Attempts to write this register from a user program are ignored. Reads always return 0x00.



<sup>1</sup> BDFR is writable only through serial background debug commands, not from user programs.

Figure 5-4. System Background Debug Force Reset Register (SBDFR)

**Table 5-5. SBDFR Register Field Descriptions**

Field	Description
0 BDFR	<b>Background Debug Force Reset</b> — A serial background command such as WRITE_BYTE can be used to allow an external debug host to force a target system reset. Writing 1 to this bit forces an MCU reset. This bit cannot be written from a user program. To enter user mode, PTA4/ACMPO/BKGD/MS must be high immediately after issuing WRITE_BYTE command. To enter BDM, PTA4/ACMPO/BKGD/MS must be low immediately after issuing WRITE_BYTE command. See the data sheet for more information.

### 5.8.4 System Options Register 1 (SOPT1)

This high page register is a write-once register so only the first write after reset is honored. It can be read at any time. Any subsequent attempt to write to SOPT1 (intentionally or unintentionally) is ignored to avoid accidental changes to these sensitive settings. SOPT1 should be written during the user's reset initialization program to set the desired controls even if the desired settings are the same as the reset settings.

	7	6	5	4	3	2	1	0
R				0	0			
W	COPE	COPT	STOPE			RSTOPE	BKGDPE	RSTPE
Reset:	1	1	0	0	0	u <sup>1</sup>	1	u <sup>1</sup>
POR:	1	1	0	0	0	0	1	0
LVR:	1	1	0	0	0	0	1	0

= Unimplemented or Reserved

**Figure 5-5. System Options Register 1 (SOPT1)**

<sup>1</sup> u = unaffected

**Table 5-6. SOPT1 Register Field Descriptions**

Field	Description
7 COPE	<b>COP Watchdog Enable</b> — This write-once bit selects whether the COP watchdog is enabled. 0 COP watchdog timer disabled. 1 COP watchdog timer enabled (force reset on timeout).
6 COPT	<b>COP Watchdog Timeout</b> — This write-once bit selects the timeout period of the COP. COPT along with COPCLKS in SOPT2 defines the COP timeout period. 0 Short timeout period selected. 1 Long timeout period selected.
5 STOPE	<b>Stop Mode Enable</b> — This write-once bit is used to enable stop mode. If stop mode is disabled and a user program attempts to execute a STOP instruction, an illegal opcode reset is forced. 0 Stop mode disabled. 1 Stop mode enabled.
2 RSTOPE	<b>RSTO Pin Enable</b> — This write-once bit when set enables the PTC4/TPM3CH4/RSTO pin to function as RSTO. When clear, the pin functions as one of its alternative functions. This pin defaults to its I/O port function following an MCU POR. 0 PTC4/TPM3CH4/RSTO pin functions as PTC4 or TPM3CH4. 1 PTC4/TPM3CH4/RSTO pin functions as RSTO.

Table 5-6. SOPT1 Register Field Descriptions (continued)

Field	Description
1 BKGDPPE	<b>Background Debug Mode Pin Enable</b> — This write-once bit when set enables the PTA4/ACMPO/BKGD/MS pin to function as BKGD/MS. When clear, the pin functions as one of its output only alternative functions. This pin defaults to the BKGD/MS function following any MCU reset. 0 PTA4/ACMPO/BKGD/MS pin functions as PTA4 or ACMPO. 1 PTA4/ACMPO/BKGD/MS pin functions as BKGD/MS.
0 RSTPE	<b>RESET Pin Enable</b> — This write-once bit when set enables the PTA5/IRQ/TCLK/RESET pin to function as RESET. When clear, the pin functions as one of its input only alternative functions. This pin defaults to the PTA5 function following an MCU POR. When RSTPE is set, an internal pullup device is enabled on RESET. 0 PTA5/IRQ/TCLK/RESET pin functions as PTA5, IRQ or TCLK. 1 PTA5/IRQ/TCLK/RESET pin functions as RESET.

### 5.8.5 System Options Register 2 (SOPT2)

This high page register contains bits to configure MCU specific features on the MC9S08QE128 Series devices.

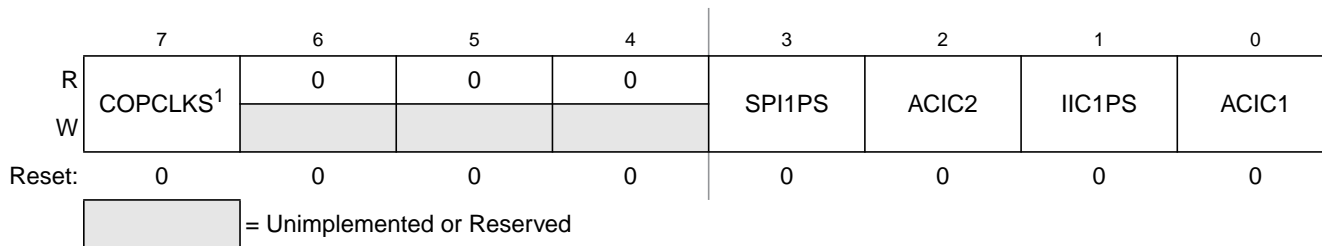


Figure 5-6. System Options Register 2 (SOPT2)

<sup>1</sup> This bit can be written only one time after reset. Additional writes are ignored.

Table 5-7. SOPT2 Register Field Descriptions

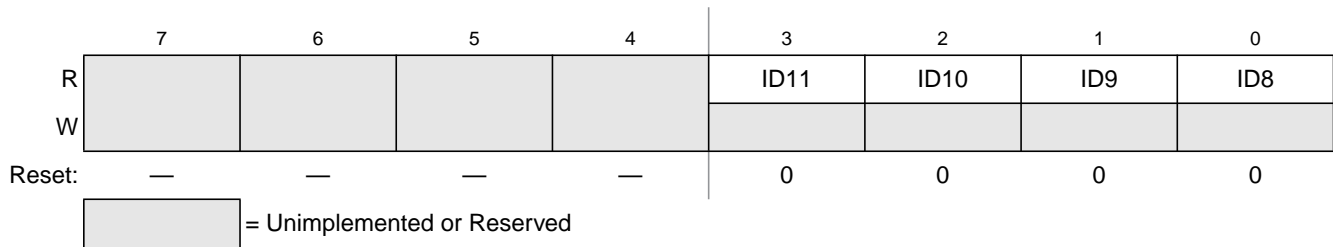
Field	Description
7 COPCLKS	<b>COP Watchdog Clock Select</b> — This write-once bit selects the clock source of the COP watchdog. 0 Internal 1-kHz clock is source to COP. 1 Bus clock is source to COP.
3 SPI1PS	<b>SPI1 Pin Select</b> — This bit selects the location of the MOSI1, MISO1, SPCLK1, and SS1 pins of the SPI1 module. 0 SPCLK1 on PTB2, MOSI1 on PTB3, MISO1 on PTB4, and SS1 on PTB5. 1 SPCLK1 on PTE0, MOSI1 on PTE1, MISO1 on PTE2, and SS1 on PTE3.
2 ACIC2	<b>Analog Comparator 2 to Input Capture Enable</b> — This bit connects the output of ACMP2 to TPM2 input channel 0. See Chapter 9, “Analog Comparator 3V (ACMPVLPV1),” and Chapter 16, “Timer/Pulse-Width Modulator (S08TPMV3),” for more details on this feature. 0 ACMP2 output not connected to TPM2 input channel 0. 1 ACMP2 output connected to TPM2 input channel 0.

**Table 5-7. SOPT2 Register Field Descriptions (continued)**

Field	Description
1 IIC1PS	<b>IIC1 Pin Select</b> — This bit selects the location of the SDA1 and SCL1 pins of the IIC1 module. 0 SDA1 on PTA2, SCL1 on PTA3. 1 SDA1 on PTB6, SCL1 on PTB7.
0 ACIC1	<b>Analog Comparator 1 to Input Capture Enable</b> — This bit connects the output of ACMP1 to TPM1 input channel 0. See Chapter 9, “Analog Comparator 3V (ACMPVLPV1),” and Chapter 16, “Timer/Pulse-Width Modulator (S08TPMV3),” for more details on this feature. 0 ACMP output not connected to TPM1 input channel 0. 1 ACMP output connected to TPM1 input channel 0.

### 5.8.6 System Device Identification Register (SDIDH, SDIDL)

These high page read-only registers are included so host development systems can identify the HCS08 derivative. This allows the development software to recognize where specific memory blocks, registers, and control bits are located in a target MCU.


**Figure 5-7. System Device Identification Register — High (SDIDH)**
**Table 5-8. SDIDH Register Field Descriptions**

Field	Description
7:4 Reserved	<b>Bits 7:4 are reserved. Reading these bits will result in an indeterminate value; writes have no effect.</b>
3:0 ID[11:8]	<b>Part Identification Number</b> — Each derivative in the HCS08 Family has a unique identification number. The MC9S08QE128 is hard coded to the value 0x015. See also ID bits in Table 5-9.

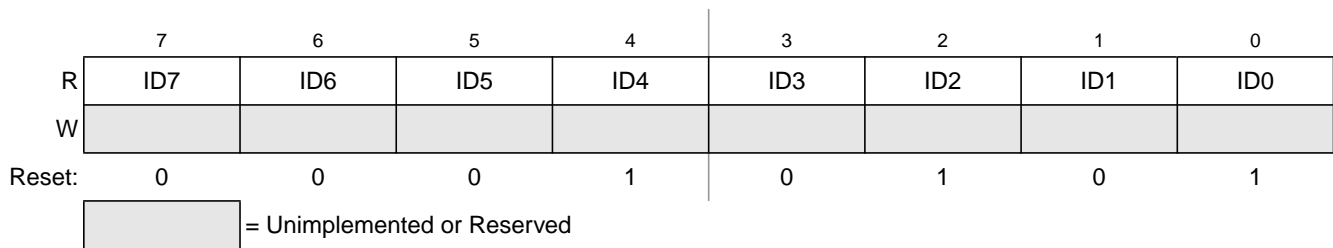

**Figure 5-8. System Device Identification Register — Low (SDIDL)**

Table 5-9. SDIDL Register Field Descriptions

Field	Description
7:0 ID[7:0]	<b>Part Identification Number</b> — Each derivative in the HCS08 Family has a unique identification number. The MC9S08QE128 is hard coded to the value 0x015. See also ID bits in Table 5-8.

## 5.8.7 System Power Management Status and Control 1 Register (SPMSC1)

This high page register contains status and control bits to support the low voltage detect function, and to enable the bandgap voltage reference for use by the ADC module. To configure the low voltage detect trip voltage, see Table 5-12 for the LVDV bit description in SPMSC3.

	7	6	5	4	3	2	1 <sup>1</sup>	0
R	LVDF	0	LVDIE	LVDRE <sup>2</sup>	LVDSE	LVDE <sup>2</sup>	0	BGBE
W		LVDACK						
Reset:	0	0	0	1	1	1	0	0
Stop2 Wakeup:	u	0	u	u	u	u	0	u

= Unimplemented or Reserved
 u = Unaffected by reset

Figure 5-9. System Power Management Status and Control 1 Register (SPMSC1)

<sup>1</sup> Bit 1 is a reserved bit that must always be written to 0.

<sup>2</sup> This bit can be written only one time after reset. Additional writes are ignored.

Table 5-10. SPMSC1 Register Field Descriptions

Field	Description
7 LVDF	<b>Low-Voltage Detect Flag</b> — Provided LVDE = 1, this read-only status bit indicates a low-voltage detect event.
6 LVDACK	<b>Low-Voltage Detect Acknowledge</b> — This write-only bit is used to acknowledge low voltage detection errors (write 1 to clear LVDF). Reads always return 0.
5 LVDIE	<b>Low-Voltage Detect Interrupt Enable</b> — This bit enables hardware interrupt requests for LVDF. 0 Hardware interrupt disabled (use polling). 1 Request a hardware interrupt when LVDF = 1.
4 LVDRE	<b>Low-Voltage Detect Reset Enable</b> — This write-once bit enables LVDF events to generate a hardware reset (provided LVDE = 1). 0 LVDF does not generate hardware resets. 1 Force an MCU reset when LVDF = 1.
3 LVDSE	<b>Low-Voltage Detect Stop Enable</b> — Provided LVDE = 1, this read/write bit determines whether the low-voltage detect function operates when the MCU is in stop mode. 0 Low-voltage detect disabled during stop mode. 1 Low-voltage detect enabled during stop mode.



**Table 5-10. SPMSC1 Register Field Descriptions (continued)**

Field	Description
2 LVDE	<b>Low-Voltage Detect Enable</b> — This write-once bit enables low-voltage detect logic and qualifies the operation of other bits in this register. 0 LVD logic disabled. 1 LVD logic enabled.
0 BGBE	<b>Bandgap Buffer Enable</b> — This bit enables an internal buffer for the bandgap voltage reference for use by the ADC module on one of its internal channels or as a voltage reference for ACMP module. 0 Bandgap buffer disabled. 1 Bandgap buffer enabled.

## 5.8.8 System Power Management Status and Control 2 Register (SPMSC2)

This high page register contains status and control bits to configure the low power run and wait modes as well as configure the stop mode behavior of the MCU. See [Section 3.3.1, “Low Power Run Mode \(LPRun\),”](#) [Section 3.5.1, “Low Power Wait Mode \(LPWait\),”](#) and [Section 3.6, “Stop Modes,”](#) for more information.

	7	6	5	4	3	2	1	0
R	LPR	LPRS	LPWUI	0	PPDF	0	PPDE <sup>1</sup>	PPDC
W						PPDACK		
Reset:	0	0	0	0	0	0	0	0
Stop2 Wakeup:	0	0	u	0	1	0	1	1

= Unimplemented or Reserved
 u = Unaffected by reset

**Figure 5-10. System Power Management Status and Control 2 Register (SPMSC2)**

<sup>1</sup> PPDE is a write-once bit that can be used to disable the PPDC bit until any reset.

**Table 5-11. SPMSC2 Register Field Descriptions**

Field	Description
7 LPR	<b>Low Power Regulator Control</b> — The LPR bit controls entry into the low power run and wait modes in which the voltage regulator is put into standby. This bit cannot be set if PPDC=1. If PPDC and LPR are set in a single write instruction, only PPDC will actually be set. Automatically cleared when LPWUI is set and an interrupt occurs. 0 Low-power run and low-power wait modes are disabled. 1 Low-power run and low-power wait modes are enabled.
6 LPRS	<b>Low Power Regulator Status</b> — This read-only status bit indicates that the voltage regulator has entered into standby for the low power run or wait mode. 0 The voltage regulator is not currently in standby. 1 The voltage regulator is currently in standby.
5 LPWUI	<b>Low Power Wake Up on Interrupt</b> — This bit controls whether or not the voltage regulator exits standby when any active MCU interrupt occurs. 0 The voltage regulator will remain in standby on an interrupt. 1 The voltage regulator will exit standby on an interrupt.

**Table 5-11. SPMSC2 Register Field Descriptions (continued)**

Field	Description
3 PPDF	<b>Partial Power Down Flag</b> — This read-only status bit indicates that the MCU has recovered from stop2 mode. 0 MCU has not recovered from stop2 mode. 1 MCU recovered from stop2 mode.
2 PPDACK	<b>Partial Power Down Acknowledge</b> — Writing a 1 to PPDACK clears the PPDF bit.
1 PPDE	<b>Partial Power-Down Enable</b> — The write-once PPDE bit can be used to disable the partial power-down feature. 0 Partial power-down is disabled 1 Partial power-down is enabled and controlled by the PPDC bit.
0 PPDC	<b>Partial Power Down Control</b> — The PPDC bit controls which power down mode is selected. This bit cannot be set if LPR = 1. If PPDC and LPR are set in a single write instruction, only PPDC will actually be set. PPDE must be set in order for PPDC to be set. There are restrictions on LVDE and LVDSE. See Table 3-1 for details. 0 Stop3 low power mode enabled. 1 Stop2 partial power down mode enabled.

### 5.8.9 System Power Management Status and Control 3 Register (SPMSC3)

This high page register is used to report the status of the low voltage warning function and to select the low voltage detect trip voltage.

	7	6	5	4	3	2	1	0
R	LVWF	0	LVDV	LVWV	LVWIE	0	0	0
W		LVWACK						
POR:	0 <sup>1</sup>	0	0	0	0	0	0	0
Stop2 Wakeup	u	0	u	u	u	0	0	0
LVR:	0 <sup>1</sup>	0	u	u	0	0	0	0
Any other reset:	0 <sup>1</sup>	0	u	u	0	0	0	0

= Unimplemented or Reserved
 u = Unaffected by reset

**Figure 5-11. System Power Management Status and Control 3 Register (SPMSC3)**

<sup>1</sup> LVWF will be set in the case when  $V_{Supply}$  transitions below the trip point or after reset and  $V_{Supply}$  is already below  $V_{LVW}$ .

**Table 5-12. SPMSC3 Register Field Descriptions**

Field	Description
7 LVWF	<b>Low-Voltage Warning Flag</b> — The LVWF bit indicates the low voltage warning status. 0 Low voltage warning <b>not</b> present. 1 Low voltage warning is present or was present.
6 LVWACK	<b>Low-Voltage Warning Acknowledge</b> — The LVWF bit indicates the low voltage warning status. Writing a 1 to LVWACK clears LVWF to a 0 if a low voltage warning is not present.

**Table 5-12. SPMSC3 Register Field Descriptions (continued)**

Field	Description
5 LVDV	<b>Low-Voltage Detect Voltage Select</b> — The LVDV bit selects the LVD trip point voltage ( $V_{LVD}$ ). 0 Low trip point selected ( $V_{LVD} = V_{LVDL}$ ). 1 High trip point selected ( $V_{LVD} = V_{LVDH}$ ).
4 LVVW	<b>Low-Voltage Warning Voltage Select</b> — The LVVW bit selects the LVW trip point voltage ( $V_{LVW}$ ). 0 Low trip point selected ( $V_{LVW} = V_{LVWL}$ ). 1 High trip point selected ( $V_{LVW} = V_{LVWH}$ ).
3 LVWIE	<b>Low-Voltage Warning Interrupt Enable</b> — This bit enables hardware interrupt requests for LVWF. 0 Hardware interrupt disabled (use polling). 1 Request a hardware interrupt when LVWF = 1.

**Table 5-13. LVD and LVW Trip Point Typical Values<sup>1</sup>**

LVDV:LVVW	LVW Trip Point	LVD Trip Point
0:0	$V_{LVWL} = 2.15 \text{ V}$	$V_{LVDL} = 1.84 \text{ V}$
0:1	$V_{LVWH} = 2.48 \text{ V}$	
1:0 <sup>2</sup>	$V_{LVWL} = 2.15 \text{ V}$	$V_{LVDH} = 2.15 \text{ V}$
1:1	$V_{LVWH} = 2.48 \text{ V}$	

<sup>1</sup> See the data sheet for minimum and maximum values.

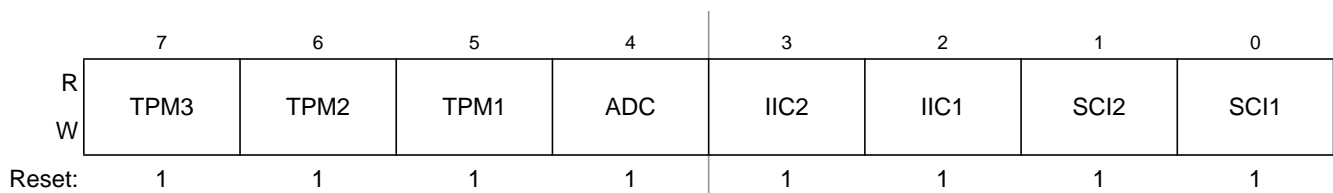
<sup>2</sup> This setting is not recommended

### 5.8.10 System Clock Gating Control 1 Register (SCGC1)

This high page register contains control bits to enable or disable the bus clock to the TPMx, ADC, IICx, and SCIx modules. Gating off the clocks to unused peripherals is used to reduce the MCU's run and wait currents. See [Section 5.7, "Peripheral Clock Gating,"](#) for more information.

#### NOTE

User software should disable the peripheral before disabling the clocks to the peripheral. When clocks are re-enabled to a peripheral, the peripheral registers need to be re-initialized by user software.


**Figure 5-12. System Clock Gating Control 1 Register (SCGC1)**

**Table 5-14. SCGC1 Register Field Descriptions**

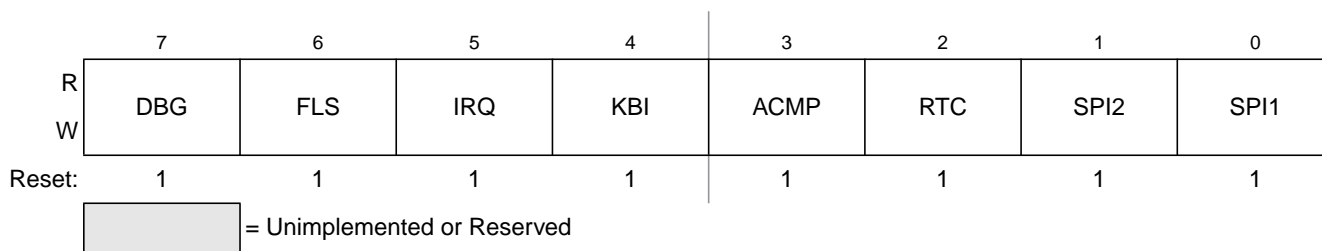
Field	Description
7 TPM3	<b>TPM3 Clock Gate Control</b> — This bit controls the clock gate to the TPM3 module. 0 Bus clock to the TPM3 module is disabled. 1 Bus clock to the TPM3 module is enabled.
6 TPM2	<b>TPM2 Clock Gate Control</b> — This bit controls the clock gate to the TPM2 module. 0 Bus clock to the TPM2 module is disabled. 1 Bus clock to the TPM2 module is enabled.
5 TPM1	<b>TPM1 Clock Gate Control</b> — This bit controls the clock gate to the TPM1 module. 0 Bus clock to the TPM1 module is disabled. 1 Bus clock to the TPM1 module is enabled.
4 ADC	<b>ADC Clock Gate Control</b> — This bit controls the clock gate to the ADC module. 0 Bus clock to the ADC module is disabled. 1 Bus clock to the ADC module is enabled.
3 IIC2	<b>IIC2 Clock Gate Control</b> — This bit controls the clock gate to the IIC2 module. 0 Bus clock to the IIC2 module is disabled. 1 Bus clock to the IIC2 module is enabled.
2 IIC1	<b>IIC1 Clock Gate Control</b> — This bit controls the clock gate to the IIC1 module. 0 Bus clock to the IIC1 module is disabled. 1 Bus clock to the IIC1 module is enabled.
1 SCI2	<b>SCI2 Clock Gate Control</b> — This bit controls the clock gate to the SCI2 module. 0 Bus clock to the SCI2 module is disabled. 1 Bus clock to the SCI2 module is enabled.
0 SCI1	<b>SCI1 Clock Gate Control</b> — This bit controls the clock gate to the SCI1 module. 0 Bus clock to the SCI1 module is disabled. 1 Bus clock to the SCI1 module is enabled.

### 5.8.11 System Clock Gating Control 2 Register (SCGC2)

This high page register contains control bits to enable or disable the bus clock to the RTC and SPIx modules. Gating off the clocks to unused peripherals is used to reduce the MCU’s run and wait currents. See Section 5.7, “Peripheral Clock Gating,” for more information.

**NOTE**

User software should disable the peripheral before disabling the clocks to the peripheral. When clocks are re-enabled to a peripheral, the peripheral registers need to be re-initialized by user software.



**Figure 5-13. System Clock Gating Control 2 Register (SCGC2)**

**Table 5-15. SCGC2 Register Field Descriptions**

Field	Description
7 DBG	<b>DBG Clock Gate Control</b> — This bit controls the bus clock gate to the DBG module. 0 Bus clock to the DBG module is disabled. 1 Bus clock to the DBG module is enabled.
6 FLS	<b>Flash Register Clock Gate Control</b> — This bit controls the bus clock gate to the flash registers. This bit does not affect normal program execution from with the flash array. Only the clock to the flash control registers is affected. 0 Bus clock to the flash registers is disabled. 1 Bus clock to the flash registers is enabled.
5 IRQ	<b>IRQ Clock Gate Control</b> — This bit controls the bus clock gate to the IRQ module. 0 Bus clock to the IRQ module is disabled. 1 Bus clock to the IRQ module is enabled.
4 KBI	<b>KBI Clock Gate Control</b> — This bit controls the clock gate to both of the KBI modules. 0 Bus clock to the KBI modules is disabled. 1 Bus clock to the KBI modules is enabled.
3 ACMP	<b>ACMP Clock Gate Control</b> — This bit controls the clock gate to both of the ACMP modules. 0 Bus clock to the ACMP modules is disabled. 1 Bus clock to the ACMP modules is enabled.
2 RTC	<b>RTC Clock Gate Control</b> — This bit controls the bus clock gate to the RTC module. Only ICSIRCLK is gated, OSCOUT and LPOCLK are still available to the RTC. 0 ICSIRCLK to the RTC module is disabled. 1 ICSIRCLK to the RTC module is enabled.
1 SPI2	<b>SPI2 Clock Gate Control</b> — This bit controls the clock gate to the SPI2 module. 0 Bus clock to the SPI2 module is disabled. 1 Bus clock to the SPI2 module is enabled.
0 SPI1	<b>SPI1 Clock Gate Control</b> — This bit controls the clock gate to the SPI1 module. 0 Bus clock to the SPI1 module is disabled. 1 Bus clock to the SPI1 module is enabled.



## Chapter 6

# Parallel Input/Output Control

This section explains software controls related to parallel input/output (I/O) and pin control. The MC9S08QE128 has nine parallel I/O ports which include a total of 70 I/O pins and one output-only pin. See [Chapter 2, “Pins and Connections,”](#) for more information about pin assignments and external hardware considerations of these pins.

Many of these pins are shared with on-chip peripherals such as timer systems, communication systems, or keyboard interrupts as shown in [Table 2-1](#). The peripheral modules have priority over the general-purpose I/O functions so that when a peripheral is enabled, the I/O functions associated with the shared pins may be disabled.

After reset, the shared peripheral functions are disabled and the pins are configured as inputs ( $PTxDDn = 0$ ). The pin control functions for each pin are configured as follows: slew rate control disabled ( $PTxSEn = 0$ ), low drive strength selected ( $PTxDSn = 0$ ), and internal pull-ups disabled ( $PTxPEn = 0$ ).

### NOTE

Not all general-purpose I/O pins are available on all packages. To avoid extra current drain from floating input pins, the user’s reset initialization routine in the application program must either enable on-chip pull-up devices or change the direction of unconnected pins to outputs so the pins do not float.

## 6.1 Port Data and Data Direction

Reading and writing of parallel I/Os are performed through the port data registers. The direction, either input or output, is controlled through the port data direction registers. The parallel I/O port function for an individual pin is illustrated in the block diagram shown in [Figure 6-1](#).

The data direction control bit ( $PTxDDn$ ) determines whether the output buffer for the associated pin is enabled, and also controls the source for port data register reads. The input buffer for the associated pin is always enabled unless the pin is enabled as an analog function or is an output-only pin.

When a shared digital function is enabled for a pin, the output buffer is controlled by the shared function. However, the data direction register bit will continue to control the source for reads of the port data register.

When a shared analog function is enabled for a pin, both the input and output buffers are disabled. A value of 0 is read for any port data bit where the bit is an input ( $PTxDDn = 0$ ) and the input buffer is disabled. In general, whenever a pin is shared with both an alternate digital function and an analog function, the analog function has priority such that if both the digital and analog functions are enabled, the analog function controls the pin.

It is a good programming practice to write to the port data register before changing the direction of a port pin to become an output. This ensures that the pin will not be driven momentarily with an old data value that happened to be in the port data register.

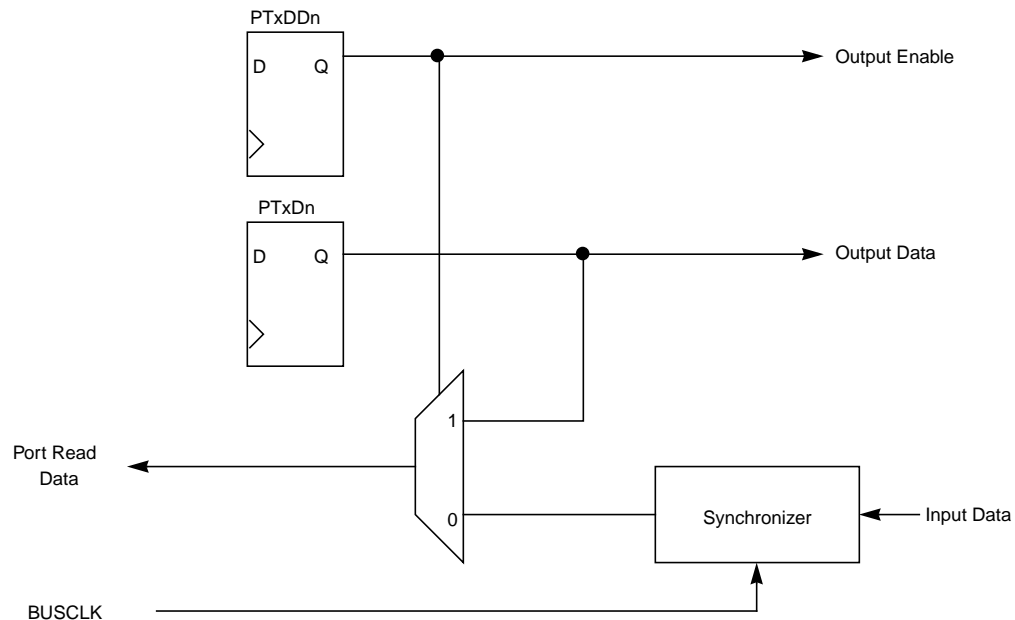


Figure 6-1. Parallel I/O Block Diagram

## 6.2 Pull-up, Slew Rate, and Drive Strength

Associated with the parallel I/O ports is a set of registers located in the high page register space that operate independently of the parallel I/O registers. These registers are used to control pull-ups, slew rate, and drive strength for the pins and may be used in conjunction with the peripheral functions on these pins.

### 6.2.1 Port Internal Pull-Up Enable

An internal pull-up device can be enabled for each port pin by setting the corresponding bit in the pull-up enable register (PTxPEn). The pull-up device is disabled if the pin is configured as an output by the parallel I/O control logic or any shared peripheral function regardless of the state of the corresponding pull-up enable register bit. The pull-up device is also disabled if the pin is controlled by an analog function.

### 6.2.2 Port Slew Rate Enable

Slew rate control can be enabled for each port pin by setting the corresponding bit in the slew rate control register (PTxSEn). When enabled, slew control limits the rate at which an output can transition in order to reduce EMC emissions. Slew rate control has no effect on pins that are configured as inputs.

### 6.2.3 Port Drive Strength Select

An output pin can be selected to have high output drive strength by setting the corresponding bit in the drive strength select register (PTxDSn). When high drive is selected, a pin is capable of sourcing and



sinking greater current. Even though every I/O pin can be selected as high drive, the user must ensure that the total current source and sink limits for the MCU are not exceeded. Drive strength selection is intended to affect the DC behavior of I/O pins. However, the AC behavior is also affected. High drive allows a pin to drive a greater load with the same switching speed as a low drive enabled pin into a smaller load. Because of this, the EMC emissions may be affected by enabling pins as high drive.

### 6.3 Port Data Set, Clear and Toggle Data Registers

The Port Data Set, Clear and Toggle registers provide an alternate method for setting and clearing individual port I/O pins within a single port. Only port C and port E have data set, clear and toggle registers. Figure 6-2 should be contrasted with Figure 6-1 to see the effects of adding Set/Clear/Toggle functionality to the port cell. SET\_Enable, CLR\_Enable, and Toggle\_Enable will be set to 1 when the user writes to the Data Set, Clear or Toggle register, respectively. The bit pattern on the peripheral bus port is then used to perform the requested function on the port data register.

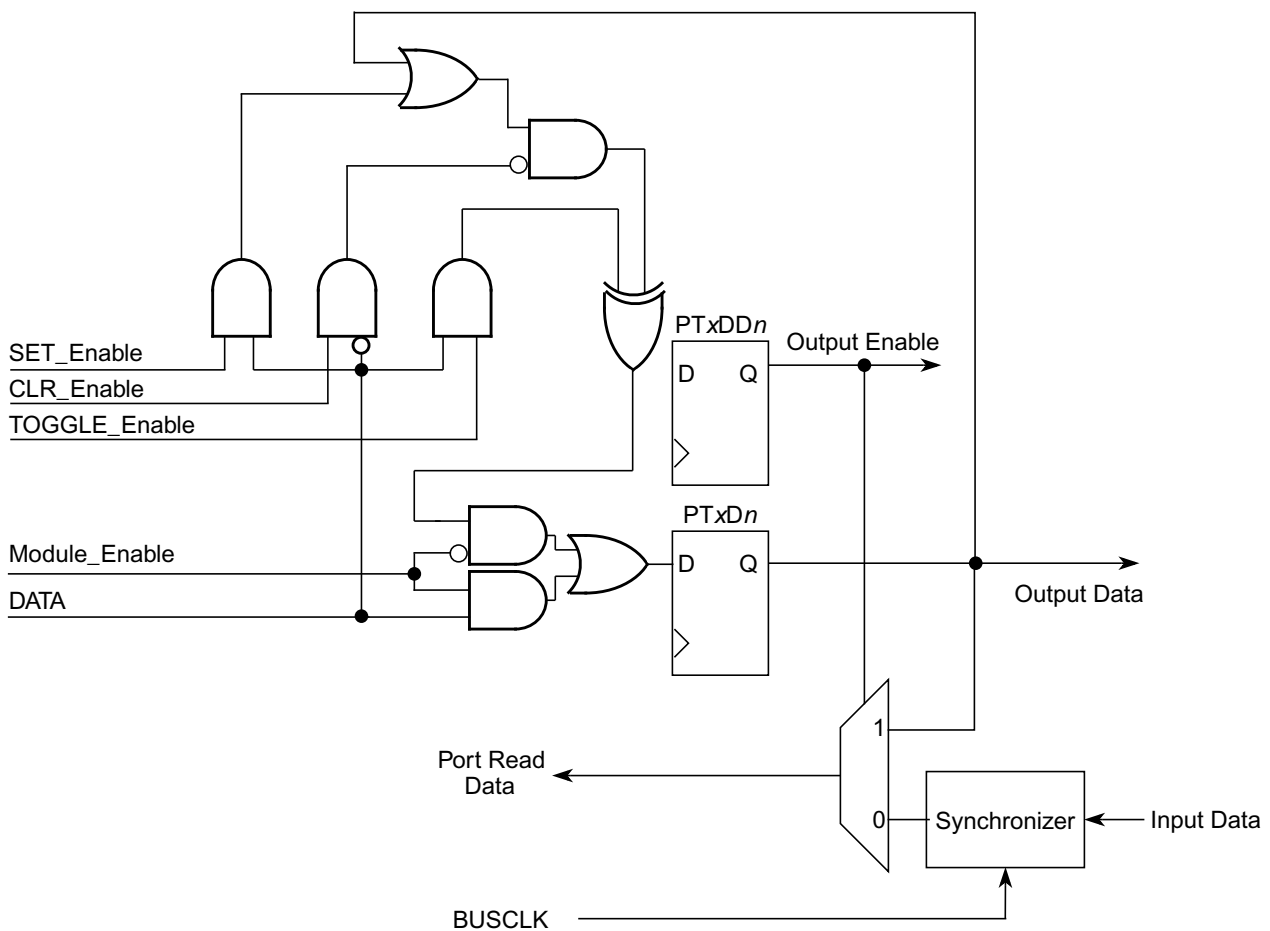


Figure 6-2. Parallel I/O Block Diagram Equipped with SET/CLR Functionality: Ports C & E

### 6.3.1 Port Data Set Registers

The Port Data Set registers (PTxSET) are write only registers associated with ports C & E. Writing to these registers has the result:  $\text{PortData} = \text{PortData} \mid \text{SetPattern}$ . A subsequent read of the corresponding port data register will reflect the changed result (a one clock cycle delay is required to see the proper value).

### 6.3.2 Port Data Clear Registers

The Port Data Clear registers (PTxCLR) are write only registers associated with ports C & E. Writing to these registers has the result:  $\text{PortData} = \text{PortData} \& \text{NOT ClrPattern}$ . A subsequent read of the corresponding port data register will reflect the changed result (a one clock cycle delay is required to see the proper value).

### 6.3.3 Port Data Toggle Register

The Port Data Toggle registers (PTxTOG) are write only registers associated with ports C & E. Writing to these registers has the result:  $\text{PortData}[i] = \text{NOT PortData}[i]$  for any bit written as a one to PTxTOG. A subsequent read of the corresponding port data register will reflect the changed result (a one clock cycle delay is required to see the proper value).

## 6.4 Pin Behavior in Stop Modes

Pin behavior following execution of a STOP instruction depends on the stop mode that is entered. An explanation of pin behavior for the various stop modes follows:

- Stop2 mode is a partial power-down mode, whereby I/O latches are maintained in their state as before the STOP instruction was executed. CPU register status and the state of I/O registers should be saved in RAM before the STOP instruction is executed to place the MCU in stop2 mode. Upon recovery from stop2 mode, before accessing any I/O, the user should examine the state of the PPDF bit in the SPMSC2 register. If the PPDF bit is 0, I/O must be initialized as if a power on reset had occurred. If the PPDF bit is 1, I/O register states should be restored from the values saved in RAM before the STOP instruction was executed and peripherals may require initialization or restoration to their pre-stop condition. The user must then write a 1 to the PPDACK bit in the SPMSC2 register. Access to I/O is now permitted again in the user application program.
- In stop3 mode, all I/O is maintained because internal logic circuitry stays powered up. Upon recovery, normal I/O function is available to the user.

## 6.5 Parallel I/O and Pin Control Registers

This section provides information about the registers associated with the parallel I/O ports. The data and data direction registers are located in page zero of the memory map. The pull up, slew rate, drive strength, and interrupt control registers are located in the high page section of the memory map.

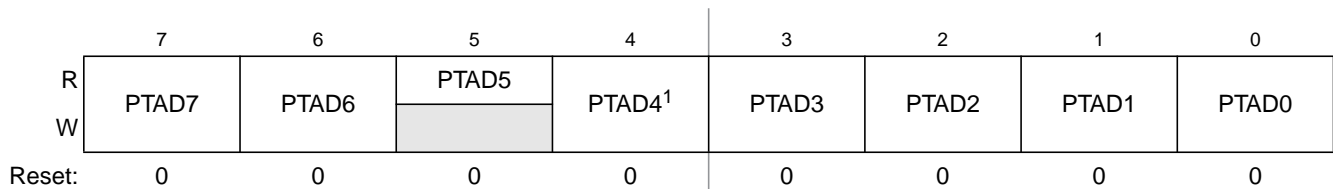
Refer to tables in Chapter 4, “Memory,” for the absolute address assignments for all parallel I/O and their pin control registers. This section refers to registers and control bits only by their names. A Freescale Semiconductor-provided equate or header file normally is used to translate these names into the appropriate absolute addresses.

## 6.5.1 Port A Registers

Port A is controlled by the registers listed below.

The pins PTA4 and PTA5 are unique. PTA4 is an output only, so the control bits for the input functions will not have any effect on this pin. PTA5 is an input only, so the control bits for the output functions will not have any effect on this pin.

### 6.5.1.1 Port A Data Register (PTAD)



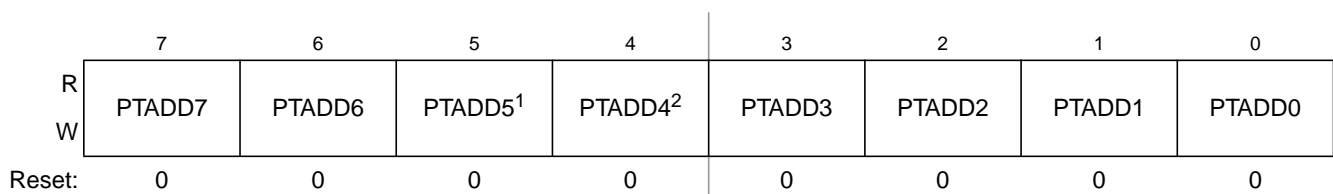
**Figure 6-3. Port A Data Register (PTAD)**

<sup>1</sup> Reads of bit PTAD4 always return the contents of PTAD4, regardless of the value stored in bit PTADD4.

**Table 6-1. PTAD Register Field Descriptions**

Field	Description
7:0 PTAD[7:0]	<b>Port A Data Register Bits</b> — For port A pins that are inputs, reads return the logic level on the pin. For port A pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port A pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTAD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pull-ups/pull-downs disabled.

### 6.5.1.2 Port A Data Direction Register (PTADD)



**Figure 6-4. Port A Data Direction Register (PTADD)**

<sup>1</sup> PTADD5 has no effect on the input-only PTA5 pin.

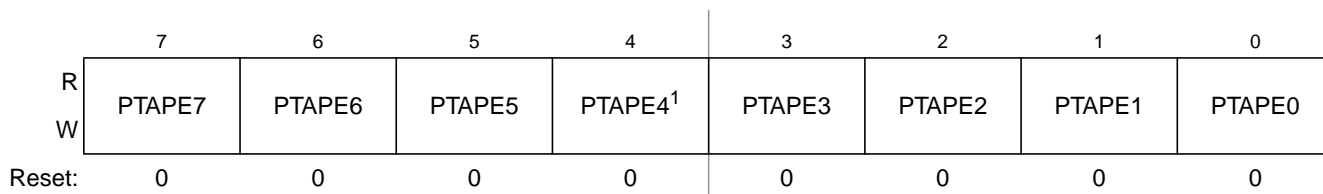
<sup>2</sup> PTADD4 has no effect on the output-only PTA4 pin.

**Table 6-2. PTADD Register Field Descriptions**

Field	Description
7:0 PTADD[7:0]	<b>Data Direction for Port A Bits</b> — These read/write bits control the direction of port A pins and what is read for PTAD reads. 0 Input (output driver disabled) and reads return the pin value. 1 Output driver enabled for port A bit n and PTAD reads return the contents of PTADn.

### 6.5.1.3 Port A Pull Enable Register (PTAPE)

The port A enable register (PTAPE) enables pull-ups on the corresponding PTA pin. In some cases, a pull-down device will be enabled if pull-downs are supported by an alternative pin function, such as KBI.



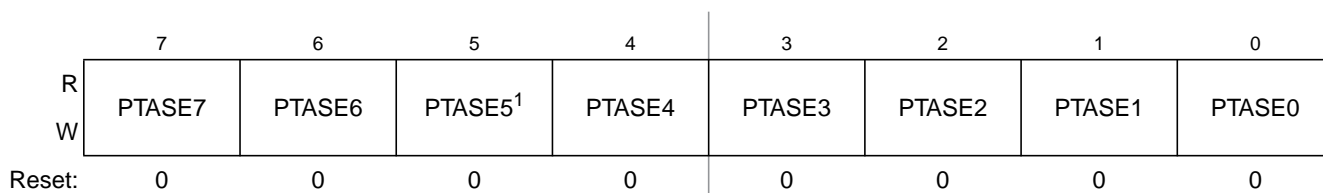
**Figure 6-5. Internal Pull Enable for Port A Register (PTAPE)**

<sup>1</sup> PTAPE4 has no effect on the output-only PTA4 pin.

**Table 6-3. PTAPE Register Field Descriptions**

Field	Description
7:0 PTAPE[7:0]	<p><b>Internal Pull Enable for Port A Bits</b> — Each of these control bits determines if the internal pull-up or pull-down device is enabled for the associated PTA pin. For port A pins that are configured as outputs, these bits have no effect and the internal pull devices are disabled.</p> <p>0 Internal pull-up/pull-down device disabled for port A bit n. 1 Internal pull-up/pull-down device enabled for port A bit n.</p>

### 6.5.1.4 Port A Slew Rate Enable Register (PTASE)



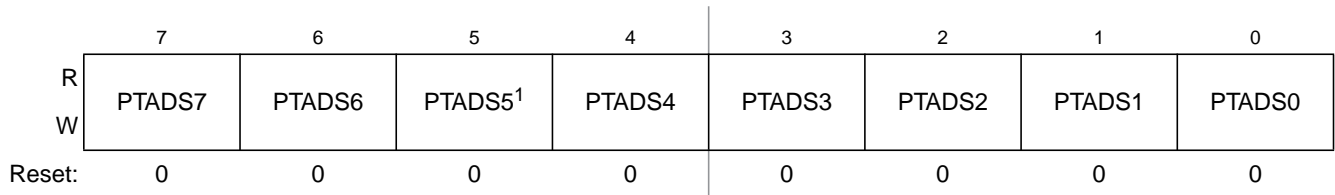
**Figure 6-6. Slew Rate Enable for Port A Register (PTASE)**

<sup>1</sup> PTASE5 will have no effect on the input-only PTA5 pin.

**Table 6-4. PTASE Register Field Descriptions**

Field	Description
7:0 PTASE[7:0]	<p><b>Output Slew Rate Enable for Port A Bits</b> — Each of these control bits determines if the output slew rate control is enabled for the associated PTA pin. For port A pins that are configured as inputs, these bits have no effect.</p> <p>0 Output slew rate control disabled for port A bit n. 1 Output slew rate control enabled for port A bit n.</p>

### 6.5.1.5 Port A Drive Strength Selection Register (PTADS)



**Figure 6-7. Drive Strength Selection for Port A Register (PTADS)**

<sup>1</sup> PTADS5 will have no effect on the input-only PTA5 pin

**Table 6-5. PTADS Register Field Descriptions**

Field	Description
7:0 PTADS[7:0]	<p><b>Output Drive Strength Selection for Port A Bits</b> — Each of these control bits selects between low and high output drive for the associated PTA pin. For port A pins that are configured as inputs, these bits have no effect.</p> <p>0 Low output drive strength selected for port A bit n.                      1 High output drive strength selected for port A bit n.</p>

### 6.5.2 Port B Registers

Port B is controlled by the registers listed below.

### 6.5.2.1 Port B Data Register (PTBD)

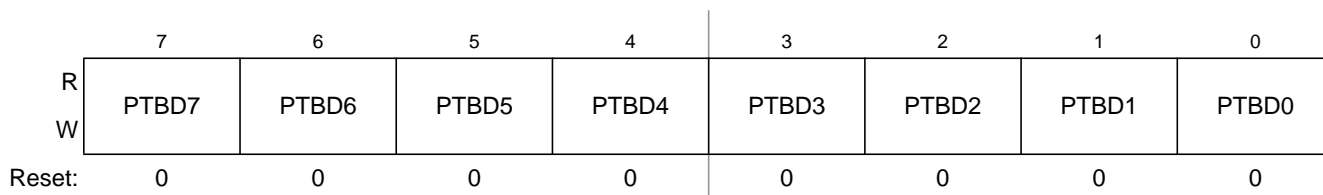


Figure 6-8. Port B Data Register (PTBD)

Table 6-6. PTBD Register Field Descriptions

Field	Description
7:0 PTBD[7:0]	<p><b>Port B Data Register Bits</b> — For port B pins that are inputs, reads return the logic level on the pin. For port B pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port B pins that are configured as outputs, the logic level is driven out the corresponding MCU pin.</p> <p>Reset forces PTBD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pull-ups/pull-downs disabled.</p>

### 6.5.2.2 Port B Data Direction Register (PTBDD)

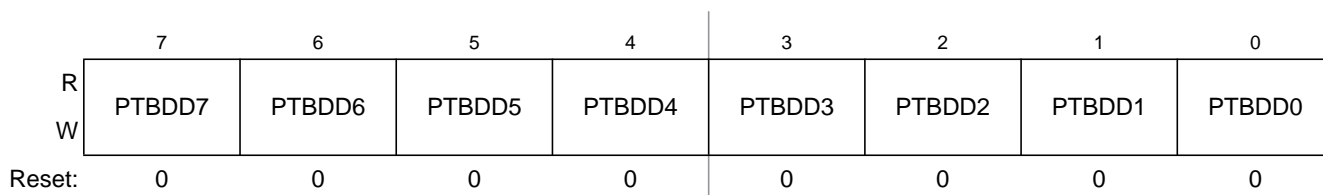


Figure 6-9. Port B Data Direction Register (PTBDD)

Table 6-7. PTBDD Register Field Descriptions

Field	Description
7:0 PTBDD[7:0]	<p><b>Data Direction for Port B Bits</b> — These read/write bits control the direction of port B pins and what is read for PTBD reads.</p> <p>0 Input (output driver disabled) and reads return the pin value.</p> <p>1 Output driver enabled for port B bit n and PTBD reads return the contents of PTBDn.</p>

### 6.5.2.3 Port B Pull Enable Register (PTBPE)

The port B enable register (PTBPE) enables pull-ups on the corresponding PTB pin. In some cases, a pull-down device will be enabled if pull-downs are supported by an alternative pin function, such as KBI.

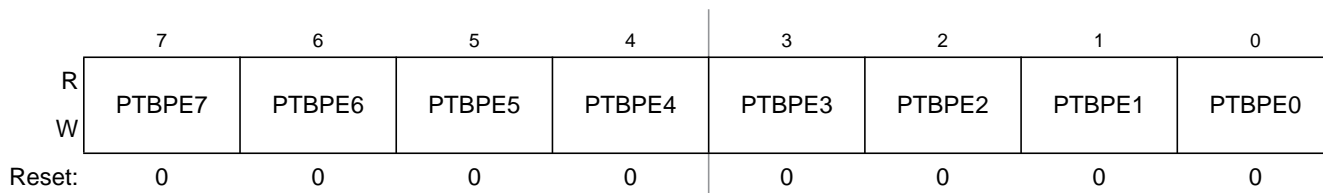
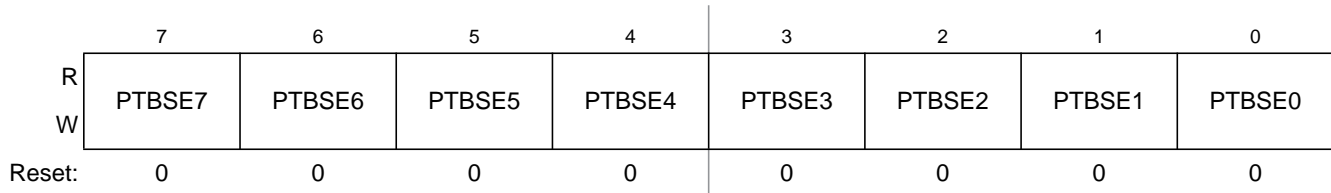


Figure 6-10. Internal Pull Enable for Port B Register (PTBPE)

**Table 6-8. PTBPE Register Field Descriptions**

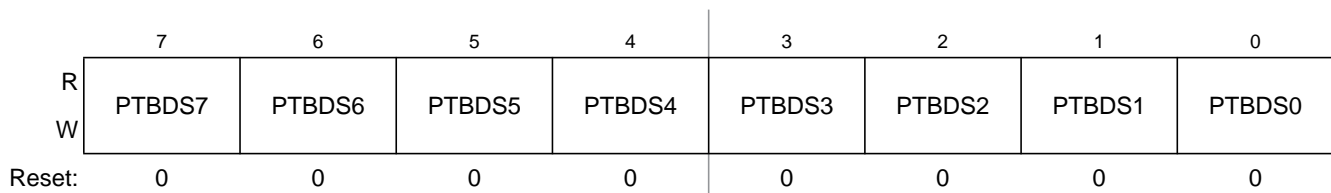
Field	Description
7:0 PTBPE[7:0]	<b>Internal Pull Enable for Port B Bits</b> — Each of these control bits determines if the internal pull-up or pull-down device is enabled for the associated PTB pin. For port B pins that are configured as outputs, these bits have no effect and the internal pull devices are disabled. 0 Internal pull-up/pull-down device disabled for port B bit n. 1 Internal pull-up/pull-down device enabled for port B bit n.

### 6.5.2.4 Port B Slew Rate Enable Register (PTBSE)


**Figure 6-11. Slew Rate Enable for Port B Register (PTBSE)**
**Table 6-9. PTBSE Register Field Descriptions**

Field	Description
7:0 PTBSE[7:0]	<b>Output Slew Rate Enable for Port B Bits</b> — Each of these control bits determines if the output slew rate control is enabled for the associated PTB pin. For port B pins that are configured as inputs, these bits have no effect. 0 Output slew rate control disabled for port B bit n. 1 Output slew rate control enabled for port B bit n.

### 6.5.2.5 Port B Drive Strength Selection Register (PTBDS)


**Figure 6-12. Drive Strength Selection for Port B Register (PTBDS)**
**Table 6-10. PTBDS Register Field Descriptions**

Field	Description
7:0 PTBDS[7:0]	<b>Output Drive Strength Selection for Port B Bits</b> — Each of these control bits selects between low and high output drive for the associated PTB pin. For port B pins that are configured as inputs, these bits have no effect. 0 Low output drive strength selected for port B bit n. 1 High output drive strength selected for port B bit n.

## 6.5.3 Port C Registers

Port C is controlled by the registers listed below.

### 6.5.3.1 Port C Data Register (PTCD)

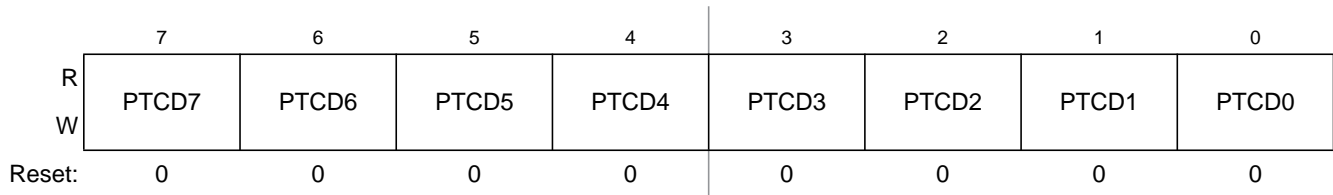


Figure 6-13. Port C Data Register (PTCD)

Table 6-11. PTCD Register Field Descriptions

Field	Description
7:0 PTCD[7:0]	<b>Port C Data Register Bits</b> — For port C pins that are inputs, reads return the logic level on the pin. For port C pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port C pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTCD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pull-ups disabled.

### 6.5.3.2 Port C Data Direction Register (PTCDD)

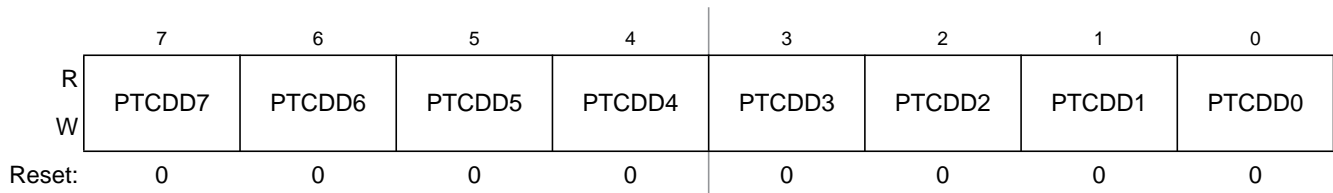


Figure 6-14. Port C Data Direction Register (PTCDD)

Table 6-12. PTCDD Register Field Descriptions

Field	Description
7:0 PTCDD[7:0]	<b>Data Direction for Port C Bits</b> — These read/write bits control the direction of port C pins and what is read for PTCD reads. 0 Input (output driver disabled) and reads return the pin value. 1 Output driver enabled for port C bit n and PTCD reads return the contents of PTCDDn.

### 6.5.3.3 Port C Data Set Register (PTCSET)

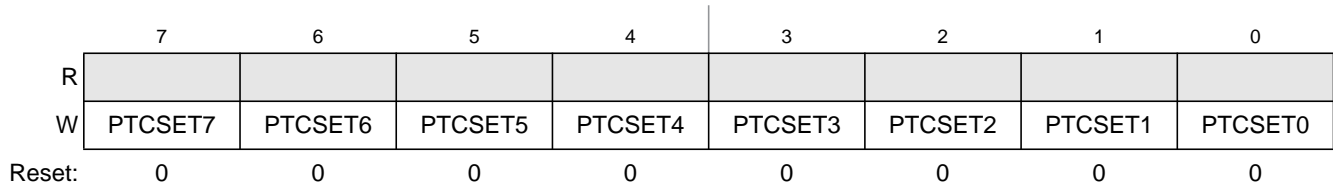


Figure 6-15. Port C Data Set Register (PTCSET)



**Table 6-13. PTCSET Register Field Descriptions**

Field	Description
7:0 PTCSET $n$	<b>Data Set for Port C Bits</b> — Writing any bit to one in this location will set the corresponding bit in the data register to one. Writing a zero to any bit in this register has no effect. 0 Corresponding PTCD $n$ maintains current value. 1 Corresponding PTCD $n$ is set.

### 6.5.3.4 Port C Data Clear Register (PTCCLR)

	7	6	5	4	3	2	1	0
R								
W	PTCCLR7	PTCCLR6	PTCCLR5	PTCCLR4	PTCCLR3	PTCCLR2	PTCCLR1	PTCCLR0
Reset:	0	0	0	0	0	0	0	0

**Figure 6-16. Port C Data Clear Register (PTCCLR)**
**Table 6-14. PTCCLR Register Field Descriptions**

Field	Description
7:0 PTCCLR $n$	<b>Data Clear for Port C Bits</b> — Writing any bit to zero in this location will clear the corresponding bit in the data register to zero. Writing a one to any bit in this register has no effect. 0 Corresponding PTCD $n$ maintains current value. 1 Corresponding PTCD $n$ is cleared.

### 6.5.3.5 Port C Toggle Register (PTCTOG)

	7	6	5	4	3	2	1	0
R								
W	PTCTOG7	PTCTOG6	PTCTOG5	PTCTOG4	PTCTOG3	PTCTOG2	PTCTOG1	PTCTOG0
Reset:	0	0	0	0	0	0	0	0

**Figure 6-17. Port C Toggle Register (PTCTOG)**
**Table 6-15. PTCTOG Register Field Descriptions**

Field	Description
7:0 PTCTOG $n$	<b>Toggle for Port C Bits</b> — Writing any bit to one in this location will toggle the corresponding bit in the data register. Writing a zero to any bit in this register has no effect. 0 Corresponding PTCD $n$ maintains current value. 1 Corresponding PTCD $n$ is inverted.

### 6.5.3.6 Port C Pull Enable Register (PTCPE)

The port C enable register (PTCPE) enables pull-ups on the corresponding PTC pin. In some cases, a pull-down device will be enabled if pull-downs are supported by an alternative pin function, such as KBI.

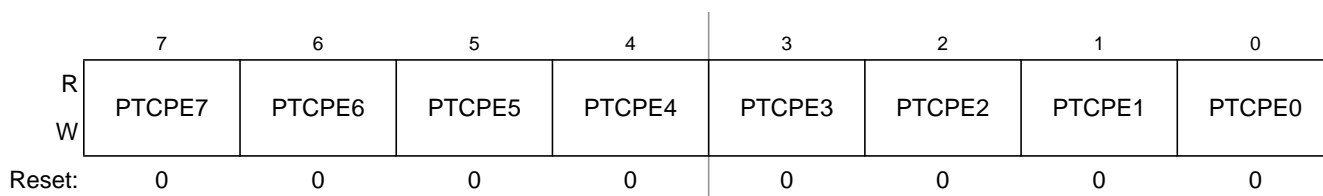


Figure 6-18. Internal Pull Enable for Port C Register (PTCPE)

Table 6-16. PTCPE Register Field Descriptions

Field	Description
7:0 PTCPE[7:0]	<b>Internal Pull Enable for Port C Bits</b> — Each of these control bits determines if the internal pull-up device is enabled for the associated PTC pin. For port C pins that are configured as outputs, these bits have no effect and the internal pull devices are disabled. 0 Internal pull-up device disabled for port C bit n. 1 Internal pull-up device enabled for port C bit n.

### 6.5.3.7 Port C Slew Rate Enable Register (PTCSE)

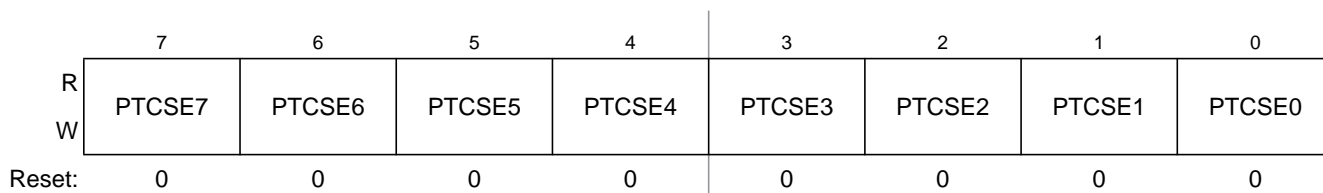


Figure 6-19. Slew Rate Enable for Port C Register (PTCSE)

Table 6-17. PTCSE Register Field Descriptions

Field	Description
7:0 PTCSE[7:0]	<b>Output Slew Rate Enable for Port C Bits</b> — Each of these control bits determines if the output slew rate control is enabled for the associated PTC pin. For port C pins that are configured as inputs, these bits have no effect. 0 Output slew rate control disabled for port C bit n. 1 Output slew rate control enabled for port C bit n.

### 6.5.3.8 Port C Drive Strength Selection Register (PTCDS)

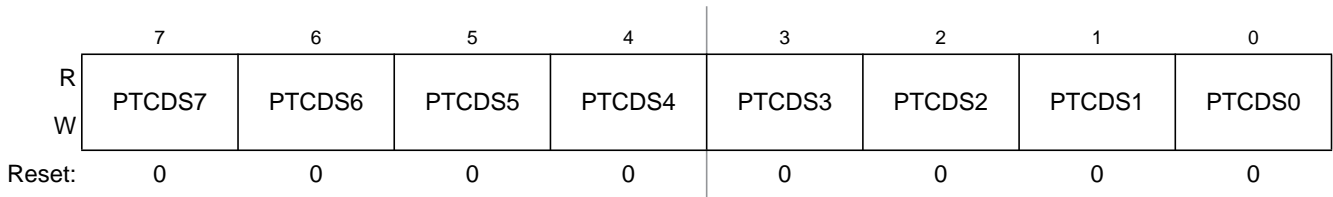


Figure 6-20. Drive Strength Selection for Port C Register (PTCDS)

Table 6-18. PTCDS Register Field Descriptions

Field	Description
7:0 PTCDS[7:0]	<p><b>Output Drive Strength Selection for Port C Bits</b> — Each of these control bits selects between low and high output drive for the associated PTC pin. For port C pins that are configured as inputs, these bits have no effect.</p> <p>0 Low output drive strength selected for port C bit n.</p> <p>1 High output drive strength selected for port C bit n.</p>

### 6.5.4 Port D Registers

Port D is controlled by the registers listed below.

### 6.5.4.1 Port D Data Register (PTDD)

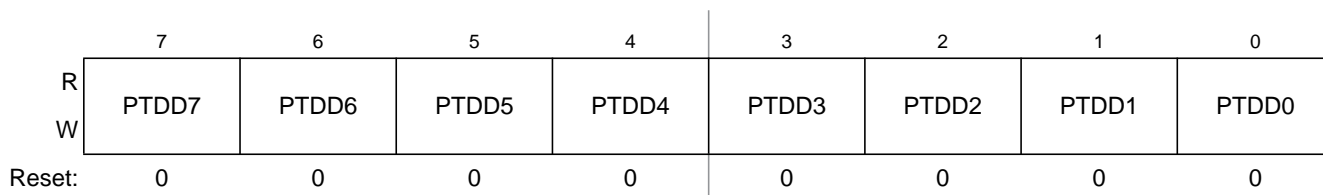


Figure 6-21. Port D Data Register (PTDD)

Table 6-19. PTDD Register Field Descriptions

Field	Description
7:0 PTDD[7:0]	<p><b>Port D Data Register Bits</b> — For port D pins that are inputs, reads return the logic level on the pin. For port D pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port D pins that are configured as outputs, the logic level is driven out the corresponding MCU pin.</p> <p>Reset forces PTDD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pull-ups/pull-downs disabled.</p>

### 6.5.4.2 Port D Data Direction Register (PTDDD)

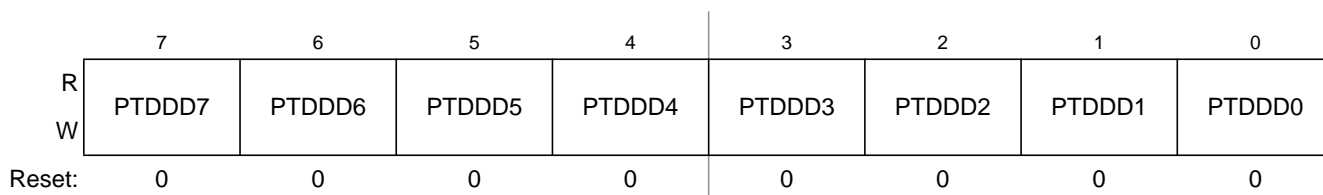


Figure 6-22. Port D Data Direction Register (PTDDD)

Table 6-20. PTDDD Register Field Descriptions

Field	Description
7:0 PTDDD[7:0]	<p><b>Data Direction for Port D Bits</b> — These read/write bits control the direction of port D pins and what is read for PTDD reads.</p> <p>0 Input (output driver disabled) and reads return the pin value.</p> <p>1 Output driver enabled for port D bit n and PTDD reads return the contents of PTDDn.</p>

### 6.5.4.3 Port D Pull Enable Register (PTDPE)

The port D enable register (PTDPE) enables pull-ups on the corresponding PTD pin. In some cases, a pull-down device will be enabled if pull-downs are supported by an alternative pin function, such as KBI.

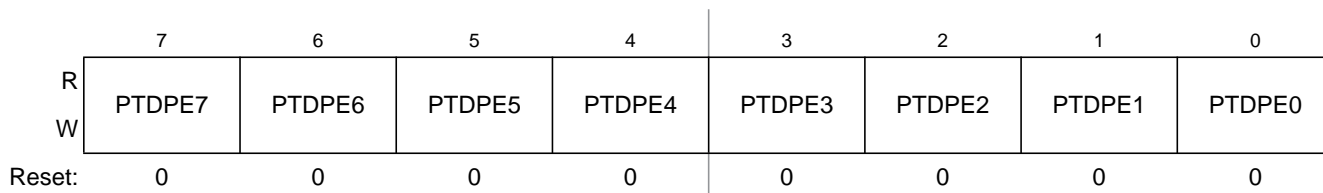
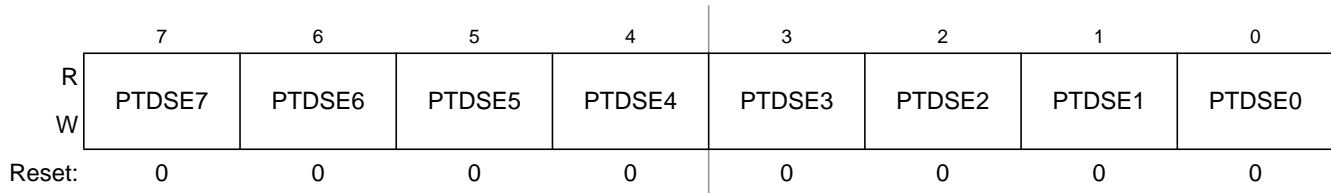


Figure 6-23. Internal Pull Enable for Port D Register (PTDPE)

**Table 6-21. PTDPE Register Field Descriptions**

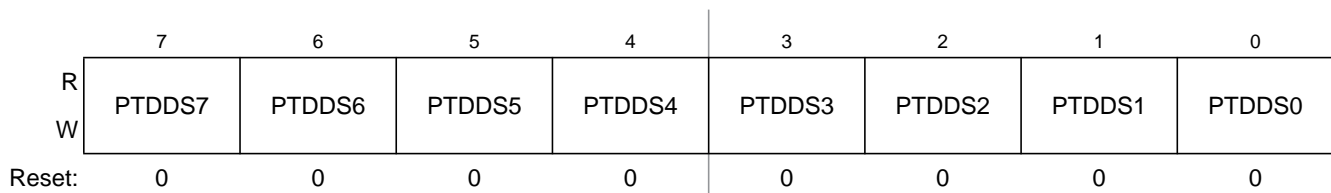
Field	Description
7:0 PTDPE[7:0]	<b>Internal Pull Enable for Port D Bits</b> — Each of these control bits determines if the internal pull-up or pull-down device is enabled for the associated PTD pin. For port D pins that are configured as outputs, these bits have no effect and the internal pull devices are disabled. 0 Internal pull-up/pull-down device disabled for port D bit n. 1 Internal pull-up/pull-down device enabled for port D bit n.

#### 6.5.4.4 Port D Slew Rate Enable Register (PTDSE)


**Figure 6-24. Slew Rate Enable for Port D Register (PTDSE)**
**Table 6-22. PTDSE Register Field Descriptions**

Field	Description
7:0 PTDSE[7:0]	<b>Output Slew Rate Enable for Port D Bits</b> — Each of these control bits determines if the output slew rate control is enabled for the associated PTD pin. For port D pins that are configured as inputs, these bits have no effect. 0 Output slew rate control disabled for port D bit n. 1 Output slew rate control enabled for port D bit n.

#### 6.5.4.5 Port D Drive Strength Selection Register (PTDDS)


**Figure 6-25. Drive Strength Selection for Port D Register (PTDDS)**
**Table 6-23. PTDDS Register Field Descriptions**

Field	Description
7:0 PTDDS[7:0]	<b>Output Drive Strength Selection for Port D Bits</b> — Each of these control bits selects between low and high output drive for the associated PTD pin. For port D pins that are configured as inputs, these bits have no effect. 0 Low output drive strength selected for port D bit n. 1 High output drive strength selected for port D bit n.

### 6.5.5 Port E Registers

Port E is controlled by the registers listed below.

### 6.5.5.1 Port E Data Register (PTED)

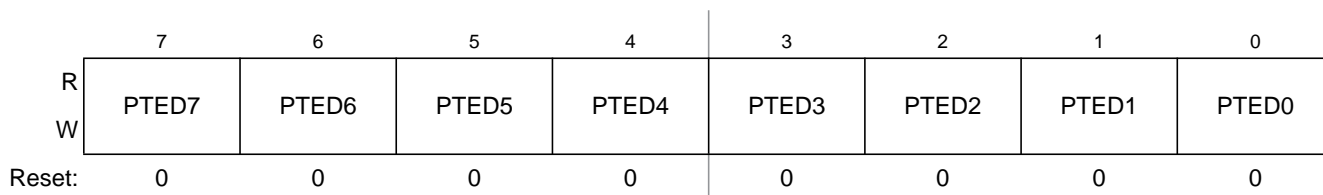


Figure 6-26. Port E Data Register (PTED)

Table 6-24. PTED Register Field Descriptions

Field	Description
7:0 PTED[7:0]	<b>Port E Data Register Bits</b> — For port E pins that are inputs, reads return the logic level on the pin. For port E pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port E pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTED to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pull-ups disabled.

### 6.5.5.2 Port E Data Direction Register (PTEDD)

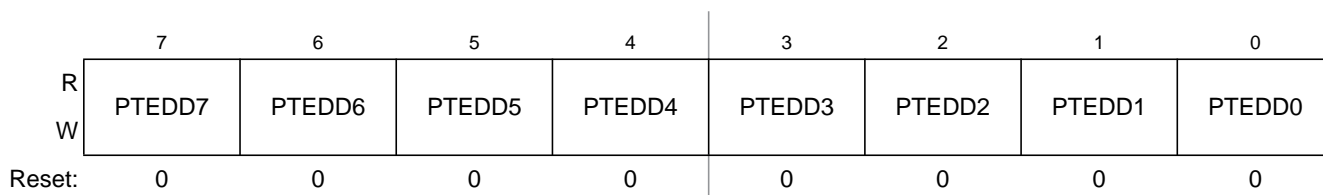


Figure 6-27. Port E Data Direction Register (PTEDD)

Table 6-25. PTEDD Register Field Descriptions

Field	Description
7:0 PTEDD[7:0]	<b>Data Direction for Port E Bits</b> — These read/write bits control the direction of port E pins and what is read for PTED reads. 0 Input (output driver disabled) and reads return the pin value. 1 Output driver enabled for port E bit n and PTED reads return the contents of PTEDn.

### 6.5.5.3 Port E Data Set Register (PTESET)

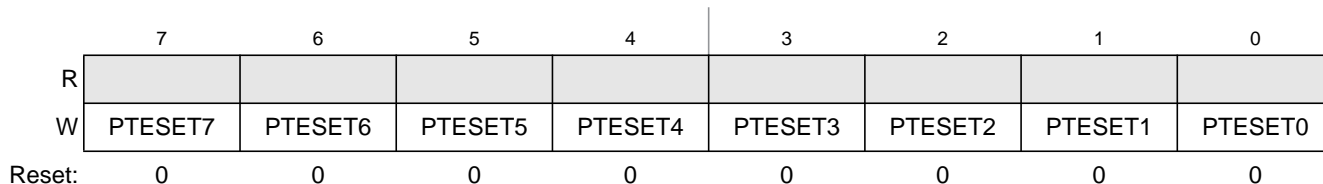


Figure 6-28. Port E Data Set Register (PTESET)

Table 6-26. PTESET Register Field Descriptions

Field	Description
7:0 PTESET $n$	<b>Data Set for Port E Bits</b> — Writing any bit to one in this location will set the corresponding bit in the data register to one. Writing a zero to any bit in this register has no effect. 0 Corresponding PTED $n$ maintains current value. 1 Corresponding PTED $n$ is set.

#### 6.5.5.4 Port E Data Clear Register (PTECLR)

	7	6	5	4	3	2	1	0
R								
W	PTECLR7	PTECLR6	PTECLR5	PTECLR4	PTECLR3	PTECLR2	PTECLR1	PTECLR0
Reset:	0	0	0	0	0	0	0	0

Figure 6-29. Port E Data Clear Register (PTECLR)

Table 6-27. PTECLR Register Field Descriptions

Field	Description
7:0 PTECLR $n$	<b>Data Clear for Port E Bits</b> — Writing any bit to zero in this location will clear the corresponding bit in the data register to zero. Writing a one to any bit in this register has no effect. 0 Corresponding PTED $n$ maintains current value. 1 Corresponding PTED $n$ is cleared.

#### 6.5.5.5 Port E Toggle Register (PTETOG)

	7	6	5	4	3	2	1	0
R								
W	PTETOG7	PTETOG6	PTETOG5	PTETOG4	PTETOG3	PTETOG2	PTETOG1	PTETOG0
Reset:	0	0	0	0	0	0	0	0

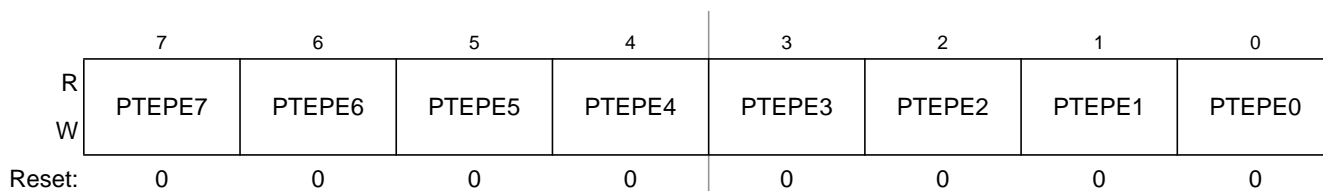
Figure 6-30. Port E Toggle Register (PTETOG)

Table 6-28. PTETOG Register Field Descriptions

Field	Description
7:0 PTETOG $n$	<b>Toggle for Port E Bits</b> — Writing any bit to one in this location will toggle the corresponding bit in the data register. Writing a zero to any bit in this register has no effect. 0 Corresponding PTED $n$ maintains current value. 1 Corresponding PTED $n$ is inverted.

#### 6.5.5.6 Port E Pull Enable Register (PTEPE)

The port E enable register (PTEPE) enables pull-ups on the corresponding PTE pin. In some cases, a pull-down device will be enabled if pull-downs are supported by an alternative pin function, such as KBI.

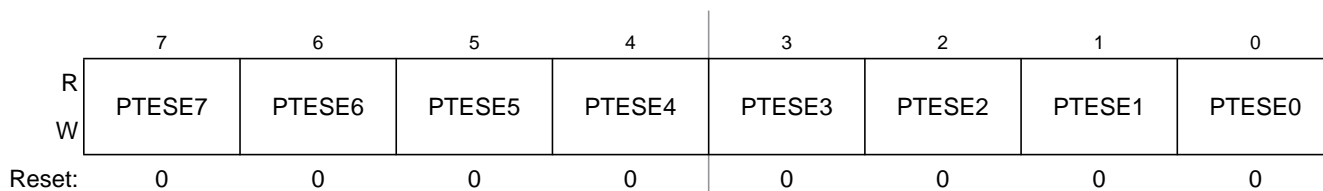


**Figure 6-31. Internal Pull Enable for Port E Register (PTEPE)**

**Table 6-29. PTEPE Register Field Descriptions**

Field	Description
7:0 PTEPE[7:0]	<p><b>Internal Pull Enable for Port E Bits</b> — Each of these control bits determines if the internal pull-up device is enabled for the associated PTE pin. For port E pins that are configured as outputs, these bits have no effect and the internal pull devices are disabled.</p> <p>0 Internal pull-up device disabled for port E bit n. 1 Internal pull-up device enabled for port E bit n.</p>

### 6.5.5.7 Port E Slew Rate Enable Register (PTESE)



**Figure 6-32. Slew Rate Enable for Port E Register (PTESE)**

**Table 6-30. PTESE Register Field Descriptions**

Field	Description
7:0 PTESE[7:0]	<p><b>Output Slew Rate Enable for Port E Bits</b> — Each of these control bits determines if the output slew rate control is enabled for the associated PTE pin. For port E pins that are configured as inputs, these bits have no effect.</p> <p>0 Output slew rate control disabled for port E bit n. 1 Output slew rate control enabled for port E bit n.</p>



### 6.5.5.8 Port E Drive Strength Selection Register (PTEDS)

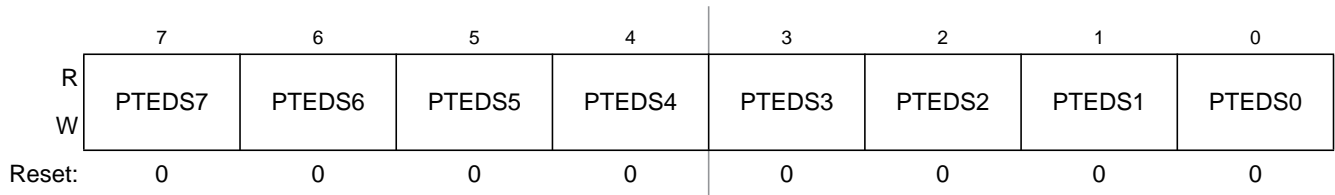


Figure 6-33. Drive Strength Selection for Port E Register (PTEDS)

Table 6-31. PTEDS Register Field Descriptions

Field	Description
7:0 PTEDS[7:0]	<p><b>Output Drive Strength Selection for Port E Bits</b> — Each of these control bits selects between low and high output drive for the associated PTE pin. For port E pins that are configured as inputs, these bits have no effect.</p> <p>0 Low output drive strength selected for port E bit n.                      1 High output drive strength selected for port E bit n.</p>

### 6.5.6 Port F Registers

Port F is controlled by the registers listed below.

### 6.5.6.1 Port F Data Register (PTFD)

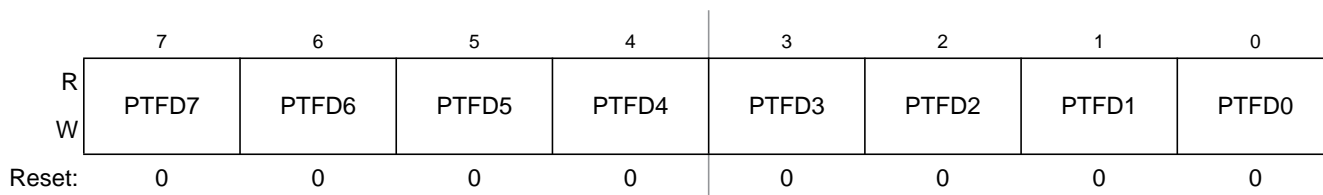


Figure 6-34. Port F Data Register (PTFD)

Table 6-32. PTFD Register Field Descriptions

Field	Description
7:0 PTFD[7:0]	<b>Port F Data Register Bits</b> — For port F pins that are inputs, reads return the logic level on the pin. For port F pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port F pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTFD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pull-ups disabled.

### 6.5.6.2 Port F Data Direction Register (PTFDD)

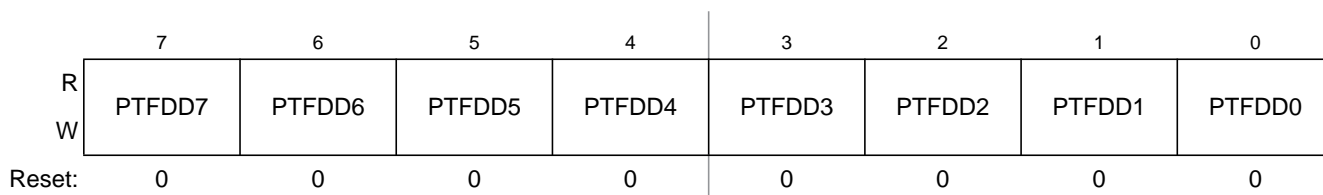


Figure 6-35. Port F Data Direction Register (PTFDD)

Table 6-33. PTFDD Register Field Descriptions

Field	Description
7:0 PTFDD[7:0]	<b>Data Direction for Port F Bits</b> — These read/write bits control the direction of port F pins and what is read for PTFD reads. 0 Input (output driver disabled) and reads return the pin value. 1 Output driver enabled for port F bit n and PTFD reads return the contents of PTFDn.

### 6.5.6.3 Port F Pull Enable Register (PTFPE)

The port F enable register (PTFPE) enables pull-ups on the corresponding PTF pin. In some cases, a pull-down device will be enabled if pull-downs are supported by an alternative pin function, such as KBI.

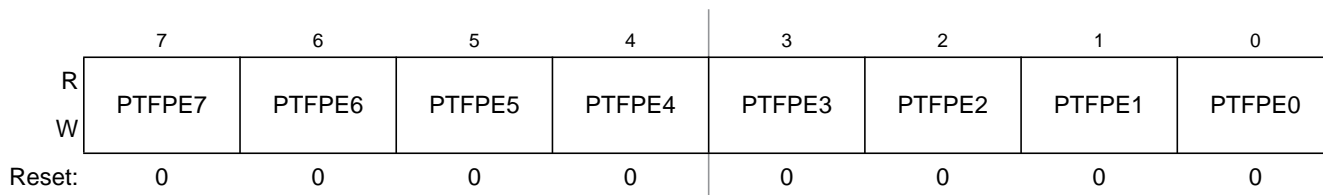
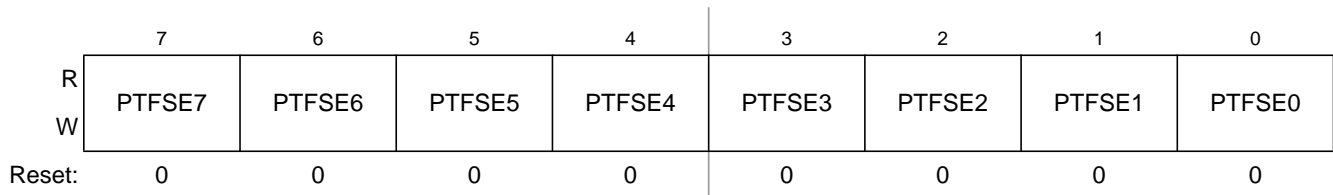


Figure 6-36. Internal Pull Enable for Port F Register (PTFPE)

**Table 6-34. PTFPE Register Field Descriptions**

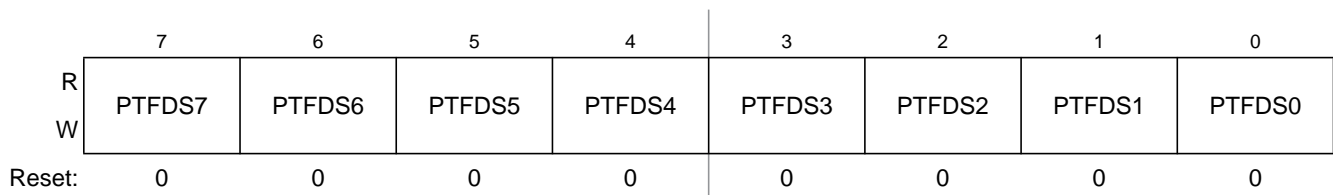
Field	Description
7:0 PTFPE[7:0]	<b>Internal Pull Enable for Port F Bits</b> — Each of these control bits determines if the internal pull-up device is enabled for the associated PTF pin. For port F pins that are configured as outputs, these bits have no effect and the internal pull devices are disabled. 0 Internal pull-up device disabled for port F bit n. 1 Internal pull-up device enabled for port F bit n.

#### 6.5.6.4 Port F Slew Rate Enable Register (PTFSE)


**Figure 6-37. Slew Rate Enable for Port F Register (PTFSE)**
**Table 6-35. PTFSE Register Field Descriptions**

Field	Description
7:0 PTFSE[7:0]	<b>Output Slew Rate Enable for Port F Bits</b> — Each of these control bits determines if the output slew rate control is enabled for the associated PTF pin. For port F pins that are configured as inputs, these bits have no effect. 0 Output slew rate control disabled for port F bit n. 1 Output slew rate control enabled for port F bit n.

#### 6.5.6.5 Port F Drive Strength Selection Register (PTFDS)


**Figure 6-38. Drive Strength Selection for Port F Register (PTFDS)**
**Table 6-36. PTFDS Register Field Descriptions**

Field	Description
7:0 PTFDS[7:0]	<b>Output Drive Strength Selection for Port F Bits</b> — Each of these control bits selects between low and high output drive for the associated PTF pin. For port F pins that are configured as inputs, these bits have no effect. 0 Low output drive strength selected for port F bit n. 1 High output drive strength selected for port F bit n.

### 6.5.7 Port G Registers

Port G is controlled by the registers listed below.

### 6.5.7.1 Port G Data Register (PTGD)

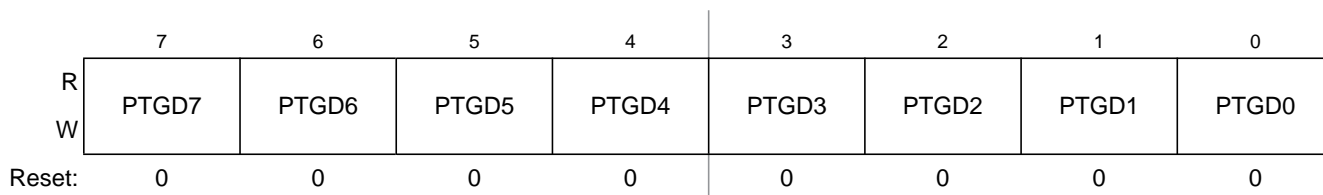


Figure 6-39. Port G Data Register (PTGD)

Table 6-37. PTGD Register Field Descriptions

Field	Description
7:0 PTGD[7:0]	<b>Port G Data Register Bits</b> — For port G pins that are inputs, reads return the logic level on the pin. For port G pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port G pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTGD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pull-ups disabled.

### 6.5.7.2 Port G Data Direction Register (PTGDD)

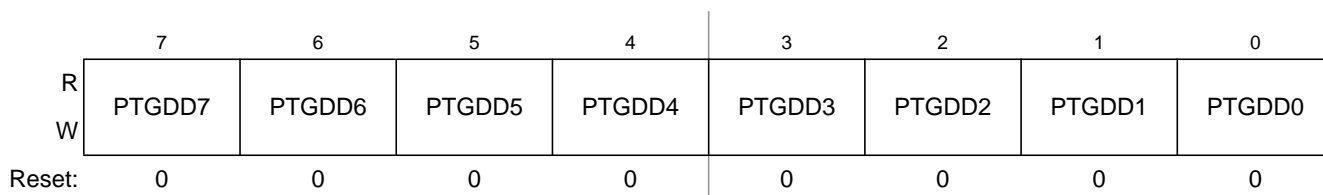


Figure 6-40. Port G Data Direction Register (PTGDD)

Table 6-38. PTGDD Register Field Descriptions

Field	Description
7:0 PTGDD[7:0]	<b>Data Direction for Port G Bits</b> — These read/write bits control the direction of port G pins and what is read for PTGD reads. 0 Input (output driver disabled) and reads return the pin value. 1 Output driver enabled for port G bit n and PTGD reads return the contents of PTGDn.

### 6.5.7.3 Port G Pull Enable Register (PTGPE)

The port G enable register (PTGPE) enables pull-ups on the corresponding PTG pin. In some cases, a pull-down device will be enabled if pull-downs are supported by an alternative pin function, such as KBI.

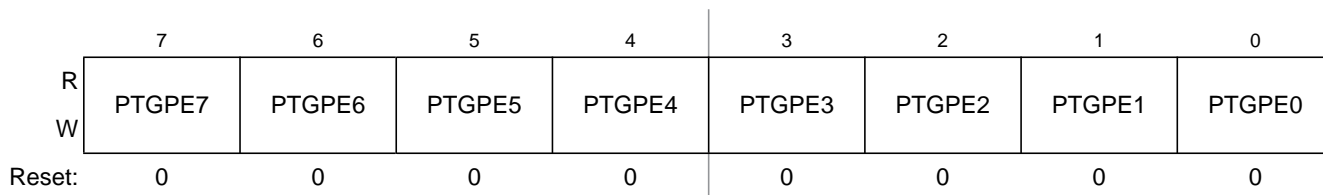
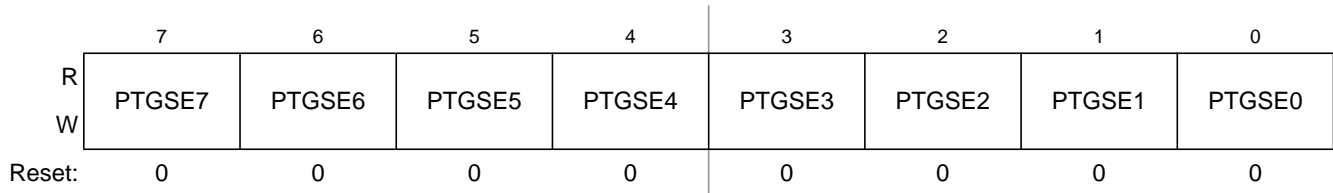


Figure 6-41. Internal Pull Enable for Port G Register (PTGPE)

**Table 6-39. PTGPE Register Field Descriptions**

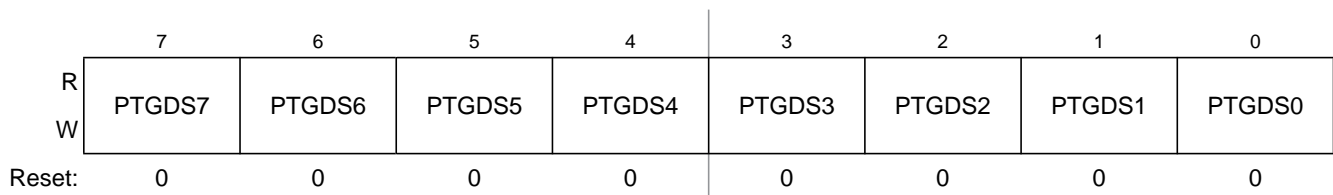
Field	Description
7:0 PTGPE[7:0]	<b>Internal Pull Enable for Port G Bits</b> — Each of these control bits determines if the internal pull-up device is enabled for the associated PTG pin. For port G pins that are configured as outputs, these bits have no effect and the internal pull devices are disabled. 0 Internal pull-up device disabled for port G bit n. 1 Internal pull-up device enabled for port G bit n.

### 6.5.7.4 Port G Slew Rate Enable Register (PTGSE)


**Figure 6-42. Slew Rate Enable for Port G Register (PTGSE)**
**Table 6-40. PTGSE Register Field Descriptions**

Field	Description
7:0 PTGSE[7:0]	<b>Output Slew Rate Enable for Port G Bits</b> — Each of these control bits determines if the output slew rate control is enabled for the associated PTG pin. For port G pins that are configured as inputs, these bits have no effect. 0 Output slew rate control disabled for port G bit n. 1 Output slew rate control enabled for port G bit n.

### 6.5.7.5 Port G Drive Strength Selection Register (PTGDS)


**Figure 6-43. Drive Strength Selection for Port G Register (PTGDS)**
**Table 6-41. PTGDS Register Field Descriptions**

Field	Description
7:0 PTGDS[7:0]	<b>Output Drive Strength Selection for Port G Bits</b> — Each of these control bits selects between low and high output drive for the associated PTG pin. For port G pins that are configured as inputs, these bits have no effect. 0 Low output drive strength selected for port G bit n. 1 High output drive strength selected for port G bit n.

## 6.5.8 Port H Registers

Port H is controlled by the registers listed below.

### 6.5.8.1 Port H Data Register (PTHD)

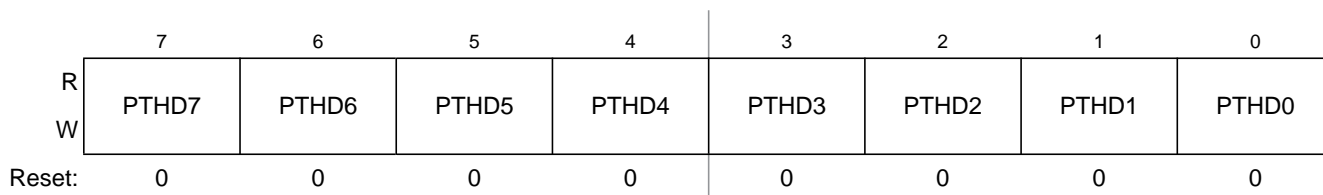


Figure 6-44. Port H Data Register (PTHD)

Table 6-42. PTHD Register Field Descriptions

Field	Description
7:0 PTHD[7:0]	<p><b>Port H Data Register Bits</b> — For port H pins that are inputs, reads return the logic level on the pin. For port H pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port H pins that are configured as outputs, the logic level is driven out the corresponding MCU pin.</p> <p>Reset forces PTHD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pull-ups disabled.</p>

### 6.5.8.2 Port H Data Direction Register (PTHDD)

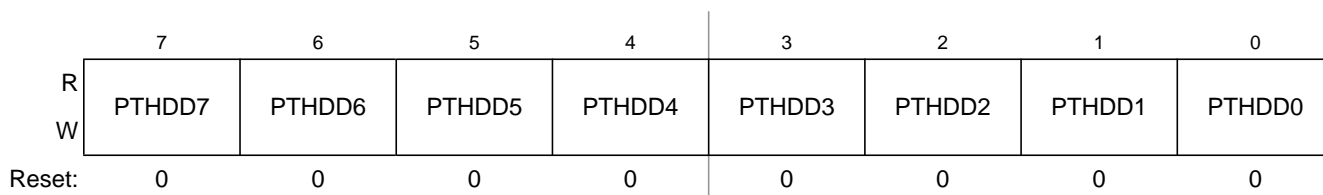


Figure 6-45. Port H Data Direction Register (PTHDD)

Table 6-43. PTHDD Register Field Descriptions

Field	Description
7:0 PTHDD[7:0]	<p><b>Data Direction for Port H Bits</b> — These read/write bits control the direction of port H pins and what is read for PTHD reads.</p> <p>0 Input (output driver disabled) and reads return the pin value.</p> <p>1 Output driver enabled for port H bit n and PTHD reads return the contents of PTHDn.</p>

### 6.5.8.3 Port H Pull Enable Register (PTHPE)

The port H enable register (PTHPE) enables pull-ups on the corresponding PTH pin. In some cases, a pull-down device will be enabled if pull-downs are supported by an alternative pin function, such as KBI.

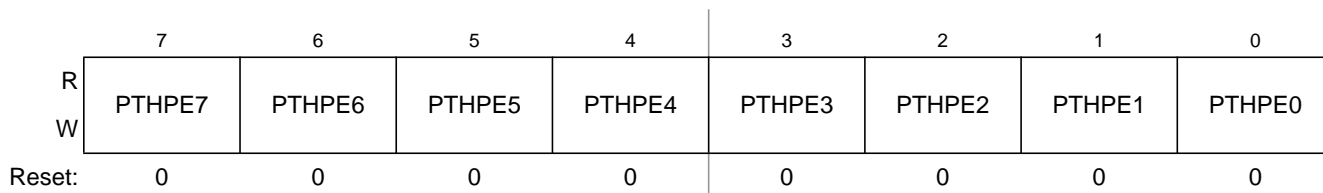
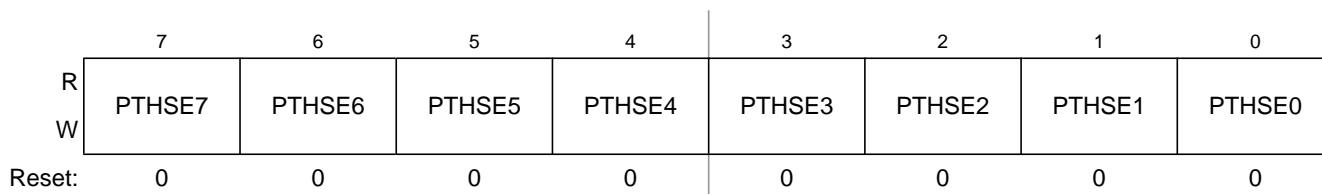


Figure 6-46. Internal Pull Enable for Port H Register (PTHPE)

**Table 6-44. PTHPE Register Field Descriptions**

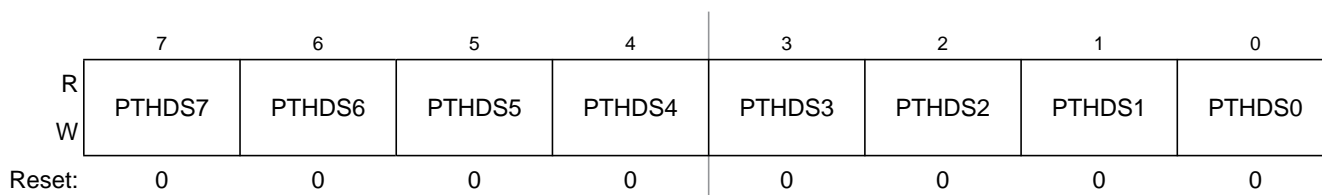
Field	Description
7:0 PTHPE[7:0]	<b>Internal Pull Enable for Port H Bits</b> — Each of these control bits determines if the internal pull-up device is enabled for the associated PTH pin. For port H pins that are configured as outputs, these bits have no effect and the internal pull devices are disabled. 0 Internal pull-up device disabled for port H bit n. 1 Internal pull-up device enabled for port H bit n.

#### 6.5.8.4 Port H Slew Rate Enable Register (PTHSE)


**Figure 6-47. Slew Rate Enable for Port H Register (PTHSE)**
**Table 6-45. PTHSE Register Field Descriptions**

Field	Description
7:0 PTHSE[7:0]	<b>Output Slew Rate Enable for Port H Bits</b> — Each of these control bits determines if the output slew rate control is enabled for the associated PTH pin. For port H pins that are configured as inputs, these bits have no effect. 0 Output slew rate control disabled for port H bit n. 1 Output slew rate control enabled for port H bit n.

#### 6.5.8.5 Port H Drive Strength Selection Register (PTHDS)


**Figure 6-48. Drive Strength Selection for Port H Register (PTHDS)**
**Table 6-46. PTHDS Register Field Descriptions**

Field	Description
7:0 PTHDS[7:0]	<b>Output Drive Strength Selection for Port H Bits</b> — Each of these control bits selects between low and high output drive for the associated PTH pin. For port H pins that are configured as inputs, these bits have no effect. 0 Low output drive strength selected for port H bit n. 1 High output drive strength selected for port H bit n.

### 6.5.9 Port J Registers

Port J is controlled by the registers listed below.

### 6.5.9.1 Port J Data Register (PTJD)

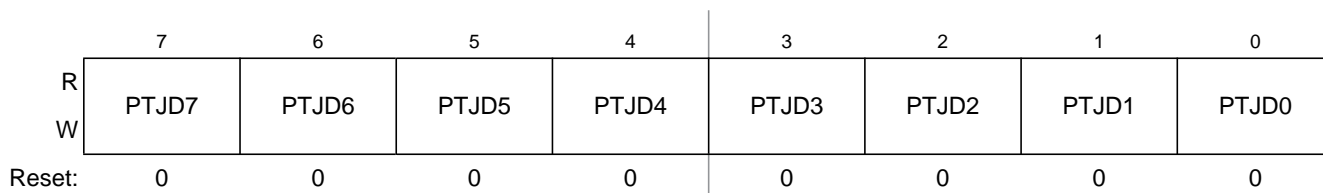


Figure 6-49. Port J Data Register (PTJD)

Table 6-47. PTJD Register Field Descriptions

Field	Description
7:0 PTJD[7:0]	<p><b>Port J Data Register Bits</b> — For port J pins that are inputs, reads return the logic level on the pin. For port J pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port J pins that are configured as outputs, the logic level is driven out the corresponding MCU pin.</p> <p>Reset forces PTJD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pull-ups disabled.</p>

### 6.5.9.2 Port J Data Direction Register (PTJDD)

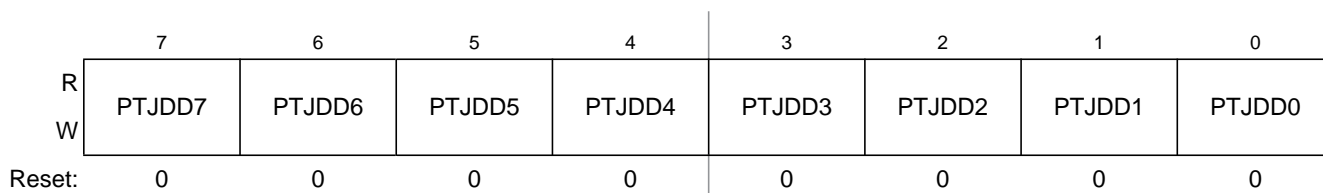


Figure 6-50. Port J Data Direction Register (PTJDD)

Table 6-48. PTJDD Register Field Descriptions

Field	Description
7:0 PTJDD[7:0]	<p><b>Data Direction for Port J Bits</b> — These read/write bits control the direction of port J pins and what is read for PTJD reads.</p> <p>0 Input (output driver disabled) and reads return the pin value.</p> <p>1 Output driver enabled for port J bit n and PTJD reads return the contents of PTJDDn.</p>

### 6.5.9.3 Port J Pull Enable Register (PTJPE)

The port J enable register (PTJPE) enables pull-ups on the corresponding PTJ pin. In some cases, a pull-down device will be enabled if pull-downs are supported by an alternative pin function, such as KBI.

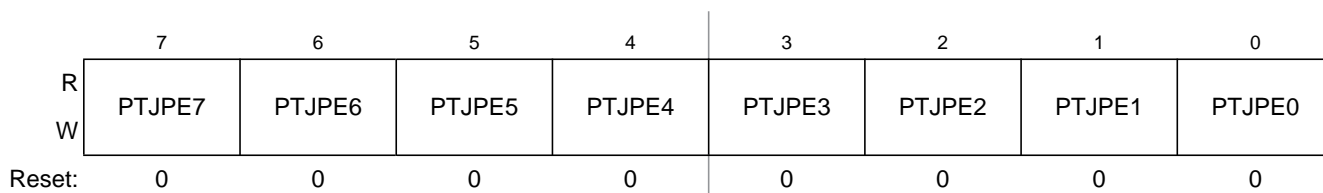


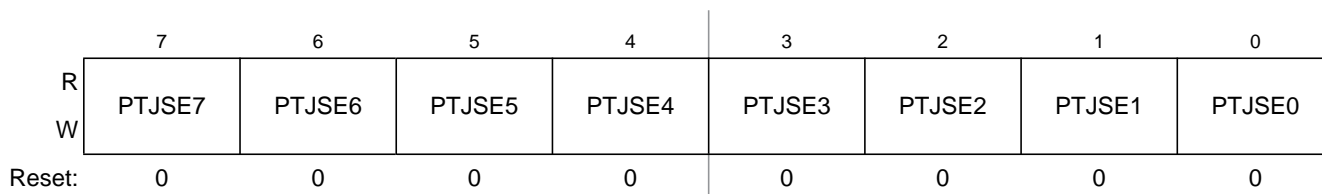
Figure 6-51. Internal Pull Enable for Port J Register (PTJPE)



**Table 6-49. PTJPE Register Field Descriptions**

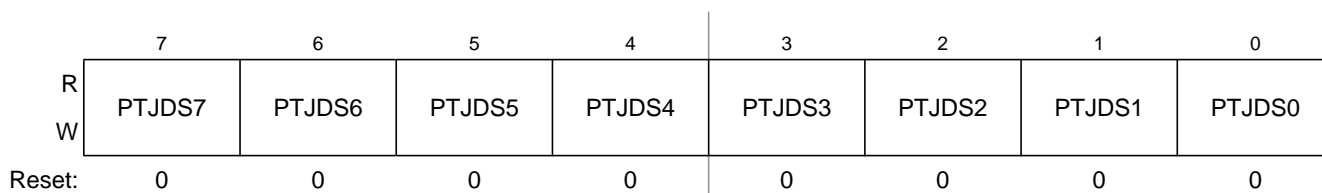
Field	Description
7:0 PTJPE[7:0]	<b>Internal Pull Enable for Port J Bits</b> — Each of these control bits determines if the internal pull-up device is enabled for the associated PTJ pin. For port J pins that are configured as outputs, these bits have no effect and the internal pull devices are disabled. 0 Internal pull-up device disabled for port J bit n. 1 Internal pull-up device enabled for port J bit n.

### 6.5.9.4 Port J Slew Rate Enable Register (PTJSE)


**Figure 6-52. Slew Rate Enable for Port J Register (PTJSE)**
**Table 6-50. PTJSE Register Field Descriptions**

Field	Description
7:0 PTJSE[7:0]	<b>Output Slew Rate Enable for Port J Bits</b> — Each of these control bits determines if the output slew rate control is enabled for the associated PTJ pin. For port J pins that are configured as inputs, these bits have no effect. 0 Output slew rate control disabled for port J bit n. 1 Output slew rate control enabled for port J bit n.

### 6.5.9.5 Port J Drive Strength Selection Register (PTJDS)


**Figure 6-53. Drive Strength Selection for Port J Register (PTJDS)**
**Table 6-51. PTJDS Register Field Descriptions**

Field	Description
7:0 PTJDS[7:0]	<b>Output Drive Strength Selection for Port J Bits</b> — Each of these control bits selects between low and high output drive for the associated PTJ pin. For port J pins that are configured as inputs, these bits have no effect. 0 Low output drive strength selected for port J bit n. 1 High output drive strength selected for port J bit n.



# Chapter 7

## Keyboard Interrupt (S08KBIV2)

### 7.1 Introduction

The keyboard interrupt (KBI) module provides up to eight independently enabled external interrupt sources. MC9S08QE128 Series devices contain two KBI modules, called KBI1 and KBI2. Each KBI module has up to eight interrupt sources.

#### 7.1.1 KBI Clock Gating

The bus clock to the KBI can be gated on and off using the KBI bit in SCGC2. This bit is set after any reset, which enables the bus clock to this module. To conserve power, the KBI bit can be cleared to disable the clock to this module when not in use. See [Section 5.7, “Peripheral Clock Gating,”](#) for details.

#### 7.1.2 Features

The KBI features include:

- Up to eight keyboard interrupt pins with individual pin enable bits.
- Each keyboard interrupt pin is programmable as falling edge (or rising edge) only, or both falling edge and low level (or both rising edge and high level) interrupt sensitivity.
- One software enabled keyboard interrupt.
- Exit from low-power modes.

#### 7.1.3 Modes of Operation

This section defines the KBI operation in wait, stop, and background debug modes.

##### 7.1.3.1 KBI in Wait Mode

The KBI continues to operate in wait mode if enabled before executing the WAIT instruction. Therefore, an enabled KBI pin ( $KBPE_x = 1$ ) can be used to bring the MCU out of wait mode if the KBI interrupt is enabled ( $KBIE = 1$ ).

##### 7.1.3.2 KBI in Stop Modes

The KBI operates asynchronously in stop3 mode if enabled before executing the STOP instruction. Therefore, an enabled KBI pin ( $KBPE_x = 1$ ) can be used to bring the MCU out of stop3 mode if the KBI interrupt is enabled ( $KBIE = 1$ ).

During stop2 mode, the KBI is disabled. Upon wake-up from stop2 mode, the KBI module will be in the reset state.

### 7.1.3.3 KBI in Active Background Mode

When the microcontroller is in active background mode, the KBI will continue to operate normally.

## 7.1.4 Block Diagram

The block diagram for the keyboard interrupt module is shown [Figure 7-1](#).

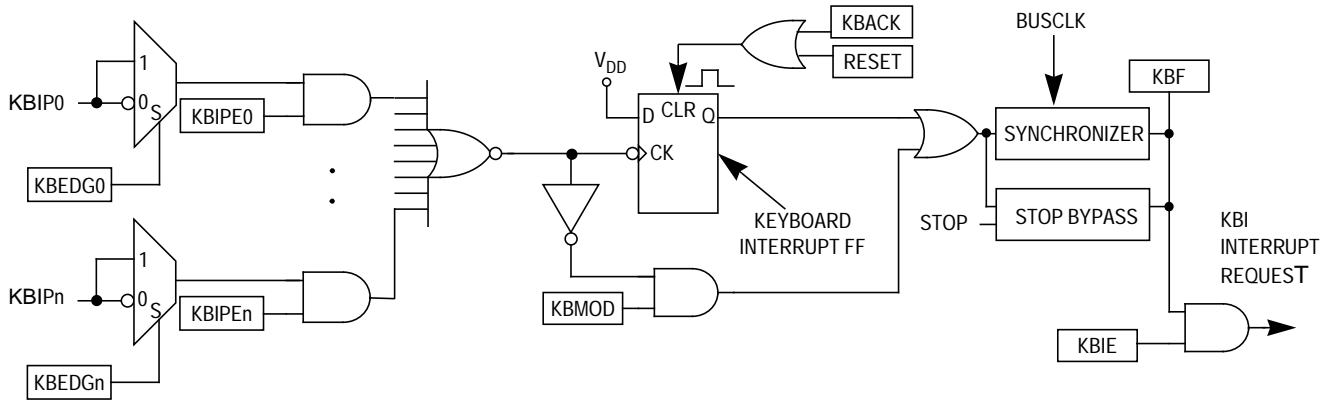


Figure 7-1. KBI Block Diagram

## 7.2 External Signal Description

The KBI input pins can be used to detect either falling edges, or both falling edge and low level interrupt requests. The KBI input pins can also be used to detect either rising edges, or both rising edge and high level interrupt requests.

Table 7-1. KBI1 Pin Mapping

Port Pin	PTB3	PTB2	PTB1	PTB0	PTA3	PTA2	PTA1	PTA0
KBI1 Pin	KBI1P7	KBI1P6	KBI1P5	KBI1P4	KBI1P3	KBI1P2	KBI1P1	KBI1P0

Table 7-2. KBI2 Pin Mapping

Port Pin	PTD7	PTD6	PTD5	PTD4	PTD3	PTD2	PTD1	PTD0
KBI2 Pin	KBI2P7	KBI2P6	KBI2P5	KBI2P4	KBI2P3	KBI2P2	KBI2P1	KBI2P0

## 7.3 Register Definition

The KBI includes three registers:

- An 8-bit pin status and control register.
- An 8-bit pin enable register.
- An 8-bit edge select register.

Refer to the direct-page register summary in the [Memory](#) chapter for the absolute address assignments for all KBI registers. This section refers to registers and control bits only by their names and relative address offsets.

Some MCUs may have more than one KBI, so register names include placeholder characters to identify which KBI is being referenced.

### 7.3.1 KBI Interrupt Status and Control Register (KBIXSC)

	7	6	5	4	3	2	1	0
R	0	0	0	0	KBF	0	KBIE	KBIMOD
W						KBACK		
Reset:	0	0	0	0	0	0	0	0

Figure 7-2. KBI Interrupt Status and Control Register (KBIXSC)

Table 7-3. KBIXSC Register Field Descriptions

Field	Description
3 KBF	<b>KBI Interrupt Flag</b> — KBF indicates when a KBI interrupt is detected. Writes have no effect on KBF. 0 No KBI interrupt detected. 1 KBI interrupt detected.
2 KBACK	<b>KBI Interrupt Acknowledge</b> — Writing a 1 to KBACK is part of the flag clearing mechanism. KBACK always reads as 0.
1 KBIE	<b>KBI Interrupt Enable</b> — KBIE determines whether a KBI interrupt is requested. 0 KBI interrupt request not enabled. 1 KBI interrupt request enabled.
0 KBIMOD	<b>KBI Detection Mode</b> — KBIMOD (along with the KBIES bits) controls the detection mode of the KBI interrupt pins. 0 KBI pins detect edges only. 1 KBI pins detect both edges and levels.

### 7.3.2 KBI Interrupt Pin Select Register (KBIXPE)



Figure 7-3. KBI Interrupt Pin Select Register (KBIXPE)

Table 7-4. KBIXPE Register Field Descriptions

Field	Description
7:0 KBIPE[7:0]	<b>KBI Interrupt Pin Selects</b> — Each of the KBIPE <sub>n</sub> bits enable the corresponding KBI interrupt pin. 0 Pin not enabled as interrupt. 1 Pin enabled as interrupt.

### 7.3.3 KBI Interrupt Edge Select Register (KBIXES)

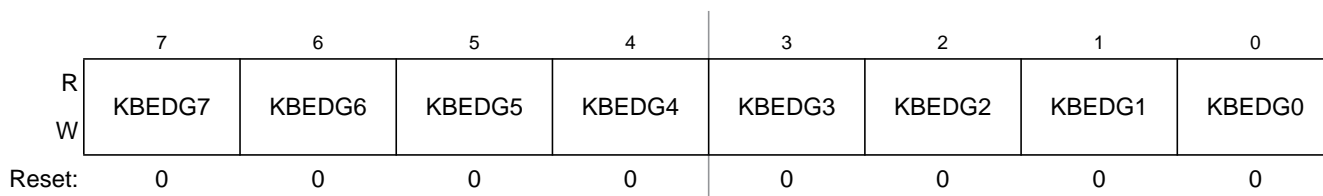


Figure 7-4. KBI Edge Select Register (KBIXES)

Table 7-5. KBIXES Register Field Descriptions

Field	Description
7:0 KBEDG[7:0]	<b>KBI Edge Selects</b> — Each of the KBEDG <sub>n</sub> bits serves a dual purpose by selecting the polarity of the active interrupt edge as well as selecting a pull-up or pull-down device if enabled. 0 A pull-up device is connected to the associated pin and detects falling edge/low level for interrupt generation. 1 A pull-down device is connected to the associated pin and detects rising edge/high level for interrupt generation.

## 7.4 Functional Description

Writing to the KBIPEn bits in the keyboard x interrupt pin enable register (KBIXPE) independently enables or disables each port pin. Each port can be configured as edge sensitive or edge and level sensitive based on the KBIMOD bit in the keyboard interrupt status and control register (KBIXSC). Edge sensitivity can be software programmed to be either falling or rising; the level can be either low or high. The polarity of the edge or edge and level sensitivity is selected using the KBEDGn bits in the keyboard interrupt edge select register (KBIXES).

Synchronous logic is used to detect edges. Prior to detecting an edge, enabled port inputs must be at the deasserted logic level. A falling edge is detected when an enabled port input signal is seen as a logic 1 (the deasserted level) during one bus cycle and then a logic 0 (the asserted level) during the next cycle. A rising

edge is detected when the input signal is seen as a logic 0 during one bus cycle and then a logic 1 during the next cycle.

### 7.4.1 Edge Only Sensitivity

A valid edge on an enabled port pin will set KBF in KBIxSC. If KBIE in KBIxSC is set, an interrupt request will be presented to the CPU. Clearing of KBF is accomplished by writing a 1 to KBACK in KBIxSC.

### 7.4.2 Edge and Level Sensitivity

A valid edge or level on an enabled port pin will set KBF in KBIxSC. If KBIE in KBIxSC is set, an interrupt request will be presented to the CPU. Clearing of KBF is accomplished by writing a 1 to KBACK in KBIxSC provided all enabled port inputs are at their deasserted levels. KBF will remain set if any enabled port pin is asserted while attempting to clear by writing a 1 to KBACK.

### 7.4.3 Pull-Up/Pull-Down Resistors

The keyboard interrupt pins can be configured to use an internal pull-up/pull-down resistor using the associated I/O port pull-up enable register. If an internal resistor is enabled, the KBIxES register is used to select whether the resistor is a pull-up (KBEDGn = 0) or a pull-down (KBEDGn = 1).

### 7.4.4 Keyboard Interrupt Initialization

When an interrupt pin is first enabled, it is possible to get a false interrupt flag. To prevent a false interrupt request during pin interrupt initialization, the user should do the following:

1. Mask interrupts by clearing KBIE in KBIxSC.
2. Select the pin polarity by setting the appropriate KBEDGn bits in KBIxES.
3. If using internal pull-up/pull-down device, configure the associated pull enable bits in KBIxPE.
4. Enable the interrupt pins by setting the appropriate KBIPEn bits in KBIxPE.
5. Write to KBACK in KBIxSC to clear any false interrupts.
6. Set KBIE in KBIxSC to enable interrupts.





## Chapter 8

# Central Processor Unit (S08CPUV4)

### 8.1 Introduction

This section provides summary information about the registers, addressing modes, and instruction set of the CPU of the HCS08 Family. For a more detailed discussion, refer to the *HCS08 Family Reference Manual, volume 1*, Freescale Semiconductor document order number HCS08RMV1/D.

The HCS08 CPU is fully source- and object-code-compatible with the M68HC08 CPU. Several instructions and enhanced addressing modes were added to improve C compiler efficiency and to support a new background debug system which replaces the monitor mode of earlier M68HC08 microcontrollers (MCU).

#### 8.1.1 Features

Features of the HCS08 CPU include:

- Object code fully upward-compatible with M68HC05 and M68HC08 Families
- 64-KB CPU address space with banked memory management unit for greater than 64 KB
- 16-bit stack pointer (any size stack anywhere in 64-KB CPU address space)
- 16-bit index register (H:X) with powerful indexed addressing modes
- 8-bit accumulator (A)
- Many instructions treat X as a second general-purpose 8-bit register
- Seven addressing modes:
  - Inherent — Operands in internal registers
  - Relative — 8-bit signed offset to branch destination
  - Immediate — Operand in next object code byte(s)
  - Direct — Operand in memory at 0x0000–0x00FF
  - Extended — Operand anywhere in 64-Kbyte address space
  - Indexed relative to H:X — Five submodes including auto increment
  - Indexed relative to SP — Improves C efficiency dramatically
- Memory-to-memory data move instructions with four address mode combinations
- Overflow, half-carry, negative, zero, and carry condition codes support conditional branching on the results of signed, unsigned, and binary-coded decimal (BCD) operations
- Efficient bit manipulation instructions
- Fast 8-bit by 8-bit multiply and 16-bit by 8-bit divide instructions
- STOP and WAIT instructions to invoke low-power operating modes

## 8.2 Programmer's Model and CPU Registers

Figure 8-1 shows the five CPU registers. CPU registers are not part of the memory map.

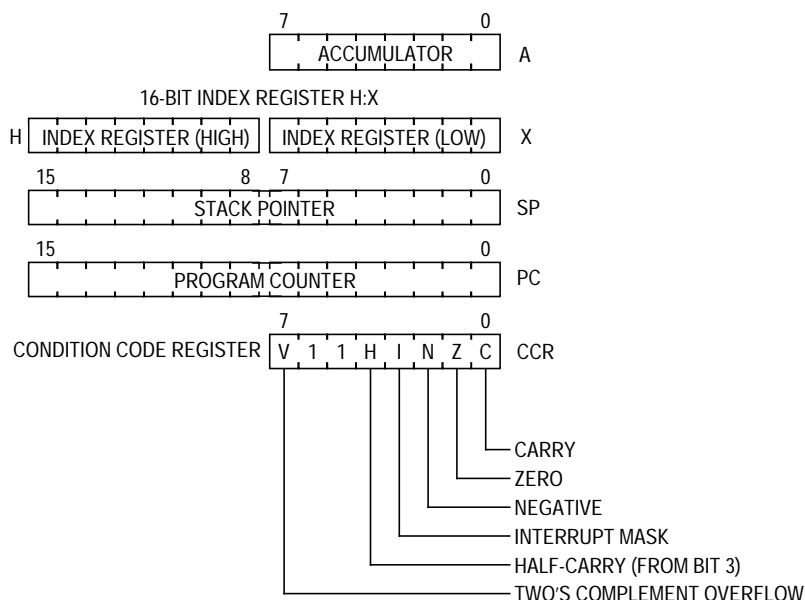


Figure 8-1. CPU Registers

### 8.2.1 Accumulator (A)

The A accumulator is a general-purpose 8-bit register. One operand input to the arithmetic logic unit (ALU) is connected to the accumulator and the ALU results are often stored into the A accumulator after arithmetic and logical operations. The accumulator can be loaded from memory using various addressing modes to specify the address where the loaded data comes from, or the contents of A can be stored to memory using various addressing modes to specify the address where data from A will be stored.

Reset has no effect on the contents of the A accumulator.

### 8.2.2 Index Register (H:X)

This 16-bit register is actually two separate 8-bit registers (H and X), which often work together as a 16-bit address pointer where H holds the upper byte of an address and X holds the lower byte of the address. All indexed addressing mode instructions use the full 16-bit value in H:X as an index reference pointer; however, for compatibility with the earlier M68HC05 Family, some instructions operate only on the low-order 8-bit half (X).

Many instructions treat X as a second general-purpose 8-bit register that can be used to hold 8-bit data values. X can be cleared, incremented, decremented, complemented, negated, shifted, or rotated. Transfer instructions allow data to be transferred from A or transferred to A where arithmetic and logical operations can then be performed.

For compatibility with the earlier M68HC05 Family, H is forced to 0x00 during reset. Reset has no effect on the contents of X.

### 8.2.3 Stack Pointer (SP)

This 16-bit address pointer register points at the next available location on the automatic last-in-first-out (LIFO) stack. The stack may be located anywhere in the 64-Kbyte address space that has RAM and can be any size up to the amount of available RAM. The stack is used to automatically save the return address for subroutine calls, the return address and CPU registers during interrupts, and for local variables. The AIS (add immediate to stack pointer) instruction adds an 8-bit signed immediate value to SP. This is most often used to allocate or deallocate space for local variables on the stack.

SP is forced to 0x00FF at reset for compatibility with the earlier M68HC05 Family. HCS08 programs normally change the value in SP to the address of the last location (highest address) in on-chip RAM during reset initialization to free up direct page RAM (from the end of the on-chip registers to 0x00FF).

The RSP (reset stack pointer) instruction was included for compatibility with the M68HC05 Family and is seldom used in new HCS08 programs because it only affects the low-order half of the stack pointer.

### 8.2.4 Program Counter (PC)

The program counter is a 16-bit register that contains the address of the next instruction or operand to be fetched.

During normal program execution, the program counter automatically increments to the next sequential memory location every time an instruction or operand is fetched. Jump, branch, interrupt, and return operations load the program counter with an address other than that of the next sequential location. This is called a change-of-flow.

During reset, the program counter is loaded with the reset vector that is located at 0xFFFFE and 0xFFFF. The vector stored there is the address of the first instruction that will be executed after exiting the reset state.

### 8.2.5 Condition Code Register (CCR)

The 8-bit condition code register contains the interrupt mask (I) and five flags that indicate the results of the instruction just executed. Bits 6 and 5 are set permanently to 1. The following paragraphs describe the functions of the condition code bits in general terms. For a more detailed explanation of how each instruction sets the CCR bits, refer to the *HCS08 Family Reference Manual, volume 1*, Freescale Semiconductor document order number HCS08RMv1.

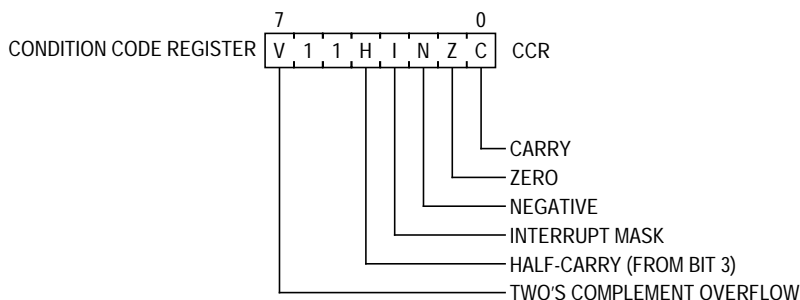


Figure 8-2. Condition Code Register

Table 8-1. CCR Register Field Descriptions

Field	Description
7 V	<b>Two's Complement Overflow Flag</b> — The CPU sets the overflow flag when a two's complement overflow occurs. The signed branch instructions BGT, BGE, BLE, and BLT use the overflow flag. 0 No overflow 1 Overflow
4 H	<b>Half-Carry Flag</b> — The CPU sets the half-carry flag when a carry occurs between accumulator bits 3 and 4 during an add-without-carry (ADD) or add-with-carry (ADC) operation. The half-carry flag is required for binary-coded decimal (BCD) arithmetic operations. The DAA instruction uses the states of the H and C condition code bits to automatically add a correction value to the result from a previous ADD or ADC on BCD operands to correct the result to a valid BCD value. 0 No carry between bits 3 and 4 1 Carry between bits 3 and 4
3 I	<b>Interrupt Mask Bit</b> — When the interrupt mask is set, all maskable CPU interrupts are disabled. CPU interrupts are enabled when the interrupt mask is cleared. When a CPU interrupt occurs, the interrupt mask is set automatically after the CPU registers are saved on the stack, but before the first instruction of the interrupt service routine is executed. Interrupts are not recognized at the instruction boundary after any instruction that clears I (CLI or TAP). This ensures that the next instruction after a CLI or TAP will always be executed without the possibility of an intervening interrupt, provided I was set. 0 Interrupts enabled 1 Interrupts disabled
2 N	<b>Negative Flag</b> — The CPU sets the negative flag when an arithmetic operation, logic operation, or data manipulation produces a negative result, setting bit 7 of the result. Simply loading or storing an 8-bit or 16-bit value causes N to be set if the most significant bit of the loaded or stored value was 1. 0 Non-negative result 1 Negative result
1 Z	<b>Zero Flag</b> — The CPU sets the zero flag when an arithmetic operation, logic operation, or data manipulation produces a result of 0x00 or 0x0000. Simply loading or storing an 8-bit or 16-bit value causes Z to be set if the loaded or stored value was all 0s. 0 Non-zero result 1 Zero result
0 C	<b>Carry/Borrow Flag</b> — The CPU sets the carry/borrow flag when an addition operation produces a carry out of bit 7 of the accumulator or when a subtraction operation requires a borrow. Some instructions — such as bit test and branch, shift, and rotate — also clear or set the carry/borrow flag. 0 No carry out of bit 7 1 Carry out of bit 7

## 8.3 Addressing Modes

Addressing modes define the way the CPU accesses operands and data. In the HCS08, memory, status and control registers, and input/output (I/O) ports share a single 64-Kbyte CPU address space. This arrangement means that the same instructions that access variables in RAM can also be used to access I/O and control registers or nonvolatile program space.

MCU derivatives with more than 64-Kbytes of memory also include a memory management unit (MMU) to support extended memory space. A PPAGE register is used to manage 16-Kbyte pages of memory which can be accessed by the CPU through a 16-Kbyte window from 0x8000 through 0xBFFF. The CPU includes two special instructions (CALL and RTC). CALL operates like the JSR instruction except that CALL saves the current PPAGE value on the stack and provides a new PPAGE value for the destination. RTC works like the RTS instruction except RTC restores the old PPAGE value in addition to the PC during the return from the called routine. The MMU also includes a linear address pointer register and data access registers so that the extended memory space operates as if it was a single linear block of memory. For additional information about the MMU, refer to the Memory chapter of this data sheet.

Some instructions use more than one addressing mode. For instance, move instructions use one addressing mode to specify the source operand and a second addressing mode to specify the destination address. Instructions such as BRCLR, BRSET, CBEQ, and DBNZ use one addressing mode to specify the location of an operand for a test and then use relative addressing mode to specify the branch destination address when the tested condition is true. For BRCLR, BRSET, CBEQ, and DBNZ, the addressing mode listed in the instruction set tables is the addressing mode needed to access the operand to be tested, and relative addressing mode is implied for the branch destination.

### 8.3.1 Inherent Addressing Mode (INH)

In this addressing mode, operands needed to complete the instruction (if any) are located within CPU registers so the CPU does not need to access memory to get any operands.

### 8.3.2 Relative Addressing Mode (REL)

Relative addressing mode is used to specify the destination location for branch instructions. A signed 8-bit offset value is located in the memory location immediately following the opcode. During execution, if the branch condition is true, the signed offset is sign-extended to a 16-bit value and is added to the current contents of the program counter, which causes program execution to continue at the branch destination address.

### 8.3.3 Immediate Addressing Mode (IMM)

In immediate addressing mode, the operand needed to complete the instruction is included in the object code immediately following the instruction opcode in memory. In the case of a 16-bit immediate operand, the high-order byte is located in the next memory location after the opcode, and the low-order byte is located in the next memory location after that.

### 8.3.4 Direct Addressing Mode (DIR)

In direct addressing mode, the instruction includes the low-order eight bits of an address in the direct page (0x0000–0x00FF). During execution a 16-bit address is formed by concatenating an implied 0x00 for the high-order half of the address and the direct address from the instruction to get the 16-bit address where the desired operand is located. This is faster and more memory efficient than specifying a complete 16-bit address for the operand.

### 8.3.5 Extended Addressing Mode (EXT)

In extended addressing mode, the full 16-bit address of the operand is located in the next two bytes of program memory after the opcode (high byte first).

### 8.3.6 Indexed Addressing Mode

Indexed addressing mode has seven variations including five that use the 16-bit H:X index register pair and two that use the stack pointer as the base reference.

#### 8.3.6.1 Indexed, No Offset (IX)

This variation of indexed addressing uses the 16-bit value in the H:X index register pair as the address of the operand needed to complete the instruction.

#### 8.3.6.2 Indexed, No Offset with Post Increment (IX+)

This variation of indexed addressing uses the 16-bit value in the H:X index register pair as the address of the operand needed to complete the instruction. The index register pair is then incremented ( $H:X = H:X + 0x0001$ ) after the operand has been fetched. This addressing mode is only used for MOV and CBEQ instructions.

#### 8.3.6.3 Indexed, 8-Bit Offset (IX1)

This variation of indexed addressing uses the 16-bit value in the H:X index register pair plus an unsigned 8-bit offset included in the instruction as the address of the operand needed to complete the instruction.

#### 8.3.6.4 Indexed, 8-Bit Offset with Post Increment (IX1+)

This variation of indexed addressing uses the 16-bit value in the H:X index register pair plus an unsigned 8-bit offset included in the instruction as the address of the operand needed to complete the instruction. The index register pair is then incremented ( $H:X = H:X + 0x0001$ ) after the operand has been fetched. This addressing mode is used only for the CBEQ instruction.

#### 8.3.6.5 Indexed, 16-Bit Offset (IX2)

This variation of indexed addressing uses the 16-bit value in the H:X index register pair plus a 16-bit offset included in the instruction as the address of the operand needed to complete the instruction.

### 8.3.6.6 SP-Relative, 8-Bit Offset (SP1)

This variation of indexed addressing uses the 16-bit value in the stack pointer (SP) plus an unsigned 8-bit offset included in the instruction as the address of the operand needed to complete the instruction.

### 8.3.6.7 SP-Relative, 16-Bit Offset (SP2)

This variation of indexed addressing uses the 16-bit value in the stack pointer (SP) plus a 16-bit offset included in the instruction as the address of the operand needed to complete the instruction.

## 8.4 Special Operations

The CPU performs a few special operations that are similar to instructions but do not have opcodes like other CPU instructions. In addition, a few instructions such as STOP and WAIT directly affect other MCU circuitry. This section provides additional information about these operations.

### 8.4.1 Reset Sequence

Reset can be caused by a power-on-reset (POR) event, internal conditions such as the COP (computer operating properly) watchdog, or by assertion of an external active-low reset pin. When a reset event occurs, the CPU immediately stops whatever it is doing (the MCU does not wait for an instruction boundary before responding to a reset event). For a more detailed discussion about how the MCU recognizes resets and determines the source, refer to the [Resets, Interrupts, and System Configuration](#) chapter.

The reset event is considered concluded when the sequence to determine whether the reset came from an internal source is done and when the reset pin is no longer asserted. At the conclusion of a reset event, the CPU performs a 6-cycle sequence to fetch the reset vector from 0xFFFFE and 0xFFFF and to fill the instruction queue in preparation for execution of the first program instruction.

### 8.4.2 Interrupt Sequence

When an interrupt is requested, the CPU completes the current instruction before responding to the interrupt. At this point, the program counter is pointing at the start of the next instruction, which is where the CPU should return after servicing the interrupt. The CPU responds to an interrupt by performing the same sequence of operations as for a software interrupt (SWI) instruction, except the address used for the vector fetch is determined by the highest priority interrupt that is pending when the interrupt sequence started.

The CPU sequence for an interrupt is:

1. Store the contents of PCL, PCH, X, A, and CCR on the stack, in that order.
2. Set the I bit in the CCR.
3. Fetch the high-order half of the interrupt vector.
4. Fetch the low-order half of the interrupt vector.
5. Delay for one free bus cycle.

6. Fetch three bytes of program information starting at the address indicated by the interrupt vector to fill the instruction queue in preparation for execution of the first instruction in the interrupt service routine.

After the CCR contents are pushed onto the stack, the I bit in the CCR is set to prevent other interrupts while in the interrupt service routine. Although it is possible to clear the I bit with an instruction in the interrupt service routine, this would allow nesting of interrupts (which is not recommended because it leads to programs that are difficult to debug and maintain).

For compatibility with the earlier M68HC05 MCUs, the high-order half of the H:X index register pair (H) is not saved on the stack as part of the interrupt sequence. The user must use a PSHH instruction at the beginning of the service routine to save H and then use a PULH instruction just before the RTI that ends the interrupt service routine. It is not necessary to save H if you are certain that the interrupt service routine does not use any instructions or auto-increment addressing modes that might change the value of H.

The software interrupt (SWI) instruction is like a hardware interrupt except that it is not masked by the global I bit in the CCR and it is associated with an instruction opcode within the program so it is not asynchronous to program execution.

### 8.4.3 Wait Mode Operation

The WAIT instruction enables interrupts by clearing the I bit in the CCR. It then halts the clocks to the CPU to reduce overall power consumption while the CPU is waiting for the interrupt or reset event that will wake the CPU from wait mode. When an interrupt or reset event occurs, the CPU clocks will resume and the interrupt or reset event will be processed normally.

If a serial BACKGROUND command is issued to the MCU through the background debug interface while the CPU is in wait mode, CPU clocks will resume and the CPU will enter active background mode where other serial background commands can be processed. This ensures that a host development system can still gain access to a target MCU even if it is in wait mode.

### 8.4.4 Stop Mode Operation

Usually, all system clocks, including the crystal oscillator (when used), are halted during stop mode to minimize power consumption. In such systems, external circuitry is needed to control the time spent in stop mode and to issue a signal to wake up the target MCU when it is time to resume processing. Unlike the earlier M68HC05 and M68HC08 MCUs, the HCS08 can be configured to keep a minimum set of clocks running in stop mode. This optionally allows an internal periodic signal to wake the target MCU from stop mode.

When a host debug system is connected to the background debug pin (BKGD) and the ENBDM control bit has been set by a serial command through the background interface (or because the MCU was reset into active background mode), the oscillator is forced to remain active when the MCU enters stop mode. In this case, if a serial BACKGROUND command is issued to the MCU through the background debug interface while the CPU is in stop mode, CPU clocks will resume and the CPU will enter active background mode where other serial background commands can be processed. This ensures that a host development system can still gain access to a target MCU even if it is in stop mode.



Recovery from stop mode depends on the particular HCS08 and whether the oscillator was stopped in stop mode. Refer to the [Modes of Operation](#) chapter for more details.

### 8.4.5 BGND Instruction

The BGND instruction is new to the HCS08 compared to the M68HC08. BGND would not be used in normal user programs because it forces the CPU to stop processing user instructions and enter the active background mode. The only way to resume execution of the user program is through reset or by a host debug system issuing a GO, TRACE1, or TAGGO serial command through the background debug interface.

Software-based breakpoints can be set by replacing an opcode at the desired breakpoint address with the BGND opcode. When the program reaches this breakpoint address, the CPU is forced to active background mode rather than continuing the user program.

The CALL is similar to a jump-to-subroutine (JSR) instruction, but the subroutine that is called can be located anywhere in the normal 64-Kbyte address space or on any page of program expansion memory. When CALL is executed, a return address is calculated, then it and the current program page register value are stacked, and a new instruction-supplied value is written to PPAGE. The PPAGE value controls which of the possible 16-Kbyte pages is visible through the window in the 64-Kbyte memory map. Execution continues at the address of the called subroutine.

The actual sequence of operations that occur during execution of CALL is:

1. CPU calculates the address of the next instruction after the CALL instruction (the return address) and pushes this 16-bit value onto the stack, low byte first.
2. CPU reads the old PPAGE value and pushes it onto the stack.
3. CPU writes the new instruction-supplied page select value to PPAGE. This switches the destination page into the program overlay window in the CPU address range 0x8000 0xBFFF.
4. Instruction queue is refilled starting from the destination address, and execution begins at the new address.

This sequence of operations is an uninterruptable CPU instruction. There is no need to inhibit interrupts during CALL execution. In addition, a CALL can be performed from any address in memory to any other address. This is a big improvement over other bank-switching schemes, where the page switch operation can be performed only by a program outside the overlay window.

For all practical purposes, the PPAGE value supplied by the instruction can be considered to be part of the effective address. The new page value is provided by an immediate operand in the instruction.

The RTC instruction is used to terminate subroutines invoked by a CALL instruction. RTC unstacks the PPAGE value and the return address, the queue is refilled, and execution resumes with the next instruction after the corresponding CALL.

The actual sequence of operations that occur during execution of RTC is:

1. The return value of the 8-bit PPAGE register is pulled from the stack.
2. The 16-bit return address is pulled from the stack and loaded into the PC.
3. The return PPAGE value is written to the PPAGE register.

4. The queue is refilled and execution begins at the new address.

Since the return operation is implemented as a single uninterruptable CPU instruction, the RTC can be executed from anywhere in memory, including from a different page of extended memory in the overlay window.

The CALL and RTC instructions behave like JSR and RTS, except they have slightly longer execution times. Since extra execution cycles are required, routinely substituting CALL/RTC for JSR/RTS is not recommended. JSR and RTS can be used to access subroutines that are located outside the program overlay window or on the same memory page. However, if a subroutine can be called from other pages, it must be terminated with an RTC. In this case, since RTC unstacks the PPAGE value as well as the return address, all accesses to the subroutine, even those made from the same page, must use CALL instructions.

## 8.5 HCS08 Instruction Set Summary

### Instruction Set Summary Nomenclature

The nomenclature listed here is used in the instruction descriptions in [Table 8-2](#).

#### Operators

( )	=	Contents of register or memory location shown inside parentheses
←	=	Is loaded with (read: “gets”)
&	=	Boolean AND
	=	Boolean OR
⊕	=	Boolean exclusive-OR
×	=	Multiply
÷	=	Divide
:	=	Concatenate
+	=	Add
–	=	Negate (two’s complement)

#### CPU registers

A	=	Accumulator
CCR	=	Condition code register
H	=	Index register, higher order (most significant) 8 bits
X	=	Index register, lower order (least significant) 8 bits
PC	=	Program counter
PCH	=	Program counter, higher order (most significant) 8 bits
PCL	=	Program counter, lower order (least significant) 8 bits
SP	=	Stack pointer

#### Memory and addressing

M	=	A memory location or absolute data, depending on addressing mode
M:M + 0x0001	=	A 16-bit value in two consecutive memory locations. The higher-order (most significant) 8 bits are located at the address of M, and the lower-order (least significant) 8 bits are located at the next higher sequential address.

#### Condition code register (CCR) bits

V	=	Two’s complement overflow indicator, bit 7
H	=	Half carry, bit 4
I	=	Interrupt mask, bit 3
N	=	Negative indicator, bit 2
Z	=	Zero indicator, bit 1
C	=	Carry/borrow, bit 0 (carry out of bit 7)

#### CCR activity notation

–	=	Bit not affected
---	---	------------------

- 0 = Bit forced to 0
- 1 = Bit forced to 1
- ↑ = Bit set or cleared according to results of operation
- U = Undefined after the operation

### Machine coding notation

- dd = Low-order 8 bits of a direct address 0x0000–0x00FF (high byte assumed to be 0x00)
- ee = Upper 8 bits of 16-bit offset
- ff = Lower 8 bits of 16-bit offset or 8-bit offset
- ii = One byte of immediate data
- jj = High-order byte of a 16-bit immediate data value
- kk = Low-order byte of a 16-bit immediate data value
- hh = High-order byte of 16-bit extended address
- ll = Low-order byte of 16-bit extended address
- pg = Page
- rr = Relative offset

### Source form

Everything in the source forms columns, *except expressions in italic characters*, is literal information that must appear in the assembly source file exactly as shown. The initial 3- to 5-letter mnemonic is always a literal expression. All commas, pound signs (#), parentheses, and plus signs (+) are literal characters.

- n* — Any label or expression that evaluates to a single integer in the range 0–7
- opr8i* — Any label or expression that evaluates to an 8-bit immediate value
- opr16i* — Any label or expression that evaluates to a 16-bit immediate value
- opr8a* — Any label or expression that evaluates to an 8-bit value. The instruction treats this 8-bit value as the low order 8 bits of an address in the direct page of the 64-Kbyte address space (0x00xx).
- opr16a* — Any label or expression that evaluates to a 16-bit value. The instruction treats this value as an address in the 64-Kbyte address space.
- opr8* — Any label or expression that evaluates to an unsigned 8-bit value, used for indexed addressing
- opr16* — Any label or expression that evaluates to a 16-bit value. Because the HCS08 has a 16-bit address bus, this can be either a signed or an unsigned value.
- page* — Any label or expression that evaluates to a valid bank number for the PPAGE register. For a 128-Kbyte derivative, any value between 0 and 7 is valid.
- rel* — Any label or expression that refers to an address that is within –128 to +127 locations from the next address after the last byte of object code for the current instruction. The assembler will calculate the 8-bit signed offset and include it in the object code for this instruction.

### Address modes

- INH = Inherent (no operands)

- IMM = 8-bit or 16-bit immediate  
 DIR = 8-bit direct  
 EXT = 16-bit extended  
 IX = 16-bit indexed no offset  
 IX+ = 16-bit indexed no offset, post increment (CBEQ and MOV only)  
 IX1 = 16-bit indexed with 8-bit offset from H:X  
 IX1+ = 16-bit indexed with 8-bit offset, post increment (CBEQ only)  
 IX2 = 16-bit indexed with 16-bit offset from H:X  
 REL = 8-bit relative offset  
 SP1 = Stack pointer with 8-bit offset  
 SP2 = Stack pointer with 16-bit offset

Table 8-2. HCS08 Instruction Set Summary (Sheet 1 of 7)

Source Form	Operation	Description	Effect on CCR						Address Mode	Opcode	Operand	Bus Cycles <sup>1</sup>
			V	H	I	N	Z	C				
ADC #opr8i ADC opr8a ADC opr16a ADC oprx16,X ADC oprx8,X ADC ,X ADC oprx16,SP ADC oprx8,SP	Add with Carry	$A \leftarrow (A) + (M) + (C)$	↑	↑	–	↑	↑	↑	IMM DIR EXT IX2 IX1 IX SP2 SP1	A9 ii B9 dd C9 hh ll D9 ee ff E9 ff F9 ff 9ED9 ee ff 9EE9 ff	2 3 4 4 3 3 5 4	
ADD #opr8i ADD opr8a ADD opr16a ADD oprx16,X ADD oprx8,X ADD ,X ADD oprx16,SP ADD oprx8,SP	Add without Carry	$A \leftarrow (A) + (M)$	↑	↑	–	↑	↑	↑	IMM DIR EXT IX2 IX1 IX SP2 SP1	AB ii BB dd CB hh ll DB ee ff EB ff FB ff 9EDB ee ff 9EEB ff	2 3 4 4 3 3 5 4	
AIS #opr8i	Add Immediate Value (Signed) to Stack Pointer	$SP \leftarrow (SP) + (M)$ M is sign extended to a 16-bit value	–	–	–	–	–	–	IMM	A7 ii	2	
AIX #opr8i	Add Immediate Value (Signed) to Index Register (H:X)	$H:X \leftarrow (H:X) + (M)$ M is sign extended to a 16-bit value	–	–	–	–	–	–	IMM	AF ii	2	
AND #opr8i AND opr8a AND opr16a AND oprx16,X AND oprx8,X AND ,X AND oprx16,SP AND oprx8,SP	Logical AND	$A \leftarrow (A) \& (M)$	0	–	–	↑	↑	–	IMM DIR EXT IX2 IX1 IX SP2 SP1	A4 ii B4 dd C4 hh ll D4 ee ff E4 ff F4 ff 9ED4 ee ff 9EE4 ff	2 3 4 4 3 3 5 4	
ASL opr8a ASLA ASLX ASL oprx8,X ASL ,X ASL oprx8,SP	Arithmetic Shift Left (Same as LSL)		↑	–	–	↑	↑	↑	DIR INH INH IX1 IX SP1	38 dd 48 dd 58 ff 68 ff 78 ff 9E68 ff	5 1 1 5 4 6	
ASR opr8a ASRA ASRX ASR oprx8,X ASR ,X ASR oprx8,SP	Arithmetic Shift Right		↑	–	–	↑	↑	↑	DIR INH INH IX1 IX SP1	37 dd 47 dd 57 ff 67 ff 77 ff 9E67 ff	5 1 1 5 4 6	
BCC rel	Branch if Carry Bit Clear	Branch if (C) = 0	–	–	–	–	–	–	REL	24 rr	3	

Table 8-2. HCS08 Instruction Set Summary (Sheet 2 of 7)

Source Form	Operation	Description	Effect on CCR						Address Mode	Opcode	Operand	Bus Cycles <sup>1</sup>
			V	H	I	N	Z	C				
BCLR <i>n,opr8a</i>	Clear Bit n in Memory	$M_n \leftarrow 0$	-	-	-	-	-	-	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	11 13 15 17 19 1B 1D 1F	dd dd dd dd dd dd dd dd	5 5 5 5 5 5 5 5
BCS <i>rel</i>	Branch if Carry Bit Set (Same as BLO)	Branch if (C) = 1	-	-	-	-	-	-	REL	25	rr	3
BEQ <i>rel</i>	Branch if Equal	Branch if (Z) = 1	-	-	-	-	-	-	REL	27	rr	3
BGE <i>rel</i>	Branch if Greater Than or Equal To (Signed Operands)	Branch if $(N \oplus V) = 0$	-	-	-	-	-	-	REL	90	rr	3
BGND	Enter Active Background if ENBDM = 1	Waits For and Processes BDM Commands Until GO, TRACE1, or TAGGO	-	-	-	-	-	-	INH	82		5+
BGT <i>rel</i>	Branch if Greater Than (Signed Operands)	Branch if $(Z)   (N \oplus V) = 0$	-	-	-	-	-	-	REL	92	rr	3
BHCC <i>rel</i>	Branch if Half Carry Bit Clear	Branch if (H) = 0	-	-	-	-	-	-	REL	28	rr	3
BHCS <i>rel</i>	Branch if Half Carry Bit Set	Branch if (H) = 1	-	-	-	-	-	-	REL	29	rr	3
BHI <i>rel</i>	Branch if Higher	Branch if $(C)   (Z) = 0$	-	-	-	-	-	-	REL	22	rr	3
BHS <i>rel</i>	Branch if Higher or Same (Same as BCC)	Branch if (C) = 0	-	-	-	-	-	-	REL	24	rr	3
BIH <i>rel</i>	Branch if IRQ Pin High	Branch if IRQ pin = 1	-	-	-	-	-	-	REL	2F	rr	3
BIL <i>rel</i>	Branch if IRQ Pin Low	Branch if IRQ pin = 0	-	-	-	-	-	-	REL	2E	rr	3
BIT # <i>opr8i</i> BIT <i>opr8a</i> BIT <i>opr16a</i> BIT <i>opr16,X</i> BIT <i>opr8,X</i> BIT <i>,X</i> BIT <i>opr16,SP</i> BIT <i>opr8,SP</i>	Bit Test	(A) & (M) (CCR Updated but Operands Not Changed)	0	-	-	↑	↓	↑	IMM DIR EXT IX2 IX1 IX SP2 SP1	A5 B5 C5 D5 E5 F5 9ED5 9EE5	ii dd hh ll ee ff ff ff ee ff ff	2 3 4 4 3 3 5 4
BLE <i>rel</i>	Branch if Less Than or Equal To (Signed Operands)	Branch if $(Z)   (N \oplus V) = 1$	-	-	-	-	-	-	REL	93	rr	3
BLO <i>rel</i>	Branch if Lower (Same as BCS)	Branch if (C) = 1	-	-	-	-	-	-	REL	25	rr	3
BLS <i>rel</i>	Branch if Lower or Same	Branch if $(C)   (Z) = 1$	-	-	-	-	-	-	REL	23	rr	3
BLT <i>rel</i>	Branch if Less Than (Signed Operands)	Branch if $(N \oplus V) = 1$	-	-	-	-	-	-	REL	91	rr	3
BMC <i>rel</i>	Branch if Interrupt Mask Clear	Branch if (I) = 0	-	-	-	-	-	-	REL	2C	rr	3
BMI <i>rel</i>	Branch if Minus	Branch if (N) = 1	-	-	-	-	-	-	REL	2B	rr	3
BMS <i>rel</i>	Branch if Interrupt Mask Set	Branch if (I) = 1	-	-	-	-	-	-	REL	2D	rr	3
BNE <i>rel</i>	Branch if Not Equal	Branch if (Z) = 0	-	-	-	-	-	-	REL	26	rr	3
BPL <i>rel</i>	Branch if Plus	Branch if (N) = 0	-	-	-	-	-	-	REL	2A	rr	3
BRA <i>rel</i>	Branch Always	No Test	-	-	-	-	-	-	REL	20	rr	3

Table 8-2. HCS08 Instruction Set Summary (Sheet 3 of 7)

Source Form	Operation	Description	Effect on CCR						Address Mode	Opcode	Operand	Bus Cycles <sup>1</sup>
			V	H	I	N	Z	C				
BRCLR <i>n,opr8a,rel</i>	Branch if Bit <i>n</i> in Memory Clear	Branch if (Mn) = 0						↓	DIR (b0)	01	dd rr	5
									DIR (b1)	03	dd rr	5
									DIR (b2)	05	dd rr	5
									DIR (b3)	07	dd rr	5
									DIR (b4)	09	dd rr	5
									DIR (b5)	0B	dd rr	5
									DIR (b6)	0D	dd rr	5
						DIR (b7)	0F	dd rr	5			
BRN <i>rel</i>	Branch Never	Uses 3 Bus Cycles	-	-	-	-	-	REL	21	rr	3	
BRSET <i>n,opr8a,rel</i>	Branch if Bit <i>n</i> in Memory Set	Branch if (Mn) = 1						↓	DIR (b0)	00	dd rr	5
									DIR (b1)	02	dd rr	5
									DIR (b2)	04	dd rr	5
									DIR (b3)	06	dd rr	5
									DIR (b4)	08	dd rr	5
									DIR (b5)	0A	dd rr	5
									DIR (b6)	0C	dd rr	5
						DIR (b7)	0E	dd rr	5			
BSET <i>n,opr8a</i>	Set Bit <i>n</i> in Memory	Mn ← 1							DIR (b0)	10	dd rr	5
									DIR (b1)	12	dd rr	5
									DIR (b2)	14	dd rr	5
									DIR (b3)	16	dd rr	5
									DIR (b4)	18	dd rr	5
									DIR (b5)	1A	dd rr	5
									DIR (b6)	1C	dd rr	5
						DIR (b7)	1E	dd	5			
BSR <i>rel</i>	Branch to Subroutine	PC ← (PC) + 0x0002 push (PCL); SP ← (SP) - 0x0001 push (PCH); SP ← (SP) - 0x0001 PC ← (PC) + <i>rel</i>	-	-	-	-	-	REL	AD	rr	5	
CALL <i>page, opr16a</i>	Call Subroutine	PC ← PC + 4 Push (PCL); SP ← (SP) - 0x0001 Push (PCH); SP ← (SP) - 0x0001 Push (PPAGE); SP ← (SP) - 0x0001 PPAGE ← <i>page</i> PC ← Unconditional Address	-	-	-	-	-	EXT	AC	pghll	8	
CBEQ <i>opr8a,rel</i> CBEQA # <i>opr8i,rel</i> CBEQX # <i>opr8i,rel</i> CBEQ <i>opr8,X+,rel</i> CBEQ <i>,X+,rel</i> CBEQ <i>opr8,SP,rel</i>	Compare and Branch if Equal	Branch if (A) = (M) Branch if (A) = (M) Branch if (X) = (M) Branch if (A) = (M) Branch if (A) = (M) Branch if (A) = (M)							DIR	31	dd rr	5
									IMM	41	ii rr	4
									IMM	51	ii rr	4
									IX1+	61	ff rr	5
									IX+ SP1	71 9E61	rr ff	rr
CLC	Clear Carry Bit	C ← 0	-	-	-	-	0	INH	98		1	
CLI	Clear Interrupt Mask Bit	I ← 0	-	-	0	-	-	INH	9A		1	
CLR <i>opr8a</i> CLRA CLR X CLR H CLR <i>opr8,X</i> CLR <i>,X</i> CLR <i>opr8,SP</i>	Clear	M ← 0x00 A ← 0x00 X ← 0x00 H ← 0x00 M ← 0x00 M ← 0x00 M ← 0x00							DIR	3F	dd	5
									INH	4F		1
									INH	5F		1
									INH	8C		1
									IX1	6F	ff	5
									IX	7F		4
									SP1	9E6F	ff	6
CMP # <i>opr8i</i> CMP <i>opr8a</i> CMP <i>opr16a</i> CMP <i>opr16,X</i> CMP <i>opr8,X</i> CMP <i>,X</i> CMP <i>opr16,SP</i> CMP <i>opr8,SP</i>	Compare Accumulator with Memory	(A) - (M) (CCR Updated But Operands Not Changed)	↓					↓	IMM	A1	ii	2
									DIR	B1	dd	3
									EXT	C1	hh ll	4
									IX2	D1	ee ff	4
									IX1	E1	ff	3
									IX	F1		3
									SP2 SP1	9ED1 9EE1	ee ff ff	5 4

Table 8-2. HCS08 Instruction Set Summary (Sheet 4 of 7)

Source Form	Operation	Description	Effect on CCR						Address Mode	Opcode	Operand	Bus Cycles <sup>1</sup>
			V	H	I	N	Z	C				
COM <i>opr8a</i> COMA COMX COM <i>opr8,X</i> COM <i>,X</i> COM <i>opr8,SP</i>	Complement (One's Complement)	$M \leftarrow (\overline{M}) = 0xFF - (M)$ $A \leftarrow (\overline{A}) = 0xFF - (A)$ $X \leftarrow (\overline{X}) = 0xFF - (X)$ $M \leftarrow (\overline{M}) = 0xFF - (M)$ $M \leftarrow (\overline{M}) = 0xFF - (M)$ $M \leftarrow (\overline{M}) = 0xFF - (M)$	0	-	-	↓	↓	1	DIR INH INH IX1 IX SP1	33 43 53 63 73 9E63	dd ff ff	5 1 1 5 4 6
CPHX <i>opr16a</i> CPHX <i>#opr16i</i> CPHX <i>opr8a</i> CPHX <i>opr8,SP</i>	Compare Index Register (H:X) with Memory	(H:X) - (M:M + 0x0001) (CCR Updated But Operands Not Changed)	↓	-	-	↓	↓	↓	EXT IMM DIR SP1	3E 65 75 9EF3	hh ll jj kk dd ff	6 3 5 6
CPX <i>#opr8i</i> CPX <i>opr8a</i> CPX <i>opr16a</i> CPX <i>opr8,X</i> CPX <i>opr8,X</i> CPX <i>,X</i> CPX <i>opr8,SP</i> CPX <i>opr16,SP</i> CPX <i>opr8,SP</i>	Compare X (Index Register Low) with Memory	(X) - (M) (CCR Updated But Operands Not Changed)	↓	-	-	↓	↓	↓	IMM DIR EXT IX2 IX1 IX SP2 SP1	A3 B3 C3 D3 E3 F3 9ED3 9EE3	ii dd hh ll ee ff ff ff ee ff ff	2 3 4 4 3 3 5 4
DAA	Decimal Adjust Accumulator After ADD or ADC of BCD Values	(A) <sub>10</sub>	U	-	-	↓	↓	↓	INH	72		1
DBNZ <i>opr8a,rel</i> DBNZ <i>rel</i> DBNZX <i>rel</i> DBNZ <i>opr8,X,rel</i> DBNZ <i>,X,rel</i> DBNZ <i>opr8,SP,rel</i>	Decrement and Branch if Not Zero	Decrement A, X, or M Branch if (result) ≠ 0 DBNZX Affects X Not H	-	-	-	-	-	-	DIR INH INH IX1 IX SP1	3B 4B 5B 6B 7B 9E6B	dd rr rr rr rr rr ff rr ff rr ff rr	7 4 4 7 6 8
DEC <i>opr8a</i> DECA DECX DEC <i>opr8,X</i> DEC <i>,X</i> DEC <i>opr8,SP</i>	Decrement	$M \leftarrow (M) - 0x01$ $A \leftarrow (A) - 0x01$ $X \leftarrow (X) - 0x01$ $M \leftarrow (M) - 0x01$ $M \leftarrow (M) - 0x01$ $M \leftarrow (M) - 0x01$	↓	-	-	↓	↓	-	DIR INH INH IX1 IX SP1	3A 4A 5A 6A 7A 9E6A	dd ff ff ff ff	5 1 1 5 4 6
DIV	Divide	$A \leftarrow (H:A) \div (X)$ H ← Remainder	-	-	-	-	↓	↓	INH	52		6
EOR <i>#opr8i</i> EOR <i>opr8a</i> EOR <i>opr16a</i> EOR <i>opr8,X</i> EOR <i>opr8,X</i> EOR <i>,X</i> EOR <i>opr8,SP</i> EOR <i>opr8,SP</i>	Exclusive OR Memory with Accumulator	$A \leftarrow (A \oplus M)$	0	-	-	↓	↓	-	IMM DIR EXT IX2 IX1 IX SP2 SP1	A8 B8 C8 D8 E8 F8 9ED8 9EE8	ii dd hh ll ee ff ff ff ee ff ff	2 3 4 4 3 3 5 4
INC <i>opr8a</i> INCA INCX INC <i>opr8,X</i> INC <i>,X</i> INC <i>opr8,SP</i>	Increment	$M \leftarrow (M) + 0x01$ $A \leftarrow (A) + 0x01$ $X \leftarrow (X) + 0x01$ $M \leftarrow (M) + 0x01$ $M \leftarrow (M) + 0x01$ $M \leftarrow (M) + 0x01$	↓	-	-	↓	↓	-	DIR INH INH IX1 IX SP1	3C 4C 5C 6C 7C 9E6C	dd ff ff ff ff	5 1 1 5 4 6
JMP <i>opr8a</i> JMP <i>opr16a</i> JMP <i>opr8,X</i> JMP <i>opr8,X</i> JMP <i>,X</i>	Jump	PC ← Jump Address	-	-	-	-	-	-	DIR EXT IX2 IX1 IX	BC CC DC EC FC	dd ll hh ll ee ff ff	3 4 4 3 3
JSR <i>opr8a</i> JSR <i>opr16a</i> JSR <i>opr8,X</i> JSR <i>opr8,X</i> JSR <i>,X</i>	Jump to Subroutine	PC ← (PC) + n (n = 1, 2, or 3) Push (PCL); SP ← (SP) - 0x0001 Push (PCH); SP ← (SP) - 0x0001 PC ← Unconditional Address	-	-	-	-	-	-	DIR EXT IX2 IX1 IX	BD CD DD ED FD	dd ll hh ll ee ff ff	5 6 6 5 5



Table 8-2. HCS08 Instruction Set Summary (Sheet 5 of 7)

Source Form	Operation	Description	Effect on CCR						Address Mode	Opcode	Operand	Bus Cycles <sup>1</sup>
			V	H	I	N	Z	C				
LDA #opr8i LDA opr8a LDA opr16a LDA oprx16,X LDA oprx8,X LDA ,X LDA oprx16,SP LDA oprx8,SP	Load Accumulator from Memory	$A \leftarrow (M)$	0	-	-	↑	↓	-	IMM DIR EXT IX2 IX1 IX SP2 SP1	A6 B6 C6 D6 E6 F6 9ED6 9EE6	ii dd hh ll ee ff ff ff ff ff	2 3 4 4 3 3 5 4
LDHX #opr16i LDHX opr8a LDHX opr16a LDHX ,X LDHX oprx16,X LDHX oprx8,X LDHX oprx8,SP	Load Index Register (H:X) from Memory	$H:X \leftarrow (M:M + 0x0001)$	0	-	-	↑	↓	-	IMM DIR EXT IX IX2 IX1 SP1	45 55 32 9EAE 9EBE 9ECE 9EFE	jj kk dd ll hh ll ff ff ff ff	3 4 5 5 6 5 5
LDX #opr8i LDX opr8a LDX opr16a LDX oprx16,X LDX oprx8,X LDX ,X LDX oprx16,SP LDX oprx8,SP	Load X (Index Register Low) from Memory	$X \leftarrow (M)$	0	-	-	↑	↓	-	IMM DIR EXT IX2 IX1 IX SP2 SP1	AE BE CE DE EE FE 9EDE 9EEE	ii dd hh ll ee ff ff ff ff ff	2 3 4 4 3 3 5 4
LSL opr8a LSLA LSLX LSL oprx8,X LSL ,X LSL oprx8,SP	Logical Shift Left (Same as ASL)		↑	-	-	↑	↓	↓	DIR INH INH IX1 IX SP1	38 48 58 68 78 9E68	dd ll ll ff ff ff	5 1 1 5 4 6
LSR opr8a LSRA LSRX LSR oprx8,X LSR ,X LSR oprx8,SP	Logical Shift Right		↑	-	-	0	↑	↓	DIR INH INH IX1 IX SP1	34 44 54 64 74 9E64	dd ll ll ff ff ff	5 1 1 5 4 6
MOV opr8a,opr8a MOV opr8a,X+ MOV #opr8i,opr8a MOV ,X+,opr8a	Move	$(M)_{\text{destination}} \leftarrow (M)_{\text{source}}$ $H:X \leftarrow (H:X) + 0x0001$ in IX+/DIR and DIR/IX+ Modes	0	-	-	↑	↓	-	DIR/DIR DIR/IX+ IMM/DIR IX+/DIR	4E 5E 6E 7E	dd dd dd dd ii dd dd	5 5 4 5
MUL	Unsigned multiply	$X:A \leftarrow (X) \times (A)$	-	0	-	-	-	0	INH	42		5
NEG opr8a NEGA NEGX NEG oprx8,X NEG ,X NEG oprx8,SP	Negate (Two's Complement)	$M \leftarrow -(M) = 0x00 - (M)$ $A \leftarrow -(A) = 0x00 - (A)$ $X \leftarrow -(X) = 0x00 - (X)$ $M \leftarrow -(M) = 0x00 - (M)$ $M \leftarrow -(M) = 0x00 - (M)$ $M \leftarrow -(M) = 0x00 - (M)$		-	-	↑	↓	↓	DIR INH INH IX1 IX SP1	30 40 50 60 70 9E60	dd ll ll ff ff ff	5 1 1 5 4 6
NOP	No Operation	Uses 1 Bus Cycle	-	-	-	-	-	-	INH	9D		1
NSA	Nibble Swap Accumulator	$A \leftarrow (A[3:0]:A[7:4])$	-	-	-	-	-	-	INH	62		1
ORA #opr8i ORA opr8a ORA opr16a ORA oprx16,X ORA oprx8,X ORA ,X ORA oprx16,SP ORA oprx8,SP	Inclusive OR Accumulator and Memory	$A \leftarrow (A)   (M)$	0	-	-	↑	↓	-	IMM DIR EXT IX2 IX1 IX SP2 SP1	AA BA CA DA EA FA 9EDA 9EEA	ii dd hh ll ee ff ff ff ff ff	2 3 4 4 3 3 5 4
PSHA	Push Accumulator onto Stack	Push (A); $SP \leftarrow (SP) - 0x0001$	-	-	-	-	-	-	INH	87		2
PSHH	Push H (Index Register High) onto Stack	Push (H); $SP \leftarrow (SP) - 0x0001$	-	-	-	-	-	-	INH	8B		2
PSHX	Push X (Index Register Low) onto Stack	Push (X); $SP \leftarrow (SP) - 0x0001$	-	-	-	-	-	-	INH	89		2

Table 8-2. HCS08 Instruction Set Summary (Sheet 6 of 7)

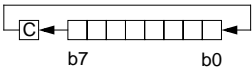
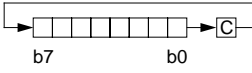
Source Form	Operation	Description	Effect on CCR						Address Mode	Opcode	Operand	Bus Cycles <sup>1</sup>
			V	H	I	N	Z	C				
PULA	Pull Accumulator from Stack	$SP \leftarrow (SP + 0x0001)$ ; Pull (A)	-	-	-	-	-	-	INH	86		3
PULH	Pull H (Index Register High) from Stack	$SP \leftarrow (SP + 0x0001)$ ; Pull (H)	-	-	-	-	-	-	INH	8A		3
PULX	Pull X (Index Register Low) from Stack	$SP \leftarrow (SP + 0x0001)$ ; Pull (X)	-	-	-	-	-	-	INH	88		3
ROL <i>opr8a</i> ROLA ROLX ROL <i>opr8,X</i> ROL <i>,X</i> ROL <i>opr8,SP</i>	Rotate Left through Carry		↑	-	-	↓	↓	↓	DIR INH INH IX1 IX SP1	39 49 59 69 79 9E69	dd ff ff	5 1 1 5 4 6
ROR <i>opr8a</i> RORA RORX ROR <i>opr8,X</i> ROR <i>,X</i> ROR <i>opr8,SP</i>	Rotate Right through Carry		↓	-	-	↑	↑	↑	DIR INH INH IX1 IX SP1	36 46 56 66 76 9E66	dd ff ff	5 1 1 5 4 6
RSP	Reset Stack Pointer	$SP \leftarrow 0xFF$ (High Byte Not Affected)	-	-	-	-	-	-	INH	9C		1
RTC	Return from CALL	$SP \leftarrow (SP) + 0x0001$ ; Pull (PPAGE) $SP \leftarrow (SP) + 0x0001$ ; Pull (PCH) $SP \leftarrow (SP) + 0x0001$ ; Pull (PCL)	-	-	-	-	-	-	INH	8D		7
RTI	Return from Interrupt	$SP \leftarrow (SP) + 0x0001$ ; Pull (CCR) $SP \leftarrow (SP) + 0x0001$ ; Pull (A) $SP \leftarrow (SP) + 0x0001$ ; Pull (X) $SP \leftarrow (SP) + 0x0001$ ; Pull (PCH) $SP \leftarrow (SP) + 0x0001$ ; Pull (PCL)	↑	↑	↑	↑	↑	↑	INH	80		9
RTS	Return from Subroutine	$SP \leftarrow SP + 0x0001$ ; Pull (PCH) $SP \leftarrow SP + 0x0001$ ; Pull (PCL)	-	-	-	-	-	-	INH	81		6
SBC <i>#opr8i</i> SBC <i>opr8a</i> SBC <i>opr16a</i> SBC <i>opr16,X</i> SBC <i>opr8,X</i> SBC <i>,X</i> SBC <i>opr16,SP</i> SBC <i>opr8,SP</i>	Subtract with Carry	$A \leftarrow (A) - (M) - (C)$	↑	-	-	↓	↓	↓	IMM DIR EXT IX2 IX1 IX SP2 SP1	A2 B2 C2 D2 E2 F2 9ED2 9EE2	ii dd hh ll ee ff ff ff ee ff ff	2 3 4 4 3 3 5 4
SEC	Set Carry Bit	$C \leftarrow 1$	-	-	-	-	-	1	INH	99		1
SEI	Set Interrupt Mask Bit	$I \leftarrow 1$	-	-	1	-	-	-	INH	9B		1
STA <i>opr8a</i> STA <i>opr16a</i> STA <i>opr16,X</i> STA <i>opr8,X</i> STA <i>,X</i> STA <i>opr16,SP</i> STA <i>opr8,SP</i>	Store Accumulator in Memory	$M \leftarrow (A)$	0	-	-	↓	↓	-	DIR EXT IX2 IX1 IX SP2 SP1	B7 C7 D7 E7 F7 9ED7 9EE7	dd hh ll ee ff ff ff ee ff ff	3 4 4 3 2 5 4
STHX <i>opr8a</i> STHX <i>opr16a</i> STHX <i>opr8,SP</i>	Store H:X (Index Reg.)	$(M:M + 0x0001) \leftarrow (H:X)$	0	-	-	↓	↓	-	DIR EXT SP1	35 96 9EFF	dd hh ll ff	4 5 5
STOP	Enable Interrupts: Stop Processing Refer to MCU Documentation	$I \text{ bit} \leftarrow 0$ ; Stop Processing	-	-	0	-	-	-	INH	8E		2+
STX <i>opr8a</i> STX <i>opr16a</i> STX <i>opr16,X</i> STX <i>opr8,X</i> STX <i>,X</i> STX <i>opr16,SP</i> STX <i>opr8,SP</i>	Store X (Low 8 Bits of Index Register) in Memory	$M \leftarrow (X)$	0	-	-	↓	↓	-	DIR EXT IX2 IX1 IX SP2 SP1	BF CF DF EF FF 9EDF 9EEF	dd hh ll ee ff ff ff ee ff ff	3 4 4 3 2 5 4

Table 8-2. HCS08 Instruction Set Summary (Sheet 7 of 7)

Source Form	Operation	Description	Effect on CCR						Address Mode	Opcode	Operand	Bus Cycles <sup>1</sup>
			V	H	I	N	Z	C				
SUB #opr8i SUB opr8a SUB opr16a SUB oprx16,X SUB oprx8,X SUB ,X SUB oprx16,SP SUB oprx8,SP	Subtract	$A \leftarrow (A) - (M)$	↓	-	-	↓	↓	↓	IMM DIR EXT IX2 IX1 IX SP2 SP1	A0 B0 C0 D0 E0 F0 9ED0 9EE0	ii dd hh ll ee ff ff ee ff ff	2 3 4 4 3 3 5 4
SWI	Software Interrupt	$PC \leftarrow (PC) + 0x0001$ Push (PCL); $SP \leftarrow (SP) - 0x0001$ Push (PCH); $SP \leftarrow (SP) - 0x0001$ Push (X); $SP \leftarrow (SP) - 0x0001$ Push (A); $SP \leftarrow (SP) - 0x0001$ Push (CCR); $SP \leftarrow (SP) - 0x0001$ $I \leftarrow 1$ ; PCH ← Interrupt Vector High Byte PCL ← Interrupt Vector Low Byte	-	-	1	-	-	-	INH	83		11
TAP	Transfer Accumulator to CCR	$CCR \leftarrow (A)$	↓	↓	↓	↓	↓	↓	INH	84		1
TAX	Transfer Accumulator to X (Index Register Low)	$X \leftarrow (A)$	-	-	-	-	-	-	INH	97		1
TPA	Transfer CCR to Accumulator	$A \leftarrow (CCR)$	-	-	-	-	-	-	INH	85		1
TST opr8a TSTA TSTX TST oprx8,X TST ,X TST oprx8,SP	Test for Negative or Zero	$(M) - 0x00$ $(A) - 0x00$ $(X) - 0x00$ $(M) - 0x00$ $(M) - 0x00$ $(M) - 0x00$	0	-	-	↓	↓	-	DIR INH INH IX1 IX SP1	3D 4D 5D 6D 7D 9E6D	dd ff ff	4 1 1 4 3 5
TSX	Transfer SP to Index Reg.	$H:X \leftarrow (SP) + 0x0001$	-	-	-	-	-	-	INH	95		2
TXA	Transfer X (Index Reg. Low) to Accumulator	$A \leftarrow (X)$	-	-	-	-	-	-	INH	9F		1
TXS	Transfer Index Reg. to SP	$SP \leftarrow (H:X) - 0x0001$	-	-	-	-	-	-	INH	94		2
WAIT	Enable Interrupts; Wait for Interrupt	$I \text{ bit} \leftarrow 0$ ; Halt CPU	-	-	0	-	-	-	INH	8F		2+

<sup>1</sup> Bus clock frequency is one-half of the CPU clock frequency.

Table 8-3. Opcode Map (Sheet 1 of 2)

Bit-Manipulation		Branch		Read-Modify-Write				Control				Register/Memory					
00 5 BRSET0 3 DIR	10 5 BSET0 2 DIR	20 3 BRA 2 REL	30 5 NEG 2 DIR	40 1 NEGA 1 INH	50 1 NEGX 1 INH	60 5 NEG 2 IX1	70 4 NEG 1 IX	80 9 RTI 1 INH	90 3 BGE 2 REL	A0 2 SUB 2 IMM	B0 3 SUB 2 DIR	C0 4 SUB 3 EXT	D0 4 SUB 3 IX2	E0 3 SUB 2 IX1	F0 3 SUB 1 IX		
01 5 BRCLR0 3 DIR	11 5 BCLR0 2 DIR	21 3 BRN 2 REL	31 5 CBEQ 3 DIR	41 4 CBEQA 3 IMM	51 4 CBEQX 3 IMM	61 5 CBEQ 3 IX1+	71 5 CBEQ 2 IX+	81 6 RTS 1 INH	91 3 BLT 2 REL	A1 2 CMP 2 IMM	B1 3 CMP 2 DIR	C1 4 CMP 3 EXT	D1 4 CMP 3 IX2	E1 3 CMP 2 IX1	F1 3 CMP 1 IX		
02 5 BRSET1 3 DIR	12 5 BSET1 2 DIR	22 3 BHI 2 REL	32 5 LDHX 3 EXT	42 5 MUL 1 INH	52 6 DIV 1 INH	62 1 NSA 1 INH	72 1 DAA 1 INH	82 5+ BGND 1 INH	92 3 BGT 2 REL	A2 2 SBC 2 IMM	B2 3 SBC 2 DIR	C2 4 SBC 3 EXT	D2 4 SBC 3 IX2	E2 3 SBC 2 IX1	F2 3 SBC 1 IX		
03 5 BRCLR1 3 DIR	13 5 BCLR1 2 DIR	23 3 BLS 2 REL	33 5 COM 2 DIR	43 1 COMA 1 INH	53 1 COMX 1 INH	63 5 COM 2 IX1	73 4 COM 1 IX	83 11 SWI 1 INH	93 3 BLE 2 REL	A3 2 CPX 2 IMM	B3 3 CPX 2 DIR	C3 4 CPX 3 EXT	D3 4 CPX 3 IX2	E3 3 CPX 2 IX1	F3 3 CPX 1 IX		
04 5 BRSET2 3 DIR	14 5 BSET2 2 DIR	24 3 BCC 2 REL	34 5 LSR 2 DIR	44 1 LSRA 1 INH	54 1 LSRX 1 INH	64 5 LSR 2 IX1	74 4 LSR 1 IX	84 1 TAP 1 INH	94 2 TXS 1 INH	A4 2 AND 2 IMM	B4 3 AND 2 DIR	C4 4 AND 3 EXT	D4 4 AND 3 IX2	E4 3 AND 2 IX1	F4 3 AND 1 IX		
05 5 BRCLR2 3 DIR	15 5 BCLR2 2 DIR	25 3 BCS 2 REL	35 4 STHX 2 DIR	45 3 LDHX 3 IMM	55 4 LDHX 2 DIR	65 3 CPHX 3 IMM	75 5 CPHX 2 DIR	85 1 TPA 1 INH	95 2 TSX 1 INH	A5 2 BIT 2 IMM	B5 3 BIT 2 DIR	C5 4 BIT 3 EXT	D5 4 BIT 3 IX2	E5 3 BIT 2 IX1	F5 3 BIT 1 IX		
06 5 BRSET3 3 DIR	16 5 BSET3 2 DIR	26 3 BNE 2 REL	36 5 ROR 2 DIR	46 1 RORA 1 INH	56 1 RORX 1 INH	66 5 ROR 2 IX1	76 4 ROR 1 IX	86 3 PULA 1 INH	96 5 STHX 3 EXT	A6 2 LDA 2 IMM	B6 3 LDA 2 DIR	C6 4 LDA 3 EXT	D6 4 LDA 3 IX2	E6 3 LDA 2 IX1	F6 3 LDA 1 IX		
07 5 BRCLR3 3 DIR	17 5 BCLR3 2 DIR	27 3 BEQ 2 REL	37 5 ASR 2 DIR	47 1 ASRA 1 INH	57 1 ASRX 1 INH	67 5 ASR 2 IX1	77 4 ASR 1 IX	87 2 PSHA 1 INH	97 1 TAX 1 INH	A7 2 AIS 2 IMM	B7 3 STA 2 DIR	C7 4 STA 3 EXT	D7 4 STA 3 IX2	E7 3 STA 2 IX1	F7 2 STA 1 IX		
08 5 BRSET4 3 DIR	18 5 BSET4 2 DIR	28 3 BHCC 2 REL	38 5 LSL 2 DIR	48 1 LSLA 1 INH	58 1 LSLX 1 INH	68 5 LSL 2 IX1	78 4 LSL 1 IX	88 3 PULX 1 INH	98 1 CLC 1 INH	A8 2 EOR 2 IMM	B8 3 EOR 2 DIR	C8 4 EOR 3 EXT	D8 4 EOR 3 IX2	E8 3 EOR 2 IX1	F8 3 EOR 1 IX		
09 5 BRCLR4 3 DIR	19 5 BCLR4 2 DIR	29 3 BHCS 2 REL	39 5 ROL 2 DIR	49 1 ROLA 1 INH	59 1 ROLX 1 INH	69 5 ROL 2 IX1	79 4 ROL 1 IX	89 2 PSHX 1 INH	99 1 SEC 1 INH	A9 2 ADC 2 IMM	B9 3 ADC 2 DIR	C9 4 ADC 3 EXT	D9 4 ADC 3 IX2	E9 3 ADC 2 IX1	F9 3 ADC 1 IX		
0A 5 BRSET5 3 DIR	1A 5 BSET5 2 DIR	2A 3 BPL 2 REL	3A 5 DEC 2 DIR	4A 1 DECA 1 INH	5A 1 DECX 1 INH	6A 5 DEC 2 IX1	7A 4 DEC 1 IX	8A 3 PULH 1 INH	9A 1 CLI 1 INH	AA 2 ORA 2 IMM	BA 3 ORA 2 DIR	CA 4 ORA 3 EXT	DA 4 ORA 3 IX2	EA 3 ORA 2 IX1	FA 3 ORA 1 IX		
0B 5 BRCLR5 3 DIR	1B 5 BCLR5 2 DIR	2B 3 BMI 2 REL	3B 7 DBNZ 3 DIR	4B 4 DBNZA 2 INH	5B 4 DBNZX 2 INH	6B 7 DBNZ 3 IX1	7B 6 DBNZ 2 IX	8B 2 PSHH 1 INH	9B 1 SEI 1 INH	AB 2 ADD 2 IMM	BB 3 ADD 2 DIR	CB 4 ADD 3 EXT	DB 4 ADD 3 IX2	EB 3 ADD 2 IX1	FB 3 ADD 1 IX		
0C 5 BRSET6 3 DIR	1C 5 BSET6 2 DIR	2C 3 BMC 2 REL	3C 5 INC 2 DIR	4C 1 INCA 1 INH	5C 1 INCX 1 INH	6C 5 INC 2 IX1	7C 4 INC 1 IX	8C 1 CLRH 1 INH	9C 1 RSP 1 INH	AC 8 CALL 4 EXT	BC 3 JMP 2 DIR	CC 4 JMP 3 EXT	DC 4 JMP 3 IX2	EC 3 JMP 2 IX1	FC 3 JMP 1 IX		
0D 5 BRCLR6 3 DIR	1D 5 BCLR6 2 DIR	2D 3 BMS 2 REL	3D 4 TST 2 DIR	4D 1 TSTA 1 INH	5D 1 TSTX 1 INH	6D 4 TST 2 IX1	7D 3 TST 1 IX	8D 7 RTC 1 INH	9D 1 NOP 1 INH	AD 5 BSR 2 REL	BD 5 JSR 2 DIR	CD 6 JSR 3 EXT	DD 6 JSR 3 IX2	ED 5 JSR 2 IX1	FD 5 JSR 1 IX		
0E 5 BRSET7 3 DIR	1E 5 BSET7 2 DIR	2E 3 BIL 2 REL	3E 6 CPHX 3 EXT	4E 5 MOV 3 DD	5E 5 MOV 2 DIX+	6E 4 MOV 3 IMD	7E 5 MOV 2 IX+D	8E 2+ STOP 1 INH	9E Page 2	AE 2 LDX 2 IMM	BE 3 LDX 2 DIR	CE 4 LDX 3 EXT	DE 4 LDX 3 IX2	EE 3 LDX 2 IX1	FE 3 LDX 1 IX		
0F 5 BRCLR7 3 DIR	1F 5 BCLR7 2 DIR	2F 3 BIH 2 REL	3F 5 CLR 2 DIR	4F 1 CLRA 1 INH	5F 1 CLR 1 INH	6F 5 CLR 2 IX1	7F 4 CLR 1 IX	8F 2+ WAIT 1 INH	9F 1 TXA 1 INH	AF 2 AIX 2 IMM	BF 3 STX 2 DIR	CF 4 STX 3 EXT	DF 4 STX 3 IX2	EF 3 STX 2 IX1	FF 2 STX 1 IX		

INH Inherent  
 IMM Immediate  
 DIR Direct  
 EXT Extended  
 DD DIR to DIR  
 IX+D IX+ to DIR  
 REL Relative  
 IX Indexed, No Offset  
 IX1 Indexed, 8-Bit Offset  
 IX2 Indexed, 16-Bit Offset  
 IMM IMM to DIR  
 DIX+ DIR to IX+  
 SP1 Stack Pointer, 8-Bit Offset  
 SP2 Stack Pointer, 16-Bit Offset  
 IX+ Indexed, No Offset with Post Increment  
 IX1+ Indexed, 1-Byte Offset with Post Increment

Opcode in Hexadecimal F0 SUB 3  
 Number of Bytes 1 IX  
 HCS08 Cycles Instruction Mnemonic Addressing Mode

**Table 8-3. Opcode Map (Sheet 2 of 2)**

Bit-Manipulation	Branch	Read-Modify-Write			Control			Register/Memory						
				9E60 NEG 3 SP1						9ED0 SUB 4 SP2	9EE0 SUB 3 SP1			
				9E61 CBEQ 4 SP1						9ED1 CMP 4 SP2	9EE1 CMP 3 SP1			
										9ED2 SBC 4 SP2	9EE2 SBC 3 SP1			
				9E63 COM 3 SP1						9ED3 CPX 4 SP2	9EE3 CPX 3 SP1	9EF3 CPHX 3 SP1		
				9E64 LSR 3 SP1						9ED4 AND 4 SP2	9EE4 AND 3 SP1			
										9ED5 BIT 4 SP2	9EE5 BIT 3 SP1			
				9E66 ROR 3 SP1						9ED6 LDA 4 SP2	9EE6 LDA 3 SP1			
				9E67 ASR 3 SP1						9ED7 STA 4 SP2	9EE7 STA 3 SP1			
				9E68 LSL 3 SP1						9ED8 EOR 4 SP2	9EE8 EOR 3 SP1			
				9E69 ROL 3 SP1						9ED9 ADC 4 SP2	9EE9 ADC 3 SP1			
				9E6A DEC 3 SP1						9EDA ORA 4 SP2	9EEA ORA 3 SP1			
				9E6B DBNZ 4 SP1						9EDB ADD 4 SP2	9EEB ADD 3 SP1			
				9E6C INC 3 SP1										
				9E6D TST 3 SP1										
									9EAE LDHX 2 IX	9EBE LDHX 4 IX2	9ECE LDHX 3 IX1	9EDE LDX 4 SP2	9EEE LDX 3 SP1	9EFE LDHX 3 SP1
				9E6F CLR 3 SP1						9EDF STX 4 SP2	9EEF STX 3 SP1	9EFF STHX 3 SP1		

INH Inherent      REL Relative      SP1 Stack Pointer, 8-Bit Offset  
 IMM Immediate    IX Indexed, No Offset    SP2 Stack Pointer, 16-Bit Offset  
 DIR Direct        IX1 Indexed, 8-Bit Offset    IX+ Indexed, No Offset with  
 EXT Extended     IX2 Indexed, 16-Bit Offset    Post Increment  
 DD DIR to DIR    IMD IMM to DIR            IX1+ Indexed, 1-Byte Offset with  
 IX+D IX+ to DIR    DIX+ DIR to IX+            Post Increment

Note: All Sheet 2 Opcodes are Preceded by the Page 2 Prebyte (9E)

Prebyte (9E) and Opcode in  
 Hexadecimal    9E60 6    HCS08 Cycles  
                               NEG    3    Instruction Mnemonic  
 Number of Bytes    3    SP1    Addressing Mode



## Chapter 9

# Analog Comparator 3V (ACMPVLPV1)

### 9.1 Introduction

MC9S08QE128 Series MCUs have two independent analog comparators (ACMPs), named ACMP1 and ACMP2.

The analog comparator module (ACMP) provides a circuit for comparing two analog input voltages or for comparing one analog input voltage to an internal reference voltage. The comparator circuit is designed to operate across the full range of the supply voltage (rail-to-rail operation).

Figure 9-1 shows the MC9S08QE128 Series block diagram with the ACMP highlighted.

#### NOTE

Ignore any references to stop1 low-power mode in this chapter, because the MC9S08QE128 device does not support it.

#### 9.1.1 ACMP Configuration Information

When using the bandgap reference voltage for input to ACMP1+ and/or ACMP2+, the user must enable the bandgap buffer by setting SPMS[BGBE]. For value of bandgap voltage reference see the data sheet.

#### 9.1.2 ACMP/TPM Configuration Information

The ACMP modules can be configured to connect the output of the analog comparator to a TPM input capture channel 0 by setting the corresponding ACICx bit in SOPT2. With ACICx set, the TPMxCH0 pin is not available externally regardless of the configuration of the TPMx module.

The ACMP1 output can be connected to TPM1CH0; The ACMP2 output can be connected to TPM2CH0.

#### 9.1.3 ACMP Clock Gating

The bus clock to both of the ACMPs can be gated on and off using the SCGC2[ACMP] bit. This bit is set after any reset, which enables the bus clock to this module. To conserve power, the ACMP bit can be cleared to disable the clock to this module when not in use. See Section 5.7, “Peripheral Clock Gating,” for details.

### 9.1.4 Interrupt Vectors

ACMP1 and ACMP2 share a single interrupt vector. When interrupts are enabled for both ACMPs, the ACF bit in ACMP1SC and ACMP2SC must be polled to determine which ACMP caused the interrupt. See Section 4.2, “Reset and Interrupt Vector Assignments,” for the ACMP interrupt vector assignment.



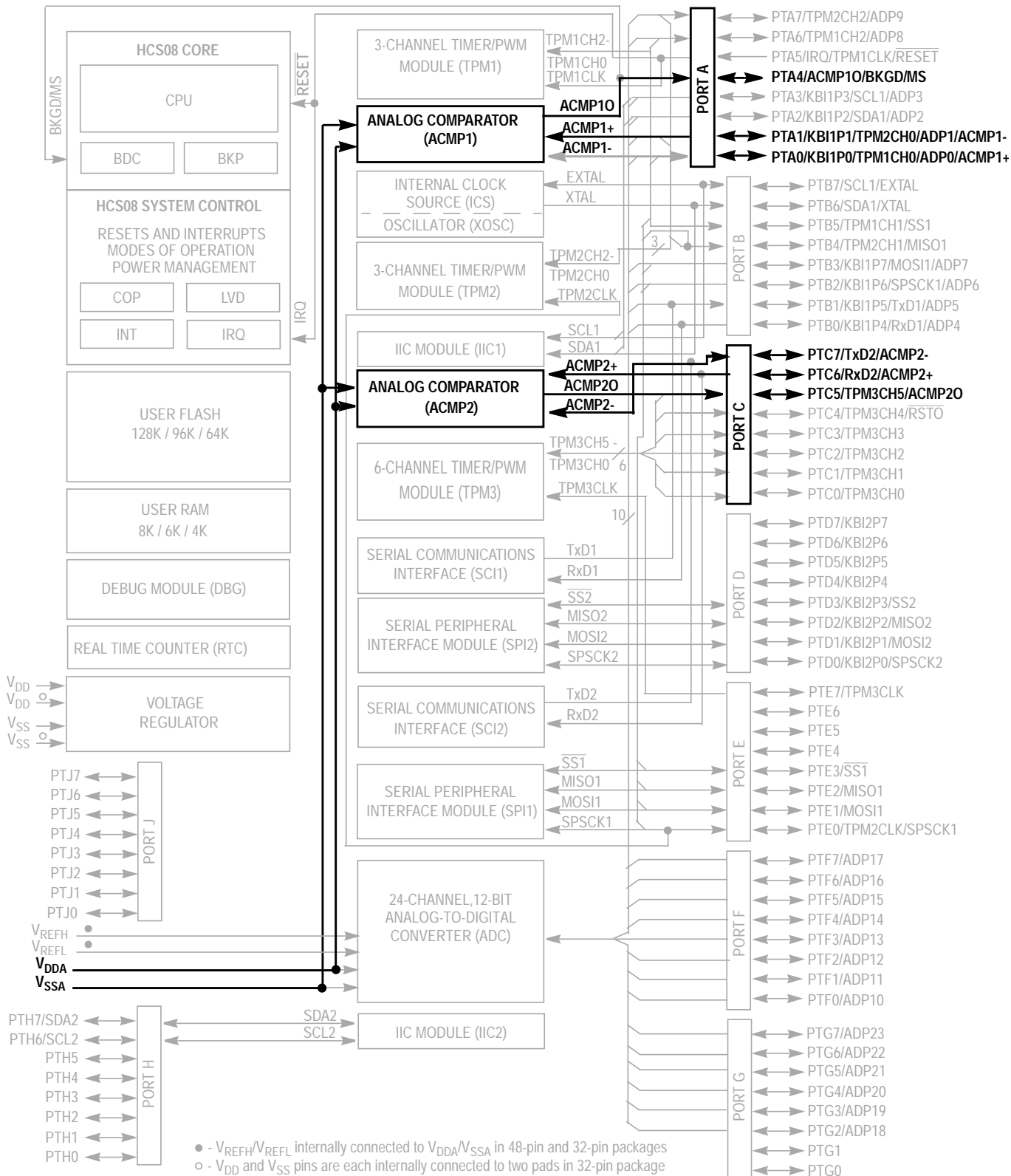


Figure 9-1. MC9S08QE128 Series Block Diagram Highlighting ACMP Block and Pins

## 9.1.5 Features

The ACMP has the following features:

- Full rail to rail supply operation.
- Selectable interrupt on rising edge, falling edge, or either rising or falling edges of comparator output.
- Option to compare to fixed internal bandgap reference voltage.
- Option to allow comparator output to be visible on a pin, ACMPxO.

## 9.1.6 Modes of Operation

This section defines the ACMP operation in wait, stop and background debug modes.

### 9.1.6.1 ACMP in Wait Mode

The ACMP continues to run in wait mode if enabled before executing the WAIT instruction. Therefore, the ACMP can be used to bring the MCU out of wait mode if the ACMP interrupt, ACIE is enabled. For lowest possible current consumption, the ACMP should be disabled by software if not required as an interrupt source during wait mode.

### 9.1.6.2 ACMP in Stop Modes

The ACMP is disabled in all stop modes, regardless of the settings before executing the STOP instruction. Therefore, the ACMP cannot be used as a wake up source from stop modes.

During either stop1 or stop2 mode, the ACMP module will be fully powered down. Upon wake-up from stop1 or stop2 mode, the ACMP module will be in the reset state.

During stop3 mode, clocks to the ACMP module are halted. No registers are affected. In addition, the ACMP comparator circuit will enter a low power state. No compare operation will occur while in stop3.

If stop3 is exited with a reset, the ACMP will be put into its reset state. If stop3 is exited with an interrupt, the ACMP continues from the state it was in when stop3 was entered.

### 9.1.6.3 ACMP in Active Background Mode

When the microcontroller is in active background mode, the ACMP will continue to operate normally.

## 9.1.7 Block Diagram

The block diagram for the Analog Comparator module is shown [Figure 9-2](#).

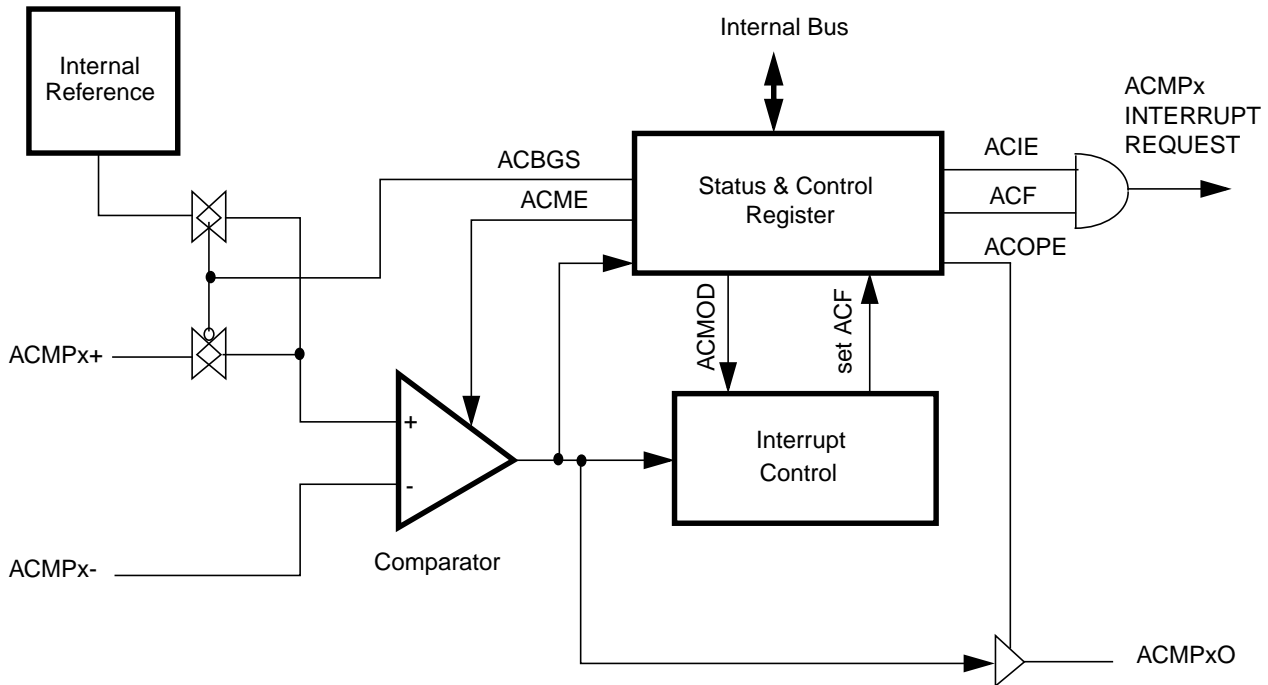


Figure 9-2. Analog Comparator (ACMP) Block Diagram

## 9.2 External Signal Description

The ACMP has two analog input pins, ACMPx+ and ACMPx- and one digital output pin ACMPxO. Each of these pins can accept an input voltage that varies across the full operating voltage range of the MCU. As shown in Figure 9-2, the ACMPx- pin is connected to the inverting input of the comparator, and the ACMPx+ pin is connected to the comparator non-inverting input if ACBGS is a 0. As shown in Figure 9-2, the ACMPxO pin can be enabled to drive an external pin.

The signal properties of ACMP are shown in Table 9-1.

Table 9-1. Signal Properties

Signal	Function	I/O
ACMPx-	Inverting analog input to the ACMP. (Minus input)	I
ACMPx+	Non-inverting analog input to the ACMP. (Positive input)	I
ACMPxO	Digital output of the ACMP.	O

## 9.3 Register Definition

The ACMP includes one register:

- An 8-bit status and control register

Refer to the direct-page register summary in the memory section of this data sheet for the absolute address assignments for the ACMP register. This section refers to register and control bits only by their names and relative address offsets.

Some MCUs may have more than one ACMP, so register names include placeholder characters to identify which ACMP is being referenced.

### 9.3.1 ACMPx Status and Control Register (ACMPxSC)

ACMPxSC contains the status flag and control bits which are used to enable and configure the ACMP.

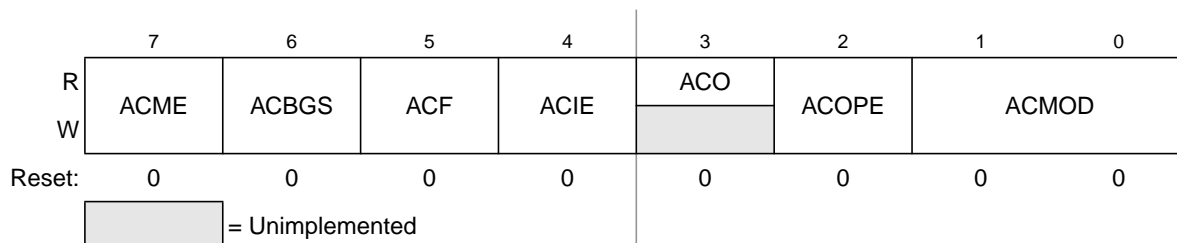


Figure 9-3. ACMPx Status and Control Register

Table 9-2. ACMPx Status and Control Register Field Descriptions

Field	Description
7 ACME	<b>Analog Comparator Module Enable</b> — ACME enables the ACMP module. 0 ACMP not enabled 1 ACMP is enabled
6 ACBGS	<b>Analog Comparator Bandgap Select</b> — ACBGS is used to select between the bandgap reference voltage or the ACMPx+ pin as the input to the non-inverting input of the analog comparator. 0 External pin ACMPx+ selected as non-inverting input to comparator 1 Internal reference select as non-inverting input to comparator
5 ACF	<b>Analog Comparator Flag</b> — ACF is set when a compare event occurs. Compare events are defined by ACMOD. ACF is cleared by writing a one to ACF. 0 Compare event has not occurred 1 Compare event has occurred
4 ACIE	<b>Analog Comparator Interrupt Enable</b> — ACIE enables the interrupt from the ACMP. When ACIE is set, an interrupt will be asserted when ACF is set. 0 Interrupt disabled 1 Interrupt enabled
3 ACO	<b>Analog Comparator Output</b> — Reading ACO will return the current value of the analog comparator output. ACO is reset to a 0 and will read as a 0 when the ACMP is disabled (ACME = 0).
2 ACOPE	<b>Analog Comparator Output Pin Enable</b> — ACOPE is used to enable the comparator output to be placed onto the external pin, ACMPxO. 0 Analog comparator output not available on ACMPxO 1 Analog comparator output is driven out on ACMPxO
1:0 ACMOD	<b>Analog Comparator Mode</b> — ACMOD selects the type of compare event which sets ACF. 00 Encoding 0 — Comparator output falling edge 01 Encoding 1 — Comparator output rising edge 10 Encoding 2 — Comparator output falling edge 11 Encoding 3 — Comparator output rising or falling edge

## 9.4 Functional Description

The analog comparator can be used to compare two analog input voltages applied to ACMP<sub>x+</sub> and ACMP<sub>x-</sub>; or it can be used to compare an analog input voltage applied to ACMP<sub>x-</sub> with an internal bandgap reference voltage. ACBGS is used to select between the bandgap reference voltage or the ACMP<sub>x+</sub> pin as the input to the non-inverting input of the analog comparator. The comparator output is high when the non-inverting input is greater than the inverting input, and is low when the non-inverting input is less than the inverting input. ACMOD is used to select the condition which will cause ACF to be set. ACF can be set on a rising edge of the comparator output, a falling edge of the comparator output, or either a rising or a falling edge (toggle). The comparator output can be read directly through ACO. The comparator output can be driven onto the ACMP<sub>xO</sub> pin using ACOPE.



## Chapter 10

# Analog-to-Digital Converter (S08ADC12V1)

### 10.1 Introduction

The 12-bit analog-to-digital converter (ADC) is a successive approximation ADC designed for operation within an integrated microcontroller system-on-chip.

Figure 10-1 shows the MC9S08QE128 Series with the ADC module and pins highlighted.

#### NOTE

Ignore any references to stop1 low-power mode in this chapter, because the MC9S08QE128 device does not support it.

#### 10.1.1 ADC Clock Gating

The bus clock to the ADC can be gated on and off using the SCGC1[ADC] bit. This bit is set after any reset, which enables the bus clock to this module. To conserve power, the ADC bit can be cleared to disable the clock to this module when not in use. See Section 5.7, “Peripheral Clock Gating,” for details.

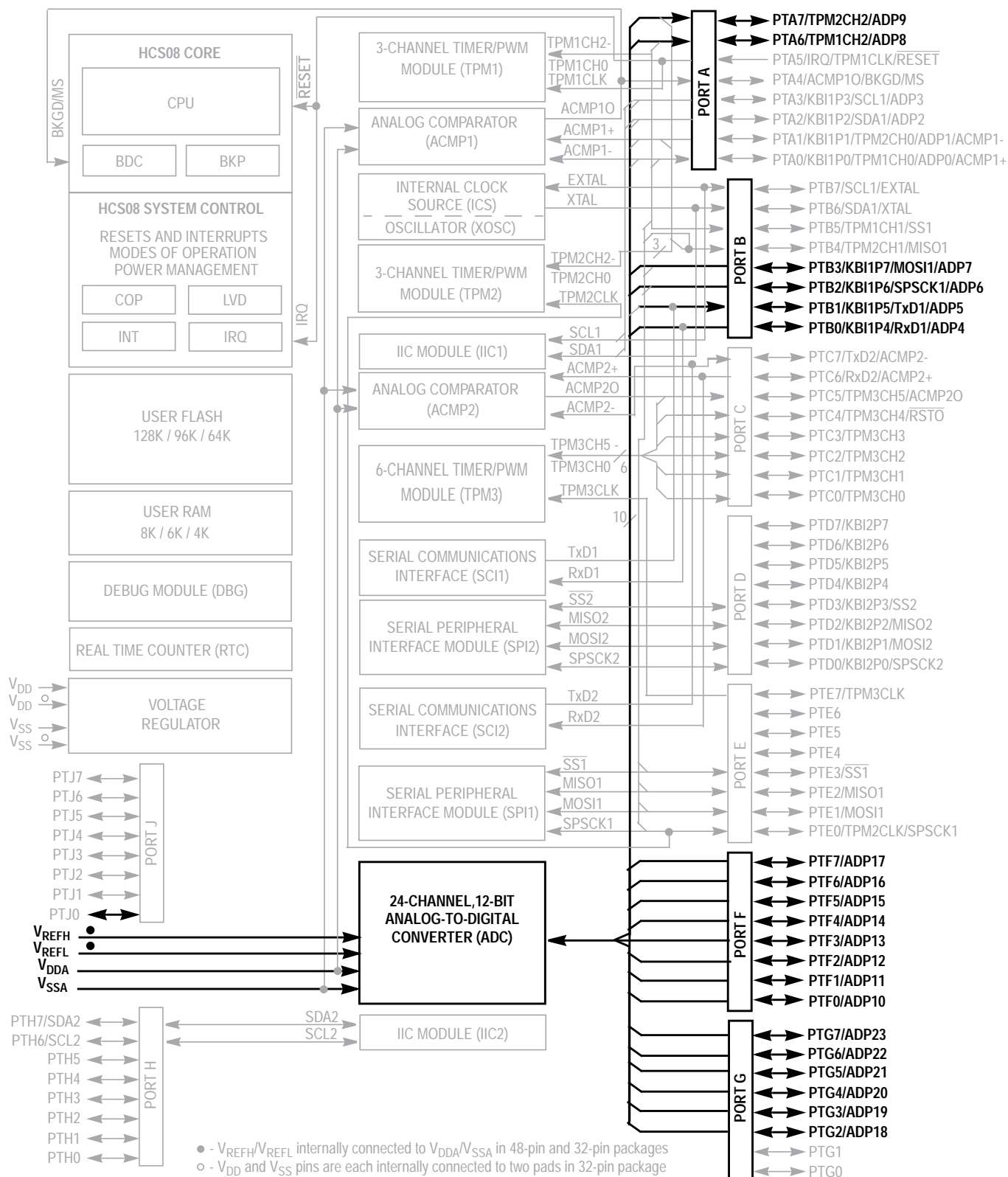


Figure 10-1. MC9S08QE128 Series Block Diagram Highlighting ADC Block and Pins



## 10.1.2 Module Configurations

This section provides device-specific information for configuring the ADC on the MC9S08QE128 Series.

### 10.1.2.1 Channel Assignments

The ADC channel assignments for the MC9S08QE128 Series devices are shown in [Table 10-1](#). Reserved channels convert to an unknown value.

**Table 10-1. ADC Channel Assignment**

ADCH	Channel	Input	Pin Control	ADCH	Channel	Input	Pin Control
00000	AD0	PTA0/ADP0	ADPC0	10000	AD16	PTF6/ADP16	N/A
00001	AD1	PTA1/ADP1	ADPC1	10001	AD17	PTF7/ADP17	N/A
00010	AD2	PTA2/ADP2	ADPC2	10010	AD18	PTG2/ADP18	N/A
00011	AD3	PTA3/ADP3	ADPC3	10011	AD19	PTG3/ADP19	N/A
00100	AD4	PTB0/ADP4	ADPC4	10100	AD20	PTG4/ADP20	N/A
00101	AD5	PTB1/ADP5	ADPC5	10101	AD21	PTG5/ADP21	N/A
00110	AD6	PTB2/ADP6	ADPC6	10110	AD22	PTG6/ADP22	N/A
00111	AD7	PTB3/ADP7	ADPC7	10111	AD23	PTG7/ADP23	N/A
01000	AD8	PTA6/ADP8	N/A	11000	AD24	Reserved	N/A
01001	AD9	PTA7/ADP9	N/A	11001	AD25	Reserved	N/A
01010	AD10	PTF0/ADP10	N/A	11010	AD26	Temperature Sensor <sup>1</sup>	N/A
01011	AD11	PTF1/ADP11	N/A	11011	AD27	Internal Bandgap	N/A
01100	AD12	PTF2/ADP12	N/A	11100	—	Reserved	N/A
01101	AD13	PTF3/ADP13	N/A	11101	V <sub>REFH</sub>	V <sub>DD</sub>	N/A
01110	AD14	PTF4/ADP14	N/A	11110	V <sub>REFL</sub>	V <sub>SS</sub>	N/A
01111	AD15	PTF5/ADP15	N/A	11111	Module Disabled	None	N/A

<sup>1</sup> For information, see [Section 10.1.2.4](#), “Temperature Sensor.”

#### NOTE

Selecting the internal bandgap channel requires SPMSC1[BGBE] to be set, see [Section 5.8.7](#), “System Power Management Status and Control 1 Register (SPMSC1).” For the value of bandgap voltage reference see the data sheet.

### 10.1.2.2 Alternate Clock

The ADC is capable of performing conversions using the MCU bus clock, the bus clock divided by two, the local asynchronous clock (ADACK) within the module, or the alternate clock (ALTCLK). The ALTCLK on the MC9S08QE128 Series is the ICSERCLK. See [Chapter 11](#), “Internal Clock Source (S08ICSV3),” for more information.

### 10.1.2.3 Hardware Trigger

The ADC may initiate a conversion via software or a hardware trigger. The RTC can be enabled as the hardware trigger for the ADC module by setting ADCSC2[ADTRG]. When enabled, the ADC is triggered each time RTCINT matches RTCMOD. The RTC interrupt does not have to be enabled to trigger the ADC.

The RTC can be configured to cause a hardware trigger in MCU run, wait, and stop3.

### 10.1.2.4 Temperature Sensor

The ADC module includes a temperature sensor whose output is connected to one of the ADC analog channel inputs. Equation 10-1 provides an approximate transfer function of the temperature sensor.

$$\text{Temp} = 25 - \frac{V_{\text{TEMP}} - V_{\text{TEMP25}}}{m} \quad \text{Eqn. 10-1}$$

where:

- $V_{\text{TEMP}}$  is the voltage of the temperature sensor channel at the ambient temperature.
- $V_{\text{TEMP25}}$  is the voltage of the temperature sensor channel at 25°C.
- $m$  is the hot or cold voltage versus temperature slope in V/°C.

For temperature calculations, use the  $V_{\text{TEMP25}}$  and  $m$  values in the data sheet.

In application code, the user reads the temperature sensor channel, calculates  $V_{\text{TEMP}}$  and compares to  $V_{\text{TEMP25}}$ . If  $V_{\text{TEMP}}$  is greater than  $V_{\text{TEMP25}}$  the cold slope value is applied in Equation 10-1. If  $V_{\text{TEMP}}$  is less than  $V_{\text{TEMP25}}$  the hot slope value is applied in Equation 10-1.

### 10.1.3 Features

Features of the ADC module include:

- Linear successive approximation algorithm with 12 bits resolution.
- Up to 28 analog inputs.
- Output formatted in 12-, 10- or 8-bit right-justified format.
- Single or continuous conversion (automatic return to idle after single conversion).
- Configurable sample time and conversion speed/power.
- Conversion complete flag and interrupt.
- Input clock selectable from up to four sources.
- Operation in wait or stop3 modes for lower noise operation.
- Asynchronous clock source for lower noise operation.
- Selectable asynchronous hardware conversion trigger.
- Automatic compare with interrupt for less-than, or greater-than or equal-to, programmable value.

### 10.1.4 Block Diagram

Figure 10-2 provides a block diagram of the ADC module



### 10.2.1 Analog Power ( $V_{DDAD}$ )

The ADC analog portion uses  $V_{DDAD}$  as its power connection. In some packages,  $V_{DDAD}$  is connected internally to  $V_{DD}$ . If externally available, connect the  $V_{DDAD}$  pin to the same voltage potential as  $V_{DD}$ . External filtering may be necessary to ensure clean  $V_{DDAD}$  for good results.

### 10.2.2 Analog Ground ( $V_{SSAD}$ )

The ADC analog portion uses  $V_{SSAD}$  as its ground connection. In some packages,  $V_{SSAD}$  is connected internally to  $V_{SS}$ . If externally available, connect the  $V_{SSAD}$  pin to the same voltage potential as  $V_{SS}$ .

### 10.2.3 Voltage Reference High ( $V_{REFH}$ )

$V_{REFH}$  is the high reference voltage for the converter. In some packages,  $V_{REFH}$  is connected internally to  $V_{DDAD}$ . If externally available,  $V_{REFH}$  may be connected to the same potential as  $V_{DDAD}$ , or may be driven by an external source that is between the minimum  $V_{DDAD}$  spec and the  $V_{DDAD}$  potential ( $V_{REFH}$  must never exceed  $V_{DDAD}$ ).

### 10.2.4 Voltage Reference Low ( $V_{REFL}$ )

$V_{REFL}$  is the low reference voltage for the converter. In some packages,  $V_{REFL}$  is connected internally to  $V_{SSAD}$ . If externally available, connect the  $V_{REFL}$  pin to the same voltage potential as  $V_{SSAD}$ .

### 10.2.5 Analog Channel Inputs (ADx)

The ADC module supports up to 28 separate analog inputs. An input is selected for conversion through the ADCH channel select bits.

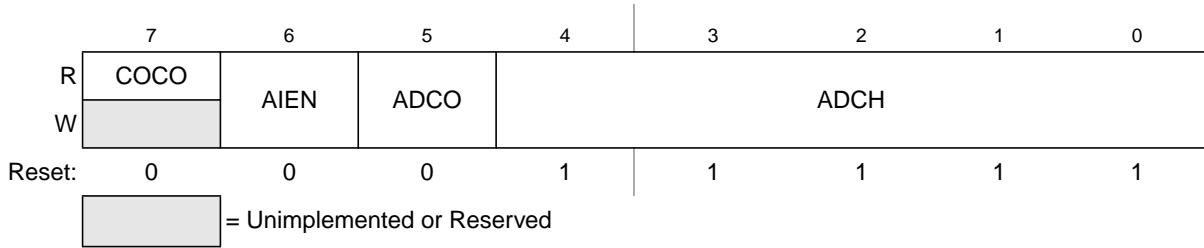
## 10.3 Register Definition

These memory mapped registers control and monitor operation of the ADC:

- Status and control register, ADCSC1
- Status and control register, ADCSC2
- Data result registers, ADCRH and ADCRL
- Compare value registers, ADCCVH and ADCCVL
- Configuration register, ADCCFG
- Pin enable registers, APCTL1, APCTL2, APCTL3

### 10.3.1 Status and Control Register 1 (ADCSC1)

This section describes the function of the ADC status and control register (ADCSC1). Writing ADCSC1 aborts the current conversion and initiates a new conversion (if the ADCH bits are equal to a value other than all 1s).



**Figure 10-3. Status and Control Register (ADCSC1)**

**Table 10-3. ADCSC1 Register Field Descriptions**

Field	Description
7 COCO	<b>Conversion Complete Flag</b> — The COCO flag is a read-only bit which is set each time a conversion is completed when the compare function is disabled (ACFE = 0). When the compare function is enabled (ACFE = 1) the COCO flag is set upon completion of a conversion only if the compare result is true. This bit is cleared whenever ADCSC1 is written or whenever ADCRL is read. 0 Conversion not completed 1 Conversion completed
6 AIEN	<b>Interrupt Enable</b> — AIEN is used to enable conversion complete interrupts. When COCO becomes set while AIEN is high, an interrupt is asserted. 0 Conversion complete interrupt disabled 1 Conversion complete interrupt enabled
5 ADCO	<b>Continuous Conversion Enable</b> — ADCO is used to enable continuous conversions. 0 One conversion following a write to the ADCSC1 when software triggered operation is selected, or one conversion following assertion of ADHWT when hardware triggered operation is selected. 1 Continuous conversions initiated following a write to ADCSC1 when software triggered operation is selected. Continuous conversions are initiated by an ADHWT event when hardware triggered operation is selected.
4:0 ADCH	<b>Input Channel Select</b> — The ADCH bits form a 5-bit field which is used to select one of the input channels. The input channels are detailed in <a href="#">Figure 10-4</a> . The successive approximation converter subsystem is turned off when the channel select bits are all set to 1. This feature allows for explicit disabling of the ADC and isolation of the input channel from all sources. Terminating continuous conversions this way will prevent an additional, single conversion from being performed. It is not necessary to set the channel select bits to all 1s to place the ADC in a low-power state when continuous conversions are not enabled because the module automatically enters a low-power state when a conversion completes.

**Figure 10-4. Input Channel Select**

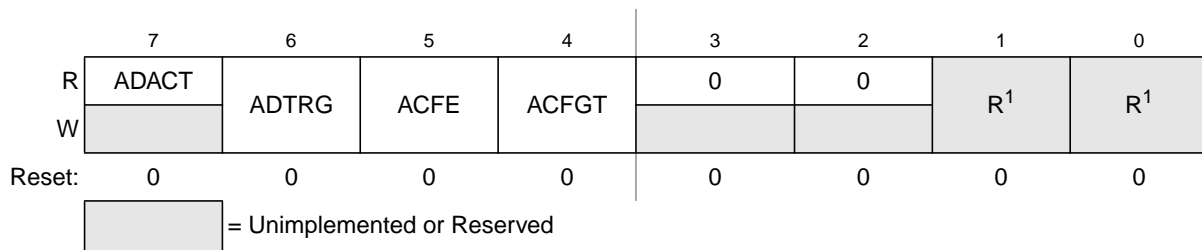
ADCH	Input Select	ADCH	Input Select
00000	AD0	10000	AD16
00001	AD1	10001	AD17
00010	AD2	10010	AD18
00011	AD3	10011	AD19
00100	AD4	10100	AD20
00101	AD5	10101	AD21
00110	AD6	10110	AD22
00111	AD7	10111	AD23

**Figure 10-4. Input Channel Select (continued)**

ADCH	Input Select	ADCH	Input Select
01000	AD8	11000	AD24
01001	AD9	11001	AD25
01010	AD10	11010	AD26
01011	AD11	11011	AD27
01100	AD12	11100	Reserved
01101	AD13	11101	V <sub>REFH</sub>
01110	AD14	11110	V <sub>REFL</sub>
01111	AD15	11111	Module disabled

### 10.3.2 Status and Control Register 2 (ADCSC2)

The ADCSC2 register is used to control the compare function, conversion trigger and conversion active of the ADC module.



<sup>1</sup> Bits 1 and 0 are reserved bits that must always be written to 0.

**Figure 10-5. Status and Control Register 2 (ADCSC2)**
**Table 10-4. ADCSC2 Register Field Descriptions**

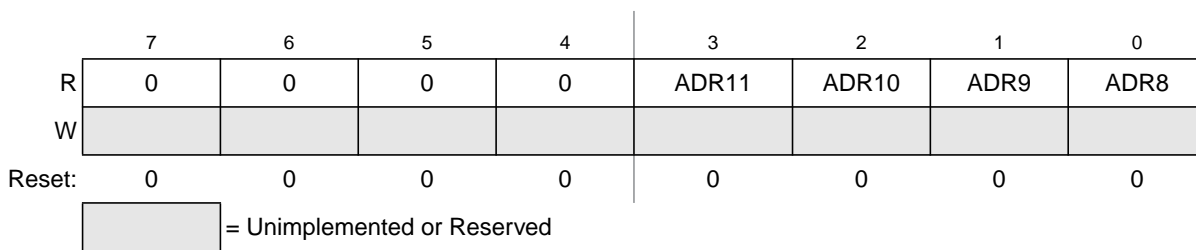
Field	Description
7 ADACT	<b>Conversion Active</b> — ADACT indicates that a conversion is in progress. ADACT is set when a conversion is initiated and cleared when a conversion is completed or aborted. 0 Conversion not in progress 1 Conversion in progress
6 ADTRG	<b>Conversion Trigger Select</b> — ADTRG is used to select the type of trigger to be used for initiating a conversion. Two types of trigger are selectable: software trigger and hardware trigger. When software trigger is selected, a conversion is initiated following a write to ADCSC1. When hardware trigger is selected, a conversion is initiated following the assertion of the ADHWT input. 0 Software trigger selected 1 Hardware trigger selected

**Table 10-4. ADCSC2 Register Field Descriptions (continued)**

Field	Description
5 ACFE	<b>Compare Function Enable</b> — ACFE is used to enable the compare function. 0 Compare function disabled 1 Compare function enabled
4 ACFGT	<b>Compare Function Greater Than Enable</b> — ACFGT is used to configure the compare function to trigger when the result of the conversion of the input being monitored is greater than or equal to the compare value. The compare function defaults to triggering when the result of the compare of the input being monitored is less than the compare value. 0 Compare triggers when input is less than compare level 1 Compare triggers when input is greater than or equal to compare level

### 10.3.3 Data Result High Register (ADCRH)

In 12-bit operation, ADCRH contains the upper four bits of the result of a 12-bit conversion.


**Figure 10-6. Data Result High Register (ADCRH)**

In 10-bit mode, ADCRH contains the upper two bits of the result of a 10-bit conversion. When configured for 10-bit mode, ADR11 – ADR10 are equal to zero. When configured for 8-bit mode, ADR11 – ADR8 are equal to zero.

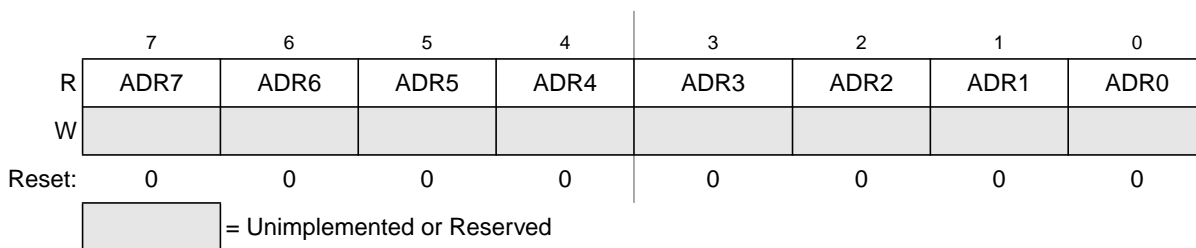
In both 12-bit and 10-bit mode, ADCRH is updated each time a conversion completes except when automatic compare is enabled and the compare condition is not met. In 12-bit and 10-bit mode, reading ADCRH prevents the ADC from transferring subsequent conversion results into the result registers until ADCRL is read. If ADCRL is not read until after the next conversion is completed, then the intermediate conversion result is lost. In 8-bit mode there is no interlocking with ADCRL.

In the case that the MODE bits are changed, any data in ADCRH becomes invalid.

### 10.3.4 Data Result Low Register (ADCRL)

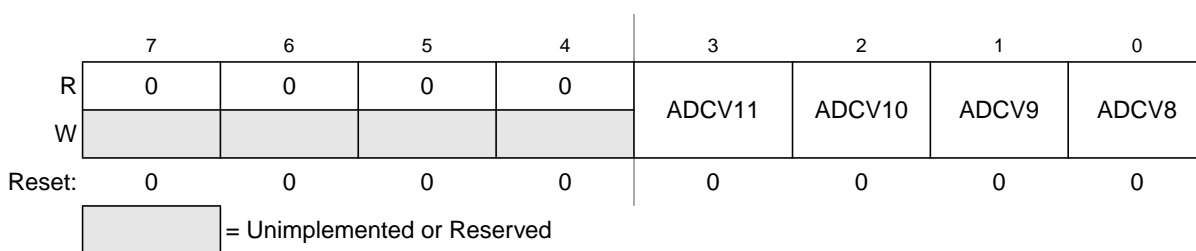
ADCRL contains the lower eight bits of the result of a 12-bit or 10-bit conversion, and all eight bits of an 8-bit conversion. This register is updated each time a conversion completes except when automatic compare is enabled and the compare condition is not met. In 12-bit and 10-bit mode, reading ADCRH prevents the ADC from transferring subsequent conversion results into the result registers until ADCRL is read. If ADCRL is not read until the after next conversion is completed, then the intermediate conversion results will be lost. In 8-bit mode, there is no interlocking with ADCRH. In the case that the MODE bits are changed, any data in ADCRL becomes invalid.




**Figure 10-7. Data Result Low Register (ADCRL)**

### 10.3.5 Compare Value High Register (ADCCVH)

In 12-bit mode, the ADCCVH register holds the upper four bits of the 12-bit compare value. These bits are compared to the upper four bits of the result following a conversion in 12-bit mode when the compare function is enabled.

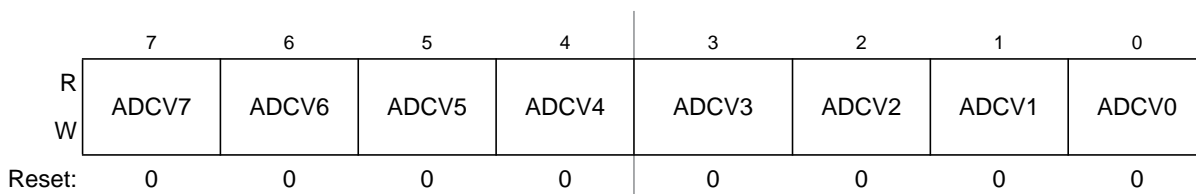

**Figure 10-8. Compare Value High Register (ADCCVH)**

In 10-bit mode, the ADCCVH register holds the upper two bits of the 10-bit compare value (ADCV9 – ADCV8). These bits are compared to the upper two bits of the result following a conversion in 10-bit mode when the compare function is enabled.

In 8-bit mode, ADCCVH is not used during compare.

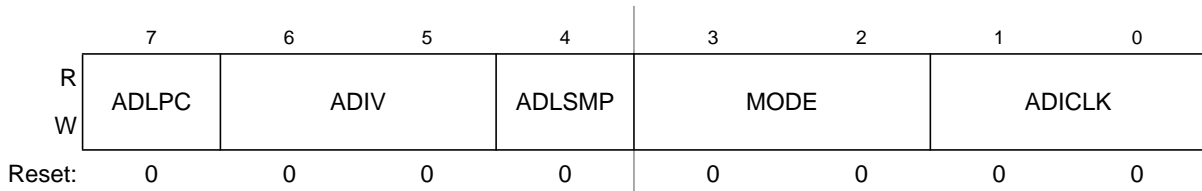
### 10.3.6 Compare Value Low Register (ADCCVL)

This register holds the lower 8 bits of the 12-bit or 10-bit compare value, or all 8 bits of the 8-bit compare value. Bits ADCV7:ADCV0 are compared to the lower 8 bits of the result following a conversion in 12-bit, 10-bit or 8-bit mode.


**Figure 10-9. Compare Value Low Register(ADCCVL)**

### 10.3.7 Configuration Register (ADCCFG)

ADCCFG is used to select the mode of operation, clock source, clock divide, and configure for low power or long sample time.



**Figure 10-10. Configuration Register (ADCCFG)**

**Table 10-5. ADCCFG Register Field Descriptions**

Field	Description
7 ADLPC	<p><b>Low Power Configuration</b> — ADLPC controls the speed and power configuration of the successive approximation converter. This is used to optimize power consumption when higher sample rates are not required.</p> <p>0 High speed configuration 1 Low power configuration: {FC31}The power is reduced at the expense of maximum clock speed.</p>
6:5 ADIV	<p><b>Clock Divide Select</b> — ADIV select the divide ratio used by the ADC to generate the internal clock ADCK. <a href="#">Table 10-6</a> shows the available clock configurations.</p>
4 ADLSMP	<p><b>Long Sample Time Configuration</b> — ADLSMP selects between long and short sample time. This adjusts the sample period to allow higher impedance inputs to be accurately sampled or to maximize conversion speed for lower impedance inputs. Longer sample times can also be used to lower overall power consumption when continuous conversions are enabled if high conversion rates are not required.</p> <p>0 Short sample time 1 Long sample time</p>
3:2 MODE	<p><b>Conversion Mode Selection</b> — MODE bits are used to select between 12-, 10- or 8-bit operation. See <a href="#">Table 10-7</a>.</p>
1:0 ADICLK	<p><b>Input Clock Select</b> — ADICLK bits select the input clock source to generate the internal clock ADCK. See <a href="#">Table 10-8</a>.</p>

**Table 10-6. Clock Divide Select**

ADIV	Divide Ratio	Clock Rate
00	1	Input clock
01	2	Input clock ÷ 2
10	4	Input clock ÷ 4
11	8	Input clock ÷ 8

**Table 10-7. Conversion Modes**

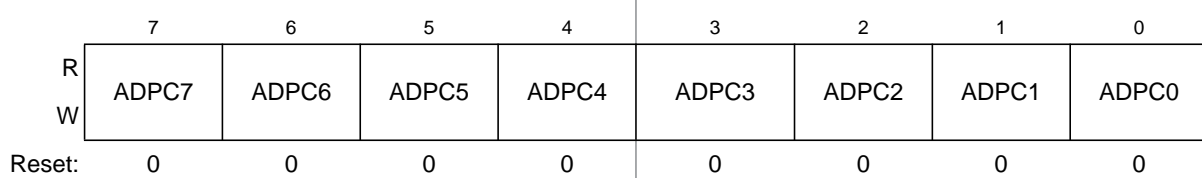
MODE	Mode Description
00	8-bit conversion (N=8)
01	12-bit conversion (N=12)
10	10-bit conversion (N=10)
11	Reserved

**Table 10-8. Input Clock Select**

ADICLK	Selected Clock Source
00	Bus clock
01	Bus clock divided by 2
10	Alternate clock (ALTCLK)
11	Asynchronous clock (ADACK)

### 10.3.8 Pin Control 1 Register (APCTL1)

The pin control registers are used to disable the I/O port control of MCU pins used as analog inputs. APCTL1 is used to control the pins associated with channels 0–7 of the ADC module.


**Figure 10-11. Pin Control 1 Register (APCTL1)**
**Table 10-9. APCTL1 Register Field Descriptions**

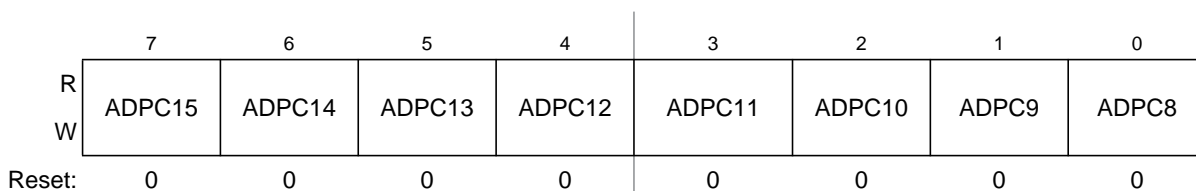
Field	Description
7 ADPC7	<b>ADC Pin Control 7</b> — ADPC7 is used to control the pin associated with channel AD7. 0 AD7 pin I/O control enabled 1 AD7 pin I/O control disabled
6 ADPC6	<b>ADC Pin Control 6</b> — ADPC6 is used to control the pin associated with channel AD6. 0 AD6 pin I/O control enabled 1 AD6 pin I/O control disabled
5 ADPC5	<b>ADC Pin Control 5</b> — ADPC5 is used to control the pin associated with channel AD5. 0 AD5 pin I/O control enabled 1 AD5 pin I/O control disabled
4 ADPC4	<b>ADC Pin Control 4</b> — ADPC4 is used to control the pin associated with channel AD4. 0 AD4 pin I/O control enabled 1 AD4 pin I/O control disabled
3 ADPC3	<b>ADC Pin Control 3</b> — ADPC3 is used to control the pin associated with channel AD3. 0 AD3 pin I/O control enabled 1 AD3 pin I/O control disabled
2 ADPC2	<b>ADC Pin Control 2</b> — ADPC2 is used to control the pin associated with channel AD2. 0 AD2 pin I/O control enabled 1 AD2 pin I/O control disabled

**Table 10-9. APCTL1 Register Field Descriptions (continued)**

Field	Description
1 ADPC1	<b>ADC Pin Control 1</b> — ADPC1 is used to control the pin associated with channel AD1. 0 AD1 pin I/O control enabled 1 AD1 pin I/O control disabled
0 ADPC0	<b>ADC Pin Control 0</b> — ADPC0 is used to control the pin associated with channel AD0. 0 AD0 pin I/O control enabled 1 AD0 pin I/O control disabled

### 10.3.9 Pin Control 2 Register (APCTL2)

APCTL2 is used to control channels 8–15 of the ADC module.



**Figure 10-12. Pin Control 2 Register (APCTL2)**

**Table 10-10. APCTL2 Register Field Descriptions**

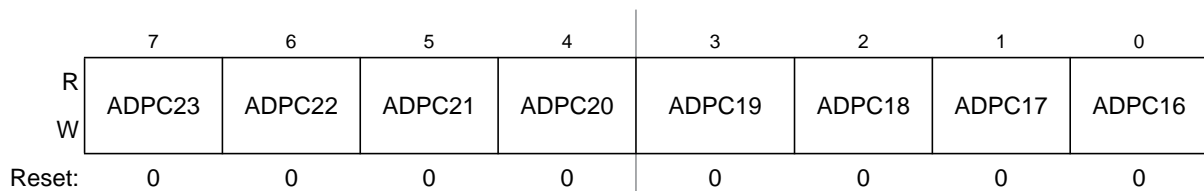
Field	Description
7 ADPC15	<b>ADC Pin Control 15</b> — ADPC15 is used to control the pin associated with channel AD15. 0 AD15 pin I/O control enabled 1 AD15 pin I/O control disabled
6 ADPC14	<b>ADC Pin Control 14</b> — ADPC14 is used to control the pin associated with channel AD14. 0 AD14 pin I/O control enabled 1 AD14 pin I/O control disabled
5 ADPC13	<b>ADC Pin Control 13</b> — ADPC13 is used to control the pin associated with channel AD13. 0 AD13 pin I/O control enabled 1 AD13 pin I/O control disabled
4 ADPC12	<b>ADC Pin Control 12</b> — ADPC12 is used to control the pin associated with channel AD12. 0 AD12 pin I/O control enabled 1 AD12 pin I/O control disabled
3 ADPC11	<b>ADC Pin Control 11</b> — ADPC11 is used to control the pin associated with channel AD11. 0 AD11 pin I/O control enabled 1 AD11 pin I/O control disabled
2 ADPC10	<b>ADC Pin Control 10</b> — ADPC10 is used to control the pin associated with channel AD10. 0 AD10 pin I/O control enabled 1 AD10 pin I/O control disabled

**Table 10-10. APCTL2 Register Field Descriptions (continued)**

Field	Description
1 ADPC9	<b>ADC Pin Control 9</b> — ADPC9 is used to control the pin associated with channel AD9. 0 AD9 pin I/O control enabled 1 AD9 pin I/O control disabled
0 ADPC8	<b>ADC Pin Control 8</b> — ADPC8 is used to control the pin associated with channel AD8. 0 AD8 pin I/O control enabled 1 AD8 pin I/O control disabled

### 10.3.10 Pin Control 3 Register (APCTL3)

APCTL3 is used to control channels 16–23 of the ADC module.


**Figure 10-13. Pin Control 3 Register (APCTL3)**
**Table 10-11. APCTL3 Register Field Descriptions**

Field	Description
7 ADPC23	<b>ADC Pin Control 23</b> — ADPC23 is used to control the pin associated with channel AD23. 0 AD23 pin I/O control enabled 1 AD23 pin I/O control disabled
6 ADPC22	<b>ADC Pin Control 22</b> — ADPC22 is used to control the pin associated with channel AD22. 0 AD22 pin I/O control enabled 1 AD22 pin I/O control disabled
5 ADPC21	<b>ADC Pin Control 21</b> — ADPC21 is used to control the pin associated with channel AD21. 0 AD21 pin I/O control enabled 1 AD21 pin I/O control disabled
4 ADPC20	<b>ADC Pin Control 20</b> — ADPC20 is used to control the pin associated with channel AD20. 0 AD20 pin I/O control enabled 1 AD20 pin I/O control disabled
3 ADPC19	<b>ADC Pin Control 19</b> — ADPC19 is used to control the pin associated with channel AD19. 0 AD19 pin I/O control enabled 1 AD19 pin I/O control disabled
2 ADPC18	<b>ADC Pin Control 18</b> — ADPC18 is used to control the pin associated with channel AD18. 0 AD18 pin I/O control enabled 1 AD18 pin I/O control disabled

**Table 10-11. APCTL3 Register Field Descriptions (continued)**

Field	Description
1 ADPC17	<b>ADC Pin Control 17</b> — ADPC17 is used to control the pin associated with channel AD17. 0 AD17 pin I/O control enabled 1 AD17 pin I/O control disabled
0 ADPC16	<b>ADC Pin Control 16</b> — ADPC16 is used to control the pin associated with channel AD16. 0 AD16 pin I/O control enabled 1 AD16 pin I/O control disabled

## 10.4 Functional Description

The ADC module is disabled during reset or when the ADCH bits are all high. The module is idle when a conversion has completed and another conversion has not been initiated. When idle, the module is in its lowest power state.

The ADC can perform an analog-to-digital conversion on any of the software selectable channels. In 12-bit and 10-bit mode, the selected channel voltage is converted by a successive approximation algorithm into a 12-bit digital result. In 8-bit mode, the selected channel voltage is converted by a successive approximation algorithm into a 9-bit digital result.

When the conversion is completed, the result is placed in the data registers (ADCRH and ADCRL). In 10-bit mode, the result is rounded to 10 bits and placed in the data registers (ADCRH and ADCRL). In 8-bit mode, the result is rounded to 8 bits and placed in ADCRL. The conversion complete flag (COCO) is then set and an interrupt is generated if the conversion complete interrupt has been enabled (AIEN = 1).

The ADC module has the capability of automatically comparing the result of a conversion with the contents of its compare registers. The compare function is enabled by setting the ACFE bit and operates in conjunction with any of the conversion modes and configurations.

### 10.4.1 Clock Select and Divide Control

One of four clock sources can be selected as the clock source for the ADC module. This clock source is then divided by a configurable value to generate the input clock to the converter (ADCK). The clock is selected from one of the following sources by means of the ADICLK bits.

- The bus clock, which is equal to the frequency at which software is executed. This is the default selection following reset.
- The bus clock divided by 2. For higher bus clock rates, this allows a maximum divide by 16 of the bus clock.
- ALTCLK, as defined for this MCU (See module section introduction).
- The asynchronous clock (ADACK) – This clock is generated from a clock source within the ADC module. When selected as the clock source this clock remains active while the MCU is in wait or stop3 mode and allows conversions in these modes for lower noise operation.

Whichever clock is selected, its frequency must fall within the specified frequency range for ADCK. If the available clocks are too slow, the ADC will not perform according to specifications. If the available clocks

are too fast, then the clock must be divided to the appropriate frequency. This divider is specified by the ADIV bits and can be divide-by 1, 2, 4, or 8.

## 10.4.2 Input Select and Pin Control

The pin control registers (APCTL3, APCTL2, and APCTL1) are used to disable the I/O port control of the pins used as analog inputs. When a pin control register bit is set, the following conditions are forced for the associated MCU pin:

- The output buffer is forced to its high impedance state.
- The input buffer is disabled. A read of the I/O port returns a zero for any pin with its input buffer disabled.
- The pullup is disabled.

## 10.4.3 Hardware Trigger

The ADC module has a selectable asynchronous hardware conversion trigger, ADHWT, that is enabled when the ADTRG bit is set. This source is not available on all MCUs. Consult the module introduction for information on the ADHWT source specific to this MCU.

When ADHWT source is available and hardware trigger is enabled (ADTRG=1), a conversion is initiated on the rising edge of ADHWT. If a conversion is in progress when a rising edge occurs, the rising edge is ignored. In continuous convert configuration, only the initial rising edge to launch continuous conversions is observed. The hardware trigger function operates in conjunction with any of the conversion modes and configurations.

## 10.4.4 Conversion Control

Conversions can be performed in 12-bit mode, 10-bit mode or 8-bit mode as determined by the MODE bits. Conversions can be initiated by either a software or hardware trigger. In addition, the ADC module can be configured for low power operation, long sample time, continuous conversion, and automatic compare of the conversion result to a software determined compare value.

### 10.4.4.1 Initiating Conversions

A conversion is initiated:

- Following a write to ADCSC1 (with ADCH bits not all 1s) if software triggered operation is selected.
- Following a hardware trigger (ADHWT) event if hardware triggered operation is selected.
- Following the transfer of the result to the data registers when continuous conversion is enabled.

If continuous conversions are enabled a new conversion is automatically initiated after the completion of the current conversion. In software triggered operation, continuous conversions begin after ADCSC1 is written and continue until aborted. In hardware triggered operation, continuous conversions begin after a hardware trigger event and continue until aborted.

### 10.4.4.2 Completing Conversions

A conversion is completed when the result of the conversion is transferred into the data result registers, ADCRH and ADCRL. This is indicated by the setting of COCO. An interrupt is generated if AIEN is high at the time that COCO is set.

A blocking mechanism prevents a new result from overwriting previous data in ADCRH and ADCRL if the previous data is in the process of being read while in 12-bit or 10-bit MODE (the ADCRH register has been read but the ADCRL register has not). When blocking is active, the data transfer is blocked, COCO is not set, and the new result is lost. In the case of single conversions with the compare function enabled and the compare condition false, blocking has no effect and ADC operation is terminated. In all other cases of operation, when a data transfer is blocked, another conversion is initiated regardless of the state of ADCO (single or continuous conversions enabled).

If single conversions are enabled, the blocking mechanism could result in several discarded conversions and excess power consumption. To avoid this issue, the data registers must not be read after initiating a single conversion until the conversion completes.

### 10.4.4.3 Aborting Conversions

Any conversion in progress will be aborted when:

- A write to ADCSC1 occurs (the current conversion will be aborted and a new conversion will be initiated, if ADCH are not all 1s).
- A write to ADCSC2, ADCCFG, ADCCVH, or ADCCVL occurs. This indicates a mode of operation change has occurred and the current conversion is therefore invalid.
- The MCU is reset.
- The MCU enters stop mode with ADACK not enabled.

When a conversion is aborted, the contents of the data registers, ADCRH and ADCRL, are not altered but continue to be the values transferred after the completion of the last successful conversion. In the case that the conversion was aborted by a reset, ADCRH and ADCRL return to their reset states.

### 10.4.4.4 Power Control

The ADC module remains in its idle state until a conversion is initiated. If ADACK is selected as the conversion clock source, the ADACK clock generator is also enabled.

Power consumption when active can be reduced by setting ADLPC. This results in a lower maximum value for  $f_{ADCK}$  (see the electrical specifications).

### 10.4.4.5 Sample Time and Total Conversion Time

The total conversion time depends on the sample time (as determined by ADLSMP), the MCU bus frequency, the conversion mode (8-bit, 10-bit or 12-bit), and the frequency of the conversion clock ( $f_{ADCK}$ ). After the module becomes active, sampling of the input begins. ADLSMP is used to select between short (3.5 ADCK cycles) and long (23.5 ADCK cycles) sample times. When sampling is complete, the converter is isolated from the input channel and a successive approximation algorithm is performed to determine the



digital value of the analog signal. The result of the conversion is transferred to ADCRH and ADCRL upon completion of the conversion algorithm.

If the bus frequency is less than the  $f_{ADCK}$  frequency, precise sample time for continuous conversions cannot be guaranteed when short sample is enabled (ADLSMP=0). If the bus frequency is less than 1/11th of the  $f_{ADCK}$  frequency, precise sample time for continuous conversions cannot be guaranteed when long sample is enabled (ADLSMP=1).

The maximum total conversion time for different conditions is summarized in Table 10-12.

**Table 10-12. Total Conversion Time vs. Control Conditions**

Conversion Type	ADICLK	ADLSMP	Max Total Conversion Time
Single or first continuous 8-bit	0x, 10	0	20 ADCK cycles + 5 bus clock cycles
Single or first continuous 10-bit or 12-bit	0x, 10	0	23 ADCK cycles + 5 bus clock cycles
Single or first continuous 8-bit	0x, 10	1	40 ADCK cycles + 5 bus clock cycles
Single or first continuous 10-bit or 12-bit	0x, 10	1	43 ADCK cycles + 5 bus clock cycles
Single or first continuous 8-bit	11	0	5 $\mu$ s + 20 ADCK + 5 bus clock cycles
Single or first continuous 10-bit or 12-bit	11	0	5 $\mu$ s + 23 ADCK + 5 bus clock cycles
Single or first continuous 8-bit	11	1	5 $\mu$ s + 40 ADCK + 5 bus clock cycles
Single or first continuous 10-bit or 12-bit	11	1	5 $\mu$ s + 43 ADCK + 5 bus clock cycles
Subsequent continuous 8-bit; $f_{BUS} \geq f_{ADCK}$	xx	0	17 ADCK cycles
Subsequent continuous 10-bit or 12-bit; $f_{BUS} \geq f_{ADCK}$	xx	0	20 ADCK cycles
Subsequent continuous 8-bit; $f_{BUS} \geq f_{ADCK}/11$	xx	1	37 ADCK cycles
Subsequent continuous 10-bit or 12-bit; $f_{BUS} \geq f_{ADCK}/11$	xx	1	40 ADCK cycles

The maximum total conversion time is determined by the clock source chosen and the divide ratio selected. The clock source is selectable by the ADICLK bits, and the divide ratio is specified by the ADIV bits. For example, in 10-bit mode, with the bus clock selected as the input clock source, the input clock divide-by-1 ratio selected, and a bus frequency of 8 MHz, then the conversion time for a single conversion is:

$$\text{Conversion time} = \frac{23 \text{ ADCK cyc}}{8 \text{ MHz}/1} + \frac{5 \text{ bus cyc}}{8 \text{ MHz}} = 3.5 \mu\text{s}$$

$$\text{Number of bus cycles} = 3.5 \mu\text{s} \times 8 \text{ MHz} = 28 \text{ cycles}$$

#### NOTE

The ADCK frequency must be between  $f_{ADCK}$  minimum and  $f_{ADCK}$  maximum to meet ADC specifications.

## 10.4.5 Automatic Compare Function

The compare function can be configured to check for either an upper limit or lower limit. After the input is sampled and converted, the result is added to the two's complement of the compare value (ADCCVH and ADCCVL). When comparing to an upper limit (ACFGT = 1), if the result is greater-than or equal-to the compare value, COCO is set. When comparing to a lower limit (ACFGT = 0), if the result is less than the compare value, COCO is set. The value generated by the addition of the conversion result and the two's complement of the compare value is transferred to ADCRH and ADCRL.

Upon completion of a conversion while the compare function is enabled, if the compare condition is not true, COCO is not set and no data is transferred to the result registers. An ADC interrupt is generated upon the setting of COCO if the ADC interrupt is enabled (AIEN = 1).

### NOTE

The compare function can be used to monitor the voltage on a channel while the MCU is in either wait or stop3 mode. The ADC interrupt will wake the MCU when the compare condition is met.

## 10.4.6 MCU Wait Mode Operation

The WAIT instruction puts the MCU in a lower power-consumption standby mode from which recovery is very fast because the clock sources remain active. If a conversion is in progress when the MCU enters wait mode, it continues until completion. Conversions can be initiated while the MCU is in wait mode by means of the hardware trigger or if continuous conversions are enabled.

The bus clock, bus clock divided by two, and ADACK are available as conversion clock sources while in wait mode. The use of ALTCLK as the conversion clock source in wait is dependent on the definition of ALTCLK for this MCU. Consult the module introduction for information on ALTCLK specific to this MCU.

A conversion complete event sets the COCO and generates an ADC interrupt to wake the MCU from wait mode if the ADC interrupt is enabled (AIEN = 1).

## 10.4.7 MCU Stop3 Mode Operation

The STOP instruction is used to put the MCU in a low power-consumption standby mode during which most or all clock sources on the MCU are disabled.

### 10.4.7.1 Stop3 Mode With ADACK Disabled

If the asynchronous clock, ADACK, is not selected as the conversion clock, executing a STOP instruction aborts the current conversion and places the ADC in its idle state. The contents of ADCRH and ADCRL are unaffected by stop3 mode. After exiting from stop3 mode, a software or hardware trigger is required to resume conversions.

### 10.4.7.2 Stop3 Mode With ADACK Enabled

If ADACK is selected as the conversion clock, the ADC continues operation during stop3 mode. For guaranteed ADC operation, the MCU's voltage regulator must remain active during stop3 mode. Consult the module introduction for configuration information for this MCU.

If a conversion is in progress when the MCU enters stop3 mode, it continues until completion. Conversions can be initiated while the MCU is in stop3 mode by means of the hardware trigger or if continuous conversions are enabled.

A conversion complete event sets the COCO and generates an ADC interrupt to wake the MCU from stop3 mode if the ADC interrupt is enabled (AIEN = 1).

#### NOTE

It is possible for the ADC module to wake the system from low power stop and cause the MCU to begin consuming run-level currents without generating a system level interrupt. To prevent this scenario, software should ensure that the data transfer blocking mechanism (discussed in [Section 10.4.4.2, "Completing Conversions"](#)) is cleared when entering stop3 and continuing ADC conversions.

## 10.4.8 MCU Stop1 and Stop2 Mode Operation

The ADC module is automatically disabled when the MCU enters either stop1 or stop2 mode. All module registers contain their reset values following exit from stop1 or stop2. Therefore the module must be re-enabled and re-configured following exit from stop1 or stop2.

## 10.5 Initialization Information

This section gives an example which provides some basic direction on how a user would initialize and configure the ADC module. The user has the flexibility of choosing between configuring the module for 8-, 10-, or 12-bit resolution, single or continuous conversion, and a polled or interrupt approach, among many other options. Refer to [Table 10-6](#), [Table 10-7](#), and [Table 10-8](#) for information used in this example.

#### NOTE

Hexadecimal values designated by a preceding 0x, binary values designated by a preceding %, and decimal values have no preceding character.

### 10.5.1 ADC Module Initialization Example

#### 10.5.1.1 Initialization Sequence

Before the ADC module can be used to complete conversions, an initialization procedure must be performed. A typical sequence is as follows:

1. Update the configuration register (ADCCFG) to select the input clock source and the divide ratio used to generate the internal clock, ADCK. This register is also used for selecting sample time and low-power configuration.

2. Update status and control register 2 (ADCSC2) to select the conversion trigger (hardware or software) and compare function options, if enabled.
3. Update status and control register 1 (ADCSC1) to select whether conversions will be continuous or completed only once, and to enable or disable conversion complete interrupts. The input channel on which conversions will be performed is also selected here.

### 10.5.1.2 Pseudo — Code Example

In this example, the ADC module will be set up with interrupts enabled to perform a single 10-bit conversion at low power with a long sample time on input channel 1, where the internal ADCK clock will be derived from the bus clock divided by 1.

#### ADCCFG = 0x98 (%10011000)

Bit 7	ADLPC	1	Configures for low power (lowers maximum clock speed)
Bit 6:5	ADIV	00	Sets the ADCK to the input clock ÷ 1
Bit 4	ADLSMP	1	Configures for long sample time
Bit 3:2	MODE	10	Sets mode at 10-bit conversions
Bit 1:0	ADICLK	00	Selects bus clock as input clock source

#### ADCSC2 = 0x00 (%00000000)

Bit 7	ADACT	0	Flag indicates if a conversion is in progress
Bit 6	ADTRG	0	Software trigger selected
Bit 5	ACFE	0	Compare function disabled
Bit 4	ACFGT	0	Not used in this example
Bit 3:2		00	Unimplemented or reserved, always reads zero
Bit 1:0		00	Reserved for Freescale's internal use; always write zero

#### ADCSC1 = 0x41 (%01000001)

Bit 7	COCO	0	Read-only flag which is set when a conversion completes
Bit 6	AIEN	1	Conversion complete interrupt enabled
Bit 5	ADCO	0	One conversion only (continuous conversions disabled)
Bit 4:0	ADCH	00001	Input channel 1 selected as ADC input channel

#### ADCRH/L = 0xxx

Holds results of conversion. Read high byte (ADCRH) before low byte (ADCRL) so that conversion data cannot be overwritten with data from the next conversion.

#### ADCCVH/L = 0xxx

Holds compare value when compare function enabled

#### APCTL1=0x02

AD1 pin I/O control disabled. All other AD pins remain general purpose I/O pins

#### APCTL2=0x00

All other AD pins remain general purpose I/O pins

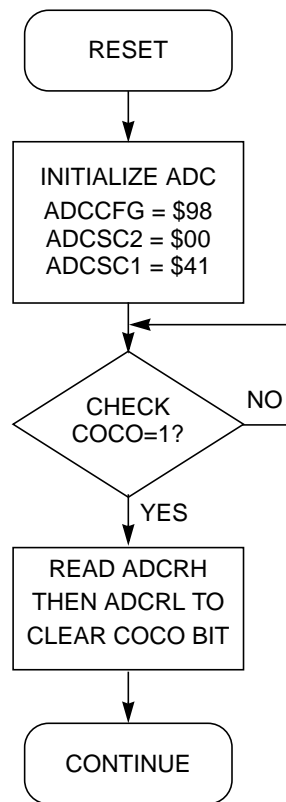


Figure 10-14. Initialization Flowchart for Example

## 10.6 Application Information

This section contains information for using the ADC module in applications. The ADC has been designed to be integrated into a microcontroller for use in embedded control applications requiring an A/D converter.

### 10.6.1 External Pins and Routing

The following sections discuss the external pins associated with the ADC module and how they should be used for best results.

#### 10.6.1.1 Analog Supply Pins

The ADC module has analog power and ground supplies ( $V_{DDAD}$  and  $V_{SSAD}$ ) which are available as separate pins on some devices. On other devices,  $V_{SSAD}$  is shared on the same pin as the MCU digital  $V_{SS}$ , and on others, both  $V_{SSAD}$  and  $V_{DDAD}$  are shared with the MCU digital supply pins. In these cases, there are separate pads for the analog supplies which are bonded to the same pin as the corresponding digital supply so that some degree of isolation between the supplies is maintained.

When available on a separate pin, both  $V_{DDAD}$  and  $V_{SSAD}$  must be connected to the same voltage potential as their corresponding MCU digital supply ( $V_{DD}$  and  $V_{SS}$ ) and must be routed carefully for maximum noise immunity and bypass capacitors placed as near as possible to the package.

In cases where separate power supplies are used for analog and digital power, the ground connection between these supplies must be at the  $V_{SSAD}$  pin. This should be the only ground connection between these supplies if possible. The  $V_{SSAD}$  pin makes a good single point ground location.

### 10.6.1.2 Analog Reference Pins

In addition to the analog supplies, the ADC module has connections for two reference voltage inputs. The high reference is  $V_{REFH}$ , which may be shared on the same pin as  $V_{DDAD}$  on some devices. The low reference is  $V_{REFL}$ , which may be shared on the same pin as  $V_{SSAD}$  on some devices.

When available on a separate pin,  $V_{REFH}$  may be connected to the same potential as  $V_{DDAD}$ , or may be driven by an external source that is between the minimum  $V_{DDAD}$  spec and the  $V_{DDAD}$  potential ( $V_{REFH}$  must never exceed  $V_{DDAD}$ ). When available on a separate pin,  $V_{REFL}$  must be connected to the same voltage potential as  $V_{SSAD}$ . Both  $V_{REFH}$  and  $V_{REFL}$  must be routed carefully for maximum noise immunity and bypass capacitors placed as near as possible to the package.

AC current in the form of current spikes required to supply charge to the capacitor array at each successive approximation step is drawn through the  $V_{REFH}$  and  $V_{REFL}$  loop. The best external component to meet this current demand is a 0.1  $\mu\text{F}$  capacitor with good high frequency characteristics. This capacitor is connected between  $V_{REFH}$  and  $V_{REFL}$  and must be placed as near as possible to the package pins. Resistance in the path is not recommended because the current will cause a voltage drop which could result in conversion errors. Inductance in this path must be minimum (parasitic only).

### 10.6.1.3 Analog Input Pins

The external analog inputs are typically shared with digital I/O pins on MCU devices. The pin I/O control is disabled by setting the appropriate control bit in one of the pin control registers. Conversions can be performed on inputs without the associated pin control register bit set. It is recommended that the pin control register bit always be set when using a pin as an analog input. This avoids problems with contention because the output buffer will be in its high impedance state and the pullup is disabled. Also, the input buffer draws DC current when its input is not at either  $V_{DD}$  or  $V_{SS}$ . Setting the pin control register bits for all pins used as analog inputs should be done to achieve lowest operating current.

Empirical data shows that capacitors on the analog inputs improve performance in the presence of noise or when the source impedance is high. Use of 0.01  $\mu\text{F}$  capacitors with good high-frequency characteristics is sufficient. These capacitors are not necessary in all cases, but when used they must be placed as near as possible to the package pins and be referenced to  $V_{SSA}$ .

For proper conversion, the input voltage must fall between  $V_{REFH}$  and  $V_{REFL}$ . If the input is equal to or exceeds  $V_{REFH}$ , the converter circuit converts the signal to \$FFF (full scale 12-bit representation), \$3FF (full scale 10-bit representation) or \$FF (full scale 8-bit representation). If the input is equal to or less than  $V_{REFL}$ , the converter circuit converts it to \$000. Input voltages between  $V_{REFH}$  and  $V_{REFL}$  are straight-line linear conversions. There will be a brief current associated with  $V_{REFL}$  when the sampling capacitor is charging. The input is sampled for 3.5 cycles of the ADCK source when ADLSMP is low, or 23.5 cycles when ADLSMP is high.

For minimal loss of accuracy due to current injection, pins adjacent to the analog input pins should not be transitioning during conversions.

## 10.6.2 Sources of Error

Several sources of error exist for A/D conversions. These are discussed in the following sections.

### 10.6.2.1 Sampling Error

For proper conversions, the input must be sampled long enough to achieve the proper accuracy. Given the maximum input resistance of approximately  $7\text{k}\Omega$  and input capacitance of approximately  $5.5\text{ pF}$ , sampling to within  $1/4\text{LSB}$  (at 12-bit resolution) can be achieved within the minimum sample window (3.5 cycles @ 8 MHz maximum ADCK frequency) provided the resistance of the external analog source ( $R_{AS}$ ) is kept below  $2\text{ k}\Omega$ .

Higher source resistances or higher-accuracy sampling is possible by setting ADLSMP (to increase the sample window to 23.5 cycles) or decreasing ADCK frequency to increase sample time.

### 10.6.2.2 Pin Leakage Error

Leakage on the I/O pins can cause conversion error if the external analog source resistance ( $R_{AS}$ ) is high. If this error cannot be tolerated by the application, keep  $R_{AS}$  lower than  $V_{DDAD} / (2^N \cdot I_{LEAK})$  for less than  $1/4\text{LSB}$  leakage error ( $N = 8$  in 8-bit,  $10$  in 10-bit or  $12$  in 12-bit mode).

### 10.6.2.3 Noise-Induced Errors

System noise which occurs during the sample or conversion process can affect the accuracy of the conversion. The ADC accuracy numbers are guaranteed as specified only if the following conditions are met:

- There is a  $0.1\text{ }\mu\text{F}$  low-ESR capacitor from  $V_{REFH}$  to  $V_{REFL}$ .
- There is a  $0.1\text{ }\mu\text{F}$  low-ESR capacitor from  $V_{DDAD}$  to  $V_{SSAD}$ .
- If inductive isolation is used from the primary supply, an additional  $1\text{ }\mu\text{F}$  capacitor is placed from  $V_{DDAD}$  to  $V_{SSAD}$ .
- $V_{SSAD}$  (and  $V_{REFL}$ , if connected) is connected to  $V_{SS}$  at a quiet point in the ground plane.
- Operate the MCU in wait or stop3 mode before initiating (hardware triggered conversions) or immediately after initiating (hardware or software triggered conversions) the ADC conversion.
  - For software triggered conversions, immediately follow the write to the ADCSC1 with a WAIT instruction or STOP instruction.
  - For stop3 mode operation, select ADACK as the clock source. Operation in stop3 reduces  $V_{DD}$  noise but increases effective conversion time due to stop recovery.
- There is no I/O switching, input or output, on the MCU during the conversion.

There are some situations where external system activity causes radiated or conducted noise emissions or excessive  $V_{DD}$  noise is coupled into the ADC. In these situations, or when the MCU cannot be placed in wait or stop3 or I/O activity cannot be halted, these recommended actions may reduce the effect of noise on the accuracy:

- Place a  $0.01\text{ }\mu\text{F}$  capacitor ( $C_{AS}$ ) on the selected input channel to  $V_{REFL}$  or  $V_{SSAD}$  (this will improve noise issues but will affect sample rate based on the external analog source resistance).

- Average the result by converting the analog input many times in succession and dividing the sum of the results. Four samples are required to eliminate the effect of a 1LSB, one-time error.
- Reduce the effect of synchronous noise by operating off the asynchronous clock (ADACK) and averaging. Noise that is synchronous to ADCK cannot be averaged out.

### 10.6.2.4 Code Width and Quantization Error

The ADC quantizes the ideal straight-line transfer function into 4096 steps (in 12-bit mode). Each step ideally has the same height (1 code) and width. The width is defined as the delta between the transition points to one code and the next. The ideal code width for an N bit converter (in this case N can be 8, 10 or 12), defined as 1LSB, is:

$$1\text{LSB} = (V_{\text{REFH}} - V_{\text{REFL}}) / 2^N \quad \text{Eqn. 10-2}$$

There is an inherent quantization error due to the digitization of the result. For 8-bit or 10-bit conversions the code will transition when the voltage is at the midpoint between the points where the straight line transfer function is exactly represented by the actual transfer function. Therefore, the quantization error will be  $\pm 1/2\text{LSB}$  in 8- or 10-bit mode. As a consequence, however, the code width of the first (\$000) conversion is only  $1/2\text{LSB}$  and the code width of the last (\$FF or \$3FF) is  $1.5\text{LSB}$ .

For 12-bit conversions the code transitions only after the full code width is present, so the quantization error is  $-1\text{LSB}$  to  $0\text{LSB}$  and the code width of each step is  $1\text{LSB}$ .

### 10.6.2.5 Linearity Errors

The ADC may also exhibit non-linearity of several forms. Every effort has been made to reduce these errors but the system should be aware of them because they affect overall accuracy. These errors are:

- Zero-scale error ( $E_{\text{ZS}}$ ) (sometimes called offset) — This error is defined as the difference between the actual code width of the first conversion and the ideal code width ( $1/2\text{LSB}$  in 8-bit or 10-bit modes and  $1\text{LSB}$  in 12-bit mode). Note, if the first conversion is \$001, then the difference between the actual \$001 code width and its ideal ( $1\text{LSB}$ ) is used.
- Full-scale error ( $E_{\text{FS}}$ ) — This error is defined as the difference between the actual code width of the last conversion and the ideal code width ( $1.5\text{LSB}$  in 8-bit or 10-bit modes and  $1\text{LSB}$  in 12-bit mode). Note, if the last conversion is \$3FE, then the difference between the actual \$3FE code width and its ideal ( $1\text{LSB}$ ) is used.
- Differential non-linearity (DNL) — This error is defined as the worst-case difference between the actual code width and the ideal code width for all conversions.
- Integral non-linearity (INL) — This error is defined as the highest-value the (absolute value of the) running sum of DNL achieves. More simply, this is the worst-case difference of the actual transition voltage to a given code and its corresponding ideal transition voltage, for all codes.
- Total unadjusted error (TUE) — This error is defined as the difference between the actual transfer function and the ideal straight-line transfer function, and therefore includes all forms of error.



### 10.6.2.6 Code Jitter, Non-Monotonicity and Missing Codes

Analog-to-digital converters are susceptible to three special forms of error. These are code jitter, non-monotonicity, and missing codes.

Code jitter is when, at certain points, a given input voltage converts to one of two values when sampled repeatedly. Ideally, when the input voltage is infinitesimally smaller than the transition voltage, the converter yields the lower code (and vice-versa). However, even very small amounts of system noise can cause the converter to be indeterminate (between two codes) for a range of input voltages around the transition voltage. This range is normally around  $1/2\text{LSB}$  in 8-bit or 10-bit mode, or around  $2\text{LSB}$  in 12-bit mode, and will increase with noise.

This error may be reduced by repeatedly sampling the input and averaging the result. Additionally the techniques discussed in [Section 10.6.2.3](#) will reduce this error.

Non-monotonicity is defined as when, except for code jitter, the converter converts to a lower code for a higher input voltage. Missing codes are those values which are never converted for any input value.

In 8-bit or 10-bit mode, the ADC is guaranteed to be monotonic and to have no missing codes.



# Chapter 11

## Internal Clock Source (S08ICSV3)

### 11.1 Introduction

The internal clock source (ICS) module provides clock source choices for the MCU. The module contains a frequency-locked loop (FLL) as a clock source that is controllable by either an internal or an external reference clock. The module can provide this FLL clock or either of the internal or external reference clocks as a source for the MCU system clock.

The ICSTRM and FTRIM bits are normally reset to the factory trim values on any reset. However, any reset that puts the device into BDM (a POR with the BKGD pin held low or a development tool setting SBDFR[BDFR]) results in the ICSTRM and FTRIM bits being set to values of 0x80 and 0. When debugging the MCU, the factory trim value can be used by copying the trim values from the Flash locations shown in table 4-4.

There are also signals provided to control a low power oscillator (XOSCVLP) module to allow the use of an external crystal/resonator as the external reference clock.

Whichever clock source is chosen, it is passed through a reduced bus divider (BDIV) which allows a lower final output clock frequency to be derived.

#### 11.1.1 External Oscillator

The external oscillator module (XOSCVLP) provides the external clock options to the ICS module. The output of this submodule (OSCOUT) can be used as the real-time counter module (RTC) clock source.

#### 11.1.2 Stop2 Mode Considerations

If you are using a low range oscillator during stop2, reconfigure the ICSC2 register (the oscillator control bits) before PPDACK is written. The low range (RANGE=0) oscillator can operate in stop2 to be the clock source for the RTC module. If the low range oscillator is active when entering stop2, it remains active in stop2 regardless of the value of EREFSTEN. To disable the oscillator in stop2, switch the ICS into FBI or FEI mode before executing the STOP instruction.

Figure 11-1 shows the MC9S08QE128 Series block diagram with the ICS highlighted.

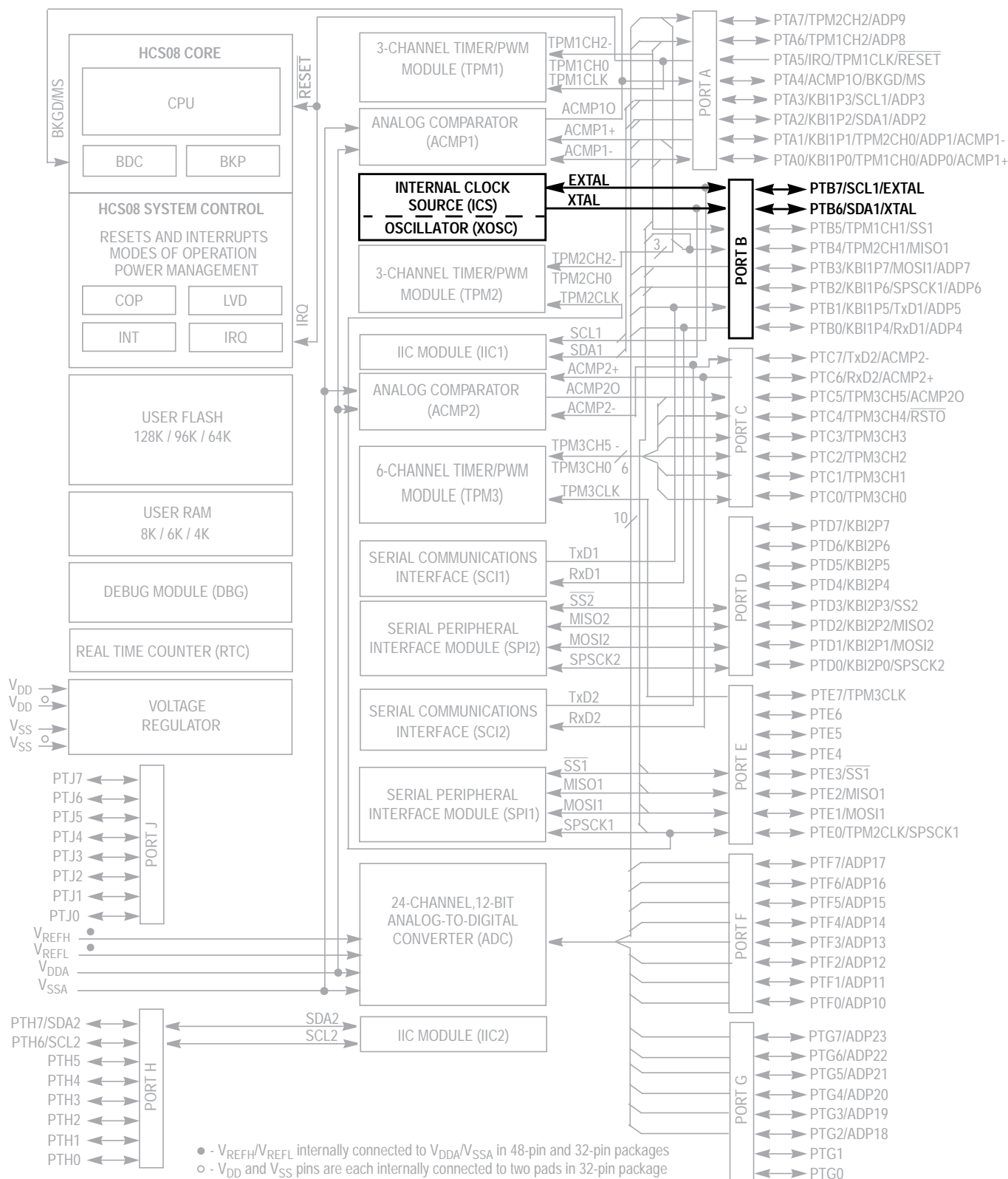


Figure 11-1. MC9S08QE128 Series Block Diagram Highlighting ICS Block and Pins

### 11.1.3 Features

Key features of the ICS module are:

- Frequency-locked loop (FLL) is trimmable for accuracy
- Internal or external reference clocks can be used to control the FLL
- Reference divider is provided for external clock
- Internal reference clock has 9 trim bits available
- Internal or external reference clocks can be selected as the clock source for the MCU
- Whichever clock is selected as the source can be divided down
  - 2 bit select for clock divider is provided
    - Allowable dividers are: 1, 2, 4, 8
- Control signals for a low power oscillator as the external reference clock are provided
  - HGO, RANGE, EREFS, ERCLKEN, EREFSTEN
- FLL Engaged Internal mode is automatically selected out of reset
- BDC clock is provided as a constant divide by 2 of the low range DCO output
- Three selectable digitally controlled oscillators (DCO) optimized for different frequency ranges.
- Option to maximize output frequency for a 32768 Hz external reference clock source.

### 11.1.4 Block Diagram

Figure 11-2 is the ICS block diagram.

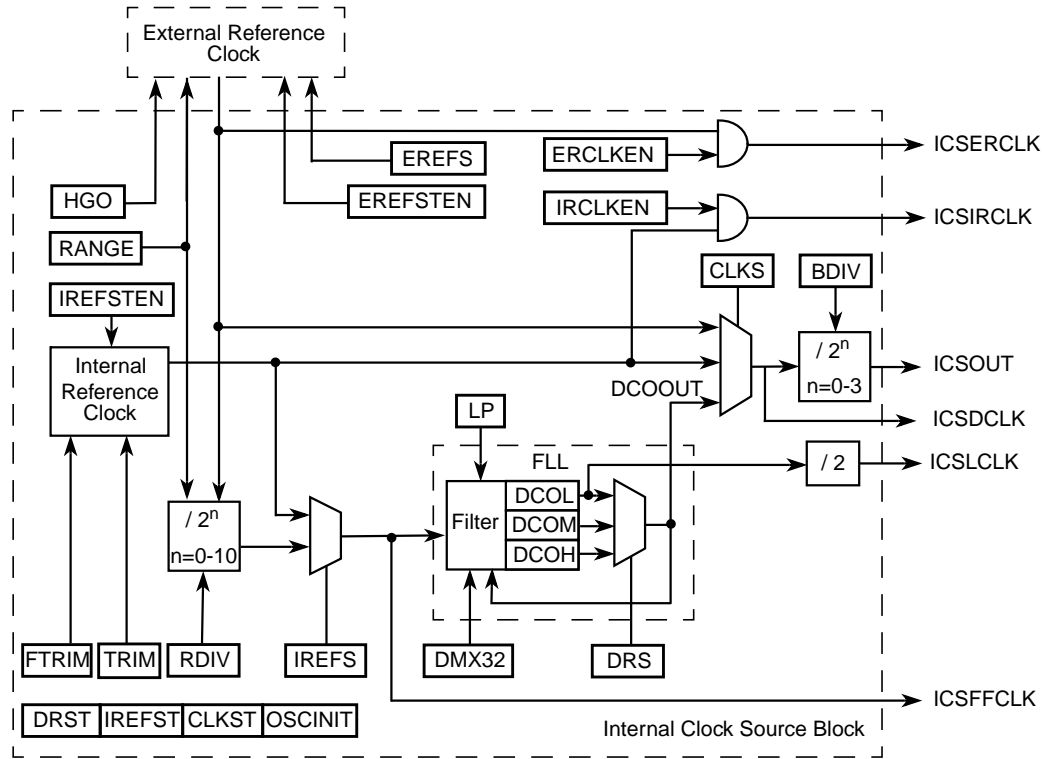


Figure 11-2. Internal Clock Source (ICS) Block Diagram

## 11.1.5 Modes of Operation

There are seven modes of operation for the ICS: FEI, FEE, FBI, FBILP, FBE, FBELP, and stop.

### 11.1.5.1 FLL Engaged Internal (FEI)

In FLL engaged internal mode, which is the default mode, the ICS supplies a clock derived from the FLL which is controlled by the internal reference clock. The BDC clock is supplied from the FLL.

### 11.1.5.2 FLL Engaged External (FEE)

In FLL engaged external mode, the ICS supplies a clock derived from the FLL which is controlled by an external reference clock. The BDC clock is supplied from the FLL.

### 11.1.5.3 FLL Bypassed Internal (FBI)

In FLL bypassed internal mode, the FLL is enabled and controlled by the internal reference clock, but is bypassed. The ICS supplies a clock derived from the internal reference clock. The BDC clock is supplied from the FLL.

### 11.1.5.4 FLL Bypassed Internal Low Power (FBILP)

In FLL bypassed internal low power mode, the FLL is disabled and bypassed, and the ICS supplies a clock derived from the internal reference clock. The BDC clock is not available.

### 11.1.5.5 FLL Bypassed External (FBE)

In FLL bypassed external mode, the FLL is enabled and controlled by an external reference clock, but is bypassed. The ICS supplies a clock derived from the external reference clock. The external reference clock can be an external crystal/resonator supplied by an OSC controlled by the ICS, or it can be another external clock source. The BDC clock is supplied from the FLL.

### 11.1.5.6 FLL Bypassed External Low Power (FBELP)

In FLL bypassed external low power mode, the FLL is disabled and bypassed, and the ICS supplies a clock derived from the external reference clock. The external reference clock can be an external crystal/resonator supplied by an OSC controlled by the ICS, or it can be another external clock source. The BDC clock is not available.

### 11.1.5.7 Stop (STOP)

In stop mode the FLL is disabled and the internal or external reference clocks can be selected to be enabled or disabled. The BDC clock is not available and the ICS does not provide an MCU clock source.

## 11.2 External Signal Description

There are no ICS signals that connect off chip.

## 11.3 Register Definition

Figure 11-1 is a summary of ICS registers.

Table 11-1. ICS Register Summary

Name		7	6	5	4	3	2	1	0
ICSC1	R	CLKS		RDIV			IREFS	IRCLKEN	IREFSTEN
	W								
ICSC2	R	BDIV		RANGE	HGO	LP	EREFS	ERCLKEN	EREFSTEN
	W								
ICSTRM	R	TRIM							
	W								
ICSSC	R	DRST	DMX32	IREFST	CLKST		OSCINIT	FTRIM	
	W	DRS							

### 11.3.1 ICS Control Register 1 (ICSC1)

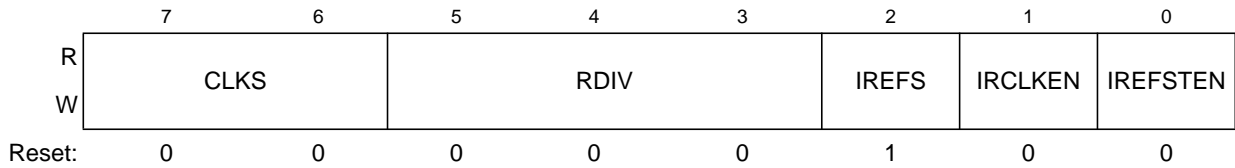


Figure 11-3. ICS Control Register 1 (ICSC1)

Table 11-2. ICS Control Register 1 Field Descriptions

Field	Description
7:6 CLKS	<b>Clock Source Select</b> — Selects the clock source that controls the bus frequency. The actual bus frequency depends on the value of the BDIV bits. 00 Output of FLL is selected. 01 Internal reference clock is selected. 10 External reference clock is selected. 11 Reserved, defaults to 00.
5:3 RDIV	<b>Reference Divider</b> — Selects the amount to divide down the external reference clock. Resulting frequency must be in the range 31.25 kHz to 39.0625 kHz. See Table 11-3 for the divide-by factors.
2 IREFS	<b>Internal Reference Select</b> — The IREFS bit selects the reference clock source for the FLL. 1 Internal reference clock selected 0 External reference clock selected
1 IRCLKEN	<b>Internal Reference Clock Enable</b> — The IRCLKEN bit enables the internal reference clock for use as ICSIRCLK. 1 ICSIRCLK active 0 ICSIRCLK inactive
0 IREFSTEN	<b>Internal Reference Stop Enable</b> — The IREFSTEN bit controls whether or not the internal reference clock remains enabled when the ICS enters stop mode. 1 Internal reference clock stays enabled in stop if IRCLKEN is set before entering stop 0 Internal reference clock is disabled in stop

Table 11-3. Reference Divide Factor

RDIV	RANGE=0	RANGE=1
0	1 <sup>1</sup>	32
1	2	64
2	4	128
3	8	256
4	16	512
5	32	1024
6	64	Reserved
7	128	Reserved

<sup>1</sup> Reset default



### 11.3.2 ICS Control Register 2 (ICSC2)

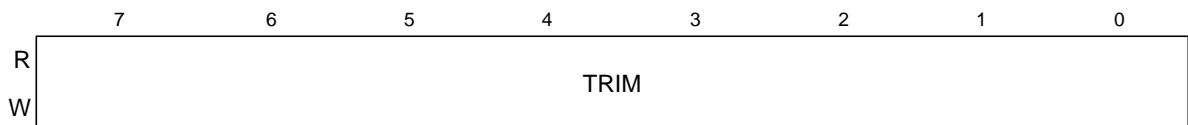


Figure 11-4. ICS Control Register 2 (ICSC2)

Table 11-4. ICS Control Register 2 Field Descriptions

Field	Description
7:6 BDIV	<b>Bus Frequency Divider</b> — Selects the amount to divide down the clock source selected by the CLKS bits. This controls the bus frequency. 00 Encoding 0 — Divides selected clock by 1 01 Encoding 1 — Divides selected clock by 2 (reset default) 10 Encoding 2 — Divides selected clock by 4 11 Encoding 3 — Divides selected clock by 8
5 RANGE	<b>Frequency Range Select</b> — Selects the frequency range for the external oscillator. 1 High frequency range selected for the external oscillator 0 Low frequency range selected for the external oscillator
4 HGO	<b>High Gain Oscillator Select</b> — The HGO bit controls the external oscillator mode of operation. 1 Configure external oscillator for high gain operation 0 Configure external oscillator for low power operation
3 LP	<b>Low Power Select</b> — The LP bit controls whether the FLL is disabled in FLL bypassed modes. 1 FLL is disabled in bypass modes unless BDM is active 0 FLL is not disabled in bypass mode
2 EREFS	<b>External Reference Select</b> — The EREFS bit selects the source for the external reference clock. 1 Oscillator requested 0 External Clock Source requested
1 ERCLKEN	<b>External Reference Enable</b> — The ERCLKEN bit enables the external reference clock for use as IC SERCLK. 1 IC SERCLK active 0 IC SERCLK inactive
0 EREFSTEN	<b>External Reference Stop Enable</b> — The EREFSTEN bit controls whether or not the external reference clock remains enabled when the ICS enters stop mode. 1 External reference clock stays enabled in stop if ERCLKEN is set before entering stop 0 External reference clock is disabled in stop

### 11.3.3 ICS Trim Register (ICSTRM)



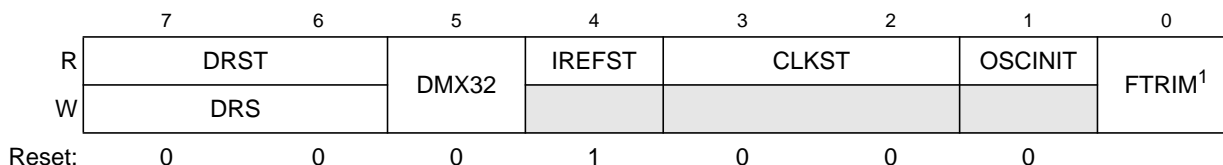
Reset: Note: TRIM is loaded during reset from a factory programmed location when not in BDM mode. If in a BDM mode, a default value of 0x80 is loaded.

Figure 11-5. ICS Trim Register (ICSTRM)

**Table 11-5. ICS Trim Register Field Descriptions**

Field	Description
7:0 TRIM	<p><b>ICS Trim Setting</b> — The TRIM bits control the internal reference clock frequency by controlling the internal reference clock period. The bits' effect are binary weighted (i.e., bit 1 will adjust twice as much as bit 0). Increasing the binary value in TRIM will increase the period, and decreasing the value will decrease the period.</p> <p>An additional fine trim bit is available in ICSSC as the FTRIM bit.</p>

### 11.3.4 ICS Status and Control (ICSSC)



**Figure 11-6. ICS Status and Control Register (ICSSC)**

<sup>1</sup> FTRIM is loaded during reset from a factory programmed location when not in any BDM mode. If in a BDM mode, FTRIM gets loaded with a value of 1'b0.

**Table 11-6. ICS Status and Control Register Field Descriptions**

Field	Description
7-6 DRST DRS	<p><b>DCO Range Status</b> — The DRST read field indicates the current frequency range for the FLL output, DCOOUT. See <a href="#">Table 11-7</a>. The DRST field does not update immediately after a write to the DRS field due to internal synchronization between clock domains. Writing the DRS bits to 2'b11 will be ignored and the DRST bits will remain with the current setting.</p> <p><b>DCO Range Select</b> — The DRS field selects the frequency range for the FLL output, DCOOUT. Writes to the DRS field while the LP bit is set are ignored.</p> <p>00 Low range. 01 Mid range. 10 High range. 11 Reserved.</p>
5 DMX32	<p><b>DCO Maximum frequency with 32.768 kHz reference</b> — The DMX32 bit controls whether or not the DCO frequency range is narrowed to its maximum frequency with a 32.768 kHz reference. See <a href="#">Table 11-7</a>.</p> <p>0 DCO has default range of 25%. 1 DCO is fined tuned for maximum frequency with 32.768 kHz reference.</p>
4 IREFST	<p><b>Internal Reference Status</b> — The IREFST bit indicates the current source for the reference clock. The IREFST bit does not update immediately after a write to the IREFS bit due to internal synchronization between clock domains.</p> <p>0 Source of reference clock is external clock. 1 Source of reference clock is internal clock.</p>

**Table 11-6. ICS Status and Control Register Field Descriptions (continued)**

Field	Description
3-2 CLKST	<b>Clock Mode Status</b> — The CLKST bits indicate the current clock mode. The CLKST bits don't update immediately after a write to the CLKS bits due to internal synchronization between clock domains. 00 Output of FLL is selected. 01 FLL Bypassed, Internal reference clock is selected. 10 FLL Bypassed, External reference clock is selected. 11 Reserved.
1 OSCINIT	<b>OSC Initialization</b> — If the external reference clock is selected by ERCLKEN or by the ICS being in FEE, FBE, or FBELP mode, and if EREFS is set, then this bit is set after the initialization cycles of the external oscillator clock have completed. This bit is only cleared when either ERCLKEN or EREFS are cleared.
0 FTRIM	<b>ICS Fine Trim</b> — The FTRIM bit controls the smallest adjustment of the internal reference clock frequency. Setting FTRIM will increase the period and clearing FTRIM will decrease the period by the smallest amount possible.

**Table 11-7. DCO frequency range<sup>1</sup>**

DRS	DMX32	Reference range	FLL factor	DCO range
00	0	31.25 - 39.0625 kHz	512	16 - 20 Mhz
	1	32.768 kHz	608	19.92 Mhz
01	0	31.25 - 39.0625 kHz	1024	32 - 40 Mhz
	1	32.768 kHz	1216	39.85 Mhz
10	0	31.25 - 39.0625 kHz	1536	48 - 60 Mhz
	1	32.768 kHz	1824	59.77 Mhz
11	Reserved			

<sup>1</sup> The resulting bus clock frequency should not exceed the maximum specified bus clock frequency of the device.

## 11.4 Functional Description

### 11.4.1 Operational Modes

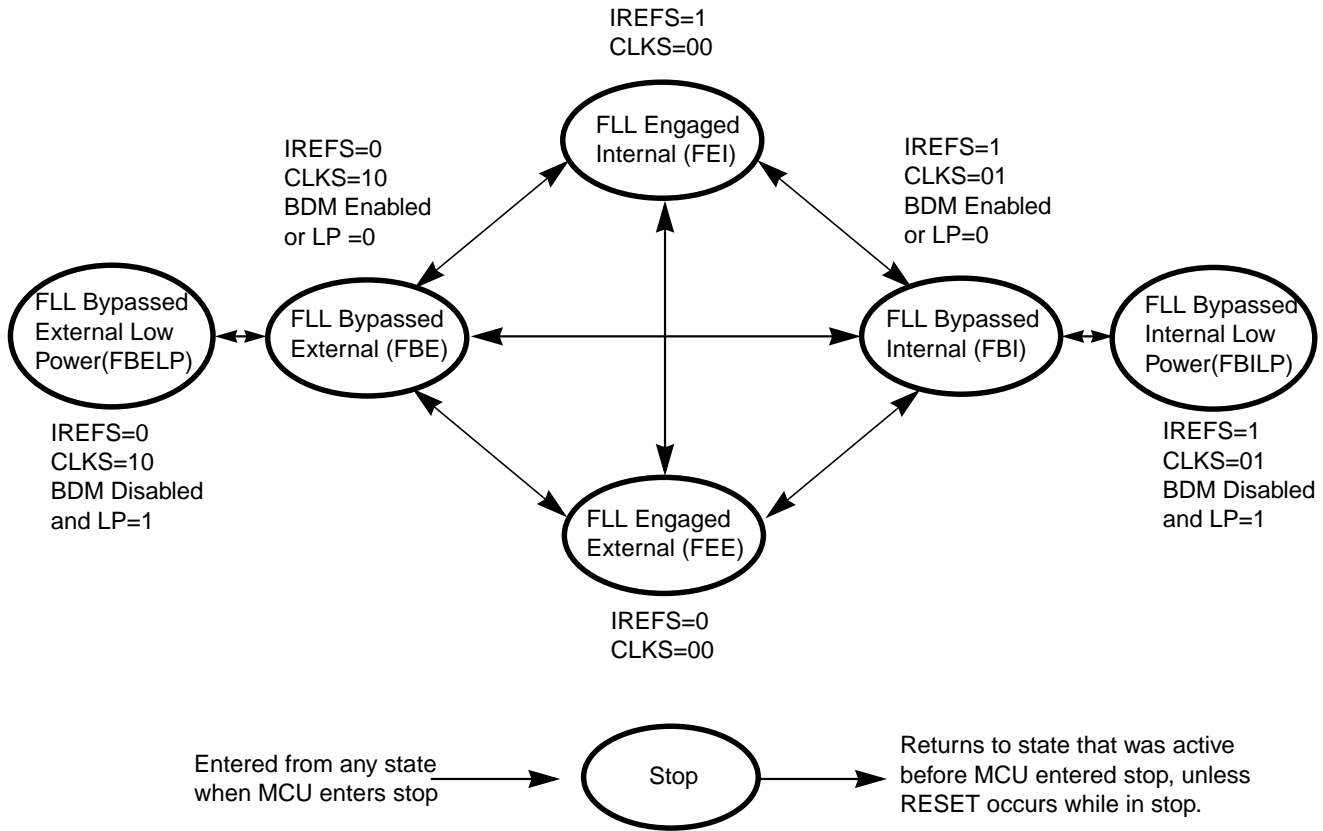


Figure 11-7. Clock Switching Modes

The seven states of the ICS are shown as a state diagram and are described below. The arrows indicate the allowed movements between the states.

#### 11.4.1.1 FLL Engaged Internal (FEI)

FLL engaged internal (FEI) is the default mode of operation and is entered when all the following conditions occur:

- CLKS bits are written to 00.
- IREFS bit is written to 1.

In FLL engaged internal mode, the ICSOUT clock is derived from the FLL clock, which is controlled by the internal reference clock. The FLL loop will lock the frequency to the FLL factor times the internal reference frequency. The ICSLCLK is available for BDC communications, and the internal reference clock is enabled.

### 11.4.1.2 FLL Engaged External (FEE)

The FLL engaged external (FEE) mode is entered when all the following conditions occur:

- CLKS bits are written to 00.
- IREFS bit is written to 0.
- RDIV bits are written to divide external reference clock to be within the range of 31.25 kHz to 39.0625 kHz.

In FLL engaged external mode, the ICSOUT clock is derived from the FLL clock which is controlled by the external reference clock. The FLL loop will lock the frequency to the FLL factor times the external reference frequency, as selected by the RDIV bits. The ICSLCLK is available for BDC communications, and the external reference clock is enabled.

### 11.4.1.3 FLL Bypassed Internal (FBI)

The FLL bypassed internal (FBI) mode is entered when all the following conditions occur:

- CLKS bits are written to 01.
- IREFS bit is written to 1.
- BDM mode is active or LP bit is written to 0.

In FLL bypassed internal mode, the ICSOUT clock is derived from the internal reference clock. The FLL clock is controlled by the internal reference clock, and the FLL loop will lock the FLL frequency to the FLL factor times the internal reference frequency. The ICSLCLK will be available for BDC communications, and the internal reference clock is enabled.

### 11.4.1.4 FLL Bypassed Internal Low Power (FBILP)

The FLL bypassed internal low power (FBILP) mode is entered when all the following conditions occur:

- CLKS bits are written to 01
- IREFS bit is written to 1.
- BDM mode is not active and LP bit is written to 1

In FLL bypassed internal low power mode, the ICSOUT clock is derived from the internal reference clock and the FLL is disabled. The ICSLCLK will be not be available for BDC communications, and the internal reference clock is enabled.

### 11.4.1.5 FLL Bypassed External (FBE)

The FLL bypassed external (FBE) mode is entered when all the following conditions occur:

- CLKS bits are written to 10.
- IREFS bit is written to 0.
- RDIV bits are written to divide external reference clock to be within the range of 31.25 kHz to 39.0625 kHz.
- BDM mode is active or LP bit is written to 0.

In FLL bypassed external mode, the ICSOUT clock is derived from the external reference clock. The FLL clock is controlled by the external reference clock, and the FLL loop will lock the FLL frequency to the FLL factor times the external reference frequency, as selected by the RDIV bits, so that the ICSLCLK will be available for BDC communications, and the external reference clock is enabled.

### 11.4.1.6 FLL Bypassed External Low Power (FBELP)

The FLL bypassed external low power (FBELP) mode is entered when all the following conditions occur:

- CLKS bits are written to 10.
- IREFS bit is written to 0.
- BDM mode is not active and LP bit is written to 1.

In FLL bypassed external low power mode, the ICSOUT clock is derived from the external reference clock and the FLL is disabled. The ICSLCLK will be not be available for BDC communications. The external reference clock is enabled.

### 11.4.1.7 Stop

Stop mode is entered whenever the MCU enters a STOP state. In this mode, all ICS clock signals are static except in the following cases:

ICSIRCLK will be active in stop mode when all the following conditions occur:

- IRCLKEN bit is written to 1
- IREFSTEN bit is written to 1

ICSERCLK will be active in stop mode when all the following conditions occur:

- ERCLKEN bit is written to 1 IREFSTEN bit is written to 1
- 

## 11.4.2 Mode Switching

The IREF bit can be changed at anytime, but the actual switch to the newly selected clock is shown by the IREFST bit. When switching between FLL engaged internal (FEI) and FLL engaged external (FEE) modes, the FLL will begin locking again after the switch is completed.

The CLKS bits can also be changed at anytime, but the actual switch to the newly selected clock is shown by the CLKST bits. If the newly selected clock is not available, the previous clock will remain selected.

The DRS bits can be changed at anytime except when LP bit is 1. If the DRS bits are changed while in FLL engaged internal (FEI) or FLL engaged external (FEE), the bus clock remains at the previous DCO range until the new DCO starts. When the new DCO starts the bus clock switches to it. After switching to the new DCO the FLL remains unlocked for several reference cycles. Once the selected DCO startup time is over, the FLL is locked. The completion of the switch is shown by the DRST bits.

### 11.4.3 Bus Frequency Divider

The BDIV bits can be changed at anytime and the actual switch to the new frequency will occur immediately.

### 11.4.4 Low Power Bit Usage

The low power bit (LP) is provided to allow the FLL to be disabled and thus conserve power when it is not being used. The DRS bits can not be written while LP bit is 1.

However, in some applications it may be desirable to allow the FLL to be enabled and to lock for maximum accuracy before switching to an FLL engaged mode. Do this by writing the LP bit to 0.

### 11.4.5 DCO Maximum Frequency with 32.768 kHz Oscillator

The FLL has an option to change the clock multiplier for the selected DCO range such that it results in the maximum bus frequency with a common 32.768 kHz crystal reference clock.

### 11.4.6 Internal Reference Clock

When IRCLKEN is set the internal reference clock signal will be presented as ICSIRCLK, which can be used as an additional clock source. The ICSIRCLK frequency can be re-targeted by trimming the period of the internal reference clock. This can be done by writing a new value to the TRIM bits in the ICSTRM register. Writing a larger value will slow down the ICSIRCLK frequency, and writing a smaller value to the ICSTRM register will speed up the ICSIRCLK frequency. The TRIM bits will effect the ICSOUT frequency if the ICS is in FLL engaged internal (FEI), FLL bypassed internal (FBI), or FLL bypassed internal low power (FBILP) mode.

Until ICSIRCLK is trimmed, programming low reference divider (RDIV) factors may result in ICSOUT frequencies that exceed the maximum chip-level frequency and violate the chip-level clock timing specifications (see the [Device Overview](#) chapter).

If IREFSTEN is set and the IRCLKEN bit is written to 1, the internal reference clock will keep running during stop mode in order to provide a fast recovery upon exiting stop.

All MCU devices are factory programmed with a trim value in a reserved memory location. This value is uploaded to the ICSTRM register and ICS FTRIM register during any reset initialization. For finer precision, the user can trim the internal oscillator in the application and set the FTRIM bit accordingly.

## 11.4.7 External Reference Clock

The ICS module supports an external reference clock with frequencies between 31.25 kHz to 40 MHz in all modes. When the ERCLKEN is set, the external reference clock signal will be presented as ICSECLK, which can be used as an additional clock source. When IREFS = 1, the external reference clock will not be used by the FLL and will only be used as ICSECLK. In these modes, the frequency can be equal to the maximum frequency the chip-level timing specifications will support (see the [Device Overview](#) chapter).

If EREFSTEN is set and the ERCLKEN bit is written to 1, the external reference clock will keep running during stop mode in order to provide a fast recovery upon exiting stop.

## 11.4.8 Fixed Frequency Clock

The ICS presents the divided FLL reference clock as ICSFFCLK for use as an additional clock source. ICSFFCLK frequency must be no more than 1/4 of the ICSOUT frequency to be valid.

## 11.4.9 Local Clock

The ICS presents the low range DCO output clock divided by two as ICSLCLK for use as a clock source for BDC communications. ICSLCLK is not available in FLL bypassed internal low power (FBILP) and FLL bypassed external low power (FBELP) modes.



# Chapter 12

## Inter-Integrated Circuit (S08IICV2)

### 12.1 Introduction

The inter-integrated circuit (IIC) provides a method of communication between a number of devices. The interface is designed to operate up to 100 kbps with maximum bus loading and timing. The device is capable of operating at higher baud rates, up to a maximum of bus clock/20, with reduced bus loading. The maximum communication length and the number of devices that can be connected are limited by a maximum bus capacitance of 400 pF.

All MC9S08QE128 Series MCUs feature the one or two IICs, as shown in [Figure 12-1](#).

#### NOTE

The SDA and SCL should not be driven above  $V_{DD}$ . These pins are psuedo open-drain containing a protection diode to  $V_{DD}$ .

#### 12.1.1 Module Configuration

The IIC1 module pins, SDA and SCL can be repositioned under software control using SOPT2[IIC1PS] as shown in [Table 12-1](#). This bit selects which general-purpose I/O ports are associated with IIC1 operation.

**Table 12-1. IIC1 Position Options**

SOPT2[IIC1PS]	Port Pin for SDA	Port Pin for SCL
0 (default)	PTA2	PTA3
1	PTB6	PTB7

#### 12.1.2 Interrupt Vectors

For MC9S08QE128 Series MCUs with two IICs, both IICs share a single interrupt vector. When interrupts are enabled for both IICs, the IICF bit must be polled in the IIC1S and IIC2S registers to determine which IIC caused the interrupt. See [Section 4.2, “Reset and Interrupt Vector Assignments,”](#) for the IIC interrupt vector assignment.

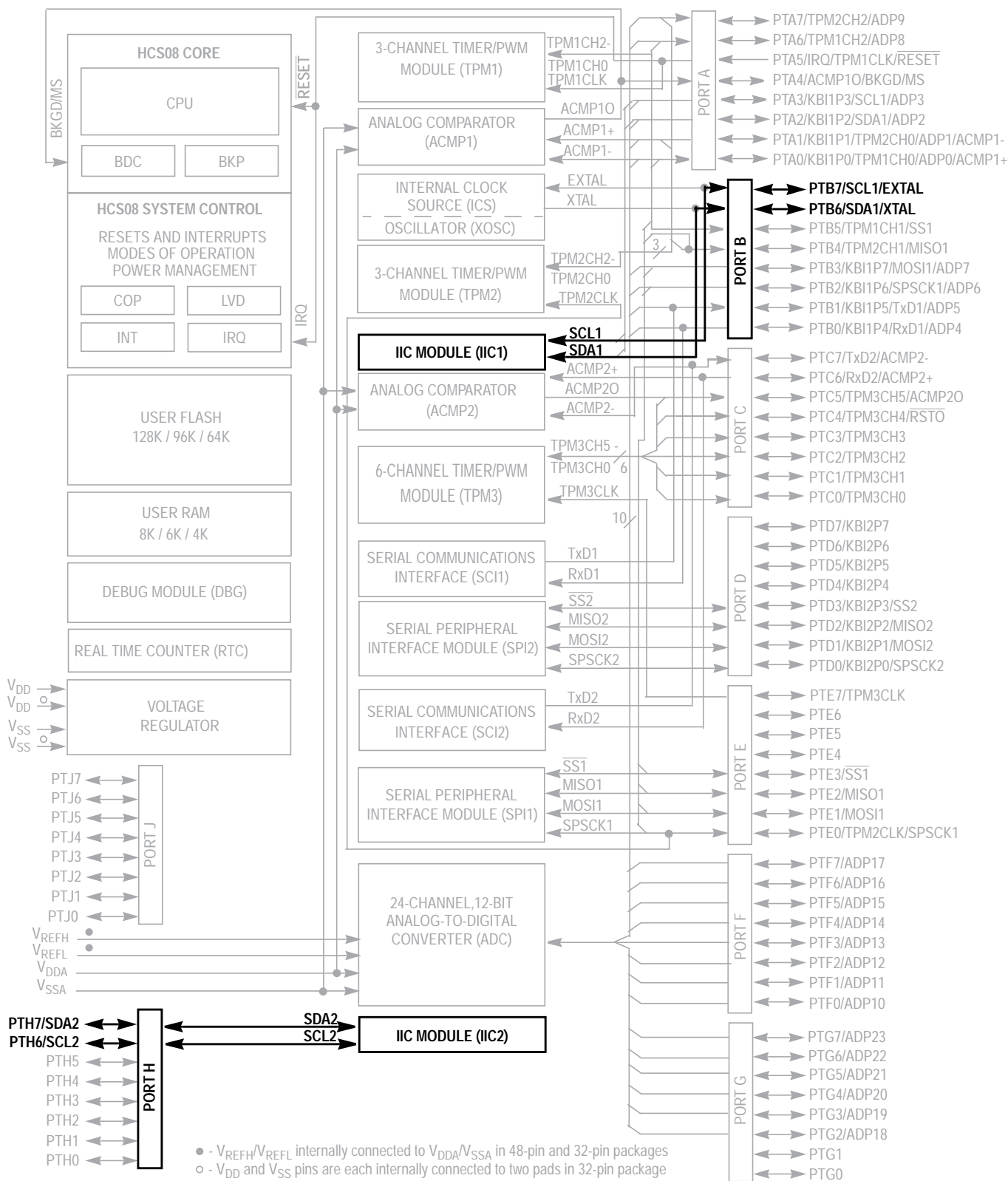


Figure 12-1. MC9S08QE128 Series Block Diagram Highlighting the IIC Modules

### 12.1.3 Features

The IIC includes these distinctive features:

- Compatible with IIC bus standard
- Multi-master operation
- Software programmable for one of 64 different serial clock frequencies
- Software selectable acknowledge bit
- Interrupt driven byte-by-byte data transfer
- Arbitration lost interrupt with automatic mode switching from master to slave
- Calling address identification interrupt
- START and STOP signal generation/detection
- Repeated START signal generation
- Acknowledge bit generation/detection
- Bus busy detection
- General call recognition
- 10-bit address extension

### 12.1.4 Modes of Operation

A brief description of the IIC in the various MCU modes is given here.

- **Run mode** — This is the basic mode of operation. To conserve power in this mode, disable the module.
- **Wait mode** — The module will continue to operate while the MCU is in wait mode and can provide a wake-up interrupt.
- **Stop mode** — The IIC is inactive in stop3 mode for reduced power consumption. The STOP instruction does not affect IIC register states. Stop2 will reset the register contents.

## 12.1.5 Block Diagram

Figure 12-2 is a block diagram of the IIC.

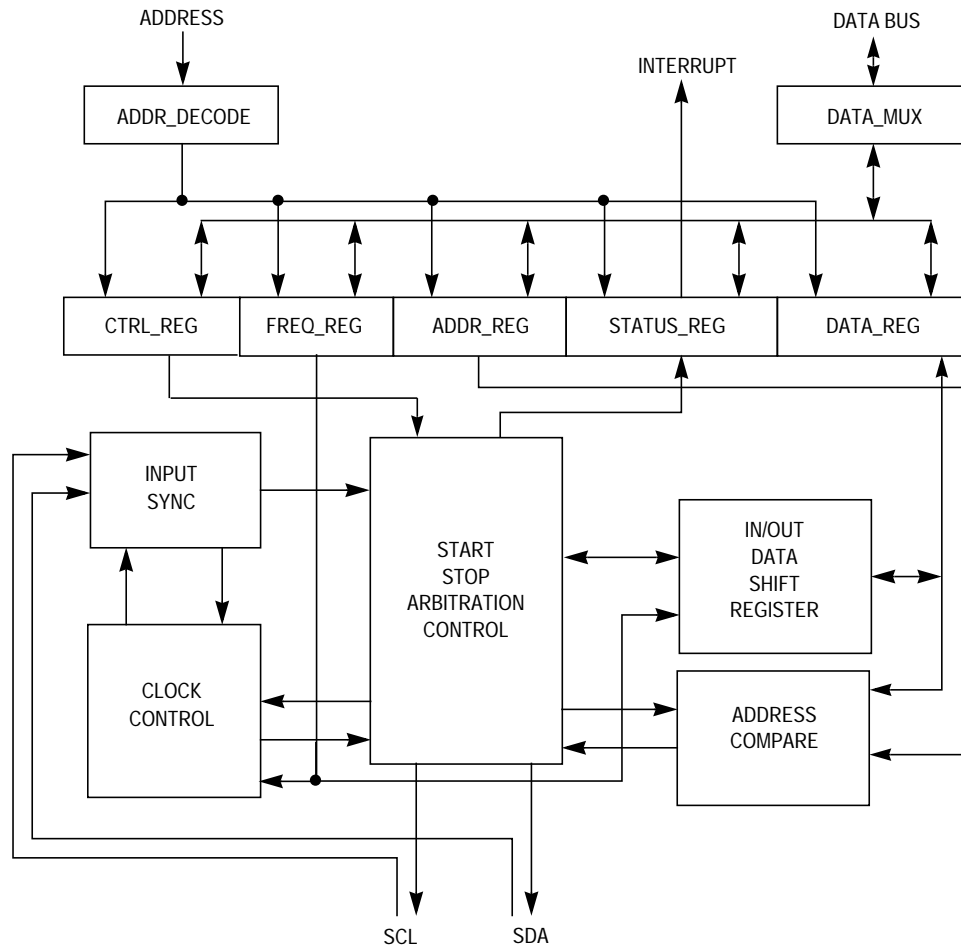


Figure 12-2. IIC Functional Block Diagram

## 12.2 External Signal Description

This section describes each user-accessible pin signal.

### 12.2.1 SCL — Serial Clock Line

The bidirectional SCL is the serial clock line of the IIC system.

### 12.2.2 SDA — Serial Data Line

The bidirectional SDA is the serial data line of the IIC system.

## 12.3 Register Definition

This section consists of the IIC register descriptions in address order.

Refer to the direct-page register summary in the [Memory](#) chapter of this data sheet for the absolute address assignments for all IIC registers. This section refers to registers and control bits only by their names. A Freescale-provided equate or header file is used to translate these names into the appropriate absolute addresses.

### 12.3.1 IIC Address Register (IICxA)



**Figure 12-3. IIC Address Register (IICxA)**

**Table 12-2. IICxA Field Descriptions**

Field	Description
7:1 AD[7:1]	<b>Slave Address</b> — The AD[7:1] field contains the slave address to be used by the IIC module. This field is used on the 7-bit address scheme and the lower seven bits of the 10-bit address scheme.

### 12.3.2 IIC Frequency Divider Register (IICxF)

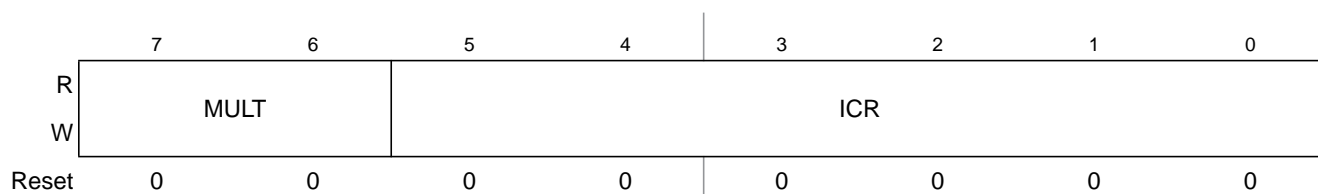


Figure 12-4. IIC Frequency Divider Register (IICxF)

Table 12-3. IICxF Field Descriptions

Field	Description
7:6 MULT	<p><b>IIC Multiplier Factor</b> — The MULT bits define the multiplier factor mul. This factor is used along with the SCL divider to generate the IIC baud rate. The multiplier factor mul as defined by the MULT bits is provided below.</p> <p>00 mul = 01 01 mul = 02 10 mul = 04 11 Reserved</p>
5:0 ICR	<p><b>IIC Clock Rate</b> — The ICR bits are used to prescale the bus clock for bit rate selection. These bits and the MULT bits are used to determine the IIC baud rate, the SDA hold time, the SCL Start hold time and the SCL Stop hold time. Table 12-4 provides the SCL divider and hold values for corresponding values of the ICR.</p> <p>The SCL divider multiplied by multiplier factor mul is used to generate IIC baud rate.</p> <p style="text-align: center;"><b>IIC baud rate = bus speed (Hz)/(mul * SCL divider) <span style="float: right;">Eqn. 12-1</span></b></p> <p>SDA hold time is the delay from the falling edge of SCL (IIC clock) to the changing of SDA (IIC data).</p> <p style="text-align: center;"><b>SDA hold time = bus period (s) * mul * SDA hold value <span style="float: right;">Eqn. 12-2</span></b></p> <p>SCL Start hold time is the delay from the falling edge of SDA (IIC data) while SCL is high (Start condition) to the falling edge of SCL (IIC clock).</p> <p style="text-align: center;"><b>SCL Start hold time = bus period (s) * mul * SCL Start hold value <span style="float: right;">Eqn. 12-3</span></b></p> <p>SCL Stop hold time is the delay from the rising edge of SCL (IIC clock) to the rising edge of SDA (IIC data) while SCL is high (Stop condition).</p> <p style="text-align: center;"><b>SCL Stop hold time = bus period (s) * mul * SCL Stop hold value <span style="float: right;">Eqn. 12-4</span></b></p>

For example if the bus speed is 8MHz, the table below shows the possible hold time values with different ICR and MULT selections to achieve an IIC baud rate of 100kbps.

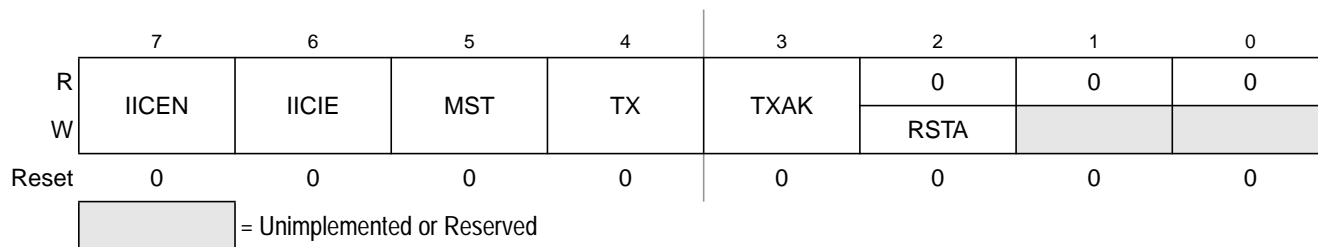
MULT	ICR	Hold times (μs)		
		SDA	SCL Start	SCL Stop
0x2	0x00	3.500	4.750	5.125
0x1	0x07	2.500	4.250	5.125
0x1	0x0B	2.250	4.000	5.250
0x0	0x14	2.125	4.000	5.250
0x0	0x18	1.125	3.000	5.500

Table 12-4. IIC Divider and Hold Values

ICR (hex)	SCL Divider	SDA Hold Value	SCL Hold (Start) Value	SDA Hold (Stop) Value
00	20	7	6	11
01	22	7	7	12
02	24	8	8	13
03	26	8	9	14
04	28	9	10	15
05	30	9	11	16
06	34	10	13	18
07	40	10	16	21
08	28	7	10	15
09	32	7	12	17
0A	36	9	14	19
0B	40	9	16	21
0C	44	11	18	23
0D	48	11	20	25
0E	56	13	24	29
0F	68	13	30	35
10	48	9	18	25
11	56	9	22	29
12	64	13	26	33
13	72	13	30	37
14	80	17	34	41
15	88	17	38	45
16	104	21	46	53
17	128	21	58	65
18	80	9	38	41
19	96	9	46	49
1A	112	17	54	57
1B	128	17	62	65
1C	144	25	70	73
1D	160	25	78	81
1E	192	33	94	97
1F	240	33	118	121

ICR (hex)	SCL Divider	SDA Hold Value	SCL Hold (Start) Value	SCL Hold (Stop) Value
20	160	17	78	81
21	192	17	94	97
22	224	33	110	113
23	256	33	126	129
24	288	49	142	145
25	320	49	158	161
26	384	65	190	193
27	480	65	238	241
28	320	33	158	161
29	384	33	190	193
2A	448	65	222	225
2B	512	65	254	257
2C	576	97	286	289
2D	640	97	318	321
2E	768	129	382	385
2F	960	129	478	481
30	640	65	318	321
31	768	65	382	385
32	896	129	446	449
33	1024	129	510	513
34	1152	193	574	577
35	1280	193	638	641
36	1536	257	766	769
37	1920	257	958	961
38	1280	129	638	641
39	1536	129	766	769
3A	1792	257	894	897
3B	2048	257	1022	1025
3C	2304	385	1150	1153
3D	2560	385	1278	1281
3E	3072	513	1534	1537
3F	3840	513	1918	1921

### 12.3.3 IIC Control Register (IICxC1)



**Figure 12-5. IIC Control Register (IICxC1)**

**Table 12-5. IICxC1 Field Descriptions**

Field	Description
7 IICEN	<b>IIC Enable</b> — The IICEN bit determines whether the IIC module is enabled. 0 IIC is not enabled. 1 IIC is enabled.
6 IICIE	<b>IIC Interrupt Enable</b> — The IICIE bit determines whether an IIC interrupt is requested. 0 IIC interrupt request not enabled. 1 IIC interrupt request enabled.
5 MST	<b>Master Mode Select</b> — The MST bit is changed from a 0 to a 1 when a START signal is generated on the bus and master mode is selected. When this bit changes from a 1 to a 0 a STOP signal is generated and the mode of operation changes from master to slave. 0 Slave mode. 1 Master mode.
4 TX	<b>Transmit Mode Select</b> — The TX bit selects the direction of master and slave transfers. In master mode this bit should be set according to the type of transfer required. Therefore, for address cycles, this bit will always be high. When addressed as a slave this bit should be set by software according to the SRW bit in the status register. 0 Receive. 1 Transmit.
3 TXAK	<b>Transmit Acknowledge Enable</b> — This bit specifies the value driven onto the SDA during data acknowledge cycles for both master and slave receivers. 0 An acknowledge signal will be sent out to the bus after receiving one data byte. 1 No acknowledge signal response is sent.
2 RSTA	<b>Repeat START</b> — Writing a 1 to this bit will generate a repeated START condition provided it is the current master. This bit will always be read as a low. Attempting a repeat at the wrong time will result in loss of arbitration.



## 12.3.4 IIC Status Register (IICxS)

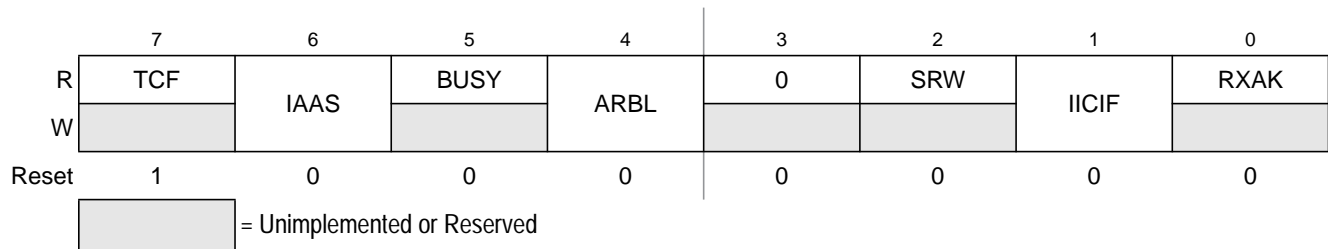


Figure 12-6. IIC Status Register (IICxS)

Table 12-6. IICxS Field Descriptions

Field	Description
7 TCF	<b>Transfer Complete Flag</b> — This bit is set on the completion of a byte transfer. Note that this bit is only valid during or immediately following a transfer to the IIC module or from the IIC module. The TCF bit is cleared by reading the IICxD register in receive mode or writing to the IICxD in transmit mode. 0 Transfer in progress. 1 Transfer complete.
6 IAAS	<b>Addressed as a Slave</b> — The IAAS bit is set when the calling address matches the programmed slave address, or when the GCAEN bit is set and a general call is received. Writing the IICxC register clears this bit. 0 Not addressed. 1 Addressed as a slave.
5 BUSY	<b>Bus Busy</b> — The BUSY bit indicates the status of the bus regardless of slave or master mode. The BUSY bit is set when a START signal is detected and cleared when a STOP signal is detected. 0 Bus is idle. 1 Bus is busy.
4 ARBL	<b>Arbitration Lost</b> — This bit is set by hardware when the arbitration procedure is lost. The ARBL bit must be cleared by software, by writing a 1 to it. 0 Standard bus operation. 1 Loss of arbitration.
2 SRW	<b>Slave Read/Write</b> — When addressed as a slave the SRW bit indicates the value of the R/W command bit of the calling address sent to the master. 0 Slave receive, master writing to slave. 1 Slave transmit, master reading from slave.
1 IICIF	<b>IIC Interrupt Flag</b> — The IICIF bit is set when an interrupt is pending. This bit must be cleared by software, by writing a 1 to it in the interrupt routine. One of the following events can set the IICIF bit: <ul style="list-style-type: none"> <li>• One byte transfer completes</li> <li>• Match of slave address to calling address</li> <li>• Arbitration lost</li> </ul> 0 No interrupt pending. 1 Interrupt pending.
0 RXAK	<b>Receive Acknowledge</b> — When the RXAK bit is low, it indicates an acknowledge signal has been received after the completion of one byte of data transmission on the bus. If the RXAK bit is high it means that no acknowledge signal is detected. 0 Acknowledge received. 1 No acknowledge received.

### 12.3.5 IIC Data I/O Register (IICxD)

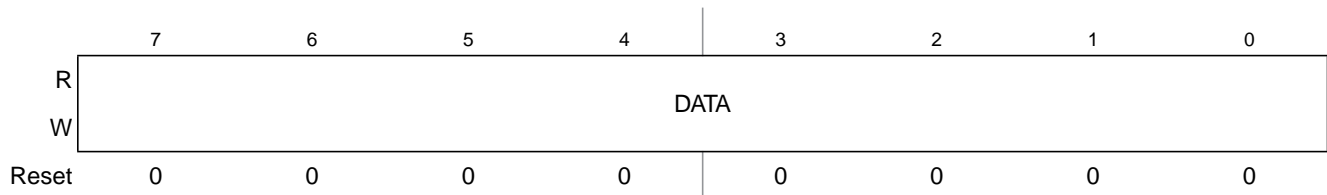


Figure 12-7. IIC Data I/O Register (IICxD)

Table 12-7. IICxD Field Descriptions

Field	Description
7:0 DATA	<b>Data</b> — In master transmit mode, when data is written to the IICxD, a data transfer is initiated. The most significant bit is sent first. In master receive mode, reading this register initiates receiving of the next byte of data.

**NOTE**

When transitioning out of master receive mode, the IIC mode should be switched before reading the IICxD register to prevent an inadvertent initiation of a master receive data transfer.

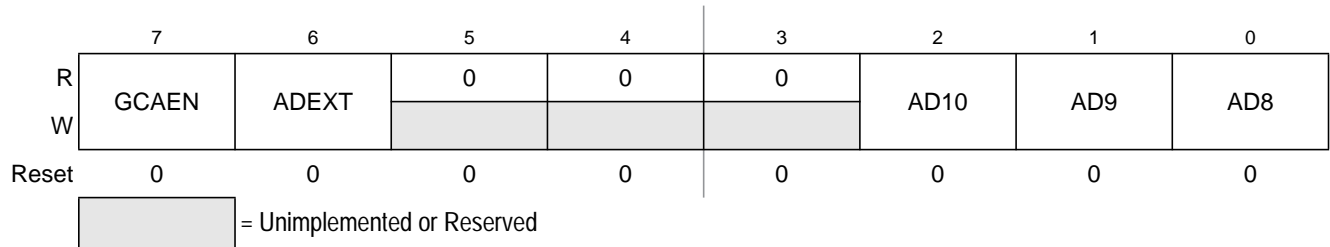
In slave mode, the same functions are available after an address match has occurred.

Note that the TX bit in IICxC must correctly reflect the desired direction of transfer in master and slave modes for the transmission to begin. For instance, if the IIC is configured for master transmit but a master receive is desired, then reading the IICxD will not initiate the receive.

Reading the IICxD will return the last byte received while the IIC is configured in either master receive or slave receive modes. The IICxD does not reflect every byte that is transmitted on the IIC bus, nor can software verify that a byte has been written to the IICxD correctly by reading it back.

In master transmit mode, the first byte of data written to IICxD following assertion of MST is used for the address transfer and should comprise of the calling address (in bit 7 to bit 1) concatenated with the required  $R/\overline{W}$  bit (in position bit 0).

### 12.3.6 IIC Control Register 2 (IICxC2)



**Figure 12-8. IIC Control Register (IICxC2)**

**Table 12-8. IICxC2 Field Descriptions**

Field	Description
7 GCAEN	<b>General Call Address Enable</b> — The GCAEN bit enables or disables general call address. 0 General call address is disabled 1 General call address is enabled.
6 ADEXT	<b>Address Extension</b> — The ADEXT bit controls the number of bits used for the slave address. 0 7-bit address scheme 1 10-bit address scheme
2:0 AD[10:8]	<b>Slave Address</b> — The AD[10:8] field contains the upper three bits of the slave address in the 10-bit address scheme. This field is only valid when the ADEXT bit is set.

## 12.4 Functional Description

This section provides a complete functional description of the IIC module.

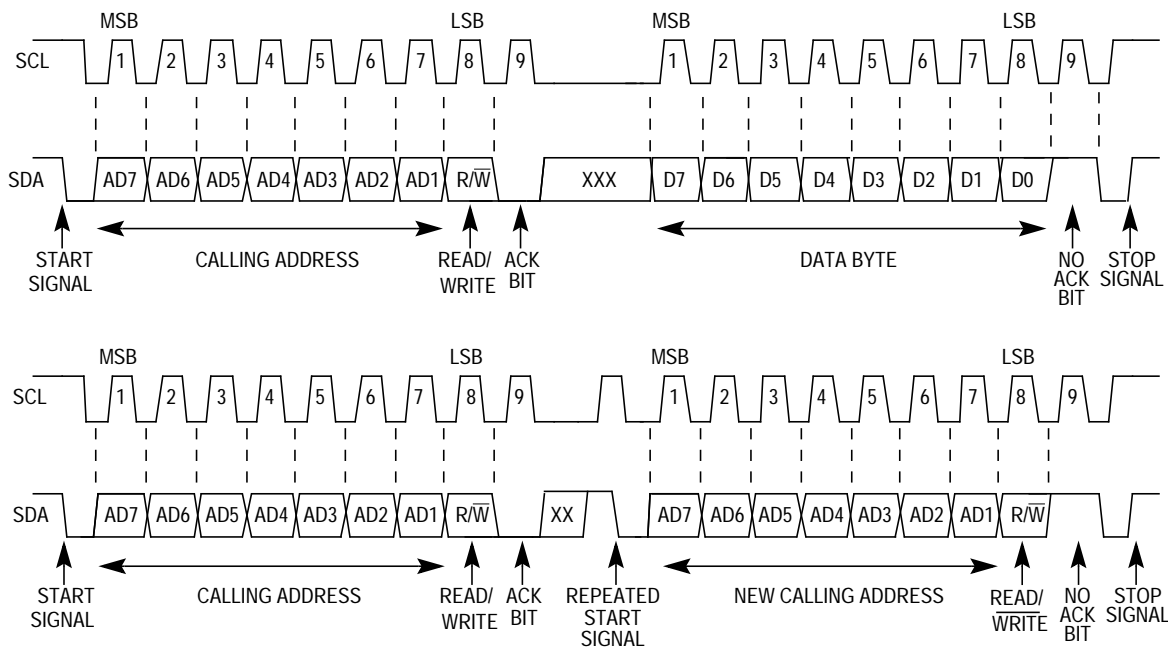
### 12.4.1 IIC Protocol

The IIC bus system uses a serial data line (SDA) and a serial clock line (SCL) for data transfer. All devices connected to it must have open drain or open collector outputs. A logic AND function is exercised on both lines with external pull-up resistors. The value of these resistors is system dependent.

Normally, a standard communication is composed of four parts:

- START signal
- Slave address transmission
- Data transfer
- STOP signal

The STOP signal should not be confused with the CPU STOP instruction. The IIC bus system communication is described briefly in the following sections and illustrated in [Figure 12-9](#).



**Figure 12-9. IIC Bus Transmission Signals**

### 12.4.1.1 START Signal

When the bus is free; i.e., no master device is engaging the bus (both SCL and SDA lines are at logical high), a master may initiate communication by sending a START signal. As shown in Figure 12-9, a START signal is defined as a high-to-low transition of SDA while SCL is high. This signal denotes the beginning of a new data transfer (each data transfer may contain several bytes of data) and brings all slaves out of their idle states.

### 12.4.1.2 Slave Address Transmission

The first byte of data transferred immediately after the START signal is the slave address transmitted by the master. This is a seven-bit calling address followed by a  $R/\overline{W}$  bit. The  $R/\overline{W}$  bit tells the slave the desired direction of data transfer.

- 1 = Read transfer, the slave transmits data to the master.
- 0 = Write transfer, the master transmits data to the slave.

Only the slave with a calling address that matches the one transmitted by the master will respond by sending back an acknowledge bit. This is done by pulling the SDA low at the 9th clock (see Figure 12-9).

No two slaves in the system may have the same address. If the IIC module is the master, it must not transmit an address that is equal to its own slave address. The IIC cannot be master and slave at the same time. However, if arbitration is lost during an address cycle, the IIC will revert to slave mode and operate correctly even if it is being addressed by another master.

### 12.4.1.3 Data Transfer

Before successful slave addressing is achieved, the data transfer can proceed byte-by-byte in a direction specified by the  $R/\overline{W}$  bit sent by the calling master.

All transfers that come after an address cycle are referred to as data transfers, even if they carry sub-address information for the slave device

Each data byte is 8 bits long. Data may be changed only while SCL is low and must be held stable while SCL is high as shown in Figure 12-9. There is one clock pulse on SCL for each data bit, the MSB being transferred first. Each data byte is followed by a 9th (acknowledge) bit, which is signalled from the receiving device. An acknowledge is signalled by pulling the SDA low at the ninth clock. In summary, one complete data transfer needs nine clock pulses.

If the slave receiver does not acknowledge the master in the 9th bit time, the SDA line must be left high by the slave. The master interprets the failed acknowledge as an unsuccessful data transfer.

If the master receiver does not acknowledge the slave transmitter after a data byte transmission, the slave interprets this as an end of data transfer and releases the SDA line.

In either case, the data transfer is aborted and the master does one of two things:

- Relinquishes the bus by generating a STOP signal.
- Commences a new calling by generating a repeated START signal.

#### 12.4.1.4 STOP Signal

The master can terminate the communication by generating a STOP signal to free the bus. However, the master may generate a START signal followed by a calling command without generating a STOP signal first. This is called repeated START. A STOP signal is defined as a low-to-high transition of SDA while SCL at logical 1 (see [Figure 12-9](#)).

The master can generate a STOP even if the slave has generated an acknowledge at which point the slave must release the bus.

#### 12.4.1.5 Repeated START Signal

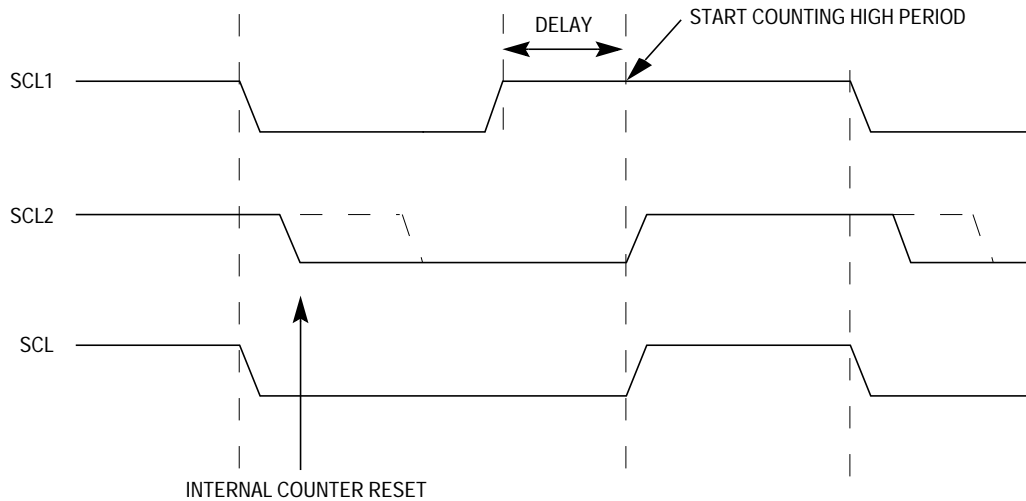
As shown in [Figure 12-9](#), a repeated START signal is a START signal generated without first generating a STOP signal to terminate the communication. This is used by the master to communicate with another slave or with the same slave in different mode (transmit/receive mode) without releasing the bus.

#### 12.4.1.6 Arbitration Procedure

The IIC bus is a true multi-master bus that allows more than one master to be connected on it. If two or more masters try to control the bus at the same time, a clock synchronization procedure determines the bus clock, for which the low period is equal to the longest clock low period and the high is equal to the shortest one among the masters. The relative priority of the contending masters is determined by a data arbitration procedure, a bus master loses arbitration if it transmits logic 1 while another master transmits logic 0. The losing masters immediately switch over to slave receive mode and stop driving SDA output. In this case, the transition from master to slave mode does not generate a STOP condition. Meanwhile, a status bit is set by hardware to indicate loss of arbitration.

#### 12.4.1.7 Clock Synchronization

Because wire-AND logic is performed on the SCL line, a high-to-low transition on the SCL line affects all the devices connected on the bus. The devices start counting their low period and after a device's clock has gone low, it holds the SCL line low until the clock high state is reached. However, the change of low to high in this device clock may not change the state of the SCL line if another device clock is still within its low period. Therefore, synchronized clock SCL is held low by the device with the longest low period. Devices with shorter low periods enter a high wait state during this time (see [Figure 12-10](#)). When all devices concerned have counted off their low period, the synchronized clock SCL line is released and pulled high. There is then no difference between the device clocks and the state of the SCL line and all the devices start counting their high periods. The first device to complete its high period pulls the SCL line low again.



**Figure 12-10. IIC Clock Synchronization**

### 12.4.1.8 Handshaking

The clock synchronization mechanism can be used as a handshake in data transfer. Slave devices may hold the SCL low after completion of one byte transfer (9 bits). In such case, it halts the bus clock and forces the master clock into wait states until the slave releases the SCL line.

### 12.4.1.9 Clock Stretching

The clock synchronization mechanism can be used by slaves to slow down the bit rate of a transfer. After the master has driven SCL low the slave can drive SCL low for the required period and then release it. If the slave SCL low period is greater than the master SCL low period then the resulting SCL bus signal low period is stretched.

## 12.4.2 10-bit Address

For 10-bit addressing, 0x11110 is used for the first 5 bits of the first address byte. Various combinations of read/write formats are possible within a transfer that includes 10-bit addressing.

### 12.4.2.1 Master-Transmitter Addresses a Slave-Receiver

The transfer direction is not changed (see Table 12-9). When a 10-bit address follows a START condition, each slave compares the first seven bits of the first byte of the slave address (11110XX) with its own address and tests whether the eighth bit ( $R/\overline{W}$  direction bit) is 0. It is possible that more than one device will find a match and generate an acknowledge (A1). Each slave that finds a match will compare the eight bits of the second byte of the slave address with its own address, but only one slave will find a match and generate an acknowledge (A2). The matching slave will remain addressed by the master until it receives a STOP condition (P) or a repeated START condition (Sr) followed by a different slave address.

S	Slave Address 1st 7 bits 11110 + AD10 + AD9	R/W 0	A1	Slave Address 2nd byte AD[8:1]	A2	Data	A	...	Data	A/A	P
---	--	----------	----	-----------------------------------	----	------	---	-----	------	-----	---

**Table 12-9. Master-Transmitter Addresses Slave-Receiver with a 10-bit Address**

After the master-transmitter has sent the first byte of the 10-bit address, the slave-receiver will see an IIC interrupt. User software must ensure that for this interrupt, the contents of IICD are ignored and not treated as valid data.

### 12.4.2.2 Master-Receiver Addresses a Slave-Transmitter

The transfer direction is changed after the second  $R/\overline{W}$  bit (see Table 12-10). Up to and including acknowledge bit A2, the procedure is the same as that described for a master-transmitter addressing a slave-receiver. After the repeated START condition (Sr), a matching slave remembers that it was addressed before. This slave then checks whether the first seven bits of the first byte of the slave address following Sr are the same as they were after the START condition (S), and tests whether the eighth ( $R/\overline{W}$ ) bit is 1. If there is a match, the slave considers that it has been addressed as a transmitter and generates acknowledge A3. The slave-transmitter remains addressed until it receives a STOP condition (P) or a repeated START condition (Sr) followed by a different slave address.

After a repeated START condition (Sr), all other slave devices will also compare the first seven bits of the first byte of the slave address with their own addresses and test the eighth ( $R/\overline{W}$ ) bit. However, none of them will be addressed because  $R/\overline{W} = 1$  (for 10-bit devices), or the 11110XX slave address (for 7-bit devices) does not match.

S	Slave Address 1st 7 bits 11110 + AD10 + AD9	R/W 0	A1	Slave Address 2nd byte AD[8:1]	A2	Sr	Slave Address 1st 7 bits 11110 + AD10 + AD9	R/W 1	A3	Data	A	...	Data	A	P
---	--	----------	----	-----------------------------------	----	----	--	----------	----	------	---	-----	------	---	---

**Table 12-10. Master-Receiver Addresses a Slave-Transmitter with a 10-bit Address**

After the master-receiver has sent the first byte of the 10-bit address, the slave-transmitter will see an IIC interrupt. User software must ensure that for this interrupt, the contents of IICD are ignored and not treated as valid data.



### 12.4.3 General Call Address

General calls can be requested in 7-bit address or 10-bit address. If the GCAEN bit is set, the IIC matches the general call address as well as its own slave address. When the IIC responds to a general call, it acts as a slave-receiver and the IAAS bit is set after the address cycle. Software must read the IICD register after the first byte transfer to determine whether the address matches its own slave address or a general call. If the value is “00”, the match is a general call. If the GCAEN bit is clear, the IIC ignores any data supplied from a general call address by not issuing an acknowledgement.

## 12.5 Resets

The IIC is disabled after reset. The IIC cannot cause an MCU reset.

## 12.6 Interrupts

The IIC generates a single interrupt.

An interrupt from the IIC is generated when any of the events in Table 12-11 occur, provided the IICIE bit is set. The interrupt is driven by bit IICIF (of the IIC status register) and masked with bit IICIE (of the IIC control register). The IICIF bit must be cleared by software by writing a 1 to it in the interrupt routine. The user can determine the interrupt type by reading the status register.

**Table 12-11. Interrupt Summary**

Interrupt Source	Status	Flag	Local Enable
Complete 1-byte transfer	TCF	IICIF	IICIE
Match of received calling address	IAAS	IICIF	IICIE
Arbitration Lost	ARBL	IICIF	IICIE

### 12.6.1 Byte Transfer Interrupt

The TCF (transfer complete flag) bit is set at the falling edge of the 9th clock to indicate the completion of byte transfer.

### 12.6.2 Address Detect Interrupt

When the calling address matches the programmed slave address (IIC address register) or when the GCAEN bit is set and a general call is received, the IAAS bit in the status register is set. The CPU is interrupted, provided the IICIE is set. The CPU must check the SRW bit and set its Tx mode accordingly.

### 12.6.3 Arbitration Lost Interrupt

The IIC is a true multi-master bus that allows more than one master to be connected on it. If two or more masters try to control the bus at the same time, the relative priority of the contending masters is determined by a data arbitration procedure. The IIC module asserts this interrupt when it loses the data arbitration process and the ARBL bit in the status register is set.

Arbitration is lost in the following circumstances:

**Inter-Integrated Circuit (S08IICV2)**

- SDA sampled as a low when the master drives a high during an address or data transmit cycle.
- SDA sampled as a low when the master drives a high during the acknowledge bit of a data receive cycle.
- A START cycle is attempted when the bus is busy.
- A repeated START cycle is requested in slave mode.
- A STOP condition is detected when the master did not request it.

This bit must be cleared by software by writing a 1 to it.

## 12.7 Initialization/Application Information

### Module Initialization (Slave)

1. Write: IICC2
  - to enable or disable general call
  - to select 10-bit or 7-bit addressing mode
2. Write: IICA
  - to set the slave address
3. Write: IICC1
  - to enable IIC and interrupts
4. Initialize RAM variables (IICEN = 1 and IICIE = 1) for transmit data
5. Initialize RAM variables used to achieve the routine shown in [Figure 11-3](#)

### Module Initialization (Master)

1. Write: IICF
  - to set the IIC baud rate (example provided in this chapter)
2. Write: IICC1
  - to enable IIC and interrupts
3. Initialize RAM variables (IICEN = 1 and IICIE = 1) for transmit data
4. Initialize RAM variables used to achieve the routine shown in [Figure 11-3](#)
5. Write: IICC1
  - to enable TX
6. Write: IICC1
  - to enable MST (master mode)
7. Write: IICD
  - with the address of the target slave. (The LSB of this byte will determine whether the communication is master receive or transmit.)

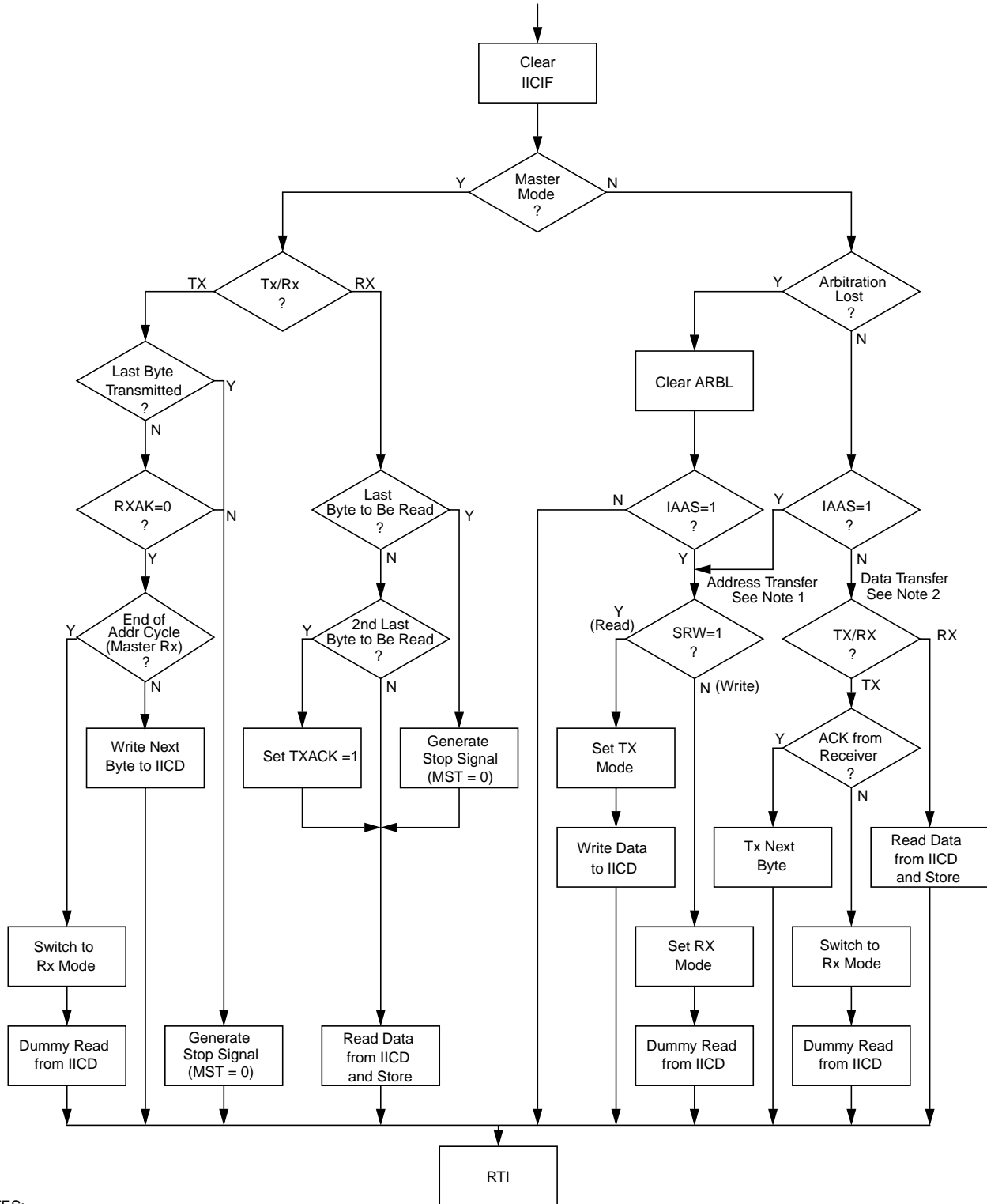
### Module Use

The routine shown in [Figure 11-3](#) can handle both master and slave IIC operations. For slave operation, an incoming IIC message that contains the proper address will begin IIC communication. For master operation, communication must be initiated by writing to the IICD register.

### Register Model

IICA	AD[7:1]							0
	Address to which the module will respond when addressed as a slave (in slave mode)							
IICF	MULT			ICR				
	Baud rate = BUSCLK / (2 x MULT x (SCL DIVIDER))							
IICC1	IICEN	IICIE	MST	TX	TXAK	RSTA	0	0
	Module configuration							
IICS	TCF	IAAS	BUSY	ARBL	0	SRW	IICIF	RXAK
	Module status flags							
IICD	DATA							
	Data register; Write to transmit IIC data read to read IIC data							
IICC2	GCAEN	ADEXT	0	0	0	AD10	AD9	AD8
	Address configuration							

Figure 12-11. IIC Module Quick Start



NOTES:

1. If general call is enabled, a check must be done to determine whether the received address was a general call address (0x00). If the received address was a general call address, then the general call must be handled by user software.
2. When 10-bit addressing is used to address a slave, the slave will see an interrupt following the first byte of the extended address. User software must ensure that for this interrupt, the contents of IICD are ignored and not treated as a valid data transfer

Figure 12-12. Typical IIC Interrupt Routine

## Chapter 13

# Real-Time Counter (S08RTCV1)

### 13.1 Introduction

The real-time counter (RTC) consists of one 8-bit counter, one 8-bit comparator, several binary-based and decimal-based prescaler dividers, three clock sources, and one programmable periodic interrupt. This module can be used for time-of-day, calendar, or any task scheduling functions. It can also serve as a cyclic wake up from low power modes without the need of external components.

#### 13.1.1 ADC Hardware Trigger

The RTC can be enabled as a hardware trigger for the ADC module by setting ADCSC2[ADTRG]. When enabled, the ADC is triggered each time RTCINT matches RTCMOD. The RTC interrupt does not have to be enabled to trigger the ADC.

#### 13.1.2 RTC Clock Sources

The RTC module on MC9S08QE128 Series can be clocked from ICSIRCLK, OSCOUT, or the LPO. In this chapter, ERCLK is replaced by OSCOUT for this MCU.

#### 13.1.3 RTC Modes of Operation

All clock sources are available in all modes except stop2. The OSCOUT and LPO can be enabled as the clock source of the RTC in stop2.

##### 13.1.3.1 RTC Status after Stop2 Wakeup

The registers associated with the RTC are unaffected after a stop2 wakeup.

##### 13.1.3.2 Clocks in Stop Modes

In the MC9S08QE128 Series, LPO and OSCOUT can be used in stop2 and stop3. IRCLK is available only in stop3.

#### 13.1.4 RTC Clock Gating

The bus clock to the RTC can be gated on and off with SCGC2[RTC]. This bit is set after any reset, which enables the bus clock to this module. To conserve power, the RTC bit can be cleared to disable the clock to this module when not in use. See [Section 5.7, “Peripheral Clock Gating,”](#) for details.

## 13.1.5 Interrupt Vector

See [Section 4.2, “Reset and Interrupt Vector Assignments,”](#) for the RTC interrupt vector assignment.

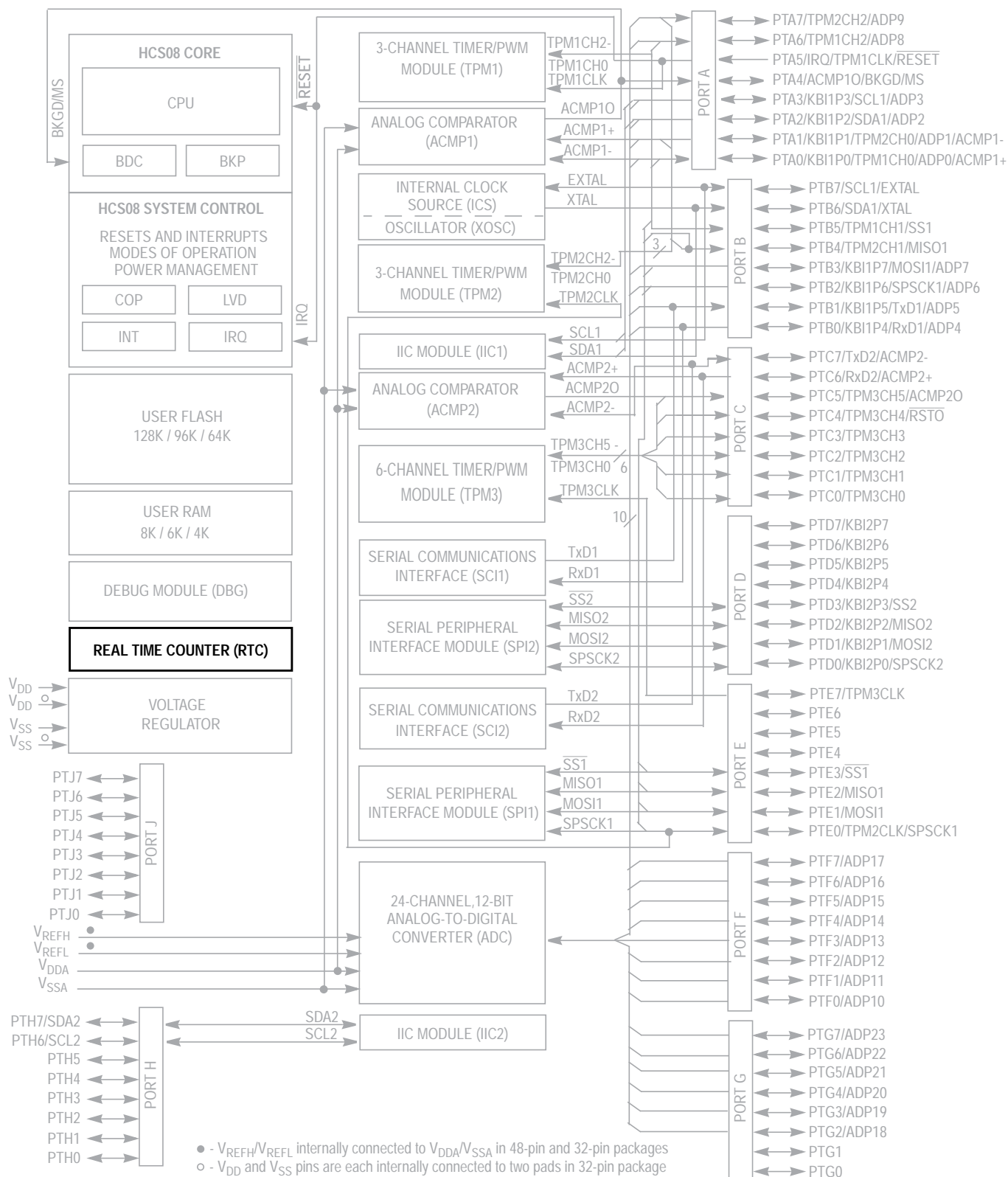


Figure 13-1. MC9S08QE128 Block Diagram Highlighting RTC Block and Pins

## 13.1.6 Features

Features of the RTC module include:

- 8-bit up-counter
  - 8-bit modulo match limit
  - Software controllable periodic interrupt on match
- Three software selectable clock sources for input to prescaler with selectable binary-based and decimal-based divider values
  - 1-kHz internal Low Power Oscillator (LPO)
  - External clock (ERCLK)
  - 32-kHz internal clock (IRCLK)

## 13.1.7 Modes of Operation

This section defines the operation in stop, wait and background debug modes.

### Wait Mode

The RTC continues to run in wait mode if enabled before executing the WAIT instruction. Therefore, the RTC can be used to bring the MCU out of wait mode if the real-time interrupt is enabled. For lowest possible current consumption, the RTC should be stopped by software if not needed as an interrupt source during wait mode.

### Stop Modes

The RTC continues to run in stop2 or stop3 mode if the RTC is enabled before executing the STOP instruction. Therefore, the RTC can be used to bring the MCU out of stop modes with no external components, if the real-time interrupt is enabled.

The LPO clock can be used in both stop2 and stop3 modes. ERCLK and IRCLK clocks are only available in stop3 mode.

Power consumption is lower when all clock sources are disabled, but in that case the real-time interrupt cannot wake up the MCU from stop modes.

### Active Background Mode

The RTC suspends all counting during active background mode until the microcontroller returns to normal user operating mode. Counting resumes from the suspended value as long as the RTCMOD register is not written and the RTCPS and RTCLKS bits are not altered.



### 13.1.8 Block Diagram

The block diagram for the RTC module is shown in Figure 13-2.

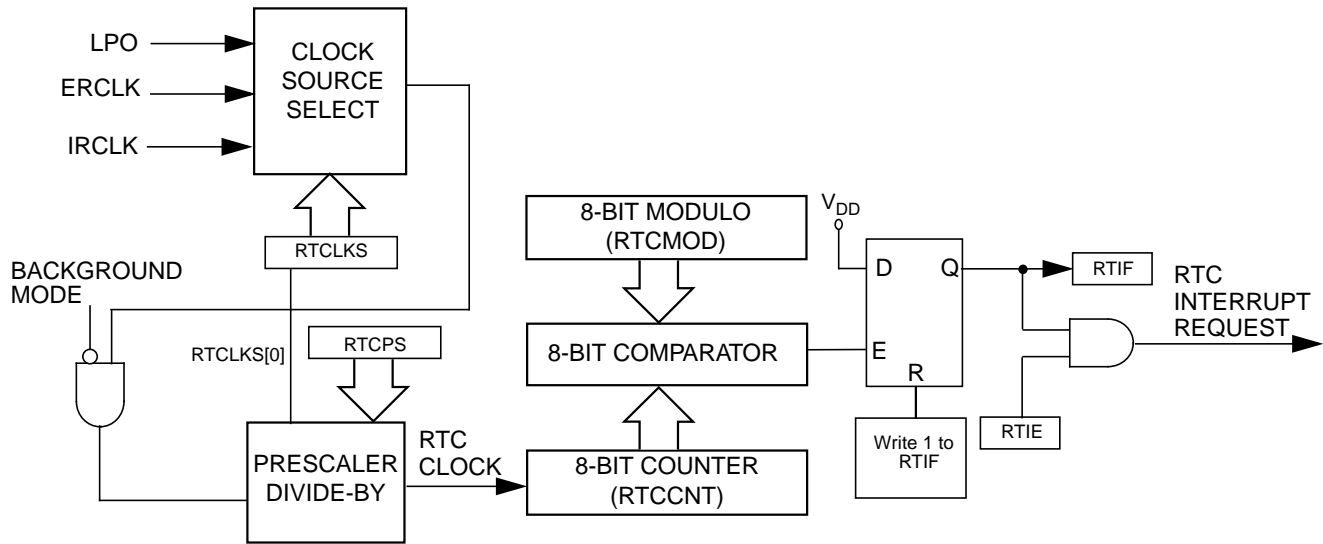


Figure 13-2. Real-Time Counter (RTC) Block Diagram

### 13.2 External Signal Description

The RTC does not include any off-chip signals.

### 13.3 Register Definition

The RTC includes a status and control register, an 8-bit counter register, and an 8-bit modulo register.

Refer to the direct-page register summary in the memory section of this data sheet for the absolute address assignments for all RTC registers. This section refers to registers and control bits only by their names and relative address offsets.

Table 13-1 is a summary of RTC registers.

Table 13-1. RTC Register Summary

Name		7	6	5	4	3	2	1	0
RTCSC	R	RTIF	RTCLKS		RTIE	RTCPS			
	W								
RTCCNT	R	RTCCNT							
	W								
RTCMOD	R	RTCMOD							
	W								

### 13.3.1 RTC Status and Control Register (RTCSC)

RTCSC contains the real-time interrupt status flag (RTIF), the clock select bits (RTCLKS), the real-time interrupt enable bit (RTIE), and the prescaler select bits (RTCPS).

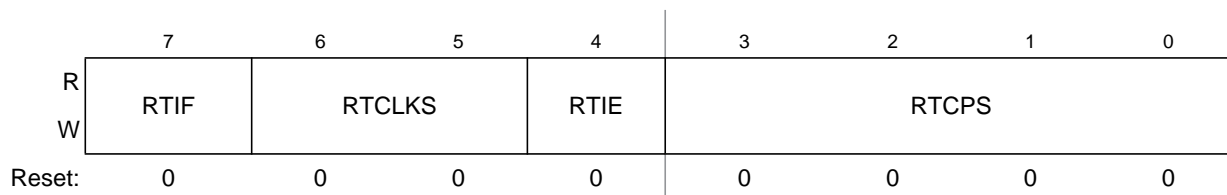


Figure 13-3. RTC Status and Control Register (RTCSC)

Table 13-2. RTCSC Field Descriptions

Field	Description
7 RTIF	<b>Real-Time Interrupt Flag</b> — This status bit indicates the RTC counter register reached the value in the RTC modulo register. Writing a logic 0 has no effect. Writing a logic 1 clears the bit and the real-time interrupt request. Reset clears RTIF to 0. 0 RTC counter has not reached the value in the RTC modulo register. 1 RTC counter has reached the value in the RTC modulo register.
6:5 RTCLKS	<b>Real-Time Clock Source Select</b> — These two read/write bits select the clock source input to the RTC prescaler. Changing the clock source clears the prescaler and RTCCNT counters. When selecting a clock source, ensure that the clock source is properly enabled (if applicable) to ensure correct operation of the RTC. Reset clears RTCLKS to 00. 00 Real-time clock source is the 1-kHz low power oscillator (LPO) 01 Real-time clock source is the external clock (ERCLK) 1x Real-time clock source is the internal clock (IRCLK)
4 RTIE	<b>Real-Time Interrupt Enable</b> — This read/write bit enables real-time interrupts. If RTIE is set, then an interrupt is generated when RTIF is set. Reset clears RTIE to 0. 0 Real-time interrupt requests are disabled. Use software polling. 1 Real-time interrupt requests are enabled.
3:0 RTCPS	<b>Real-Time Clock Prescaler Select</b> — These four read/write bits select binary-based or decimal-based divide-by values for the clock source. See Table 13-3. Changing the prescaler value clears the prescaler and RTCCNT counters. Reset clears RTCPS to 0000.

Table 13-3. RTC Prescaler Divide-by values

RTCLKS[0]	RTCPS															
	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
<b>0</b>	OFF	2 <sup>3</sup>	2 <sup>5</sup>	2 <sup>6</sup>	2 <sup>7</sup>	2 <sup>8</sup>	2 <sup>9</sup>	2 <sup>10</sup>	1	2	2 <sup>2</sup>	10	2 <sup>4</sup>	10 <sup>2</sup>	5x10 <sup>2</sup>	10 <sup>3</sup>
<b>1</b>	OFF	2 <sup>10</sup>	2 <sup>11</sup>	2 <sup>12</sup>	2 <sup>13</sup>	2 <sup>14</sup>	2 <sup>15</sup>	2 <sup>16</sup>	10 <sup>3</sup>	2x10 <sup>3</sup>	5x10 <sup>3</sup>	10 <sup>4</sup>	2x10 <sup>4</sup>	5x10 <sup>4</sup>	10 <sup>5</sup>	2x10 <sup>5</sup>

### 13.3.2 RTC Counter Register (RTCCNT)

RTCCNT is the read-only value of the current RTC count of the 8-bit counter.

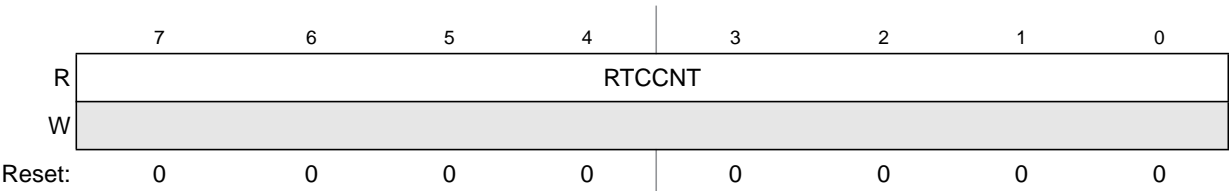


Figure 13-4. RTC Counter Register (RTCCNT)

Table 13-4. RTCCNT Field Description

Field	Description
7:0 RTCCNT	<b>RTC Count</b> — These eight read-only bits contain the current value of the 8-bit counter. Writes have no effect to this register. Reset, writing to RTCMOD, or writing different values to RTCLKS and RTCPS clear the count to 0x00.

### 13.3.3 RTC Modulo Register (RTCMOD)

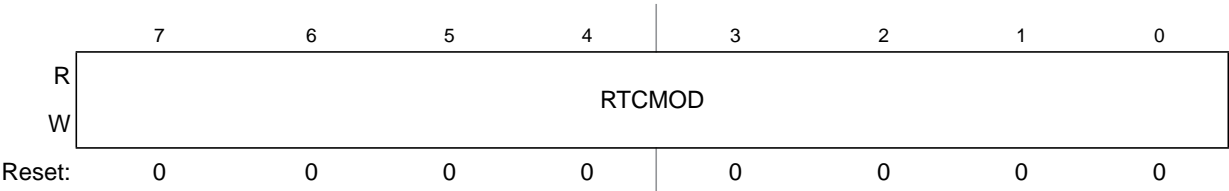


Figure 13-5. RTC Modulo Register (RTCMOD)

Table 13-5. RTCMOD Field Descriptions

Field	Description
7:0 RTCMOD	<b>RTC Modulo</b> — These eight read/write bits contain the modulo value used to reset the count to 0x00 upon a compare match and set the RTIF status bit. A value of 0x00 sets the RTIF bit on each rising edge of the prescaler output. Writing to RTCMOD resets the prescaler and the RTCCNT counters to 0x00. Reset sets the modulo to 0x00.

## 13.4 Functional Description

The RTC is composed of a main 8-bit up-counter with an 8-bit modulo register, a clock source selector, and a prescaler block with binary-based and decimal-based selectable values. The module also contains software selectable interrupt logic.

After any MCU reset, the counter is stopped and reset to 0x00, the modulus register is set to 0x00, and the prescaler is off. The 1-kHz internal oscillator clock is selected as the default clock source. To start the prescaler, write any value other than zero to the prescaler select bits (RTCPS).

Three clock sources are software selectable: the low power oscillator clock (LPO), the external clock (ERCLK) and the internal clock (IRCLK). The RTC clock select bits (RTCLKS) are used to select the desired clock source. If a different value is written to RTCLKS, the prescaler and RTCCNT counters are reset to 0x00.

RTCPS and the RTCLKS[0] bit select the desired divide-by value. If a different value is written to RTCPS, the prescaler and RTCCNT counters are reset to 0x00. Table 13-6 shows different prescaler period values.

**Table 13-6. Prescaler Period**

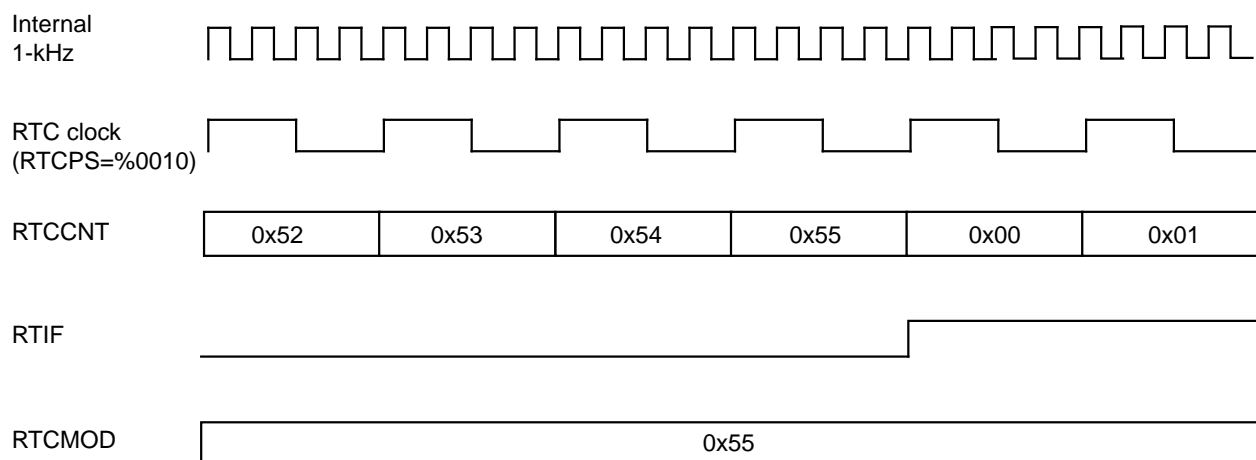
RTCPS	1-kHz internal clock source prescaler period (RTCLKS = 00)	1-MHz external clock source prescaler period (RTCLKS = 01)	32-kHz internal clock source prescaler period (RTCLKS = 10)	32-kHz internal clock source prescaler period (RTCLKS = 11)
0000	Off	Off	Off	Off
0001	8 ms	1.024 ms	250 $\mu$ s	32 ms
0010	32 ms	2.048 ms	1 ms	64 ms
0011	64 ms	4.096 ms	2 ms	128 ms
0100	128 ms	8.192 ms	4 ms	256 ms
0101	256 ms	16.4 ms	8 ms	512 ms
0110	512 ms	32.8 ms	16 ms	1.024 s
0111	1.024 s	65.5 ms	32 ms	2.048 s
1000	1 ms	1 ms	31.25 $\mu$ s	31.25 ms
1001	2 ms	2 ms	62.5 $\mu$ s	62.5 ms
1010	4 ms	5 ms	125 $\mu$ s	156.25 ms
1011	10 ms	10 ms	312.5 $\mu$ s	312.5 ms
1100	16 ms	20 ms	0.5 ms	0.625 s
1101	0.1 s	50 ms	3.125 ms	1.5625 s
1110	0.5 s	0.1 s	15.625 ms	3.125 s
1111	1 s	0.2 s	31.25 ms	6.25 s

The RTC modulo register (RTCMOD) allows the compare value to be set to any value from 0x00 to 0xFF. When the counter is active, the counter increments at the selected rate until the count matches the modulo value. When these values match, the counter resets to 0x00 and continues counting. The real-time interrupt flag (RTIF) is set whenever a match occurs. The flag sets on the transition from the modulo value to 0x00. Writing to RTCMOD resets the prescaler and the RTCCNT counters to 0x00. Writing to RTCMOD resets the prescaler and the RTCCNT counters to 0x00.

The RTC allows for an interrupt to be generated whenever RTIF is set. To enable the real-time interrupt, set the real-time interrupt enable bit (RTIE) in RTCSC. RTIF is cleared by writing a 1 to RTIF.

### 13.4.1 RTC Operation Example

This section shows an example of the RTC operation as the counter reaches a matching value from the modulo register.



**Figure 13-6. RTC counter overflow example**

In the example of Figure 13-6, the selected clock source is the internal clock source. The prescaler is set to  $RTCPs = \%0010$  or divide-by-4. The modulo value in the RTCMOD register is set to 0x55. When the counter, RTCCNT, reaches the modulo value of 0x55, the counter overflows to 0x00 and continues counting. The real-time interrupt flag, RTIF, sets when the counter value changes from 0x55 to 0x00. A real-time interrupt is generated when RTIF is set, if  $RTIE = 1$ .

## 13.5 Initialization/Application Information

This section provides example code to give some basic direction to a user on how to initialize and configure the RTC module. The example software is implemented in C language.

The example below shows how to implement time of day with the RTC using the 1-kHz clock source to achieve the lowest possible power consumption. Since the 1-kHz clock source is not as accurate as a crystal, software can be added for any adjustments. For accuracy without adjustments at the expense of additional power consumption, the external clock (ERCLK) or the internal clock (IRCLK) can be selected with appropriate prescaler and modulo values.

## Real-Time Counter (S08RTCV1)

```

/* Initialize the elapsed time counters */
Seconds = 0;
Minutes = 0;
Hours = 0;
Days=0;

/* Configure RTC to interrupt every 1 second from 1-kHz clock source */
RTCMOD.byte = 0x00;
RTCSC.byte = 0x1F;

/*****
Function Name : RTC_ISR
Notes : Interrupt service routine for RTC module.
*****/
#pragma TRAP_PROC
void RTC_ISR(void)
{
    /* Clear the interrupt flag */
    RTCSC.byte = RTCSC.byte | 0x80;

    /* RTC interrupts every 1 Second */
    Seconds++;

    /* 60 seconds in a minute */
    if (Seconds > 59){
        Minutes++;
        Seconds = 0;
    }

    /* 60 minutes in an hour */
    if (Minutes > 59){
        Hours++;
        Minutes = 0;
    }

    /* 24 hours in a day */
    if (Hours > 23){
        Days ++;
        Hours = 0;
    }
}

```

## Chapter 14

# Serial Communications Interface (S08SCIV4)

### 14.1 Introduction

Figure 14-1 shows the MC9S08QE128 Series block diagram with the SCI highlighted.

#### NOTE

Ignore any references to stop1 low-power mode in this chapter, because the MC9S08QE128 device does not support it.

#### 14.1.1 SCI Clock Gating

The bus clock to SCI1 and SCI2 can be gated on and off using the SCGC1[SCI1,SCI2] bits, respectively. These bits are set after any reset, which enables the bus clock to these modules. To conserve power, these bits can be cleared to disable the clock to either of these modules when not in use. See [Section 5.7](#), “Peripheral Clock Gating,” for details.

#### 14.1.2 Interrupt Vectors

Each SCI module contains three interrupt sources: transmit, receive, and error. See [Section 4.2](#), “Reset and Interrupt Vector Assignments,” for a list of the SCI interrupt vector assignments.

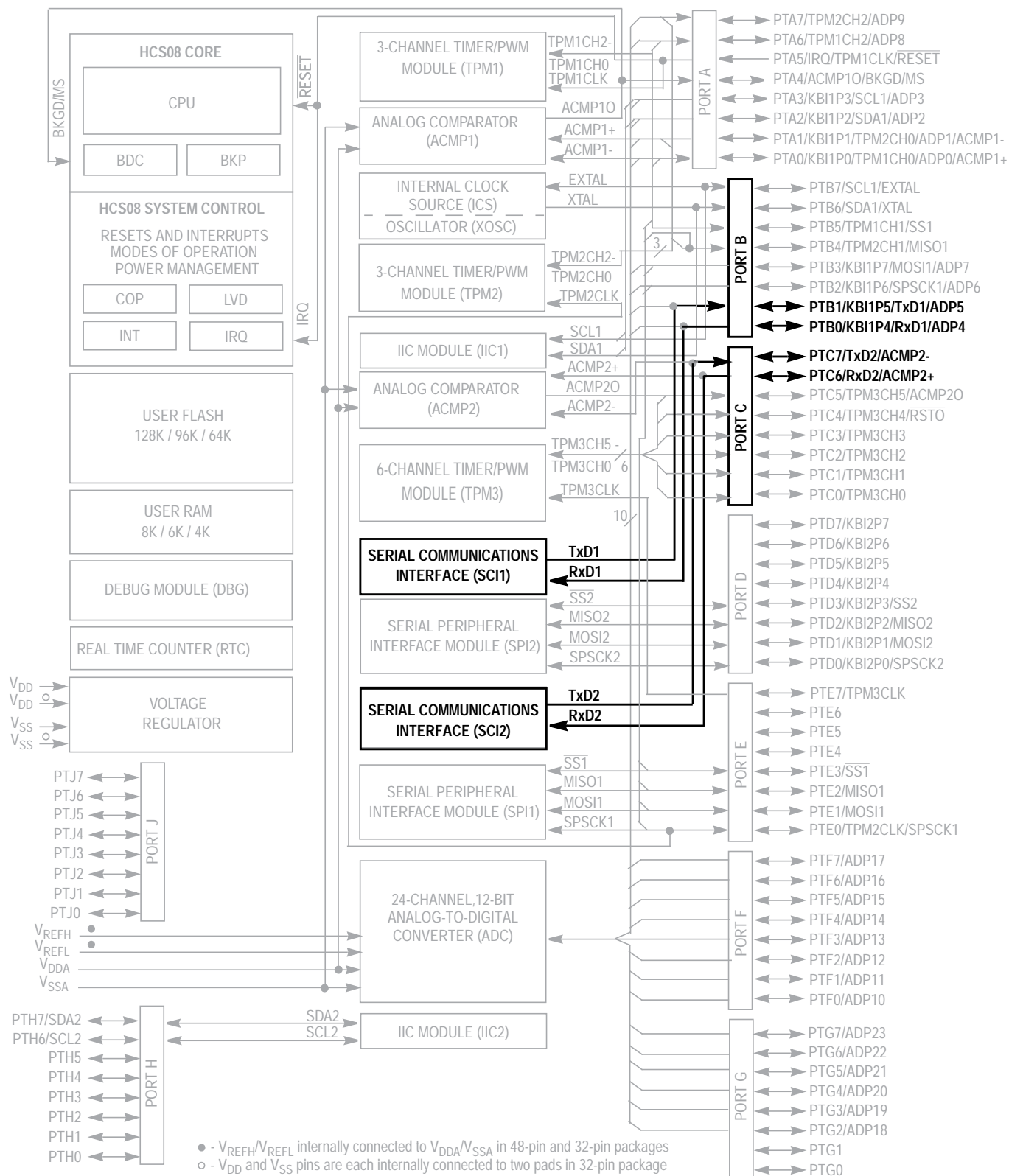


Figure 14-1. MC9S08QE128 Series Block Diagram Highlighting SCI Block and Pins

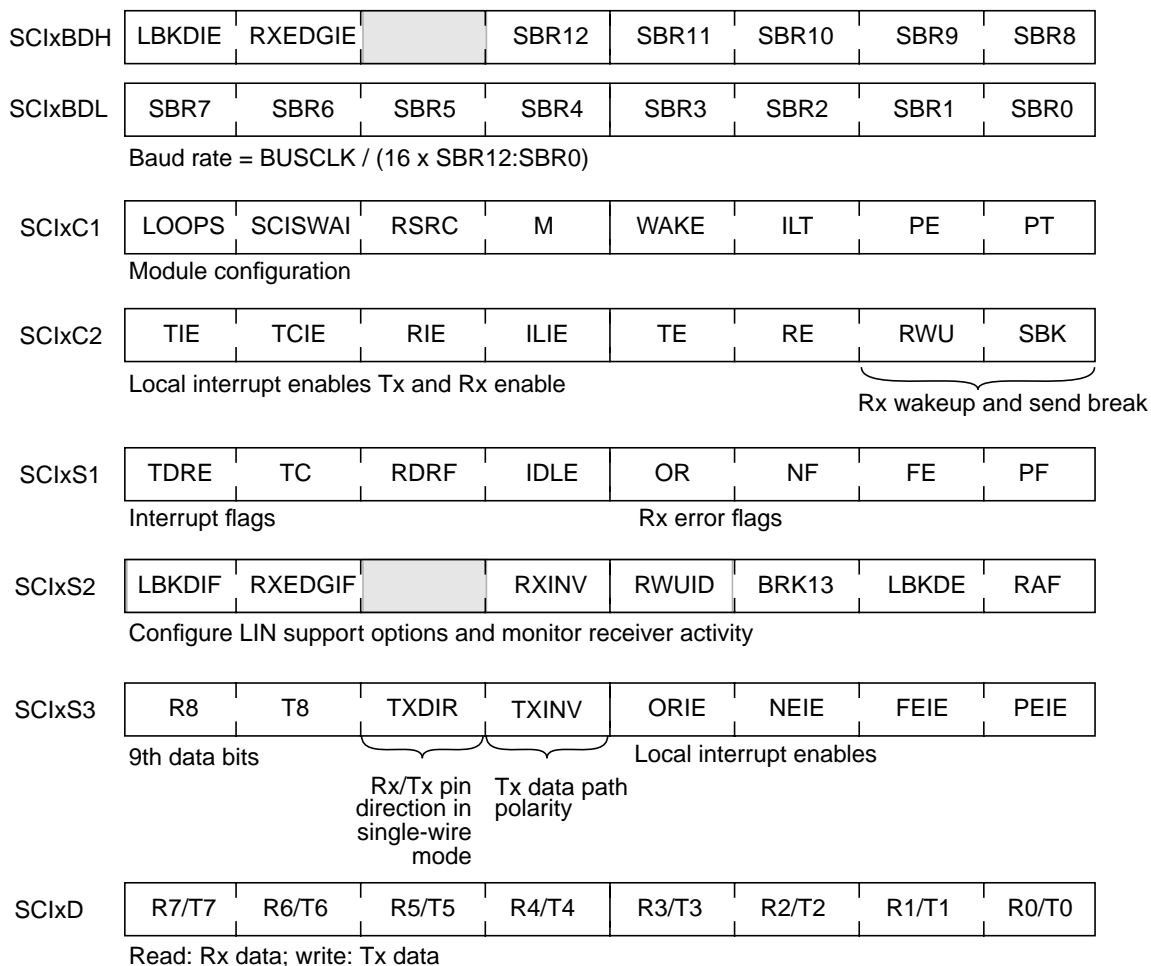


**Module Initialization:**

Write: SCixBDH:SCixBDL to set baud rate  
 Write: SCixC1 to configure 1-wire/2-wire, 9/8-bit data, wakeup, and parity, if used.  
 Write; SCixC2 to configure interrupts, enable Rx and Tx, RWU  
 Enable Rx wakeup, SBK sends break character  
 Write: SCixC3 to enable Rx error interrupt sources. Also controls pin direction in 1-wire modes. R8 and T8 only used in 9-bit data modes.

**Module Use:**

Wait for TDRE, then write data to SCixD  
 Wait for RDRF, then read data from SCixD  
 A small number of applications will use RWU to manage automatic receiver wakeup, SBK to send break characters, and R8 and T8 for 9-bit data.



**Figure 14-2. SCI Module Quick Start**

### 14.1.3 Features

Features of SCI module include:

- Full-duplex, standard non-return-to-zero (NRZ) format
- Double-buffered transmitter and receiver with separate enables
- Programmable baud rates (13-bit modulo divider)
- Interrupt-driven or polled operation:
  - Transmit data register empty and transmission complete
  - Receive data register full
  - Receive overrun, parity error, framing error, and noise error
  - Idle receiver detect
  - Active edge on receive pin
  - Break detect supporting LIN
- Hardware parity generation and checking
- Programmable 8-bit or 9-bit character length
- Receiver wakeup by idle-line or address-mark
- Optional 13-bit break character generation / 11-bit break character detection
- Selectable transmitter output polarity

### 14.1.4 Modes of Operation

See [Section 14.3, “Functional Description,”](#) For details concerning SCI operation in these modes:

- 8- and 9-bit data modes
- Stop mode operation
- Loop mode
- Single-wire mode

### 14.1.5 Block Diagram

Figure 14-3 shows the transmitter portion of the SCI.

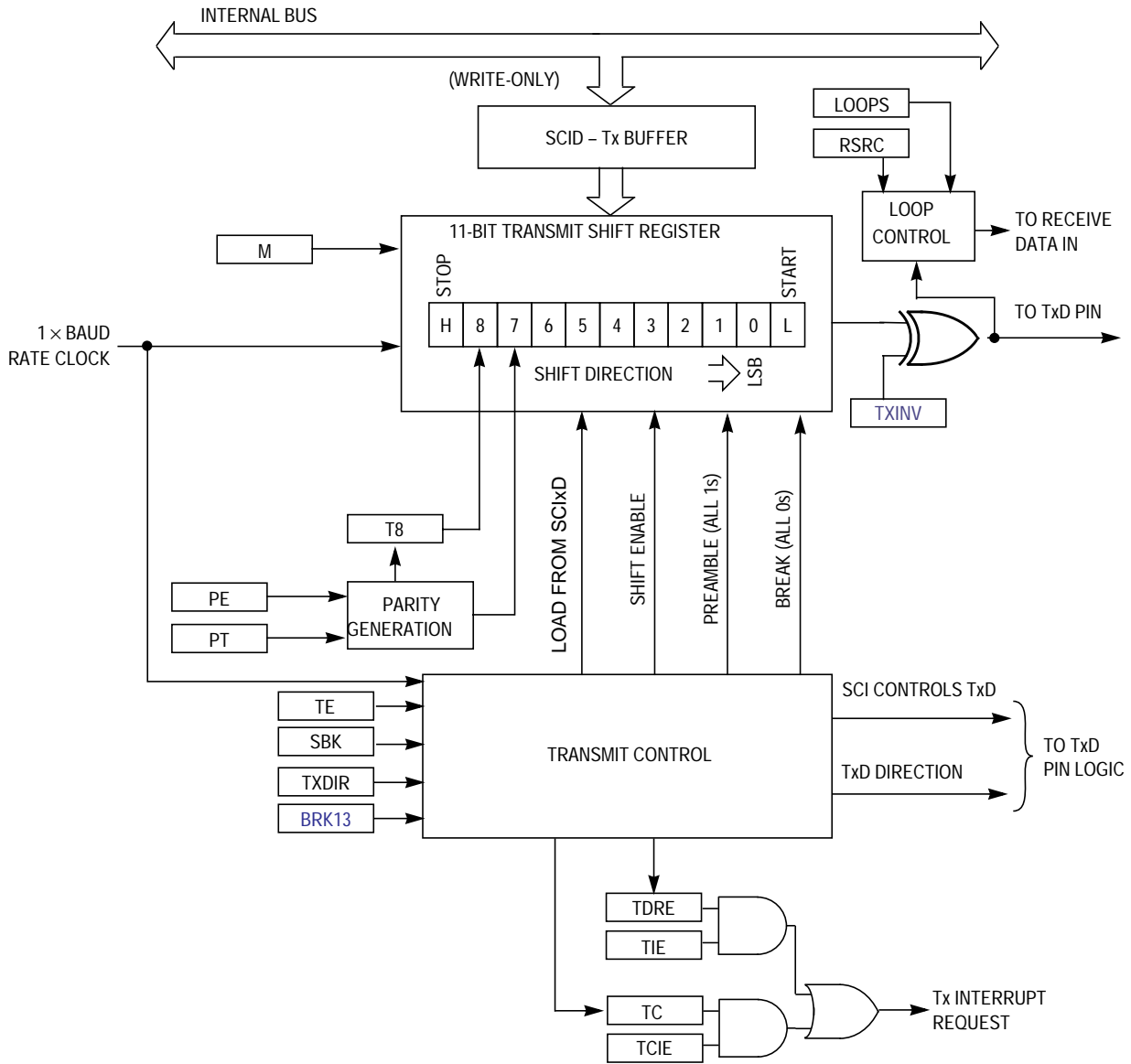


Figure 14-3. SCI Transmitter Block Diagram



## 14.2 Register Definition

The SCI has eight 8-bit registers to control baud rate, select SCI options, report SCI status, and for transmit/receive data.

Refer to the direct-page register summary in the [Memory](#) chapter of this data sheet for the absolute address assignments for all SCI registers. This section refers to registers and control bits only by their names. A Freescale-provided equate or header file is used to translate these names into the appropriate absolute addresses.

### 14.2.1 SCI Baud Rate Registers (SCIxBDH, SCIxBDL)

This pair of registers controls the prescale divisor for SCI baud rate generation. To update the 13-bit baud rate setting [SBR12:SBR0], first write to SCIxBDH to buffer the high half of the new value and then write to SCIxBDL. The working value in SCIxBDH does not change until SCIxBDL is written.

SCIxBDL is reset to a non-zero value, so after reset the baud rate generator remains disabled until the first time the receiver or transmitter is enabled (RE or TE bits in SCIxC2 are written to 1).

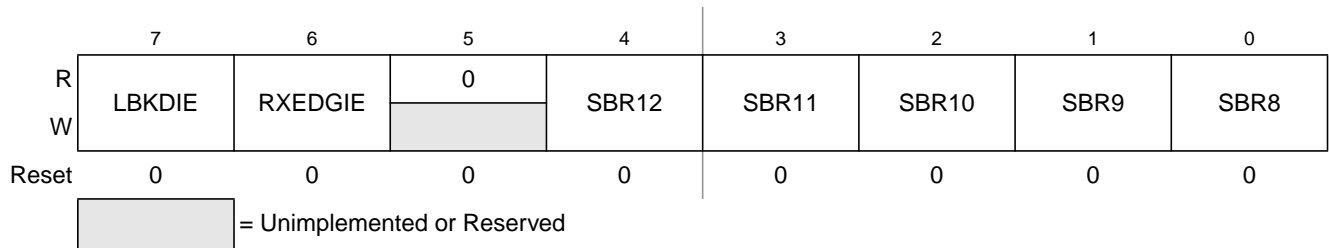


Figure 14-5. SCI Baud Rate Register (SCIxBDH)

Table 14-1. SCIxBDH Field Descriptions

Field	Description
7 LBKDIE	<b>LIN Break Detect Interrupt Enable (for LBKDIF)</b> 0 Hardware interrupts from LBKDIF disabled (use polling). 1 Hardware interrupt requested when LBKDIF flag is 1.
6 RXEDGIE	<b>RxD Input Active Edge Interrupt Enable (for RXEDGIF)</b> 0 Hardware interrupts from RXEDGIF disabled (use polling). 1 Hardware interrupt requested when RXEDGIF flag is 1.
4:0 SBR[12:8]	<b>Baud Rate Modulo Divisor</b> — The 13 bits in SBR[12:0] are referred to collectively as BR, and they set the modulo divide rate for the SCI baud rate generator. When BR = 0, the SCI baud rate generator is disabled to reduce supply current. When BR = 1 to 8191, the SCI baud rate = $BUSCLK/(16 \times BR)$ . See also BR bits in <a href="#">Table 14-2</a> .

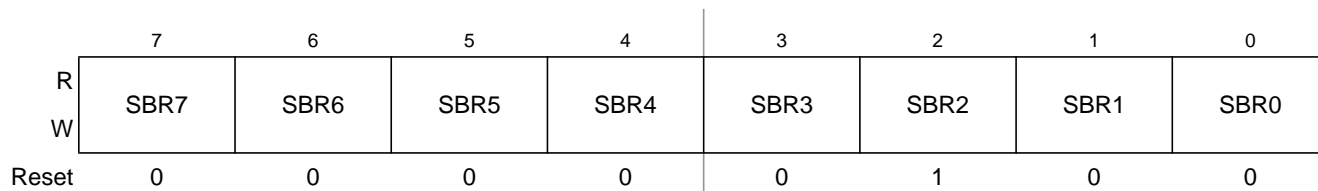


Figure 14-6. SCI Baud Rate Register (SClxBDL)

Table 14-2. SClxBDL Field Descriptions

Field	Description
7:0 SBR[7:0]	<b>Baud Rate Modulo Divisor</b> — These 13 bits in SBR[12:0] are referred to collectively as BR, and they set the modulo divide rate for the SCI baud rate generator. When BR = 0, the SCI baud rate generator is disabled to reduce supply current. When BR = 1 to 8191, the SCI baud rate = BUSCLK/(16×BR). See also BR bits in Table 14-1.

### 14.2.2 SCI Control Register 1 (SClxC1)

This read/write register is used to control various optional features of the SCI system.

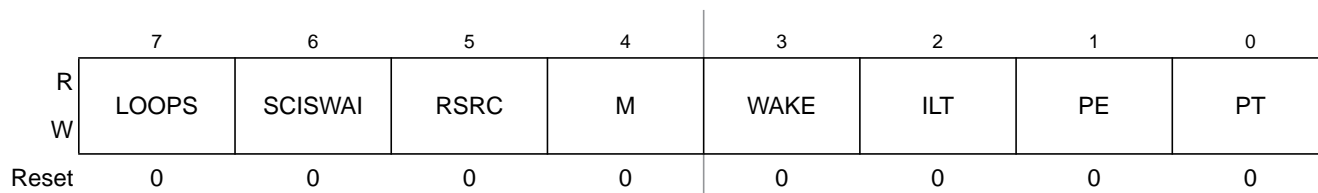


Figure 14-7. SCI Control Register 1 (SClxC1)

Table 14-3. SClxC1 Field Descriptions

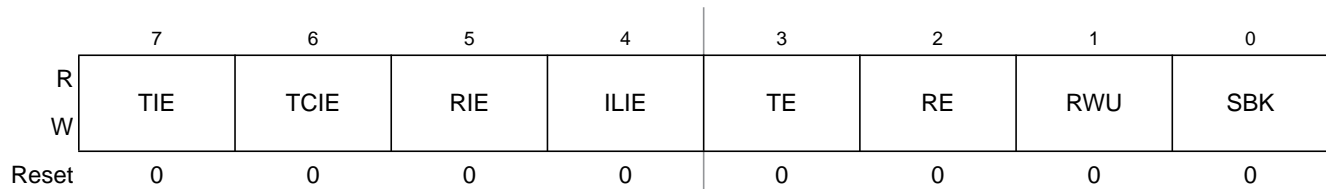
Field	Description
7 LOOPS	<b>Loop Mode Select</b> — Selects between loop back modes and normal 2-pin full-duplex modes. When LOOPS = 1, the transmitter output is internally connected to the receiver input. 0 Normal operation — RxD and TxD use separate pins. 1 Loop mode or single-wire mode where transmitter outputs are internally connected to receiver input. (See RSRC bit.) RxD pin is not used by SCI.
6 SCISWAI	<b>SCI Stops in Wait Mode</b> 0 SCI clocks continue to run in wait mode so the SCI can be the source of an interrupt that wakes up the CPU. 1 SCI clocks freeze while CPU is in wait mode.
5 RSRC	<b>Receiver Source Select</b> — This bit has no meaning or effect unless the LOOPS bit is set to 1. When LOOPS = 1, the receiver input is internally connected to the TxD pin and RSRC determines whether this connection is also connected to the transmitter output. 0 Provided LOOPS = 1, RSRC = 0 selects internal loop back mode and the SCI does not use the RxD pins. 1 Single-wire SCI mode where the TxD pin is connected to the transmitter output and receiver input.
4 M	<b>9-Bit or 8-Bit Mode Select</b> 0 Normal — start + 8 data bits (LSB first) + stop. 1 Receiver and transmitter use 9-bit data characters start + 8 data bits (LSB first) + 9th data bit + stop.

**Table 14-3. SC1xC1 Field Descriptions (continued)**

Field	Description
3 WAKE	<b>Receiver Wakeup Method Select</b> — Refer to <a href="#">Section 14.3.3.2, “Receiver Wakeup Operation”</a> for more information. 0 Idle-line wakeup. 1 Address-mark wakeup.
2 ILT	<b>Idle Line Type Select</b> — Setting this bit to 1 ensures that the stop bit and logic 1 bits at the end of a character do not count toward the 10 or 11 bit times of logic high level needed by the idle line detection logic. Refer to <a href="#">Section 14.3.3.2.1, “Idle-Line Wakeup”</a> for more information. 0 Idle character bit count starts after start bit. 1 Idle character bit count starts after stop bit.
1 PE	<b>Parity Enable</b> — Enables hardware parity generation and checking. When parity is enabled, the most significant bit (MSB) of the data character (eighth or ninth data bit) is treated as the parity bit. 0 No hardware parity generation or checking. 1 Parity enabled.
0 PT	<b>Parity Type</b> — Provided parity is enabled (PE = 1), this bit selects even or odd parity. Odd parity means the total number of 1s in the data character, including the parity bit, is odd. Even parity means the total number of 1s in the data character, including the parity bit, is even. 0 Even parity. 1 Odd parity.

### 14.2.3 SCI Control Register 2 (SC1x2)

This register can be read or written at any time.


**Figure 14-8. SCI Control Register 2 (SC1x2)**
**Table 14-4. SC1x2 Field Descriptions**

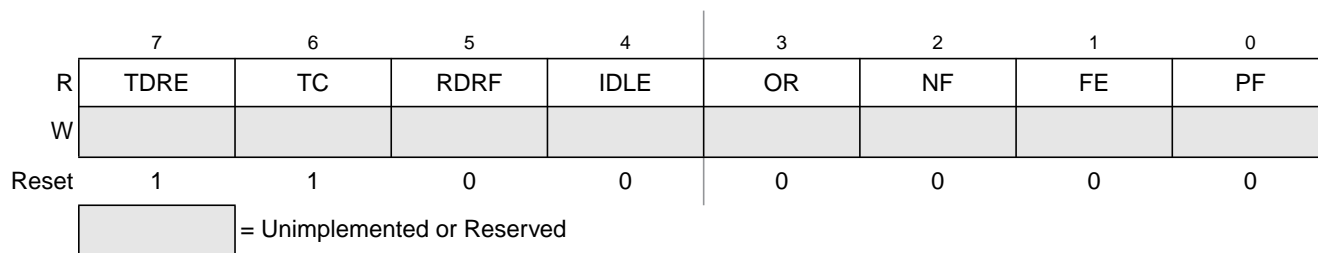
Field	Description
7 TIE	<b>Transmit Interrupt Enable (for TDRE)</b> 0 Hardware interrupts from TDRE disabled (use polling). 1 Hardware interrupt requested when TDRE flag is 1.
6 TCIE	<b>Transmission Complete Interrupt Enable (for TC)</b> 0 Hardware interrupts from TC disabled (use polling). 1 Hardware interrupt requested when TC flag is 1.
5 RIE	<b>Receiver Interrupt Enable (for RDRF)</b> 0 Hardware interrupts from RDRF disabled (use polling). 1 Hardware interrupt requested when RDRF flag is 1.
4 ILIE	<b>Idle Line Interrupt Enable (for IDLE)</b> 0 Hardware interrupts from IDLE disabled (use polling). 1 Hardware interrupt requested when IDLE flag is 1.

**Table 14-4. SCIxC2 Field Descriptions (continued)**

Field	Description
3 TE	<p><b>Transmitter Enable</b>                      0 Transmitter off.                      1 Transmitter on.                      TE must be 1 in order to use the SCI transmitter. When TE = 1, the SCI forces the TxD pin to act as an output for the SCI system.                      When the SCI is configured for single-wire operation (LOOPS = RSRC = 1), TXDIR controls the direction of traffic on the single SCI communication line (TxD pin).                      TE also can be used to queue an idle character by writing TE = 0 then TE = 1 while a transmission is in progress. Refer to <a href="#">Section 14.3.2.1, “Send Break and Queued Idle”</a> for more details.                      When TE is written to 0, the transmitter keeps control of the port TxD pin until any data, queued idle, or queued break character finishes transmitting before allowing the pin to revert to a general-purpose I/O pin.</p>
2 RE	<p><b>Receiver Enable</b> — When the SCI receiver is off, the RxD pin reverts to being a general-purpose port I/O pin. If LOOPS = 1 the RxD pin reverts to being a general-purpose I/O pin even if RE = 1.                      0 Receiver off.                      1 Receiver on.</p>
1 RWU	<p><b>Receiver Wakeup Control</b> — This bit can be written to 1 to place the SCI receiver in a standby state where it waits for automatic hardware detection of a selected wakeup condition. The wakeup condition is either an idle line between messages (WAKE = 0, idle-line wakeup), or a logic 1 in the most significant data bit in a character (WAKE = 1, address-mark wakeup). Application software sets RWU and (normally) a selected hardware condition automatically clears RWU. Refer to <a href="#">Section 14.3.3.2, “Receiver Wakeup Operation”</a> for more details.                      0 Normal SCI receiver operation.                      1 SCI receiver in standby waiting for wakeup condition.</p>
0 SBK	<p><b>Send Break</b> — Writing a 1 and then a 0 to SBK queues a break character in the transmit data stream. Additional break characters of 10 or 11 (13 or 14 if BRK13 = 1) bit times of logic 0 are queued as long as SBK = 1. Depending on the timing of the set and clear of SBK relative to the information currently being transmitted, a second break character may be queued before software clears SBK. Refer to <a href="#">Section 14.3.2.1, “Send Break and Queued Idle”</a> for more details.                      0 Normal transmitter operation.                      1 Queue break character(s) to be sent.</p>

### 14.2.4 SCI Status Register 1 (SCIxS1)

This register has eight read-only status flags. Writes have no effect. Special software sequences (which do not involve writing to this register) are used to clear these status flags.



**Figure 14-9. SCI Status Register 1 (SCIxS1)**



**Table 14-5. SC1xS1 Field Descriptions**

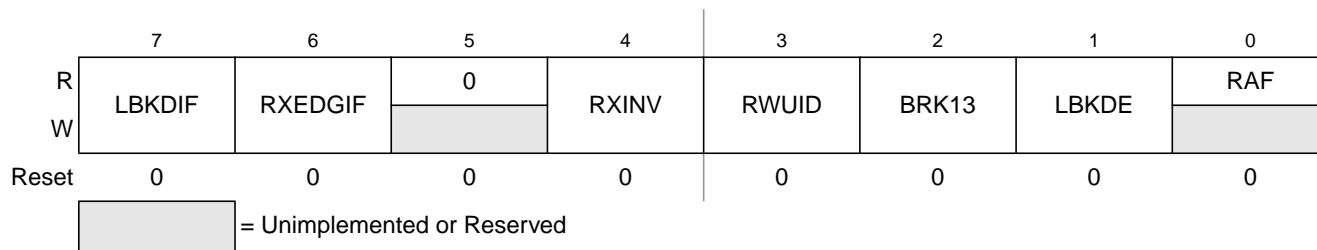
Field	Description
7 TDRE	<p><b>Transmit Data Register Empty Flag</b> — TDRE is set out of reset and when a transmit data value transfers from the transmit data buffer to the transmit shifter, leaving room for a new character in the buffer. To clear TDRE, read SC1xS1 with TDRE = 1 and then write to the SCI data register (SC1xD).</p> <p>0 Transmit data register (buffer) full. 1 Transmit data register (buffer) empty.</p>
6 TC	<p><b>Transmission Complete Flag</b> — TC is set out of reset and when TDRE = 1 and no data, preamble, or break character is being transmitted.</p> <p>0 Transmitter active (sending data, a preamble, or a break). 1 Transmitter idle (transmission activity complete).</p> <p>TC is cleared automatically by reading SC1xS1 with TC = 1 and then doing one of the following three things:</p> <ul style="list-style-type: none"> <li>• Write to the SCI data register (SC1xD) to transmit new data</li> <li>• Queue a preamble by changing TE from 0 to 1</li> <li>• Queue a break character by writing 1 to SBK in SC1xC2</li> </ul>
5 RDRF	<p><b>Receive Data Register Full Flag</b> — RDRF becomes set when a character transfers from the receive shifter into the receive data register (SC1xD). To clear RDRF, read SC1xS1 with RDRF = 1 and then read the SCI data register (SC1xD).</p> <p>0 Receive data register empty. 1 Receive data register full.</p>
4 IDLE	<p><b>Idle Line Flag</b> — IDLE is set when the SCI receive line becomes idle for a full character time after a period of activity. When ILT = 0, the receiver starts counting idle bit times after the start bit. So if the receive character is all 1s, these bit times and the stop bit time count toward the full character time of logic high (10 or 11 bit times depending on the M control bit) needed for the receiver to detect an idle line. When ILT = 1, the receiver doesn't start counting idle bit times until after the stop bit. So the stop bit and any logic high bit times at the end of the previous character do not count toward the full character time of logic high needed for the receiver to detect an idle line.</p> <p>To clear IDLE, read SC1xS1 with IDLE = 1 and then read the SCI data register (SC1xD). After IDLE has been cleared, it cannot become set again until after a new character has been received and RDRF has been set. IDLE will get set only once even if the receive line remains idle for an extended period.</p> <p>0 No idle line detected. 1 Idle line was detected.</p>
3 OR	<p><b>Receiver Overrun Flag</b> — OR is set when a new serial character is ready to be transferred to the receive data register (buffer), but the previously received character has not been read from SC1xD yet. In this case, the new character (and all associated error information) is lost because there is no room to move it into SC1xD. To clear OR, read SC1xS1 with OR = 1 and then read the SCI data register (SC1xD).</p> <p>0 No overrun. 1 Receive overrun (new SCI data lost).</p>
2 NF	<p><b>Noise Flag</b> — The advanced sampling technique used in the receiver takes seven samples during the start bit and three samples in each data bit and the stop bit. If any of these samples disagrees with the rest of the samples within any bit time in the frame, the flag NF will be set at the same time as the flag RDRF gets set for the character. To clear NF, read SC1xS1 and then read the SCI data register (SC1xD).</p> <p>0 No noise detected. 1 Noise detected in the received character in SC1xD.</p>

**Table 14-5. SC1xS1 Field Descriptions (continued)**

Field	Description
1 FE	<b>Framing Error Flag</b> — FE is set at the same time as RDRF when the receiver detects a logic 0 where the stop bit was expected. This suggests the receiver was not properly aligned to a character frame. To clear FE, read SC1xS1 with FE = 1 and then read the SCI data register (SCIxD). 0 No framing error detected. This does not guarantee the framing is correct. 1 Framing error.
0 PF	<b>Parity Error Flag</b> — PF is set at the same time as RDRF when parity is enabled (PE = 1) and the parity bit in the received character does not agree with the expected parity value. To clear PF, read SC1xS1 and then read the SCI data register (SCIxD). 0 No parity error. 1 Parity error.

### 14.2.5 SCI Status Register 2 (SC1xS2)

This register has one read-only status flag.



**Figure 14-10. SCI Status Register 2 (SC1xS2)**

**Table 14-6. SC1xS2 Field Descriptions**

Field	Description
7 LBKDIF	<b>LIN Break Detect Interrupt Flag</b> — LBKDIF is set when the LIN break detect circuitry is enabled and a LIN break character is detected. LBKDIF is cleared by writing a “1” to it. 0 No LIN break character has been detected. 1 LIN break character has been detected.
6 RXEDGIF	<b>RxD Pin Active Edge Interrupt Flag</b> — RXEDGIF is set when an active edge (falling if RXINV = 0, rising if RXINV=1) on the RxD pin occurs. RXEDGIF is cleared by writing a “1” to it. 0 No active edge on the receive pin has occurred. 1 An active edge on the receive pin has occurred.
4 RXINV <sup>1</sup>	<b>Receive Data Inversion</b> — Setting this bit reverses the polarity of the received data input. 0 Receive data not inverted 1 Receive data inverted
3 RWUID	<b>Receive Wake Up Idle Detect</b> — RWUID controls whether the idle character that wakes up the receiver sets the IDLE bit. 0 During receive standby state (RWU = 1), the IDLE bit does not get set upon detection of an idle character. 1 During receive standby state (RWU = 1), the IDLE bit gets set upon detection of an idle character.
2 BRK13	<b>Break Character Generation Length</b> — BRK13 is used to select a longer transmitted break character length. Detection of a framing error is not affected by the state of this bit. 0 Break character is transmitted with length of 10 bit times (11 if M = 1) 1 Break character is transmitted with length of 13 bit times (14 if M = 1)

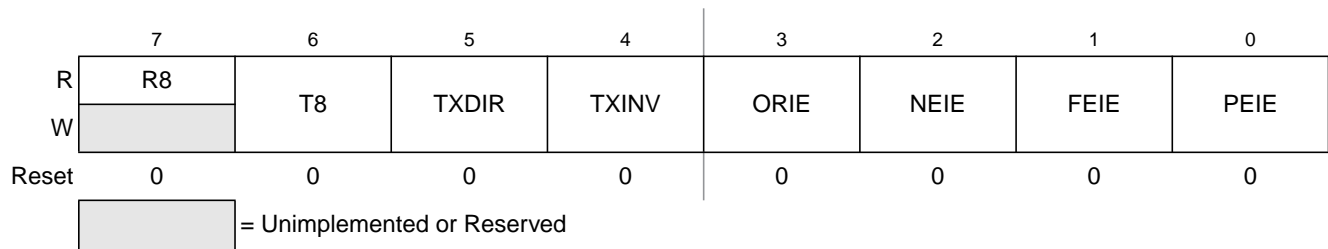
**Table 14-6. SCIxS2 Field Descriptions (continued)**

Field	Description
1 LBKDE	<b>LIN Break Detection Enable</b> — LBKDE is used to select a longer break character detection length. While LBKDE is set, framing error (FE) and receive data register full (RDRF) flags are prevented from setting. 0 Break character is detected at length of 10 bit times (11 if M = 1). 1 Break character is detected at length of 11 bit times (12 if M = 1).
0 RAF	<b>Receiver Active Flag</b> — RAF is set when the SCI receiver detects the beginning of a valid start bit, and RAF is cleared automatically when the receiver detects an idle line. This status flag can be used to check whether an SCI character is being received before instructing the MCU to go to stop mode. 0 SCI receiver idle waiting for a start bit. 1 SCI receiver active (RxD input not idle).

<sup>1</sup> Setting RXINV inverts the RxD input for all cases: data bits, start and stop bits, break, and idle.

When using an internal oscillator in a LIN system, it is necessary to raise the break detection threshold by one bit time. Under the worst case timing conditions allowed in LIN, it is possible that a 0x00 data character can appear to be 10.26 bit times long at a slave which is running 14% faster than the master. This would trigger normal break detection circuitry which is designed to detect a 10 bit break symbol. When the LBKDE bit is set, framing errors are inhibited and the break detection threshold changes from 10 bits to 11 bits, preventing false detection of a 0x00 data character as a LIN break symbol.

## 14.2.6 SCI Control Register 3 (SCIxC3)


**Figure 14-11. SCI Control Register 3 (SCIxC3)**
**Table 14-7. SCIxC3 Field Descriptions**

Field	Description
7 R8	<b>Ninth Data Bit for Receiver</b> — When the SCI is configured for 9-bit data (M = 1), R8 can be thought of as a ninth receive data bit to the left of the MSB of the buffered data in the SCIxD register. When reading 9-bit data, read R8 before reading SCIxD because reading SCIxD completes automatic flag clearing sequences which could allow R8 and SCIxD to be overwritten with new data.
6 T8	<b>Ninth Data Bit for Transmitter</b> — When the SCI is configured for 9-bit data (M = 1), T8 may be thought of as a ninth transmit data bit to the left of the MSB of the data in the SCIxD register. When writing 9-bit data, the entire 9-bit value is transferred to the SCI shift register after SCIxD is written so T8 should be written (if it needs to change from its previous value) before SCIxD is written. If T8 does not need to change in the new value (such as when it is used to generate mark or space parity), it need not be written each time SCIxD is written.
5 TXDIR	<b>TxD Pin Direction in Single-Wire Mode</b> — When the SCI is configured for single-wire half-duplex operation (LOOPS = RSRC = 1), this bit determines the direction of data at the TxD pin. 0 TxD pin is an input in single-wire mode. 1 TxD pin is an output in single-wire mode.

**Table 14-7. SC1xC3 Field Descriptions (continued)**

Field	Description
4 TXINV <sup>1</sup>	<b>Transmit Data Inversion</b> — Setting this bit reverses the polarity of the transmitted data output. 0 Transmit data not inverted 1 Transmit data inverted
3 ORIE	<b>Overrun Interrupt Enable</b> — This bit enables the overrun flag (OR) to generate hardware interrupt requests. 0 OR interrupts disabled (use polling). 1 Hardware interrupt requested when OR = 1.
2 NEIE	<b>Noise Error Interrupt Enable</b> — This bit enables the noise flag (NF) to generate hardware interrupt requests. 0 NF interrupts disabled (use polling). 1 Hardware interrupt requested when NF = 1.
1 FEIE	<b>Framing Error Interrupt Enable</b> — This bit enables the framing error flag (FE) to generate hardware interrupt requests. 0 FE interrupts disabled (use polling). 1 Hardware interrupt requested when FE = 1.
0 PEIE	<b>Parity Error Interrupt Enable</b> — This bit enables the parity error flag (PF) to generate hardware interrupt requests. 0 PF interrupts disabled (use polling). 1 Hardware interrupt requested when PF = 1.

<sup>1</sup> Setting TXINV inverts the TxD output for all cases: data bits, start and stop bits, break, and idle.

## 14.2.7 SCI Data Register (SC1xD)

This register is actually two separate registers. Reads return the contents of the read-only receive data buffer and writes go to the write-only transmit data buffer. Reads and writes of this register are also involved in the automatic flag clearing mechanisms for the SCI status flags.

	7	6	5	4	3	2	1	0
R	R7	R6	R5	R4	R3	R2	R1	R0
W	T7	T6	T5	T4	T3	T2	T1	T0
Reset	0	0	0	0	0	0	0	0

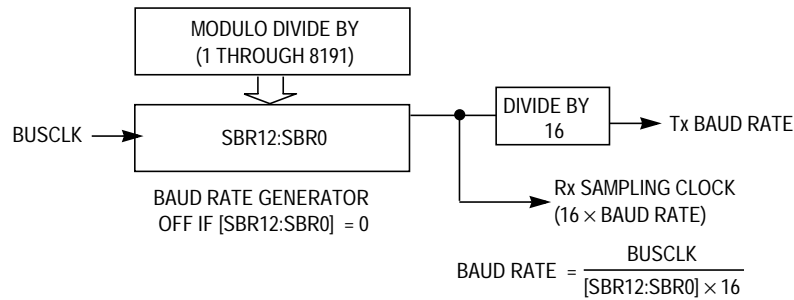
**Figure 14-12. SCI Data Register (SC1xD)**

## 14.3 Functional Description

The SCI allows full-duplex, asynchronous, NRZ serial communication among the MCU and remote devices, including other MCUs. The SCI comprises a baud rate generator, transmitter, and receiver block. The transmitter and receiver operate independently, although they use the same baud rate generator. During normal operation, the MCU monitors the status of the SCI, writes the data to be transmitted, and processes received data. The following describes each of the blocks of the SCI.

### 14.3.1 Baud Rate Generation

As shown in [Figure 14-13](#), the clock source for the SCI baud rate generator is the bus-rate clock.



**Figure 14-13. SCI Baud Rate Generation**

SCI communications require the transmitter and receiver (which typically derive baud rates from independent clock sources) to use the same baud rate. Allowed tolerance on this baud frequency depends on the details of how the receiver synchronizes to the leading edge of the start bit and how bit sampling is performed.

The MCU resynchronizes to bit boundaries on every high-to-low transition, but in the worst case, there are no such transitions in the full 10- or 11-bit time character frame so any mismatch in baud rate is accumulated for the whole character time. For a Freescale Semiconductor SCI system whose bus frequency is driven by a crystal, the allowed baud rate mismatch is about 4.5 percent for 8-bit data format and about 4 percent for 9-bit data format. Although baud rate modulo divider settings do not always produce baud rates that exactly match standard rates, it is normally possible to get within a few percent, which is acceptable for reliable communications.

### 14.3.2 Transmitter Functional Description

This section describes the overall block diagram for the SCI transmitter, as well as specialized functions for sending break and idle characters. The transmitter block diagram is shown in Figure 14-3.

The transmitter output (TxD) idle state defaults to logic high (TXINV = 0 following reset). The transmitter output is inverted by setting TXINV = 1. The transmitter is enabled by setting the TE bit in SCIx C2. This queues a preamble character that is one full character frame of the idle state. The transmitter then remains idle until data is available in the transmit data buffer. Programs store data into the transmit data buffer by writing to the SCI data register (SCIxD).

The central element of the SCI transmitter is the transmit shift register that is either 10 or 11 bits long depending on the setting in the M control bit. For the remainder of this section, we will assume M = 0, selecting the normal 8-bit data mode. In 8-bit data mode, the shift register holds a start bit, eight data bits, and a stop bit. When the transmit shift register is available for a new SCI character, the value waiting in the transmit data register is transferred to the shift register (synchronized with the baud rate clock) and the transmit data register empty (TDRE) status flag is set to indicate another character may be written to the transmit data buffer at SCIxD.

If no new character is waiting in the transmit data buffer after a stop bit is shifted out the TxD pin, the transmitter sets the transmit complete flag and enters an idle mode, with TxD high, waiting for more characters to transmit.

Writing 0 to TE does not immediately release the pin to be a general-purpose I/O pin. Any transmit activity that is in progress must first be completed. This includes data characters in progress, queued idle characters, and queued break characters.

### 14.3.2.1 Send Break and Queued Idle

The SBK control bit in SCIxC2 is used to send break characters which were originally used to gain the attention of old teletype receivers. Break characters are a full character time of logic 0 (10 bit times including the start and stop bits). A longer break of 13 bit times can be enabled by setting BRK13 = 1. Normally, a program would wait for TDRE to become set to indicate the last character of a message has moved to the transmit shifter, then write 1 and then write 0 to the SBK bit. This action queues a break character to be sent as soon as the shifter is available. If SBK is still 1 when the queued break moves into the shifter (synchronized to the baud rate clock), an additional break character is queued. If the receiving device is another Freescale Semiconductor SCI, the break characters will be received as 0s in all eight data bits and a framing error (FE = 1) occurs.

When idle-line wakeup is used, a full character time of idle (logic 1) is needed between messages to wake up any sleeping receivers. Normally, a program would wait for TDRE to become set to indicate the last character of a message has moved to the transmit shifter, then write 0 and then write 1 to the TE bit. This action queues an idle character to be sent as soon as the shifter is available. As long as the character in the shifter does not finish while TE = 0, the SCI transmitter never actually releases control of the TxD pin. If there is a possibility of the shifter finishing while TE = 0, set the general-purpose I/O controls so the pin that is shared with TxD is an output driving a logic 1. This ensures that the TxD line will look like a normal idle line even if the SCI loses control of the port pin between writing 0 and then 1 to TE.

The length of the break character is affected by the BRK13 and M bits as shown below.

**Table 14-8. Break Character Length**

BRK13	M	Break Character Length
0	0	10 bit times
0	1	11 bit times
1	0	13 bit times
1	1	14 bit times

### 14.3.3 Receiver Functional Description

In this section, the receiver block diagram (Figure 14-4) is used as a guide for the overall receiver functional description. Next, the data sampling technique used to reconstruct receiver data is described in more detail. Finally, two variations of the receiver wakeup function are explained.

The receiver input is inverted by setting RXINV = 1. The receiver is enabled by setting the RE bit in SCIxC2. Character frames consist of a start bit of logic 0, eight (or nine) data bits (LSB first), and a stop bit of logic 1. For information about 9-bit data mode, refer to Section 14.3.5.1, “8- and 9-Bit Data Modes.” For the remainder of this discussion, we assume the SCI is configured for normal 8-bit data mode.

After receiving the stop bit into the receive shifter, and provided the receive data register is not already full, the data character is transferred to the receive data register and the receive data register full (RDRF) status

flag is set. If RDRF was already set indicating the receive data register (buffer) was already full, the overrun (OR) status flag is set and the new data is lost. Because the SCI receiver is double-buffered, the program has one full character time after RDRF is set before the data in the receive data buffer must be read to avoid a receiver overrun.

When a program detects that the receive data register is full ( $RDRF = 1$ ), it gets the data from the receive data register by reading SCIxD. The RDRF flag is cleared automatically by a 2-step sequence which is normally satisfied in the course of the user's program that handles receive data. Refer to [Section 14.3.4, "Interrupts and Status Flags"](#) for more details about flag clearing.

### 14.3.3.1 Data Sampling Technique

The SCI receiver uses a  $16\times$  baud rate clock for sampling. The receiver starts by taking logic level samples at 16 times the baud rate to search for a falling edge on the RxD serial data input pin. A falling edge is defined as a logic 0 sample after three consecutive logic 1 samples. The  $16\times$  baud rate clock is used to divide the bit time into 16 segments labeled RT1 through RT16. When a falling edge is located, three more samples are taken at RT3, RT5, and RT7 to make sure this was a real start bit and not merely noise. If at least two of these three samples are 0, the receiver assumes it is synchronized to a receive character.

The receiver then samples each bit time, including the start and stop bits, at RT8, RT9, and RT10 to determine the logic level for that bit. The logic level is interpreted to be that of the majority of the samples taken during the bit time. In the case of the start bit, the bit is assumed to be 0 if at least two of the samples at RT3, RT5, and RT7 are 0 even if one or all of the samples taken at RT8, RT9, and RT10 are 1s. If any sample in any bit time (including the start and stop bits) in a character frame fails to agree with the logic level for that bit, the noise flag (NF) will be set when the received character is transferred to the receive data buffer.

The falling edge detection logic continuously looks for falling edges, and if an edge is detected, the sample clock is resynchronized to bit times. This improves the reliability of the receiver in the presence of noise or mismatched baud rates. It does not improve worst case analysis because some characters do not have any extra falling edges anywhere in the character frame.

In the case of a framing error, provided the received character was not a break character, the sampling logic that searches for a falling edge is filled with three logic 1 samples so that a new start bit can be detected almost immediately.

In the case of a framing error, the receiver is inhibited from receiving any new characters until the framing error flag is cleared. The receive shift register continues to function, but a complete character cannot transfer to the receive data buffer if FE is still set.

### 14.3.3.2 Receiver Wakeup Operation

Receiver wakeup is a hardware mechanism that allows an SCI receiver to ignore the characters in a message that is intended for a different SCI receiver. In such a system, all receivers evaluate the first character(s) of each message, and as soon as they determine the message is intended for a different receiver, they write logic 1 to the receiver wake up (RWU) control bit in SCIxC2. When RWU bit is set, the status flags associated with the receiver (with the exception of the idle bit, IDLE, when RWUID bit is set) are inhibited from setting, thus eliminating the software overhead for handling the unimportant

message characters. At the end of a message, or at the beginning of the next message, all receivers automatically force RWU to 0 so all receivers wake up in time to look at the first character(s) of the next message.

#### 14.3.3.2.1 Idle-Line Wakeup

When WAKE = 0, the receiver is configured for idle-line wakeup. In this mode, RWU is cleared automatically when the receiver detects a full character time of the idle-line level. The M control bit selects 8-bit or 9-bit data mode that determines how many bit times of idle are needed to constitute a full character time (10 or 11 bit times because of the start and stop bits).

When RWU is one and RWUID is zero, the idle condition that wakes up the receiver does not set the IDLE flag. The receiver wakes up and waits for the first data character of the next message which will set the RDRF flag and generate an interrupt if enabled. When RWUID is one, any idle condition sets the IDLE flag and generates an interrupt if enabled, regardless of whether RWU is zero or one.

The idle-line type (ILT) control bit selects one of two ways to detect an idle line. When ILT = 0, the idle bit counter starts after the start bit so the stop bit and any logic 1s at the end of a character count toward the full character time of idle. When ILT = 1, the idle bit counter does not start until after a stop bit time, so the idle detection is not affected by the data in the last character of the previous message.

#### 14.3.3.2.2 Address-Mark Wakeup

When WAKE = 1, the receiver is configured for address-mark wakeup. In this mode, RWU is cleared automatically when the receiver detects a logic 1 in the most significant bit of a received character (eighth bit in M = 0 mode and ninth bit in M = 1 mode).

Address-mark wakeup allows messages to contain idle characters but requires that the MSB be reserved for use in address frames. The logic 1 MSB of an address frame clears the RWU bit before the stop bit is received and sets the RDRF flag. In this case the character with the MSB set is received even though the receiver was sleeping during most of this character time.

### 14.3.4 Interrupts and Status Flags

The SCI system has three separate interrupt vectors to reduce the amount of software needed to isolate the cause of the interrupt. One interrupt vector is associated with the transmitter for TDRE and TC events. Another interrupt vector is associated with the receiver for RDRF, IDLE, RXEDGIF and LBKDIF events, and a third vector is used for OR, NF, FE, and PF error conditions. Each of these ten interrupt sources can be separately masked by local interrupt enable masks. The flags can still be polled by software when the local masks are cleared to disable generation of hardware interrupt requests.

The SCI transmitter has two status flags that optionally can generate hardware interrupt requests. Transmit data register empty (TDRE) indicates when there is room in the transmit data buffer to write another transmit character to SCIxD. If the transmit interrupt enable (TIE) bit is set, a hardware interrupt will be requested whenever TDRE = 1. Transmit complete (TC) indicates that the transmitter is finished transmitting all data, preamble, and break characters and is idle with TxD at the inactive level. This flag is often used in systems with modems to determine when it is safe to turn off the modem. If the transmit complete interrupt enable (TCIE) bit is set, a hardware interrupt will be requested whenever TC = 1.



Instead of hardware interrupts, software polling may be used to monitor the TDRE and TC status flags if the corresponding TIE or TCIE local interrupt masks are 0s.

When a program detects that the receive data register is full ( $RDRF = 1$ ), it gets the data from the receive data register by reading SCIxD. The RDRF flag is cleared by reading SCIxS1 while  $RDRF = 1$  and then reading SCIxD.

When polling is used, this sequence is naturally satisfied in the normal course of the user program. If hardware interrupts are used, SCIxS1 must be read in the interrupt service routine (ISR). Normally, this is done in the ISR anyway to check for receive errors, so the sequence is automatically satisfied.

The IDLE status flag includes logic that prevents it from getting set repeatedly when the RxD line remains idle for an extended period of time. IDLE is cleared by reading SCIxS1 while  $IDLE = 1$  and then reading SCIxD. After IDLE has been cleared, it cannot become set again until the receiver has received at least one new character and has set RDRF.

If the associated error was detected in the received character that caused RDRF to be set, the error flags — noise flag (NF), framing error (FE), and parity error flag (PF) — get set at the same time as RDRF. These flags are not set in overrun cases.

If RDRF was already set when a new character is ready to be transferred from the receive shifter to the receive data buffer, the overrun (OR) flag gets set instead the data along with any associated NF, FE, or PF condition is lost.

At any time, an active edge on the RxD serial data input pin causes the RXEDGIF flag to set. The RXEDGIF flag is cleared by writing a “1” to it. This function does depend on the receiver being enabled ( $RE = 1$ ).

### 14.3.5 Additional SCI Functions

The following sections describe additional SCI functions.

#### 14.3.5.1 8- and 9-Bit Data Modes

The SCI system (transmitter and receiver) can be configured to operate in 9-bit data mode by setting the M control bit in SCIxC1. In 9-bit mode, there is a ninth data bit to the left of the MSB of the SCI data register. For the transmit data buffer, this bit is stored in T8 in SCIxC3. For the receiver, the ninth bit is held in R8 in SCIxC3.

For coherent writes to the transmit data buffer, write to the T8 bit before writing to SCIxD.

If the bit value to be transmitted as the ninth bit of a new character is the same as for the previous character, it is not necessary to write to T8 again. When data is transferred from the transmit data buffer to the transmit shifter, the value in T8 is copied at the same time data is transferred from SCIxD to the shifter.

9-bit data mode typically is used in conjunction with parity to allow eight bits of data plus the parity in the ninth bit. Or it is used with address-mark wakeup so the ninth data bit can serve as the wakeup bit. In custom protocols, the ninth bit can also serve as a software-controlled marker.

### 14.3.5.2 Stop Mode Operation

During all stop modes, clocks to the SCI module are halted.

In stop1 and stop2 modes, all SCI register data is lost and must be re-initialized upon recovery from these two stop modes. No SCI module registers are affected in stop3 mode.

The receive input active edge detect circuit is still active in stop3 mode, but not in stop2.. An active edge on the receive input brings the CPU out of stop3 mode if the interrupt is not masked (RXEDGIE = 1).

Note, because the clocks are halted, the SCI module will resume operation upon exit from stop (only in stop3 mode). Software should ensure stop mode is not entered while there is a character being transmitted out of or received into the SCI module.

### 14.3.5.3 Loop Mode

When LOOPS = 1, the RSRC bit in the same register chooses between loop mode (RSRC = 0) or single-wire mode (RSRC = 1). Loop mode is sometimes used to check software, independent of connections in the external system, to help isolate system problems. In this mode, the transmitter output is internally connected to the receiver input and the RxD pin is not used by the SCI, so it reverts to a general-purpose port I/O pin.

### 14.3.5.4 Single-Wire Operation

When LOOPS = 1, the RSRC bit in the same register chooses between loop mode (RSRC = 0) or single-wire mode (RSRC = 1). Single-wire mode is used to implement a half-duplex serial connection. The receiver is internally connected to the transmitter output and to the TxD pin. The RxD pin is not used and reverts to a general-purpose port I/O pin.

In single-wire mode, the TXDIR bit in SCIxC3 controls the direction of serial data on the TxD pin. When TXDIR = 0, the TxD pin is an input to the SCI receiver and the transmitter is temporarily disconnected from the TxD pin so an external device can send serial data to the receiver. When TXDIR = 1, the TxD pin is an output driven by the transmitter. In single-wire mode, the internal loop back connection from the transmitter to the receiver causes the receiver to receive characters that are sent out by the transmitter.

## Chapter 15

# Serial Peripheral Interface (S08SPIV3)

### 15.1 Introduction

Figure 15-1 shows the MC9S08QE128 Series block diagram with the SPI highlighted.

#### NOTE

Ignore any references to stop1 low-power mode in this chapter, because the MC9S08QE128 device does not support it.

#### 15.1.1 SPI Clock Gating

The bus clock to SPI1 and SPI2 can be gated on and off using the SPI1 and SPI2 bits, respectively, in SCGC2. These bits are set after any reset, which enables the bus clock to this module. To conserve power, these bits can be cleared to disable the clock to either of these modules when not in use. See [Section 5.7](#), “Peripheral Clock Gating,” for details.

#### 15.1.2 Interrupt Vector

See [Section 4.2](#), “Reset and Interrupt Vector Assignments,” for the SPI interrupt vector assignments.

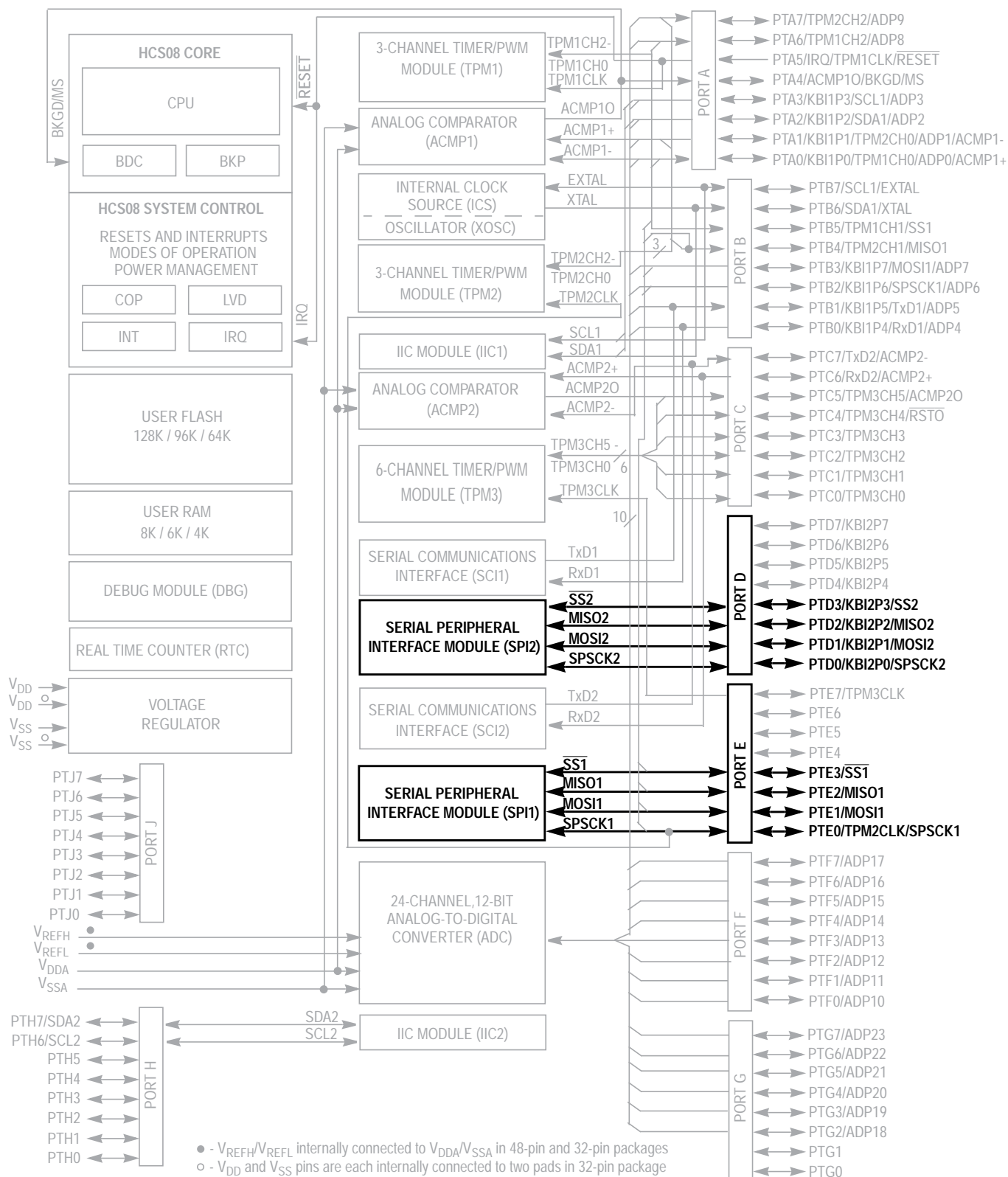


Figure 15-1. MC9S08QE128 Block Diagram Highlighting SPI Block and Pins

### 15.1.3 Features

Features of the SPI module include:

- Master or slave mode operation
- Full-duplex or single-wire bidirectional option
- Programmable transmit bit rate
- Double-buffered transmit and receive
- Serial clock phase and polarity options
- Slave select output
- Selectable MSB-first or LSB-first shifting

### 15.1.4 Block Diagrams

This section includes block diagrams showing SPI system connections, the internal organization of the SPI module, and the SPI clock dividers that control the master mode bit rate.

#### 15.1.4.1 SPI System Block Diagram

Figure 15-2 shows the SPI modules of two MCUs connected in a master-slave arrangement. The master device initiates all SPI data transfers. During a transfer, the master shifts data out (on the MOSI pin) to the slave while simultaneously shifting data in (on the MISO pin) from the slave. The transfer effectively exchanges the data that was in the SPI shift registers of the two SPI systems. The SPSCCK signal is a clock output from the master and an input to the slave. The slave device must be selected by a low level on the slave select input ( $\overline{SS}$  pin). In this system, the master device has configured its  $\overline{SS}$  pin as an optional slave select output.

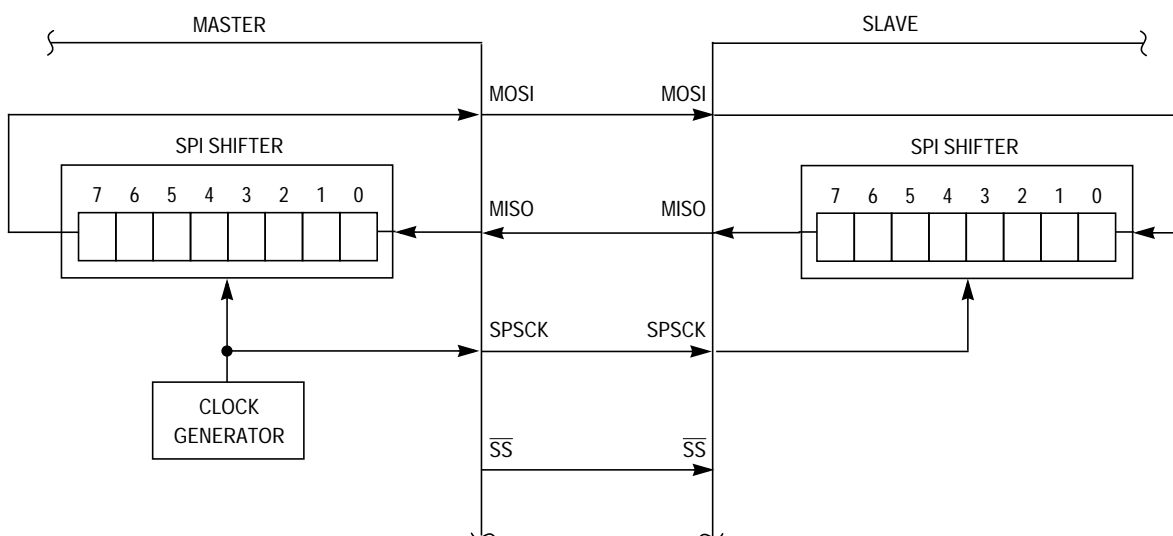


Figure 15-2. SPI System Connections

The most common uses of the SPI system include connecting simple shift registers for adding input or output ports or connecting small peripheral devices such as serial A/D or D/A converters. Although [Figure 15-2](#) shows a system where data is exchanged between two MCUs, many practical systems involve simpler connections where data is unidirectionally transferred from the master MCU to a slave or from a slave to the master MCU.

#### 15.1.4.2 SPI Module Block Diagram

[Figure 15-3](#) is a block diagram of the SPI module. The central element of the SPI is the SPI shift register. Data is written to the double-buffered transmitter (write to SPIxD) and gets transferred to the SPI shift register at the start of a data transfer. After shifting in a byte of data, the data is transferred into the double-buffered receiver where it can be read (read from SPIxD). Pin multiplexing logic controls connections between MCU pins and the SPI module.

When the SPI is configured as a master, the clock output is routed to the SPSCCK pin, the shifter output is routed to MOSI, and the shifter input is routed from the MISO pin.

When the SPI is configured as a slave, the SPSCCK pin is routed to the clock input of the SPI, the shifter output is routed to MISO, and the shifter input is routed from the MOSI pin.

In the external SPI system, simply connect all SPSCCK pins to each other, all MISO pins together, and all MOSI pins together. Peripheral devices often use slightly different names for these pins.

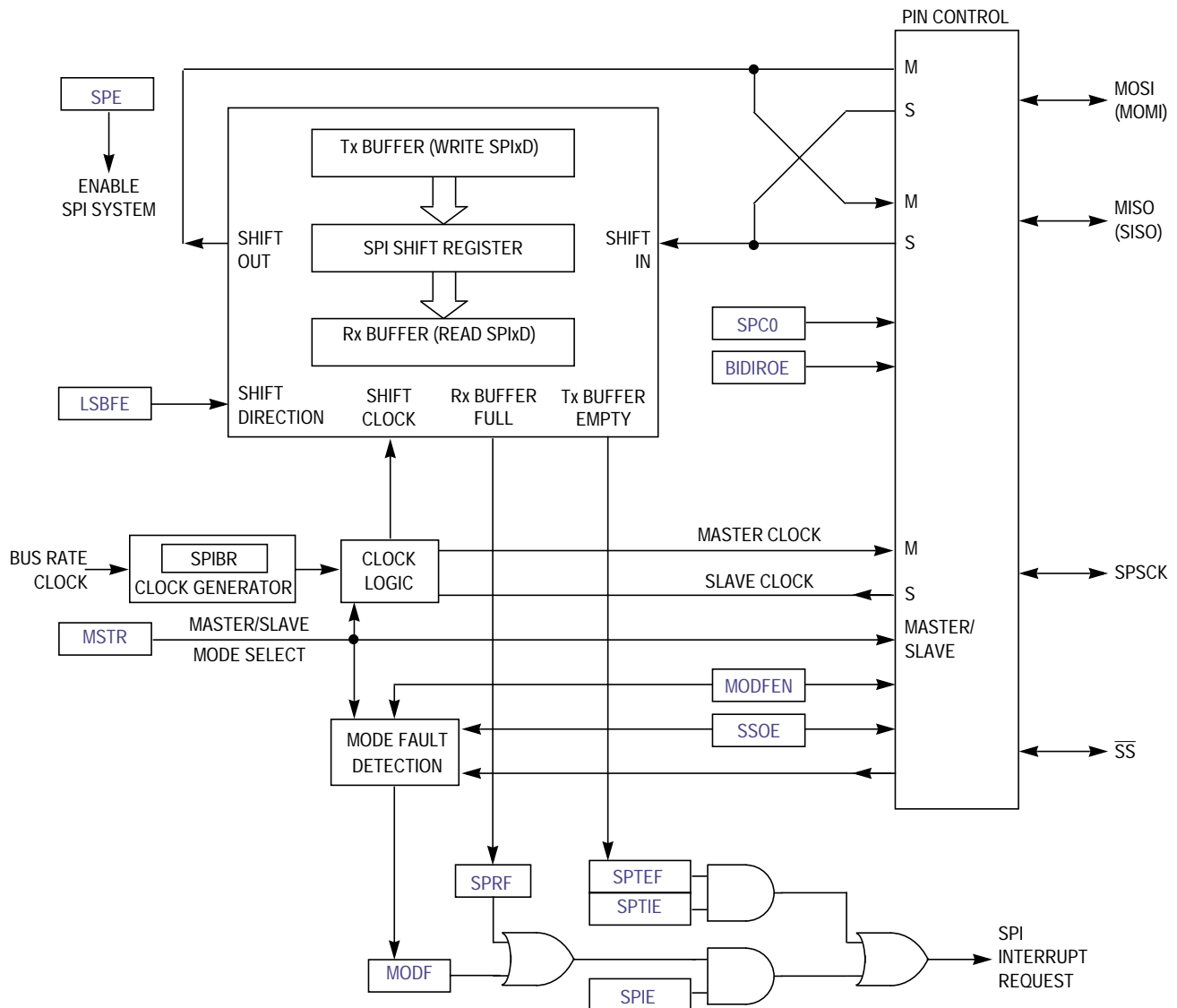


Figure 15-3. SPI Module Block Diagram

### 15.1.5 SPI Baud Rate Generation

As shown in Figure 15-4, the clock source for the SPI baud rate generator is the bus clock. The three prescale bits (SPPR2:SPPR1:SPPR0) choose a prescale divisor of 1, 2, 3, 4, 5, 6, 7, or 8. The three rate select bits (SPR2:SPR1:SPR0) divide the output of the prescaler stage by 2, 4, 8, 16, 32, 64, 128, or 256 to get the internal SPI master mode bit-rate clock.

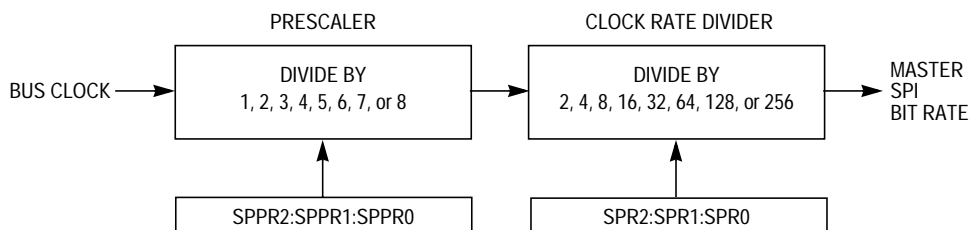


Figure 15-4. SPI Baud Rate Generation

## 15.2 External Signal Description

The SPI optionally shares four port pins. The function of these pins depends on the settings of SPI control bits. When the SPI is disabled ( $SPE = 0$ ), these four pins revert to being general-purpose port I/O pins that are not controlled by the SPI.

### 15.2.1 SPCK — SPI Serial Clock

When the SPI is enabled as a slave, this pin is the serial clock input. When the SPI is enabled as a master, this pin is the serial clock output.

### 15.2.2 MOSI — Master Data Out, Slave Data In

When the SPI is enabled as a master and SPI pin control zero ( $SPC0$ ) is 0 (not bidirectional mode), this pin is the serial data output. When the SPI is enabled as a slave and  $SPC0 = 0$ , this pin is the serial data input. If  $SPC0 = 1$  to select single-wire bidirectional mode, and master mode is selected, this pin becomes the bidirectional data I/O pin (MOMI). Also, the bidirectional mode output enable bit determines whether the pin acts as an input ( $BIDIROE = 0$ ) or an output ( $BIDIROE = 1$ ). If  $SPC0 = 1$  and slave mode is selected, this pin is not used by the SPI and reverts to being a general-purpose port I/O pin.

### 15.2.3 MISO — Master Data In, Slave Data Out

When the SPI is enabled as a master and SPI pin control zero ( $SPC0$ ) is 0 (not bidirectional mode), this pin is the serial data input. When the SPI is enabled as a slave and  $SPC0 = 0$ , this pin is the serial data output. If  $SPC0 = 1$  to select single-wire bidirectional mode, and slave mode is selected, this pin becomes the bidirectional data I/O pin (SISO) and the bidirectional mode output enable bit determines whether the pin acts as an input ( $BIDIROE = 0$ ) or an output ( $BIDIROE = 1$ ). If  $SPC0 = 1$  and master mode is selected, this pin is not used by the SPI and reverts to being a general-purpose port I/O pin.

### 15.2.4 $\overline{SS}$ — Slave Select

When the SPI is enabled as a slave, this pin is the low-true slave select input. When the SPI is enabled as a master and mode fault enable is off ( $MODFEN = 0$ ), this pin is not used by the SPI and reverts to being a general-purpose port I/O pin. When the SPI is enabled as a master and  $MODFEN = 1$ , the slave select output enable bit determines whether this pin acts as the mode fault input ( $SSOE = 0$ ) or as the slave select output ( $SSOE = 1$ ).



## 15.3 Modes of Operation

### 15.3.1 SPI in Stop Modes

The SPI is disabled in all stop modes, regardless of the settings before executing the STOP instruction. During either stop1 or stop2 mode, the SPI module will be fully powered down. Upon wake-up from stop1 or stop2 mode, the SPI module will be in the reset state. During stop3 mode, clocks to the SPI module are halted. No registers are affected. If stop3 is exited with a reset, the SPI will be put into its reset state. If stop3 is exited with an interrupt, the SPI continues from the state it was in when stop3 was entered.

## 15.4 Register Definition

The SPI has five 8-bit registers to select SPI options, control baud rate, report SPI status, and for transmit/receive data.

Refer to the direct-page register summary in the [Memory](#) chapter of this data sheet for the absolute address assignments for all SPI registers. This section refers to registers and control bits only by their names, and a Freescale-provided equate or header file is used to translate these names into the appropriate absolute addresses.

### 15.4.1 SPI Control Register 1 (SPIxC1)

This read/write register includes the SPI enable control, interrupt enables, and configuration options.

	7	6	5	4	3	2	1	0
R	SPIE	SPE	SPTIE	MSTR	CPOL	CPHA	SSOE	LSBFE
W								
Reset	0	0	0	0	0	1	0	0

Figure 15-5. SPI Control Register 1 (SPIxC1)

Table 15-1. SPIxC1 Field Descriptions

Field	Description
7 SPIE	<b>SPI Interrupt Enable (for SPRF and MODF)</b> — This is the interrupt enable for SPI receive buffer full (SPRF) and mode fault (MODF) events. 0 Interrupts from SPRF and MODF inhibited (use polling) 1 When SPRF or MODF is 1, request a hardware interrupt
6 SPE	<b>SPI System Enable</b> — Disabling the SPI halts any transfer that is in progress, clears data buffers, and initializes internal state machines. SPRF is cleared and SPTEF is set to indicate the SPI transmit data buffer is empty. 0 SPI system inactive 1 SPI system enabled
5 SPTIE	<b>SPI Transmit Interrupt Enable</b> — This is the interrupt enable bit for SPI transmit buffer empty (SPTEF). 0 Interrupts from SPTEF inhibited (use polling) 1 When SPTEF is 1, hardware interrupt requested

**Table 15-1. SPIxC1 Field Descriptions (continued)**

Field	Description
4 MSTR	<b>Master/Slave Mode Select</b> 0 SPI module configured as a slave SPI device 1 SPI module configured as a master SPI device
3 CPOL	<b>Clock Polarity</b> — This bit effectively places an inverter in series with the clock signal from a master SPI or to a slave SPI device. Refer to <a href="#">Section 15.5.1, “SPI Clock Formats”</a> for more details. 0 Active-high SPI clock (idles low) 1 Active-low SPI clock (idles high)
2 CPHA	<b>Clock Phase</b> — This bit selects one of two clock formats for different kinds of synchronous serial peripheral devices. Refer to <a href="#">Section 15.5.1, “SPI Clock Formats”</a> for more details. 0 First edge on SPSCK occurs at the middle of the first cycle of an 8-cycle data transfer 1 First edge on SPSCK occurs at the start of the first cycle of an 8-cycle data transfer
1 SSOE	<b>Slave Select Output Enable</b> — This bit is used in combination with the mode fault enable (MODFEN) bit in SPCR2 and the master/slave (MSTR) control bit to determine the function of the $\overline{SS}$ pin as shown in <a href="#">Table 15-2</a> .
0 LSBFE	<b>LSB First (Shifter Direction)</b> 0 SPI serial data transfers start with most significant bit 1 SPI serial data transfers start with least significant bit

**Table 15-2.  $\overline{SS}$  Pin Function**

MODFEN	SSOE	Master Mode	Slave Mode
0	0	General-purpose I/O (not SPI)	Slave select input
0	1	General-purpose I/O (not SPI)	Slave select input
1	0	$\overline{SS}$ input for mode fault	Slave select input
1	1	Automatic $\overline{SS}$ output	Slave select input

### NOTE

Ensure that the SPI should not be disabled (SPE=0) at the same time as a bit change to the CPHA bit. These changes should be performed as separate operations or unexpected behavior may occur.

## 15.4.2 SPI Control Register 2 (SPIxC2)

This read/write register is used to control optional features of the SPI system. Bits 7, 6, 5, and 2 are not implemented and always read 0.

	7	6	5	4	3	2	1	0
R	0	0	0	MODFEN	BIDIROE	0	SPISWAI	SPC0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

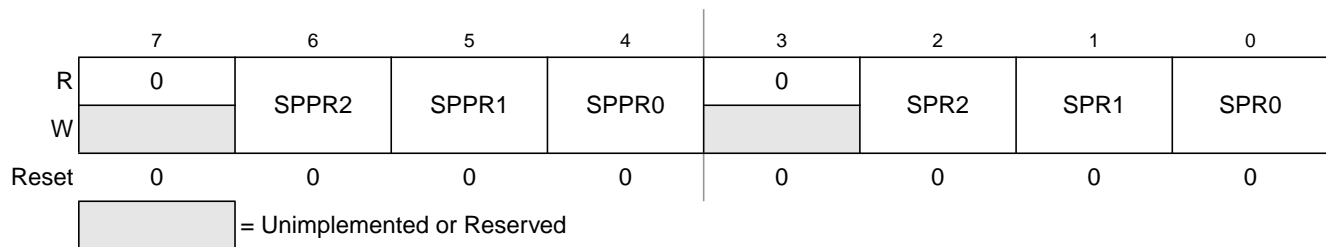
**Figure 15-6. SPI Control Register 2 (SPIxC2)**

**Table 15-3. SPIxC2 Register Field Descriptions**

Field	Description
4 MODFEN	<b>Master Mode-Fault Function Enable</b> — When the SPI is configured for slave mode, this bit has no meaning or effect. (The $\overline{SS}$ pin is the slave select input.) In master mode, this bit determines how the $\overline{SS}$ pin is used (refer to Table 15-2 for more details). 0 Mode fault function disabled, master $\overline{SS}$ pin reverts to general-purpose I/O not controlled by SPI 1 Mode fault function enabled, master $\overline{SS}$ pin acts as the mode fault input or the slave select output
3 BIDIROE	<b>Bidirectional Mode Output Enable</b> — When bidirectional mode is enabled by SPI pin control 0 (SPC0) = 1, BIDIROE determines whether the SPI data output driver is enabled to the single bidirectional SPI I/O pin. Depending on whether the SPI is configured as a master or a slave, it uses either the MOSI (MOMI) or MISO (SISO) pin, respectively, as the single SPI data I/O pin. When SPC0 = 0, BIDIROE has no meaning or effect. 0 Output driver disabled so SPI data I/O pin acts as an input 1 SPI I/O pin enabled as an output
1 SPISWAI	<b>SPI Stop in Wait Mode</b> 0 SPI clocks continue to operate in wait mode 1 SPI clocks stop when the MCU enters wait mode
0 SPC0	<b>SPI Pin Control 0</b> — The SPC0 bit chooses single-wire bidirectional mode. If MSTR = 0 (slave mode), the SPI uses the MISO (SISO) pin for bidirectional SPI data transfers. If MSTR = 1 (master mode), the SPI uses the MOSI (MOMI) pin for bidirectional SPI data transfers. When SPC0 = 1, BIDIROE is used to enable or disable the output driver for the single bidirectional SPI I/O pin. 0 SPI uses separate pins for data input and data output 1 SPI configured for single-wire bidirectional operation

### 15.4.3 SPI Baud Rate Register (SPIxBR)

This register is used to set the prescaler and bit rate divisor for an SPI master. This register may be read or written at any time.


**Figure 15-7. SPI Baud Rate Register (SPIxBR)**
**Table 15-4. SPIxBR Register Field Descriptions**

Field	Description
6:4 SPPR[2:0]	<b>SPI Baud Rate Prescale Divisor</b> — This 3-bit field selects one of eight divisors for the SPI baud rate prescaler as shown in Table 15-5. The input to this prescaler is the bus rate clock (BUSCLK). The output of this prescaler drives the input of the SPI baud rate divider (see Figure 15-4).
2:0 SPR[2:0]	<b>SPI Baud Rate Divisor</b> — This 3-bit field selects one of eight divisors for the SPI baud rate divider as shown in Table 15-6. The input to this divider comes from the SPI baud rate prescaler (see Figure 15-4). The output of this divider is the SPI bit rate clock for master mode.

**Table 15-5. SPI Baud Rate Prescaler Divisor**

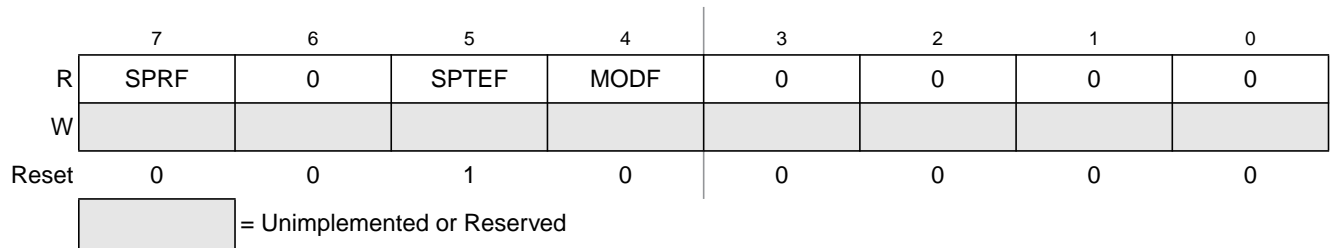
SPPR2:SPPR1:SPPR0	Prescaler Divisor
0:0:0	1
0:0:1	2
0:1:0	3
0:1:1	4
1:0:0	5
1:0:1	6
1:1:0	7
1:1:1	8

**Table 15-6. SPI Baud Rate Divisor**

SPR2:SPR1:SPR0	Rate Divisor
0:0:0	2
0:0:1	4
0:1:0	8
0:1:1	16
1:0:0	32
1:0:1	64
1:1:0	128
1:1:1	256

### 15.4.4 SPI Status Register (SPIxS)

This register has three read-only status bits. Bits 6, 3, 2, 1, and 0 are not implemented and always read 0. Writes have no meaning or effect.

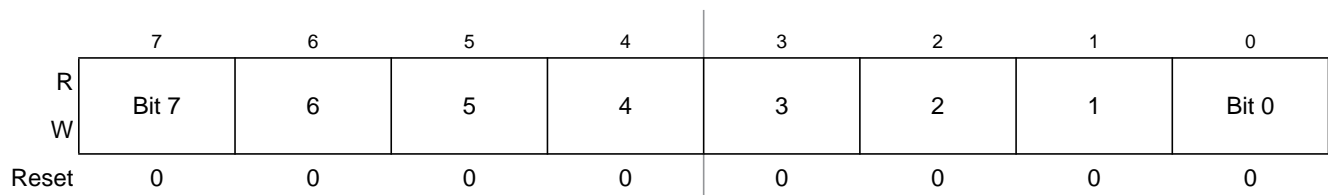


**Figure 15-8. SPI Status Register (SPIxS)**

**Table 15-7. SPIxS Register Field Descriptions**

Field	Description
7 SPRF	<b>SPI Read Buffer Full Flag</b> — SPRF is set at the completion of an SPI transfer to indicate that received data may be read from the SPI data register (SPIxD). SPRF is cleared by reading SPRF while it is set, then reading the SPI data register. 0 No data available in the receive data buffer 1 Data available in the receive data buffer
5 SPTEF	<b>SPI Transmit Buffer Empty Flag</b> — This bit is set when there is room in the transmit data buffer. It is cleared by reading SPIxS with SPTEF set, followed by writing a data value to the transmit buffer at SPIxD. SPIxS must be read with SPTEF = 1 before writing data to SPIxD or the SPIxD write will be ignored. SPTEF generates an SPTEF CPU interrupt request if the SPTIE bit in the SPIxC1 is also set. SPTEF is automatically set when a data byte transfers from the transmit buffer into the transmit shift register. For an idle SPI (no data in the transmit buffer or the shift register and no transfer in progress), data written to SPIxD is transferred to the shifter almost immediately so SPTEF is set within two bus cycles allowing a second 8-bit data value to be queued into the transmit buffer. After completion of the transfer of the value in the shift register, the queued value from the transmit buffer will automatically move to the shifter and SPTEF will be set to indicate there is room for new data in the transmit buffer. If no new data is waiting in the transmit buffer, SPTEF simply remains set and no data moves from the buffer to the shifter. 0 SPI transmit buffer not empty 1 SPI transmit buffer empty
4 MODF	<b>Master Mode Fault Flag</b> — MODF is set if the SPI is configured as a master and the slave select input goes low, indicating some other SPI device is also configured as a master. The $\overline{SS}$ pin acts as a mode fault error input only when MSTR = 1, MODFEN = 1, and SSOE = 0; otherwise, MODF will never be set. MODF is cleared by reading MODF while it is 1, then writing to SPI control register 1 (SPIxC1). 0 No mode fault error 1 Mode fault error detected

### 15.4.5 SPI Data Register (SPIxD)


**Figure 15-9. SPI Data Register (SPIxD)**

Reads of this register return the data read from the receive data buffer. Writes to this register write data to the transmit data buffer. When the SPI is configured as a master, writing data to the transmit data buffer initiates an SPI transfer.

Data should not be written to the transmit data buffer unless the SPI transmit buffer empty flag (SPTEF) is set, indicating there is room in the transmit buffer to queue a new transmit byte.

Data may be read from SPIxD any time after SPRF is set and before another transfer is finished. Failure to read the data out of the receive data buffer before a new transfer ends causes a receive overrun condition and the data from the new transfer is lost.

## 15.5 Functional Description

An SPI transfer is initiated by checking for the SPI transmit buffer empty flag (SPTEF = 1) and then writing a byte of data to the SPI data register (SPIxD) in the master SPI device. When the SPI shift register is available, this byte of data is moved from the transmit data buffer to the shifter, SPTEF is set to indicate there is room in the buffer to queue another transmit character if desired, and the SPI serial transfer starts.

During the SPI transfer, data is sampled (read) on the MISO pin at one SPSCCK edge and shifted, changing the bit value on the MOSI pin, one-half SPSCCK cycle later. After eight SPSCCK cycles, the data that was in the shift register of the master has been shifted out the MOSI pin to the slave while eight bits of data were shifted in the MISO pin into the master's shift register. At the end of this transfer, the received data byte is moved from the shifter into the receive data buffer and SPRF is set to indicate the data can be read by reading SPIxD. If another byte of data is waiting in the transmit buffer at the end of a transfer, it is moved into the shifter, SPTEF is set, and a new transfer is started.

Normally, SPI data is transferred most significant bit (MSB) first. If the least significant bit first enable (LSBFE) bit is set, SPI data is shifted LSB first.

When the SPI is configured as a slave, its  $\overline{SS}$  pin must be driven low before a transfer starts and  $\overline{SS}$  must stay low throughout the transfer. If a clock format where CPHA = 0 is selected,  $\overline{SS}$  must be driven to a logic 1 between successive transfers. If CPHA = 1,  $\overline{SS}$  may remain low between successive transfers. See [Section 15.5.1, "SPI Clock Formats"](#) for more details.

Because the transmitter and receiver are double buffered, a second byte, in addition to the byte currently being shifted out, can be queued into the transmit data buffer, and a previously received character can be in the receive data buffer while a new character is being shifted in. The SPTEF flag indicates when the transmit buffer has room for a new character. The SPRF flag indicates when a received character is available in the receive data buffer. The received character must be read out of the receive buffer (read SPIxD) before the next transfer is finished or a receive overrun error results.

In the case of a receive overrun, the new data is lost because the receive buffer still held the previous character and was not ready to accept the new data. There is no indication for such an overrun condition so the application system designer must ensure that previous data has been read from the receive buffer before a new transfer is initiated.

### 15.5.1 SPI Clock Formats

To accommodate a wide variety of synchronous serial peripherals from different manufacturers, the SPI system has a clock polarity (CPOL) bit and a clock phase (CPHA) control bit to select one of four clock formats for data transfers. CPOL selectively inserts an inverter in series with the clock. CPHA chooses between two different clock phase relationships between the clock and data.

[Figure 15-10](#) shows the clock formats when CPHA = 1. At the top of the figure, the eight bit times are shown for reference with bit 1 starting at the first SPSCCK edge and bit 8 ending one-half SPSCCK cycle after the sixteenth SPSCCK edge. The MSB first and LSB first lines show the order of SPI data bits depending on the setting in LSBFE. Both variations of SPSCCK polarity are shown, but only one of these waveforms applies for a specific transfer, depending on the value in CPOL. The SAMPLE IN waveform applies to the MOSI input of a slave or the MISO input of a master. The MOSI waveform applies to the MOSI output

pin from a master and the MISO waveform applies to the MISO output from a slave. The  $\overline{SS}$  OUT waveform applies to the slave select output from a master (provided MODFEN and SSOE = 1). The master  $\overline{SS}$  output goes to active low one-half SPSCK cycle before the start of the transfer and goes back high at the end of the eighth bit time of the transfer. The  $\overline{SS}$  IN waveform applies to the slave select input of a slave.

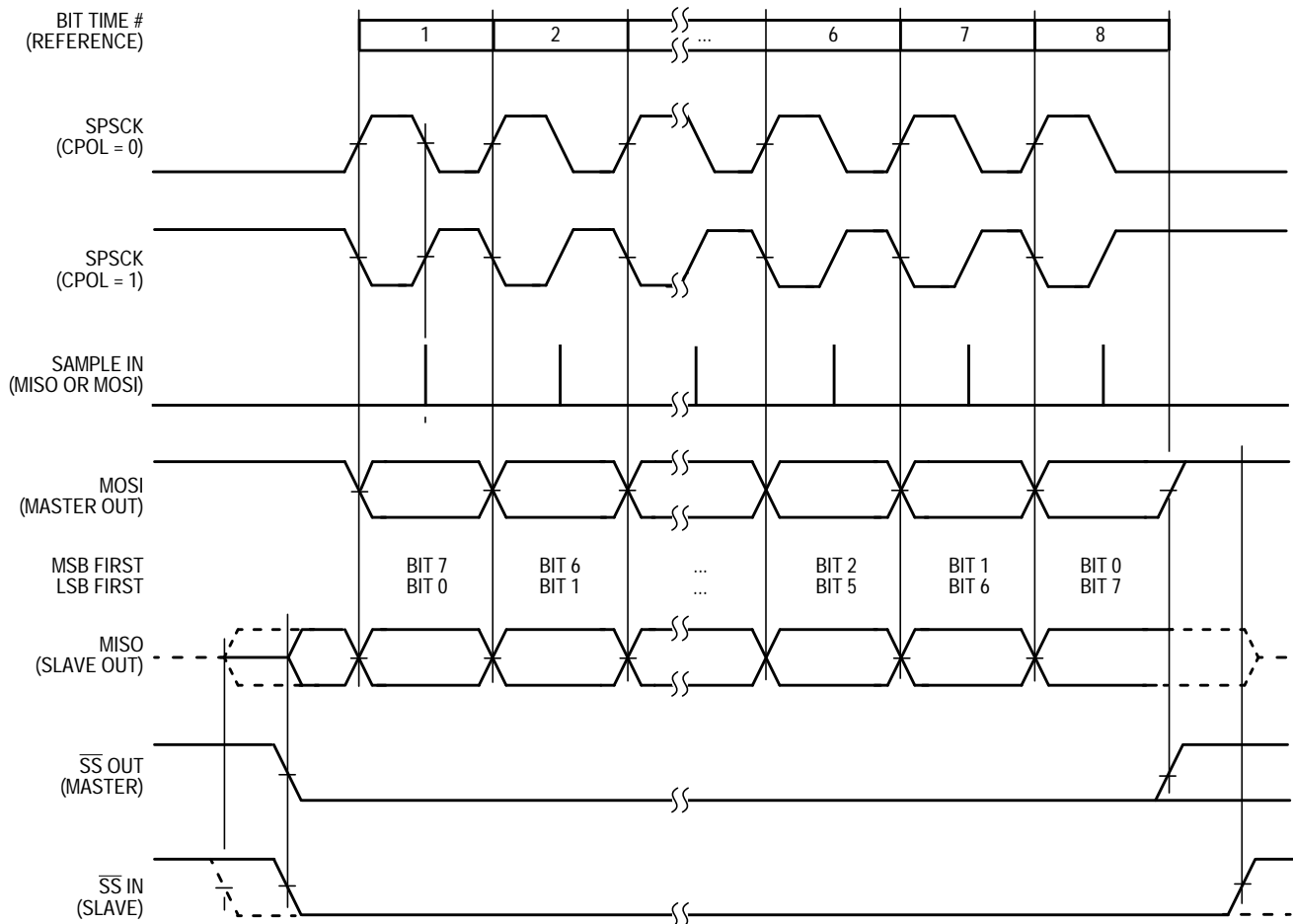


Figure 15-10. SPI Clock Formats (CPHA = 1)

When CPHA = 1, the slave begins to drive its MISO output when  $\overline{SS}$  goes to active low, but the data is not defined until the first SPSCK edge. The first SPSCK edge shifts the first bit of data from the shifter onto the MOSI output of the master and the MISO output of the slave. The next SPSCK edge causes both the master and the slave to sample the data bit values on their MISO and MOSI inputs, respectively. At the third SPSCK edge, the SPI shifter shifts one bit position which shifts in the bit value that was just sampled, and shifts the second data bit value out the other end of the shifter to the MOSI and MISO outputs of the master and slave, respectively. When CPHA = 1, the slave's  $\overline{SS}$  input is not required to go to its inactive high level between transfers.

Figure 15-11 shows the clock formats when CPHA = 0. At the top of the figure, the eight bit times are shown for reference with bit 1 starting as the slave is selected ( $\overline{SS}$  IN goes low), and bit 8 ends at the last SPSCK edge. The MSB first and LSB first lines show the order of SPI data bits depending on the setting

in LSBFE. Both variations of SPSCCK polarity are shown, but only one of these waveforms applies for a specific transfer, depending on the value in CPOL. The SAMPLE IN waveform applies to the MOSI input of a slave or the MISO input of a master. The MOSI waveform applies to the MOSI output pin from a master and the MISO waveform applies to the MISO output from a slave. The  $\overline{SS}$  OUT waveform applies to the slave select output from a master (provided MODFEN and SSOE = 1). The master  $\overline{SS}$  output goes to active low at the start of the first bit time of the transfer and goes back high one-half SPSCCK cycle after the end of the eighth bit time of the transfer. The  $\overline{SS}$  IN waveform applies to the slave select input of a slave.

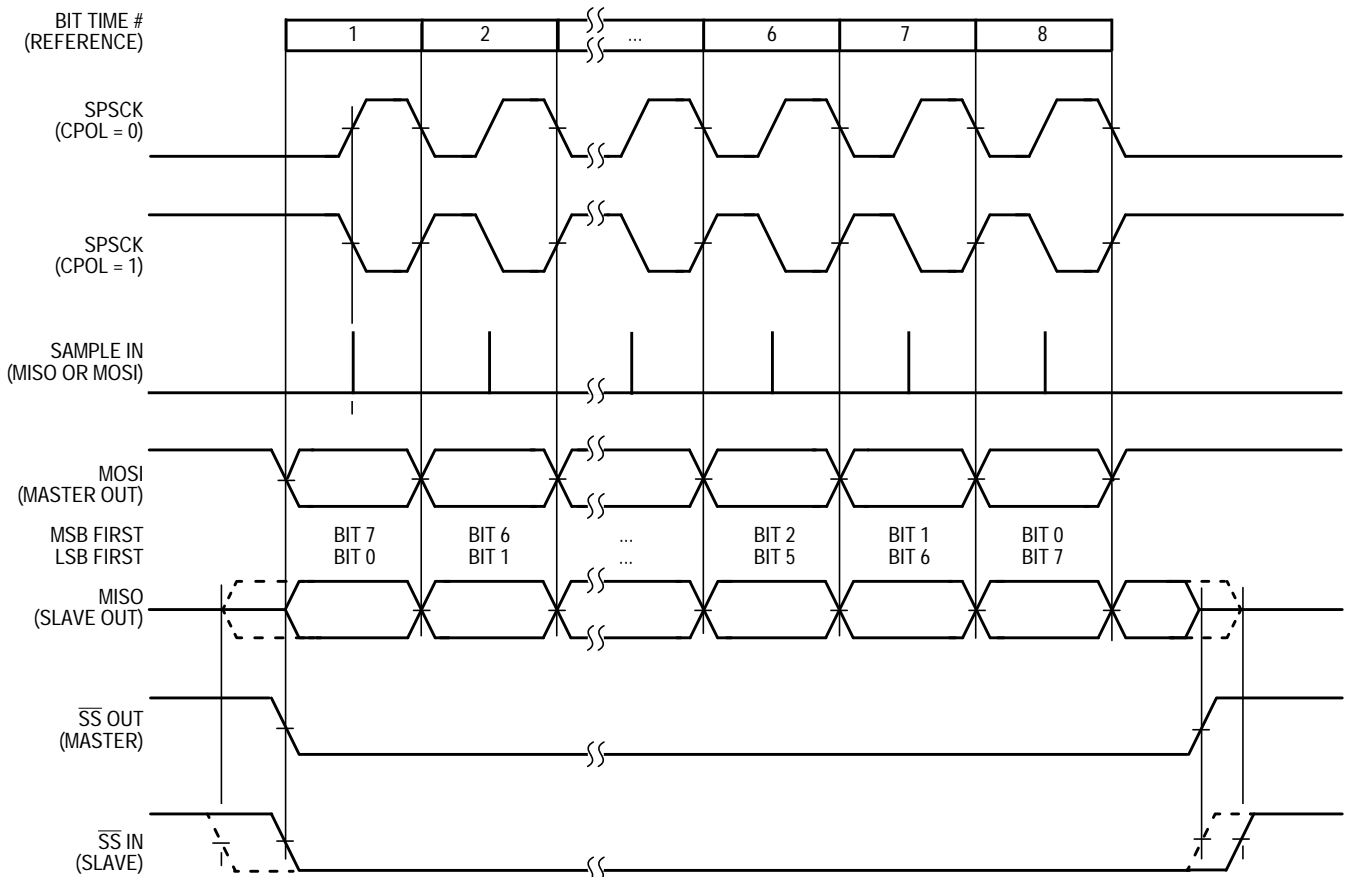


Figure 15-11. SPI Clock Formats (CPHA = 0)

When CPHA = 0, the slave begins to drive its MISO output with the first data bit value (MSB or LSB depending on LSBFE) when  $\overline{SS}$  goes to active low. The first SPSCCK edge causes both the master and the slave to sample the data bit values on their MISO and MOSI inputs, respectively. At the second SPSCCK edge, the SPI shifter shifts one bit position which shifts in the bit value that was just sampled and shifts the second data bit value out the other end of the shifter to the MOSI and MISO outputs of the master and slave, respectively. When CPHA = 0, the slave's  $\overline{SS}$  input must go to its inactive high level between transfers.



## 15.5.2 SPI Interrupts

There are three flag bits, two interrupt mask bits, and one interrupt vector associated with the SPI system. The SPI interrupt enable mask (SPIE) enables interrupts from the SPI receiver full flag (SPRF) and mode fault flag (MODF). The SPI transmit interrupt enable mask (SPTIE) enables interrupts from the SPI transmit buffer empty flag (SPTEF). When one of the flag bits is set, and the associated interrupt mask bit is set, a hardware interrupt request is sent to the CPU. If the interrupt mask bits are cleared, software can poll the associated flag bits instead of using interrupts. The SPI interrupt service routine (ISR) should check the flag bits to determine what event caused the interrupt. The service routine should also clear the flag bit(s) before returning from the ISR (usually near the beginning of the ISR).

## 15.5.3 Mode Fault Detection

A mode fault occurs and the mode fault flag (MODF) becomes set when a master SPI device detects an error on the  $\overline{SS}$  pin (provided the  $\overline{SS}$  pin is configured as the mode fault input signal). The  $\overline{SS}$  pin is configured to be the mode fault input signal when MSTR = 1, mode fault enable is set (MODFEN = 1), and slave select output enable is clear (SSOE = 0).

The mode fault detection feature can be used in a system where more than one SPI device might become a master at the same time. The error is detected when a master's  $\overline{SS}$  pin is low, indicating that some other SPI device is trying to address this master as if it were a slave. This could indicate a harmful output driver conflict, so the mode fault logic is designed to disable all SPI output drivers when such an error is detected.

When a mode fault is detected, MODF is set and MSTR is cleared to change the SPI configuration back to slave mode. The output drivers on the SPSCCK, MOSI, and MISO (if not bidirectional mode) are disabled.

MODF is cleared by reading it while it is set, then writing to the SPI control register 1 (SPIxC1). User software should verify the error condition has been corrected before changing the SPI back to master mode.



## Chapter 16

# Timer/Pulse-Width Modulator (S08TPMV3)

### 16.1 Introduction

Figure 16-1 shows the MC9S08QE128 Series block diagram with the TPM highlighted.

#### 16.1.1 ACMP/TPM Configuration Information

The ACMP modules can be configured to connect the output of the analog comparator to a TPM input capture channel 0 by setting the corresponding SOPT2[ACICx] bit. With ACICx set, the TPMxCH0 pin is not available externally regardless of the configuration of the TPMx module.

The ACMP1 output can be connected to TPM1CH0; The ACMP2 output can be connected to TPM2CH0.

#### 16.1.2 TPM Clock Gating

The bus clock to TPM1, TPM2, and TPM3 can be gated on and off using the SCGC1[TPMx] bits. These bits are set after any reset, which enables the bus clock to this module. To conserve power, these bits can be cleared to disable the clock to any of these modules when not in use. See [Section 5.7, “Peripheral Clock Gating,”](#) for details.

#### 16.1.3 Interrupt Vector

See [Section 4.2, “Reset and Interrupt Vector Assignments,”](#) for the TPM interrupt vector assignments.

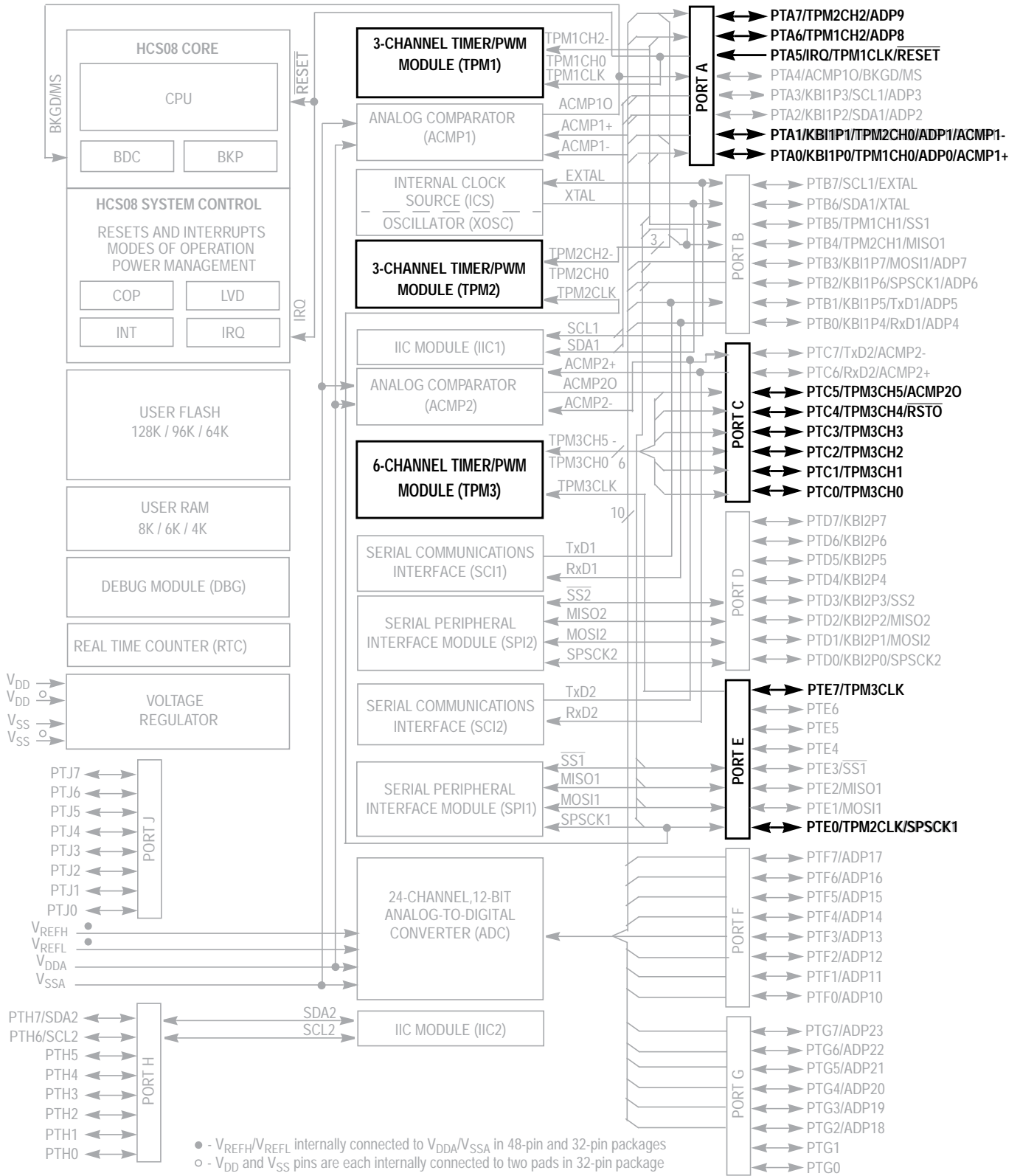


Figure 16-1. MC9S08QE128 Series Block Diagram Highlighting TPM Block and Pins

## 16.1.4 Features

The TPM includes these distinctive features:

- One to eight channels:
  - Each channel may be input capture, output compare, or edge-aligned PWM
  - Rising-Edge, falling-edge, or any-edge input capture trigger
  - Set, clear, or toggle output compare action
  - Selectable polarity on PWM outputs
- Module may be configured for buffered, center-aligned pulse-width-modulation (CPWM) on all channels
- Timer clock source selectable as prescaled bus clock, fixed system clock, or an external clock pin
  - Prescale taps for divide-by 1, 2, 4, 8, 16, 32, 64, or 128
  - Fixed system clock source are synchronized to the bus clock by an on-chip synchronization circuit
  - External clock pin may be shared with any timer channel pin or a separated input pin
- 16-bit free-running or modulo up/down count operation
- Timer system enable
- One interrupt per channel plus terminal count interrupt

## 16.1.5 Modes of Operation

In general, TPM channels may be independently configured to operate in input capture, output compare, or edge-aligned PWM modes. A control bit allows the whole TPM (all channels) to switch to center-aligned PWM mode. When center-aligned PWM mode is selected, input capture, output compare, and edge-aligned PWM functions are not available on any channels of this TPM module.

When the microcontroller is in active BDM background or BDM foreground mode, the TPM temporarily suspends all counting until the microcontroller returns to normal user operating mode. During stop mode, all system clocks, including the main oscillator, are stopped; therefore, the TPM is effectively disabled until clocks resume. During wait mode, the TPM continues to operate normally. Provided the TPM does not need to produce a real time reference or provide the interrupt source(s) needed to wake the MCU from wait mode, the user can save power by disabling TPM functions before entering wait mode.

- Input capture mode

When a selected edge event occurs on the associated MCU pin, the current value of the 16-bit timer counter is captured into the channel value register and an interrupt flag bit is set. Rising edges, falling edges, any edge, or no edge (disable channel) may be selected as the active edge which triggers the input capture.
- Output compare mode

When the value in the timer counter register matches the channel value register, an interrupt flag bit is set, and a selected output action is forced on the associated MCU pin. The output compare action may be selected to force the pin to zero, force the pin to one, toggle the pin, or ignore the pin (used for software timing functions).

- Edge-aligned PWM mode  
The value of a 16-bit modulo register plus 1 sets the period of the PWM output signal. The channel value register sets the duty cycle of the PWM output signal. The user may also choose the polarity of the PWM output signal. Interrupts are available at the end of the period and at the duty-cycle transition point. This type of PWM signal is called edge-aligned because the leading edges of all PWM signals are aligned with the beginning of the period, which is the same for all channels within a TPM.
- Center-aligned PWM mode  
Twice the value of a 16-bit modulo register sets the period of the PWM output, and the channel-value register sets the half-duty-cycle duration. The timer counter counts up until it reaches the modulo value and then counts down until it reaches zero. As the count matches the channel value register while counting down, the PWM output becomes active. When the count matches the channel value register while counting up, the PWM output becomes inactive. This type of PWM signal is called center-aligned because the centers of the active duty cycle periods for all channels are aligned with a count value of zero. This type of PWM is required for types of motors used in small appliances.

This is a high-level description only. Detailed descriptions of operating modes are in later sections.

### 16.1.6 Block Diagram

The TPM uses one input/output (I/O) pin per channel, TPMxCHn (timer channel n) where n is the channel number (1-8). The TPM shares its I/O pins with general purpose I/O port pins (refer to I/O pin descriptions in full-chip specification for the specific chip implementation).

Figure 16-2 shows the TPM structure. The central component of the TPM is the 16-bit counter that can operate as a free-running counter or a modulo up/down counter. The TPM counter (when operating in normal up-counting mode) provides the timing reference for the input capture, output compare, and edge-aligned PWM functions. The timer counter modulo registers, TPMxMODH:TPMxMODL, control the modulo value of the counter (the values 0x0000 or 0xFFFF effectively make the counter free running). Software can read the counter value at any time without affecting the counting sequence. Any write to either half of the TPMxCNT counter resets the counter, regardless of the data value written.



The TPM channels are programmable independently as input capture, output compare, or edge-aligned PWM channels. Alternately, the TPM can be configured to produce CPWM outputs on all channels. When the TPM is configured for CPWMs, the counter operates as an up/down counter; input capture, output compare, and EPWM functions are not practical.

If a channel is configured as input capture, an internal pullup device may be enabled for that channel. The details of how a module interacts with pin controls depends upon the chip implementation because the I/O pins and associated general purpose I/O controls are not part of the module. Refer to the discussion of the I/O port logic in a full-chip specification.

Because center-aligned PWMs are usually used to drive 3-phase AC-induction motors and brushless DC motors, they are typically used in sets of three or six channels.

## 16.2 Signal Description

Table 16-1 shows the user-accessible signals for the TPM. The number of channels may be varied from one to eight. When an external clock is included, it can be shared with the same pin as any TPM channel; however, it could be connected to a separate input pin. Refer to the I/O pin descriptions in full-chip specification for the specific chip implementation.

**Table 16-1. Signal Properties**

Name	Function
EXTCLK <sup>1</sup>	External clock source which may be selected to drive the TPM counter.
TPMxCHn <sup>2</sup>	I/O pin associated with TPM channel n

<sup>1</sup> When preset, this signal can share any channel pin; however depending upon full-chip implementation, this signal could be connected to a separate external pin.

<sup>2</sup> n=channel number (1 to 8)

Refer to documentation for the full-chip for details about reset states, port connections, and whether there is any pullup device on these pins.

TPM channel pins can be associated with general purpose I/O pins and have passive pullup devices which can be enabled with a control bit when the TPM or general purpose I/O controls have configured the associated pin as an input. When no TPM function is enabled to use a corresponding pin, the pin reverts to being controlled by general purpose I/O controls, including the port-data and data-direction registers. Immediately after reset, no TPM functions are enabled, so all associated pins revert to general purpose I/O control.

### 16.2.1 Detailed Signal Descriptions

This section describes each user-accessible pin signal in detail. Although Table 16-1 grouped all channel pins together, any TPM pin can be shared with the external clock source signal. Since I/O pin logic is not part of the TPM, refer to full-chip documentation for a specific derivative for more details about the interaction of TPM pin functions and general purpose I/O controls including port data, data direction, and pullup controls.



### 16.2.1.1 EXTCLK — External Clock Source

Control bits in the timer status and control register allow the user to select nothing (timer disable), the bus-rate clock (the normal default source), a crystal-related clock, or an external clock as the clock which drives the TPM prescaler and subsequently the 16-bit TPM counter. The external clock source is synchronized in the TPM. The bus clock clocks the synchronizer; the frequency of the external source must be no more than one-fourth the frequency of the bus-rate clock, to meet Nyquist criteria and allowing for jitter.

The external clock signal shares the same pin as a channel I/O pin, so the channel pin will not be usable for channel I/O function when selected as the external clock source. It is the user's responsibility to avoid such settings. If this pin is used as an external clock source (CLKSB:CLKSA = 1:1), the channel can still be used in output compare mode as a software timer (ELSnB:ELSnA = 0:0).

### 16.2.1.2 TPMxCHn — TPM Channel n I/O Pin(s)

Each TPM channel is associated with an I/O pin on the MCU. The function of this pin depends on the channel configuration. The TPM pins share with general purpose I/O pins, where each pin has a port data register bit, and a data direction control bit, and the port has optional passive pullups which may be enabled whenever a port pin is acting as an input.

The TPM channel does not control the I/O pin when (ELSnB:ELSnA = 0:0) or when (CLKSB:CLKSA = 0:0) so it normally reverts to general purpose I/O control. When CPWMS = 1 (and ELSnB:ELSnA not = 0:0), all channels within the TPM are configured for center-aligned PWM and the TPMxCHn pins are all controlled by the TPM system. When CPWMS=0, the MSnB:MSnA control bits determine whether the channel is configured for input capture, output compare, or edge-aligned PWM.

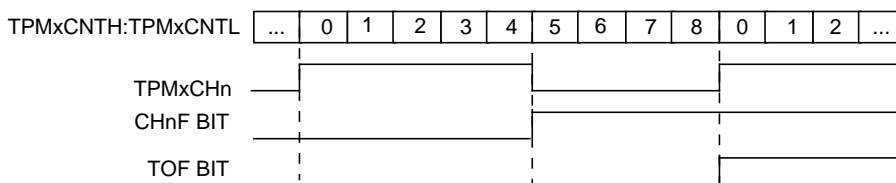
When a channel is configured for input capture (CPWMS=0, MSnB:MSnA = 0:0 and ELSnB:ELSnA not = 0:0), the TPMxCHn pin is forced to act as an edge-sensitive input to the TPM. ELSnB:ELSnA control bits determine what polarity edge or edges will trigger input-capture events. A synchronizer based on the bus clock is used to synchronize input edges to the bus clock. This implies the minimum pulse width—that can be reliably detected—on an input capture pin is four bus clock periods (with ideal clock pulses as near as two bus clocks can be detected). TPM uses this pin as an input capture input to override the port data and data direction controls for the same pin.

When a channel is configured for output compare (CPWMS=0, MSnB:MSnA = 0:1 and ELSnB:ELSnA not = 0:0), the associated data direction control is overridden, the TPMxCHn pin is considered an output controlled by the TPM, and the ELSnB:ELSnA control bits determine how the pin is controlled. The remaining three combinations of ELSnB:ELSnA determine whether the TPMxCHn pin is toggled, cleared, or set each time the 16-bit channel value register matches the timer counter.

When the output compare toggle mode is initially selected, the previous value on the pin is driven out until the next output compare event—then the pin is toggled.

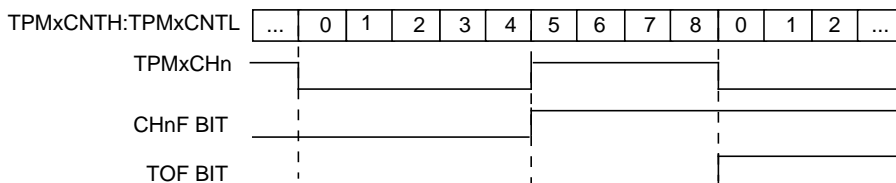
When a channel is configured for edge-aligned PWM (CPWMS=0, MSnB=1 and ELSnB:ELSnA not = 0:0), the data direction is overridden, the TPMxCHn pin is forced to be an output controlled by the TPM, and ELSnA controls the polarity of the PWM output signal on the pin. When ELSnB:ELSnA=1:0, the TPMxCHn pin is forced high at the start of each new period (TPMxCNT=0x0000), and the pin is forced low when the channel value register matches the timer counter. When ELSnA=1, the TPMxCHn pin is forced low at the start of each new period (TPMxCNT=0x0000), and the pin is forced high when the channel value register matches the timer counter.

TPMxMODH:TPMxMODL = 0x0008  
 TPMxMODH:TPMxMODL = 0x0005



**Figure 16-3. High-True Pulse of an Edge-Aligned PWM**

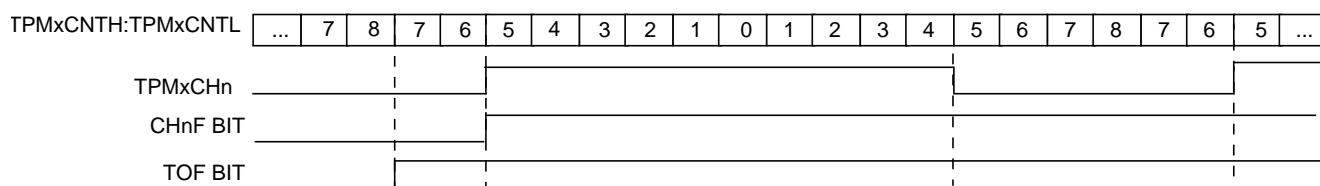
TPMxMODH:TPMxMODL = 0x0008  
 TPMxMODH:TPMxMODL = 0x0005



**Figure 16-4. Low-True Pulse of an Edge-Aligned PWM**

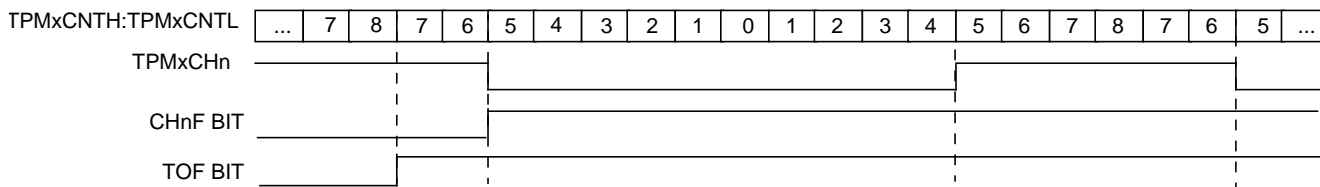
When the TPM is configured for center-aligned PWM (and ELSnB:ELSnA not = 0:0), the data direction for all channels in this TPM are overridden, the TPMxCHn pins are forced to be outputs controlled by the TPM, and the ELSnA bits control the polarity of each TPMxCHn output. If ELSnB:ELSnA=1:0, the corresponding TPMxCHn pin is cleared when the timer counter is counting up, and the channel value register matches the timer counter; the TPMxCHn pin is set when the timer counter is counting down, and the channel value register matches the timer counter. If ELSnA=1, the corresponding TPMxCHn pin is set when the timer counter is counting up and the channel value register matches the timer counter; the TPMxCHn pin is cleared when the timer counter is counting down and the channel value register matches the timer counter.

TPMxMODH:TPMxMODL = 0x0008  
 TPMxMODH:TPMxMODL = 0x0005



**Figure 16-5. High-True Pulse of a Center-Aligned PWM**

TPMxMODH:TPMxMODL = 0x0008  
 TPMxMODH:TPMxMODL = 0x0005



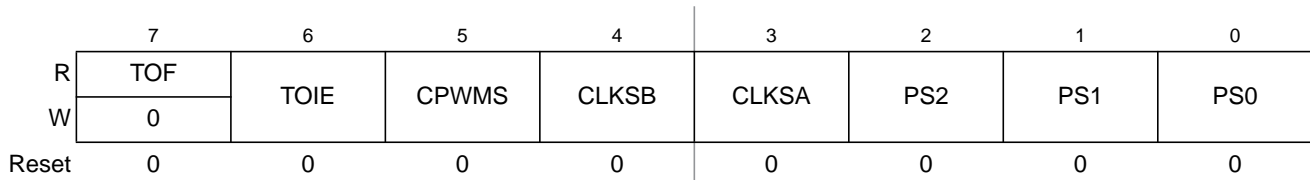
**Figure 16-6. Low-True Pulse of a Center-Aligned PWM**

## 16.3 Register Definition

This section consists of register descriptions in address order.

### 16.3.1 TPM Status and Control Register (TPMxSC)

TPMxSC contains the overflow status flag and control bits used to configure the interrupt enable, TPM configuration, clock source, and prescale factor. These controls relate to all channels within this timer module.



**Figure 16-7. TPM Status and Control Register (TPMxSC)**

**Table 16-2. TPMxSC Field Descriptions**

Field	Description
7 TOF	Timer overflow flag. This read/write flag is set when the TPM counter resets to 0x0000 after reaching the modulo value programmed in the TPM counter modulo registers. Clear TOF by reading the TPM status and control register when TOF is set and then writing a logic 0 to TOF. If another TPM overflow occurs before the clearing sequence is complete, the sequence is reset so TOF would remain set after the clear sequence was completed for the earlier TOF. This is done so a TOF interrupt request cannot be lost during the clearing sequence for a previous TOF. Reset clears TOF. Writing a logic 1 to TOF has no effect. 0 TPM counter has not reached modulo value or overflow 1 TPM counter has overflowed
6 TOIE	Timer overflow interrupt enable. This read/write bit enables TPM overflow interrupts. If TOIE is set, an interrupt is generated when TOF equals one. Reset clears TOIE. 0 TOF interrupts inhibited (use for software polling) 1 TOF interrupts enabled
5 CPWMS	Center-aligned PWM select. When present, this read/write bit selects CPWM operating mode. By default, the TPM operates in up-counting mode for input capture, output compare, and edge-aligned PWM functions. Setting CPWMS reconfigures the TPM to operate in up/down counting mode for CPWM functions. Reset clears CPWMS. 0 All channels operate as input capture, output compare, or edge-aligned PWM mode as selected by the MSnB:MSnA control bits in each channel's status and control register. 1 All channels operate in center-aligned PWM mode.
4–3 CLKS[B:A]	Clock source selects. As shown in <a href="#">Table 16-3</a> , this 2-bit field is used to disable the TPM system or select one of three clock sources to drive the counter prescaler. The fixed system clock source is only meaningful in systems with a PLL-based system clock. When there is no PLL, the fixed-system clock source is the same as the bus rate clock. The external source is synchronized to the bus clock by TPM module, and the fixed system clock source (when a PLL is present) is synchronized to the bus clock by an on-chip synchronization circuit. When a PLL is present but not enabled, the fixed-system clock source is the same as the bus-rate clock.
2–0 PS[2:0]	Prescale factor select. This 3-bit field selects one of 8 division factors for the TPM clock input as shown in <a href="#">Table 16-4</a> . This prescaler is located after any clock source synchronization or clock source selection so it affects the clock source selected to drive the TPM system. The new prescale factor will affect the clock source on the next system clock cycle after the new value is updated into the register bits.

**Table 16-3. TPM-Clock-Source Selection**

CLKSB:CLKSA	TPM Clock Source to Prescaler Input
00	No clock selected (TPM counter disable)
01	Bus rate clock
10	Fixed system clock
11	External source

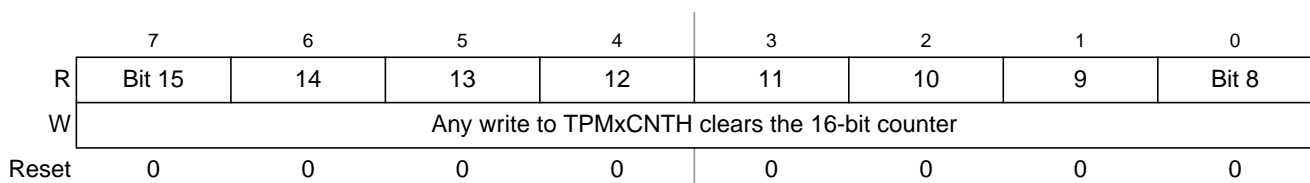
**Table 16-4. Prescale Factor Selection**

PS2:PS1:PS0	TPM Clock Source Divided-by
000	1
001	2
010	4
011	8
100	16
101	32
110	64
111	128

### 16.3.2 TPM-Counter Registers (TPMxCNTH:TPMxCNTL)

The two read-only TPM counter registers contain the high and low bytes of the value in the TPM counter. Reading either byte (TPMxCNTH or TPMxCNTL) latches the contents of both bytes into a buffer where they remain latched until the other half is read. This allows coherent 16-bit reads in either big-endian or little-endian order which makes this more friendly to various compiler implementations. The coherency mechanism is automatically restarted by an MCU reset or any write to the timer status/control register (TPMxSC).

Reset clears the TPM counter registers. Writing any value to TPMxCNTH or TPMxCNTL also clears the TPM counter (TPMxCNTH:TPMxCNTL) and resets the coherency mechanism, regardless of the data involved in the write.


**Figure 16-8. TPM Counter Register High (TPMxCNTH)**

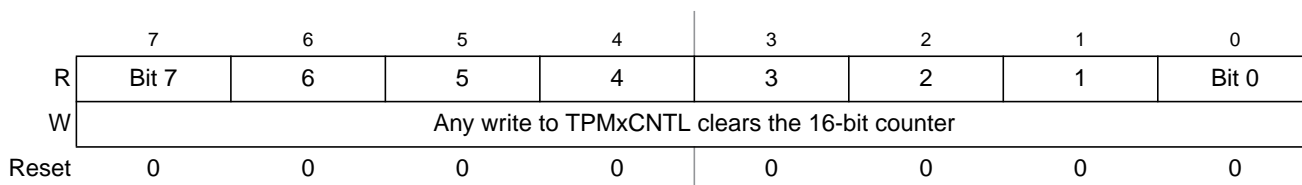


Figure 16-9. TPM Counter Register Low (TPMxCNTL)

When BDM is active, the timer counter is frozen (this is the value that will be read by user); the coherency mechanism is frozen such that the buffer latches remain in the state they were in when the BDM became active, even if one or both counter halves are read while BDM is active. This assures that if the user was in the middle of reading a 16-bit register when BDM became active, it will read the appropriate value from the other half of the 16-bit value after returning to normal execution.

### 16.3.3 TPM Counter Modulo Registers (TPMxMODH:TPMxMODL)

The read/write TPM modulo registers contain the modulo value for the TPM counter. After the TPM counter reaches the modulo value, the TPM counter resumes counting from 0x0000 at the next clock, and the overflow flag (TOF) becomes set. Writing to TPMxMODH or TPMxMODL inhibits the TOF bit and overflow interrupts until the other byte is written. Reset sets the TPM counter modulo registers to 0x0000 which results in a free running timer counter (modulo disabled).

Writing to either byte (TPMxMODH or TPMxMODL) latches the value into a buffer and the registers are updated with the value of their write buffer according to the value of CLKSB:CLKSA bits, so:

- If (CLKSB:CLKSA = 0:0), then the registers are updated when the second byte is written
- If (CLKSB:CLKSA not = 0:0), then the registers are updated after both bytes were written, and the TPM counter changes from (TPMxMODH:TPMxMODL - 1) to (TPMxMODH:TPMxMODL). If the TPM counter is a free-running counter, the update is made when the TPM counter changes from 0xFFFFE to 0xFFFF

The latching mechanism may be manually reset by writing to the TPMxSC address (whether BDM is active or not).

When BDM is active, the coherency mechanism is frozen such that the buffer latches remain in the state they were in when the BDM became active, even if one or both halves of the modulo register are written while BDM is active. Any write to the modulo registers bypasses the buffer latches and directly writes to the modulo register while BDM is active.

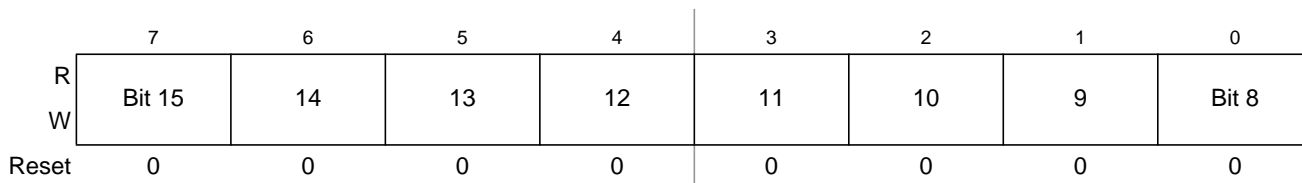


Figure 16-10. TPM Counter Modulo Register High (TPMxMODH)

	7	6	5	4	3	2	1	0
R	Bit 7	6	5	4	3	2	1	Bit 0
W								
Reset	0	0	0	0	0	0	0	0

Reset the TPM counter before writing to the TPM modulo registers to avoid confusion about when the first counter overflow will occur.

### 16.3.4 TPM Channel n Status and Control Register (TPMxCnSC)

TPMxCnSC contains the channel-interrupt-status flag and control bits used to configure the interrupt enable, channel configuration, and pin function.

	7	6	5	4	3	2	1	0
R	CHnF	CHnIE	MSnB	MSnA	ELSnB	ELSnA	0	0
W	0							
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

**Figure 16-12. TPM Channel n Status and Control Register (TPMxCnSC)**

**Table 16-5. TPMxCnSC Field Descriptions**

Field	Description
7 CHnF	<p>Channel n flag. When channel n is an input-capture channel, this read/write bit is set when an active edge occurs on the channel n pin. When channel n is an output compare or edge-aligned/center-aligned PWM channel, CHnF is set when the value in the TPM counter registers matches the value in the TPM channel n value registers. When channel n is an edge-aligned/center-aligned PWM channel and the duty cycle is set to 0% or 100%, CHnF will not be set even when the value in the TPM counter registers matches the value in the TPM channel n value registers.</p> <p>A corresponding interrupt is requested when CHnF is set and interrupts are enabled (CHnIE = 1). Clear CHnF by reading TPMxCnSC while CHnF is set and then writing a logic 0 to CHnF. If another interrupt request occurs before the clearing sequence is complete, the sequence is reset so CHnF remains set after the clear sequence completed for the earlier CHnF. This is done so a CHnF interrupt request cannot be lost due to clearing a previous CHnF.</p> <p>Reset clears the CHnF bit. Writing a logic 1 to CHnF has no effect.</p> <p>0 No input capture or output compare event occurred on channel n 1 Input capture or output compare event on channel n</p>
6 CHnIE	<p>Channel n interrupt enable. This read/write bit enables interrupts from channel n. Reset clears CHnIE.</p> <p>0 Channel n interrupt requests disabled (use for software polling) 1 Channel n interrupt requests enabled</p>
5 MSnB	<p>Mode select B for TPM channel n. When CPWMS=0, MSnB=1 configures TPM channel n for edge-aligned PWM mode. Refer to the summary of channel mode and setup controls in <a href="#">Table 16-6</a>.</p>

**Table 16-5. TPMxCnSC Field Descriptions (continued)**

Field	Description
4 MSnA	Mode select A for TPM channel n. When CPWMS=0 and MSnB=0, MSnA configures TPM channel n for input-capture mode or output compare mode. Refer to <a href="#">Table 16-6</a> for a summary of channel mode and setup controls. <b>Note:</b> If the associated port pin is not stable for at least two bus clock cycles before changing to input capture mode, it is possible to get an unexpected indication of an edge trigger.
3–2 ELSnB ELSnA	Edge/level select bits. Depending upon the operating mode for the timer channel as set by CPWMS:MSnB:MSnA and shown in <a href="#">Table 16-6</a> , these bits select the polarity of the input edge that triggers an input capture event, select the level that will be driven in response to an output compare match, or select the polarity of the PWM output. Setting ELSnB:ELSnA to 0:0 configures the related timer pin as a general purpose I/O pin not related to any timer functions. This function is typically used to temporarily disable an input capture channel or to make the timer pin available as a general purpose I/O pin when the associated timer channel is set up as a software timer that does not require the use of a pin.

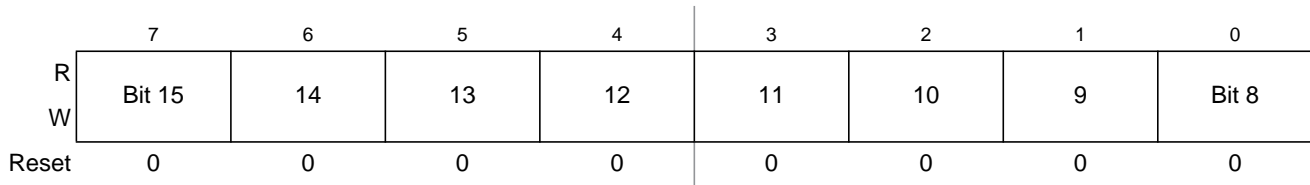
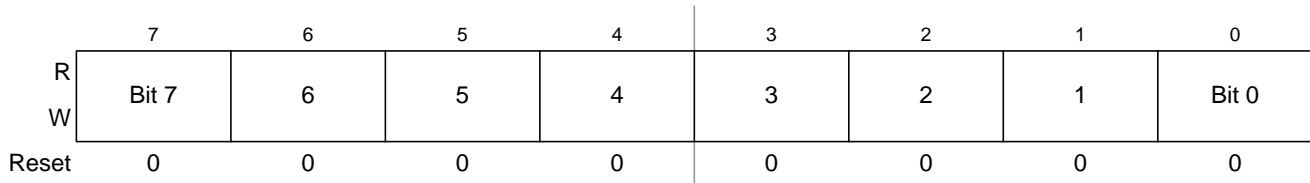
**Table 16-6. Mode, Edge, and Level Selection**

CPWMS	MSnB:MSnA	ELSnB:ELSnA	Mode	Configuration
X	XX	00	Pin not used for TPM - revert to general purpose I/O or other peripheral control	
0	00	01	Input capture	Capture on rising edge only
		10		Capture on falling edge only
		11		Capture on rising or falling edge
	01	01	Output compare	Toggle output on compare
		10		Clear output on compare
		11		Set output on compare
1X	10	Edge-aligned PWM	High-true pulses (clear output on compare)	
	X1		Low-true pulses (set output on compare)	
1	XX	10	Center-aligned PWM	High-true pulses (clear output on compare-up)
		X1		Low-true pulses (set output on compare-up)

### 16.3.5 TPM Channel Value Registers (TPMxCnVH:TPMxCnVL)

These read/write registers contain the captured TPM counter value of the input capture function or the output compare value for the output compare or PWM functions. The channel registers are cleared by reset.




**Figure 16-13. TPM Channel Value Register High (TPMxCnVH)**

**Figure 16-14. TPM Channel Value Register Low (TPMxCnVL)**

In input capture mode, reading either byte (TPMxCnVH or TPMxCnVL) latches the contents of both bytes into a buffer where they remain latched until the other half is read. This latching mechanism also resets (becomes unlatched) when the TPMxCnSC register is written (whether BDM mode is active or not). Any write to the channel registers will be ignored during the input capture mode.

When BDM is active, the coherency mechanism is frozen such that the buffer latches remain in the state they were in when the BDM became active, even if one or both halves of the channel register are read while BDM is active. This assures that if the user was in the middle of reading a 16-bit register when BDM became active, it will read the appropriate value from the other half of the 16-bit value after returning to normal execution. The value read from the TPMxCnVH and TPMxCnVL registers in BDM mode is the value of these registers and not the value of their read buffer.

In output compare or PWM modes, writing to either byte (TPMxCnVH or TPMxCnVL) latches the value into a buffer. After both bytes are written, they are transferred as a coherent 16-bit value into the timer-channel registers according to the value of CLKS<sub>B</sub>:CLKS<sub>A</sub> bits and the selected mode, so:

- If (CLKS<sub>B</sub>:CLKS<sub>A</sub> = 0:0), then the registers are updated when the second byte is written.
- If (CLKS<sub>B</sub>:CLKS<sub>A</sub> not = 0:0 and in output compare mode) then the registers are updated after the second byte is written and on the next change of the TPM counter (end of the prescaler counting).
- If (CLKS<sub>B</sub>:CLKS<sub>A</sub> not = 0:0 and in EPWM or CPWM modes), then the registers are updated after the both bytes were written, and the TPM counter changes from (TPMxMODH:TPMxMODL - 1) to (TPMxMODH:TPMxMODL). If the TPM counter is a free-running counter then the update is made when the TPM counter changes from 0xFFFFE to 0xFFFF.

The latching mechanism may be manually reset by writing to the TPMxCnSC register (whether BDM mode is active or not). This latching mechanism allows coherent 16-bit writes in either big-endian or little-endian order which is friendly to various compiler implementations.

When BDM is active, the coherency mechanism is frozen such that the buffer latches remain in the state they were in when the BDM became active even if one or both halves of the channel register are written while BDM is active. Any write to the channel registers bypasses the buffer latches and directly write to the channel register while BDM is active. The values written to the channel register while BDM is active are used for PWM & output compare operation once normal execution resumes. Writes to the channel

registers while BDM is active do not interfere with partial completion of a coherency sequence. After the coherency mechanism has been fully exercised, the channel registers are updated using the buffered values written (while BDM was not active) by the user.

## 16.4 Functional Description

All TPM functions are associated with a central 16-bit counter which allows flexible selection of the clock source and prescale factor. There is also a 16-bit modulo register associated with the main counter.

The CPWMS control bit chooses between center-aligned PWM operation for all channels in the TPM (CPWMS=1) or general purpose timing functions (CPWMS=0) where each channel can independently be configured to operate in input capture, output compare, or edge-aligned PWM mode. The CPWMS control bit is located in the main TPM status and control register because it affects all channels within the TPM and influences the way the main counter operates. (In CPWM mode, the counter changes to an up/down mode rather than the up-counting mode used for general purpose timer functions.)

The following sections describe the main counter and each of the timer operating modes (input capture, output compare, edge-aligned PWM, and center-aligned PWM). Because details of pin operation and interrupt activity depend upon the operating mode, these topics will be covered in the associated mode explanation sections.

### 16.4.1 Counter

All timer functions are based on the main 16-bit counter (TPMxCNTH:TPMxCNTL). This section discusses selection of the clock source, end-of-count overflow, up-counting vs. up/down counting, and manual counter reset.

#### 16.4.1.1 Counter Clock Source

The 2-bit field, CLKS<sub>B</sub>:CLKS<sub>A</sub>, in the timer status and control register (TPMxSC) selects one of three possible clock sources or OFF (which effectively disables the TPM). See [Table 16-3](#). After any MCU reset, CLKS<sub>B</sub>:CLKS<sub>A</sub>=0:0 so no clock source is selected, and the TPM is in a very low power state. These control bits may be read or written at any time and disabling the timer (writing 00 to the CLKS<sub>B</sub>:CLKS<sub>A</sub> field) does not affect the values in the counter or other timer registers.

**Table 16-7. TPM Clock Source Selection**

CLKSB:CLKSA	TPM Clock Source to Prescaler Input
00	No clock selected (TPM counter disabled)
01	Bus rate clock
10	Fixed system clock
11	External source

The bus rate clock is the main system bus clock for the MCU. This clock source requires no synchronization because it is the clock that is used for all internal MCU activities including operation of the CPU and buses.

In MCUs that have no PLL or the PLL is not engaged, the fixed system clock source is the same as the bus-rate-clock source, and it does not go through a synchronizer. When a PLL is present and engaged, a synchronizer is required between the crystal divided-by two clock source and the timer counter so counter transitions will be properly aligned to bus-clock transitions. A synchronizer will be used at chip level to synchronize the crystal-related source clock to the bus clock.

The external clock source may be connected to any TPM channel pin. This clock source always has to pass through a synchronizer to assure that counter transitions are properly aligned to bus clock transitions. The bus-rate clock drives the synchronizer; therefore, to meet Nyquist criteria even with jitter, the frequency of the external clock source must not be faster than the bus rate divided-by four. With ideal clocks the external clock can be as fast as bus clock divided by four.

When the external clock source shares the TPM channel pin, this pin should not be used for other channel timing functions. For example, it would be ambiguous to configure channel 0 for input capture when the TPM channel 0 pin was also being used as the timer external clock source. (It is the user's responsibility to avoid such settings.) The TPM channel could still be used in output compare mode for software timing functions (pin controls set not to affect the TPM channel pin).

### 16.4.1.2 Counter Overflow and Modulo Reset

An interrupt flag and enable are associated with the 16-bit main counter. The flag (TOF) is a software-accessible indication that the timer counter has overflowed. The enable signal selects between software polling (TOIE=0) where no hardware interrupt is generated, or interrupt-driven operation (TOIE=1) where a static hardware interrupt is generated whenever the TOF flag is equal to one.

The conditions causing TOF to become set depend on whether the TPM is configured for center-aligned PWM (CPWMS=1). In the simplest mode, there is no modulus limit and the TPM is not in CPWMS=1 mode. In this case, the 16-bit timer counter counts from 0x0000 through 0xFFFF and overflows to 0x0000 on the next counting clock. TOF becomes set at the transition from 0xFFFF to 0x0000. When a modulus limit is set, TOF becomes set at the transition from the value set in the modulus register to 0x0000. When the TPM is in center-aligned PWM mode (CPWMS=1), the TOF flag gets set as the counter changes direction at the end of the count value set in the modulus register (that is, at the transition from the value set in the modulus register to the next lower count value). This corresponds to the end of a PWM period (the 0x0000 count value corresponds to the center of a period).

### 16.4.1.3 Counting Modes

The main timer counter has two counting modes. When center-aligned PWM is selected (CPWMS=1), the counter operates in up/down counting mode. Otherwise, the counter operates as a simple up counter. As an up counter, the timer counter counts from 0x0000 through its terminal count and then continues with 0x0000. The terminal count is 0xFFFF or a modulus value in TPMxMODH:TPMxMODL.

When center-aligned PWM operation is specified, the counter counts up from 0x0000 through its terminal count and then down to 0x0000 where it changes back to up counting. Both 0x0000 and the terminal count value are normal length counts (one timer clock period long). In this mode, the timer overflow flag (TOF) becomes set at the end of the terminal-count period (as the count changes to the next lower count value).

### 16.4.1.4 Manual Counter Reset

The main timer counter can be manually reset at any time by writing any value to either half of TPMxCNTH or TPMxCNTL. Resetting the counter in this manner also resets the coherency mechanism in case only half of the counter was read before resetting the count.

## 16.4.2 Channel Mode Selection

Provided CPWMS=0, the MSnB and MSnA control bits in the channel n status and control registers determine the basic mode of operation for the corresponding channel. Choices include input capture, output compare, and edge-aligned PWM.

### 16.4.2.1 Input Capture Mode

With the input-capture function, the TPM can capture the time at which an external event occurs. When an active edge occurs on the pin of an input-capture channel, the TPM latches the contents of the TPM counter into the channel-value registers (TPMxCnVH:TPMxCnVL). Rising edges, falling edges, or any edge may be chosen as the active edge that triggers an input capture.

In input capture mode, the TPMxCnVH and TPMxCnVL registers are read only.

When either half of the 16-bit capture register is read, the other half is latched into a buffer to support coherent 16-bit accesses in big-endian or little-endian order. The coherency sequence can be manually reset by writing to the channel status/control register (TPMxCnSC).

An input capture event sets a flag bit (CHnF) which may optionally generate a CPU interrupt request.

While in BDM, the input capture function works as configured by the user. When an external event occurs, the TPM latches the contents of the TPM counter (which is frozen because of the BDM mode) into the channel value registers and sets the flag bit.

### 16.4.2.2 Output Compare Mode

With the output-compare function, the TPM can generate timed pulses with programmable position, polarity, duration, and frequency. When the counter reaches the value in the channel-value registers of an output-compare channel, the TPM can set, clear, or toggle the channel pin.

In output compare mode, values are transferred to the corresponding timer channel registers only after both 8-bit halves of a 16-bit register have been written and according to the value of CLKSB:CLKSA bits, so:

- If (CLKSB:CLKSA = 0:0), the registers are updated when the second byte is written
- If (CLKSB:CLKSA not = 0:0), the registers are updated at the next change of the TPM counter (end of the prescaler counting) after the second byte is written.

The coherency sequence can be manually reset by writing to the channel status/control register (TPMxCnSC).

An output compare event sets a flag bit (CHnF) which may optionally generate a CPU-interrupt request.

### 16.4.2.3 Edge-Aligned PWM Mode

This type of PWM output uses the normal up-counting mode of the timer counter (CPWMS=0) and can be used when other channels in the same TPM are configured for input capture or output compare functions. The period of this PWM signal is determined by the value of the modulus register (TPMxMODH:TPMxMODL) plus 1. The duty cycle is determined by the setting in the timer channel register (TPMxCnVH:TPMxCnVL). The polarity of this PWM signal is determined by the setting in the ELSnA control bit. 0% and 100% duty cycle cases are possible.

The output compare value in the TPM channel registers determines the pulse width (duty cycle) of the PWM signal (Figure 16-15). The time between the modulus overflow and the output compare is the pulse width. If ELSnA=0, the counter overflow forces the PWM signal high, and the output compare forces the PWM signal low. If ELSnA=1, the counter overflow forces the PWM signal low, and the output compare forces the PWM signal high.

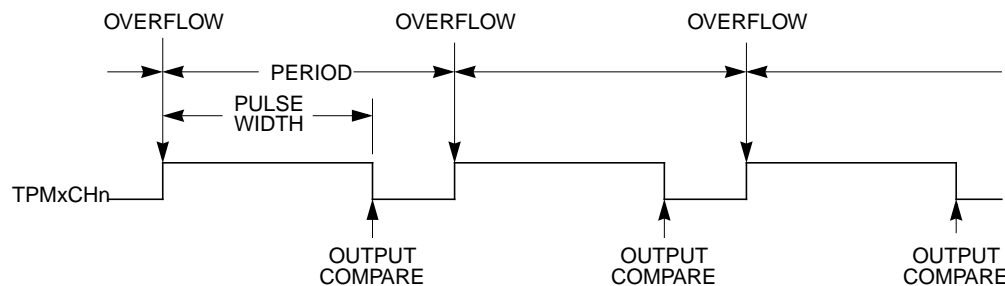


Figure 16-15. PWM Period and Pulse Width (ELSnA=0)

When the channel value register is set to 0x0000, the duty cycle is 0%. 100% duty cycle can be achieved by setting the timer-channel register (TPMxCnVH:TPMxCnVL) to a value greater than the modulus setting. This implies that the modulus setting must be less than 0xFFFF in order to get 100% duty cycle.

Because the TPM may be used in an 8-bit MCU, the settings in the timer channel registers are buffered to ensure coherent 16-bit updates and to avoid unexpected PWM pulse widths. Writes to any of the registers TPMxCnVH and TPMxCnVL, actually write to buffer registers. In edge-aligned PWM mode, values are transferred to the corresponding timer-channel registers according to the value of CLKSB:CLKSA bits, so:

- If (CLKSB:CLKSA = 0:0), the registers are updated when the second byte is written
- If (CLKSB:CLKSA not = 0:0), the registers are updated after the both bytes were written, and the TPM counter changes from (TPMxMODH:TPMxMODL - 1) to (TPMxMODH:TPMxMODL). If

the TPM counter is a free-running counter then the update is made when the TPM counter changes from 0xFFFFE to 0xFFFF.

#### 16.4.2.4 Center-Aligned PWM Mode

This type of PWM output uses the up/down counting mode of the timer counter (CPWMS=1). The output compare value in TPMxCnVH:TPMxCnVL determines the pulse width (duty cycle) of the PWM signal while the period is determined by the value in TPMxMODH:TPMxMODL. TPMxMODH:TPMxMODL should be kept in the range of 0x0001 to 0x7FFF because values outside this range can produce ambiguous results. ELSnA will determine the polarity of the CPWM output.

$$\text{pulse width} = 2 \times (\text{TPMxCnVH:TPMxCnVL})$$

$$\text{period} = 2 \times (\text{TPMxMODH:TPMxMODL}); \text{TPMxMODH:TPMxMODL} = 0x0001 - 0x7FFF$$

If the channel-value register TPMxCnVH:TPMxCnVL is zero or negative (bit 15 set), the duty cycle will be 0%. If TPMxCnVH:TPMxCnVL is a positive value (bit 15 clear) and is greater than the (non-zero) modulus setting, the duty cycle will be 100% because the duty cycle compare will never occur. This implies the usable range of periods set by the modulus register is 0x0001 through 0x7FFE (0x7FFF if you do not need to generate 100% duty cycle). This is not a significant limitation. The resulting period would be much longer than required for normal applications.

TPMxMODH:TPMxMODL=0x0000 is a special case that should not be used with center-aligned PWM mode. When CPWMS=0, this case corresponds to the counter running free from 0x0000 through 0xFFFF, but when CPWMS=1 the counter needs a valid match to the modulus register somewhere other than at 0x0000 in order to change directions from up-counting to down-counting.

The output compare value in the TPM channel registers (times 2) determines the pulse width (duty cycle) of the CPWM signal (Figure 16-16). If ELSnA=0, a compare occurred while counting up forces the CPWM output signal low and a compare occurred while counting down forces the output high. The counter counts up until it reaches the modulo setting in TPMxMODH:TPMxMODL, then counts down until it reaches zero. This sets the period equal to two times TPMxMODH:TPMxMODL.

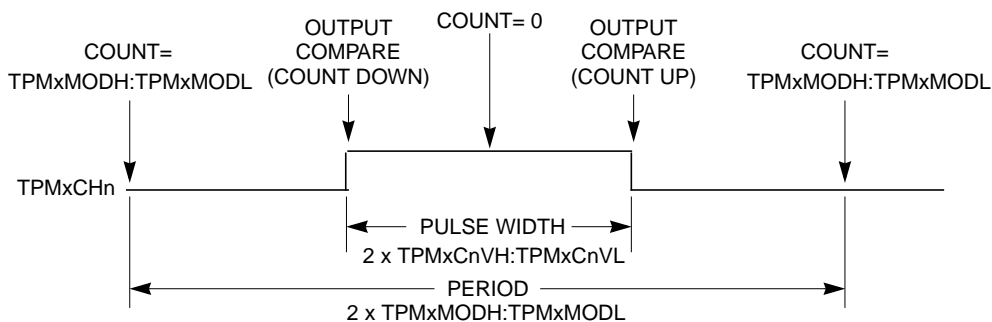


Figure 16-16. CPWM Period and Pulse Width (ELSnA=0)

Center-aligned PWM outputs typically produce less noise than edge-aligned PWMs because fewer I/O pin transitions are lined up at the same system clock edge. This type of PWM is also required for some types of motor drives.

Input capture, output compare, and edge-aligned PWM functions do not make sense when the counter is operating in up/down counting mode so this implies that all active channels within a TPM must be used in CPWM mode when CPWMS=1.

The TPM may be used in an 8-bit MCU. The settings in the timer channel registers are buffered to ensure coherent 16-bit updates and to avoid unexpected PWM pulse widths. Writes to any of the registers TPMxMODH, TPMxMODL, TPMxCnVH, and TPMxCnVL, actually write to buffer registers.

In center-aligned PWM mode, the TPMxCnVH:L registers are updated with the value of their write buffer according to the value of CLKSB:CLKSA bits, so:

- If (CLKSB:CLKSA = 0:0), the registers are updated when the second byte is written
- If (CLKSB:CLKSA not = 0:0), the registers are updated after the both bytes were written, and the TPM counter changes from (TPMxMODH:TPMxMODL - 1) to (TPMxMODH:TPMxMODL). If the TPM counter is a free-running counter, the update is made when the TPM counter changes from 0xFFFFE to 0xFFFF.

When TPMxCNTH:TPMxCNTL=TPMxMODH:TPMxMODL, the TPM can optionally generate a TOF interrupt (at the end of this count).

Writing to TPMxSC cancels any values written to TPMxMODH and/or TPMxMODL and resets the coherency mechanism for the modulo registers. Writing to TPMxCnSC cancels any values written to the channel value registers and resets the coherency mechanism for TPMxCnVH:TPMxCnVL.

## 16.5 Reset Overview

### 16.5.1 General

The TPM is reset whenever any MCU reset occurs.

### 16.5.2 Description of Reset Operation

Reset clears the TPMxSC register which disables clocks to the TPM and disables timer overflow interrupts (TOIE=0). CPWMS, MSnB, MSnA, ELSnB, and ELSnA are all cleared which configures all TPM channels for input-capture operation with the associated pins disconnected from I/O pin logic (so all MCU pins related to the TPM revert to general purpose I/O pins).

## 16.6 Interrupts

### 16.6.1 General

The TPM generates an optional interrupt for the main counter overflow and an interrupt for each channel. The meaning of channel interrupts depends on each channel's mode of operation. If the channel is configured for input capture, the interrupt flag is set each time the selected input capture edge is recognized. If the channel is configured for output compare or PWM modes, the interrupt flag is set each time the main timer counter matches the value in the 16-bit channel value register.

All TPM interrupts are listed in Table 16-8 which shows the interrupt name, the name of any local enable that can block the interrupt request from leaving the TPM and getting recognized by the separate interrupt processing logic.

**Table 16-8. Interrupt Summary**

Interrupt	Local Enable	Source	Description
TOF	TOIE	Counter overflow	Set each time the timer counter reaches its terminal count (at transition to next count value which is usually 0x0000)
CHnF	CHnIE	Channel event	An input capture or output compare event took place on channel n

The TPM module will provide a high-true interrupt signal. Vectors and priorities are determined at chip integration time in the interrupt module so refer to the user’s guide for the interrupt module or to the chip’s complete documentation for details.

## 16.6.2 Description of Interrupt Operation

For each interrupt source in the TPM, a flag bit is set upon recognition of the interrupt condition such as timer overflow, channel-input capture, or output-compare events. This flag may be read (polled) by software to determine that the action has occurred, or an associated enable bit (TOIE or CHnIE) can be set to enable hardware interrupt generation. While the interrupt enable bit is set, a static interrupt will generate whenever the associated interrupt flag equals one. The user’s software must perform a sequence of steps to clear the interrupt flag before returning from the interrupt-service routine.

TPM interrupt flags are cleared by a two-step process including a read of the flag bit while it is set (1) followed by a write of zero (0) to the bit. If a new event is detected between these two steps, the sequence is reset and the interrupt flag remains set after the second step to avoid the possibility of missing the new event.

### 16.6.2.1 Timer Overflow Interrupt (TOF) Description

The meaning and details of operation for TOF interrupts varies slightly depending upon the mode of operation of the TPM system (general purpose timing functions versus center-aligned PWM operation). The flag is cleared by the two step sequence described above.

#### 16.6.2.1.1 Normal Case

Normally TOF is set when the timer counter changes from 0xFFFF to 0x0000. When the TPM is not configured for center-aligned PWM (CPWMS=0), TOF gets set when the timer counter changes from the terminal count (the value in the modulo register) to 0x0000. This case corresponds to the normal meaning of counter overflow.



### 16.6.2.1.2 Center-Aligned PWM Case

When CPWMS=1, TOF gets set when the timer counter changes direction from up-counting to down-counting at the end of the terminal count (the value in the modulo register). In this case the TOF corresponds to the end of a PWM period.

## 16.6.2.2 Channel Event Interrupt Description

The meaning of channel interrupts depends on the channel's current mode (input-capture, output-compare, edge-aligned PWM, or center-aligned PWM).

### 16.6.2.2.1 Input Capture Events

When a channel is configured as an input capture channel, the ELSnB:ELSnA control bits select no edge (off), rising edges, falling edges or any edge as the edge which triggers an input capture event. When the selected edge is detected, the interrupt flag is set. The flag is cleared by the two-step sequence described in [Section 16.6.2, "Description of Interrupt Operation."](#)

### 16.6.2.2.2 Output Compare Events

When a channel is configured as an output compare channel, the interrupt flag is set each time the main timer counter matches the 16-bit value in the channel value register. The flag is cleared by the two-step sequence described [Section 16.6.2, "Description of Interrupt Operation."](#)

### 16.6.2.2.3 PWM End-of-Duty-Cycle Events

For channels configured for PWM operation there are two possibilities. When the channel is configured for edge-aligned PWM, the channel flag gets set when the timer counter matches the channel value register which marks the end of the active duty cycle period. When the channel is configured for center-aligned PWM, the timer count matches the channel value register twice during each PWM cycle. In this CPWM case, the channel flag is set at the start and at the end of the active duty cycle period which are the times when the timer counter matches the channel value register. The flag is cleared by the two-step sequence described [Section 16.6.2, "Description of Interrupt Operation."](#)



# Chapter 17

## Development Support

### 17.1 Introduction

Development support systems in the HCS08 include the background debug controller (BDC) and the on-chip debug module (DBG). The BDC provides a single-wire debug interface to the target MCU that provides a convenient interface for programming the on-chip flash and other nonvolatile memories. The BDC is also the primary debug interface for development and allows non-intrusive access to memory data and traditional debug features such as CPU register modify, breakpoints, and single instruction trace commands.

In the HCS08 Family, address and data bus signals are not available on external pins. Debug is done through commands fed into the target MCU via the single-wire background debug interface. The debug module provides a means to selectively trigger and capture bus information so an external development system can reconstruct what happened inside the MCU on a cycle-by-cycle basis without having external access to the address and data signals.

#### 17.1.1 Forcing Active Background

The method for forcing active background mode depends on the specific HCS08 derivative. For the MC9S08QE128 Series, you can force active background after a power-on reset by holding the BKGD pin low as the device exits the reset condition. You can also force active background by driving BKGD low immediately after a serial background command that writes a one to the BDFR bit in the SBDFR register. Other causes of reset including an external pin reset or an internally generated error reset ignore the state of the BKGD pin and reset into normal user mode. If no debug pod is connected to the BKGD pin, the MCU will always reset into normal operating mode.

#### 17.1.2 DBG Clock Gating

The bus clock to the DBG can be gated on and off using the DBG bit in SCGC2. This bit is set after any reset, which enables the bus clock to this module. To conserve power, the DBG bit can be cleared to disable the clock to this module when not in use. See [Section 5.7, “Peripheral Clock Gating,”](#) for details.

#### 17.1.3 Module Configuration

The alternate BDC clock source is the ICSLCLK. This clock source is selected by clearing the CLKSW bit in the BDCSCR register. For details on ICSLCLK, see the “Functional Description” section of the ICS chapter.

## 17.1.4 Features

Features of the BDC module include:

- Single pin for mode selection and background communications
- BDC registers are not located in the memory map
- SYNC command to determine target communications rate
- Non-intrusive commands for memory access
- Active background mode commands for CPU register access
- GO and TRACE1 commands
- BACKGROUND command can wake CPU from stop or wait modes
- One hardware address breakpoint built into BDC
- Oscillator runs in stop mode, if BDC enabled
- COP watchdog disabled while in active background mode

## 17.2 Background Debug Controller (BDC)

All MCUs in the HCS08 Family contain a single-wire background debug interface that supports in-circuit programming of on-chip nonvolatile memory and sophisticated non-intrusive debug capabilities. Unlike debug interfaces on earlier 8-bit MCUs, this system does not interfere with normal application resources. It does not use any user memory or locations in the memory map and does not share any on-chip peripherals.

BDC commands are divided into two groups:

- Active background mode commands require that the target MCU is in active background mode (the user program is not running). Active background mode commands allow the CPU registers to be read or written, and allow the user to trace one user instruction at a time, or GO to the user program from active background mode.
- Non-intrusive commands can be executed at any time even while the user's program is running. Non-intrusive commands allow a user to read or write MCU memory locations or access status and control registers within the background debug controller.

Typically, a relatively simple interface pod is used to translate commands from a host computer into commands for the custom serial interface to the single-wire background debug system. Depending on the development tool vendor, this interface pod may use a standard RS-232 serial port, a parallel printer port, or some other type of communications such as a universal serial bus (USB) to communicate between the host PC and the pod. The pod typically connects to the target system with ground, the BKGD pin,  $\overline{\text{RESET}}$ , and sometimes  $V_{DD}$ . An open-drain connection to reset allows the host to force a target system reset, which is useful to regain control of a lost target system or to control startup of a target system before the on-chip nonvolatile memory has been programmed. Sometimes  $V_{DD}$  can be used to allow the pod to use power from the target system to avoid the need for a separate power supply. However, if the pod is powered separately, it can be connected to a running target system without forcing a target system reset or otherwise disturbing the running application program.

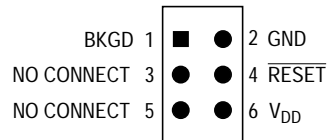


Figure 17-1. BDM Tool Connector

## 17.2.1 BKGD Pin Description

BKGD is the single-wire background debug interface pin. The primary function of this pin is for bidirectional serial communication of active background mode commands and data. During reset, this pin is used to select between starting in active background mode or starting the user's application program. This pin is also used to request a timed sync response pulse to allow a host development tool to determine the correct clock frequency for background debug serial communications.

BDC serial communications use a custom serial protocol first introduced on the M68HC12 Family of microcontrollers. This protocol assumes the host knows the communication clock rate that is determined by the target BDC clock rate. All communication is initiated and controlled by the host that drives a high-to-low edge to signal the beginning of each bit time. Commands and data are sent most significant bit first (MSB first). For a detailed description of the communications protocol, refer to [Section 17.2.2, "Communication Details."](#)

If a host is attempting to communicate with a target MCU that has an unknown BDC clock rate, a SYNC command may be sent to the target MCU to request a timed sync response signal from which the host can determine the correct communication speed.

BKGD is a pseudo-open-drain pin and there is an on-chip pullup so no external pullup resistor is required. Unlike typical open-drain pins, the external RC time constant on this pin, which is influenced by external capacitance, plays almost no role in signal rise time. The custom protocol provides for brief, actively driven speedup pulses to force rapid rise times on this pin without risking harmful drive level conflicts. Refer to [Section 17.2.2, "Communication Details,"](#) for more detail.

When no debugger pod is connected to the 6-pin BDM interface connector, the internal pullup on BKGD chooses normal operating mode. When a debug pod is connected to BKGD it is possible to force the MCU into active background mode after reset. The specific conditions for forcing active background depend upon the HCS08 derivative (refer to the introduction to this Development Support section). It is not necessary to reset the target MCU to communicate with it through the background debug interface.

## 17.2.2 Communication Details

The BDC serial interface requires the external controller to generate a falling edge on the BKGD pin to indicate the start of each bit time. The external controller provides this falling edge whether data is transmitted or received.

BKGD is a pseudo-open-drain pin that can be driven either by an external controller or by the MCU. Data is transferred MSB first at 16 BDC clock cycles per bit (nominal speed). The interface times out if 512 BDC clock cycles occur between falling edges from the host. Any BDC command that was in progress

when this timeout occurs is aborted without affecting the memory or operating mode of the target MCU system.

The custom serial protocol requires the debug pod to know the target BDC communication clock speed.

The clock switch (CLKSW) control bit in the BDC status and control register allows the user to select the BDC clock source. The BDC clock source can either be the bus or the alternate BDC clock source.

The BKGD pin can receive a high or low level or transmit a high or low level. The following diagrams show timing for each of these cases. Interface timing is synchronous to clocks in the target BDC, but asynchronous to the external host. The internal BDC clock signal is shown for reference in counting cycles.

Figure 17-2 shows an external host transmitting a logic 1 or 0 to the BKGD pin of a target HCS08 MCU. The host is asynchronous to the target so there is a 0-to-1 cycle delay from the host-generated falling edge to where the target perceives the beginning of the bit time. Ten target BDC clock cycles later, the target senses the bit level on the BKGD pin. Typically, the host actively drives the pseudo-open-drain BKGD pin during host-to-target transmissions to speed up rising edges. Because the target does not drive the BKGD pin during the host-to-target transmission period, there is no need to treat the line as an open-drain signal during this period.

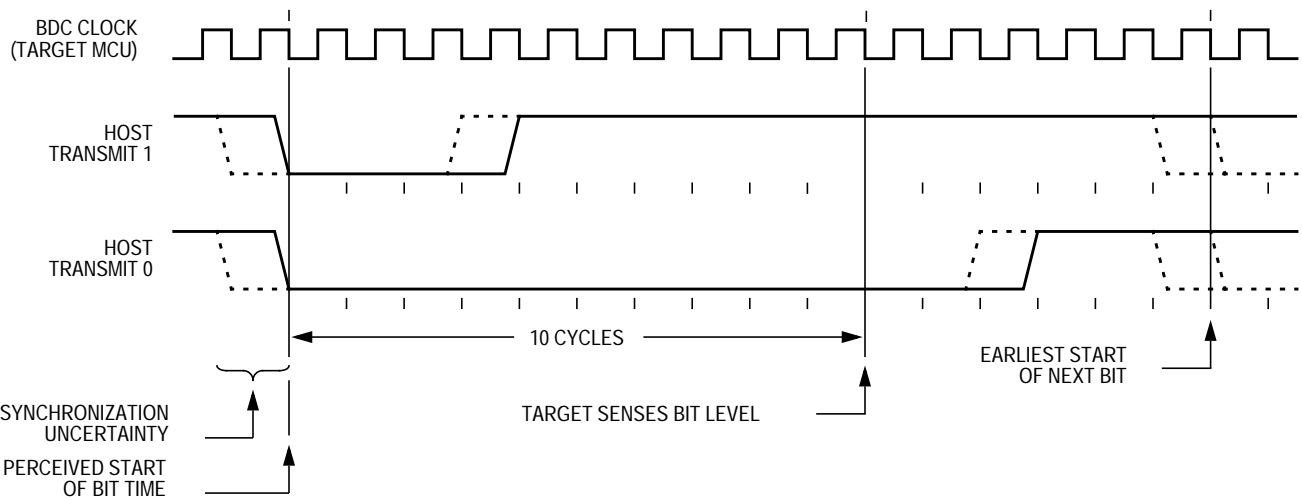
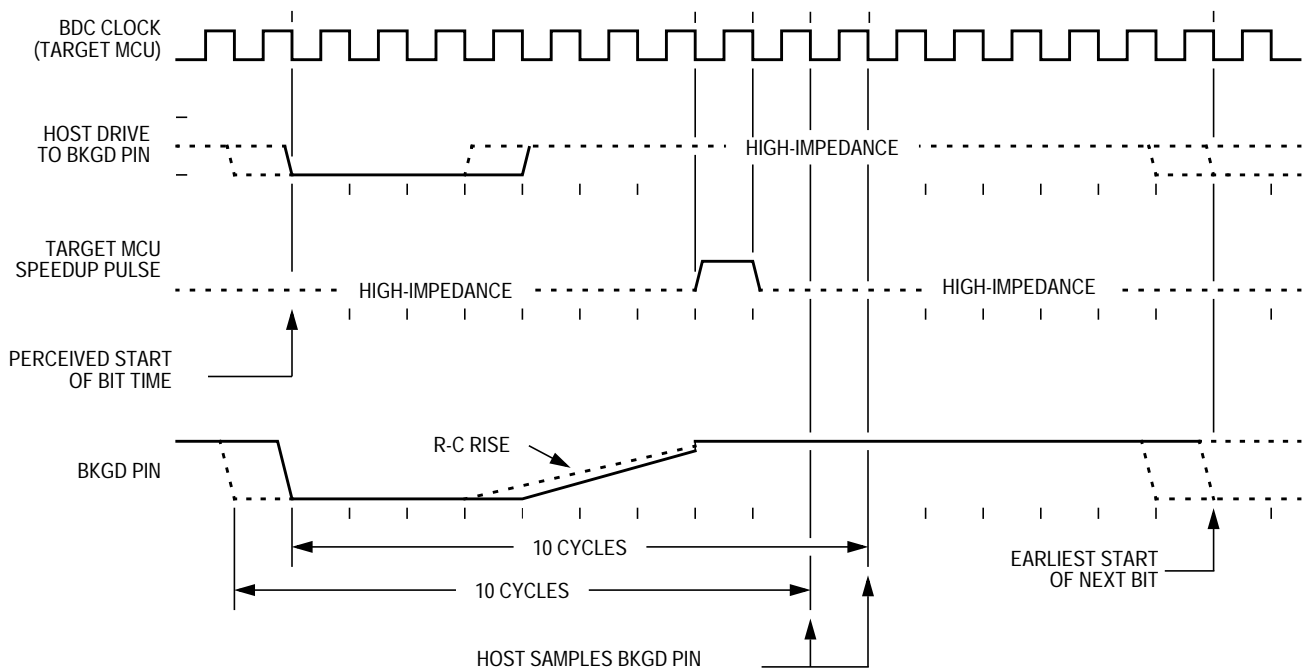


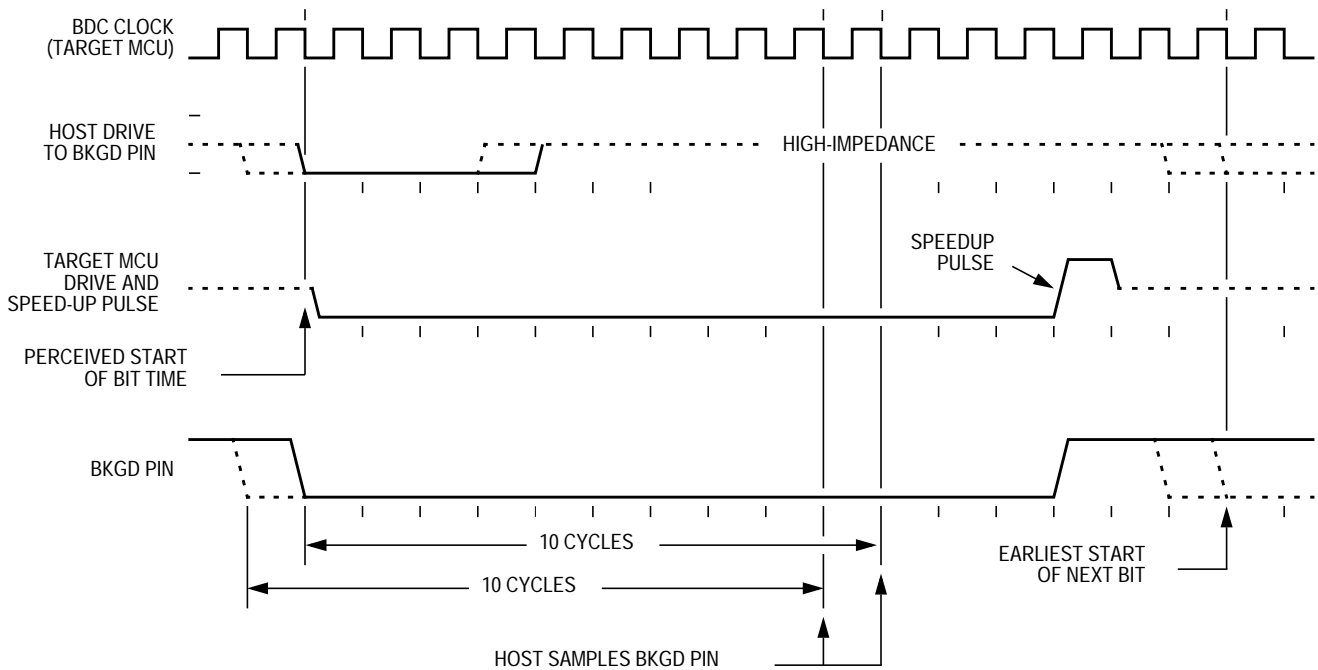
Figure 17-2. BDC Host-to-Target Serial Bit Timing

Figure 17-3 shows the host receiving a logic 1 from the target HCS08 MCU. Because the host is asynchronous to the target MCU, there is a 0-to-1 cycle delay from the host-generated falling edge on BKGD to the perceived start of the bit time in the target MCU. The host holds the BKGD pin low long enough for the target to recognize it (at least two target BDC cycles). The host must release the low drive before the target MCU drives a brief active-high speedup pulse seven cycles after the perceived start of the bit time. The host should sample the bit level about 10 cycles after it started the bit time.



**Figure 17-3. BDC Target-to-Host Serial Bit Timing (Logic 1)**

Figure 17-4 shows the host receiving a logic 0 from the target HCS08 MCU. Because the host is asynchronous to the target MCU, there is a 0-to-1 cycle delay from the host-generated falling edge on BKGD to the start of the bit time as perceived by the target MCU. The host initiates the bit time but the target HCS08 finishes it. Because the target wants the host to receive a logic 0, it drives the BKGD pin low for 13 BDC clock cycles, then briefly drives it high to speed up the rising edge. The host samples the bit level about 10 cycles after starting the bit time.



**Figure 17-4. BDM Target-to-Host Serial Bit Timing (Logic 0)**



### 17.2.3 BDC Commands

BDC commands are sent serially from a host computer to the BKGD pin of the target HCS08 MCU. All commands and data are sent MSB-first using a custom BDC communications protocol. Active background mode commands require that the target MCU is currently in the active background mode while non-intrusive commands may be issued at any time whether the target MCU is in active background mode or running a user application program.

Table 17-1 shows all HCS08 BDC commands, a shorthand description of their coding structure, and the meaning of each command.

#### Coding Structure Nomenclature

This nomenclature is used in Table 17-1 to describe the coding structure of the BDC commands.

	Commands begin with an 8-bit hexadecimal command code in the host-to-target direction (most significant bit first)
/	= separates parts of the command
d	= delay 16 target BDC clock cycles
AAAA	= a 16-bit address in the host-to-target direction
RD	= 8 bits of read data in the target-to-host direction
WD	= 8 bits of write data in the host-to-target direction
RD16	= 16 bits of read data in the target-to-host direction
WD16	= 16 bits of write data in the host-to-target direction
SS	= the contents of BDCSCR in the target-to-host direction (STATUS)
CC	= 8 bits of write data for BDCSCR in the host-to-target direction (CONTROL)
RBKP	= 16 bits of read data in the target-to-host direction (from BDCBKPT breakpoint register)
WBKP	= 16 bits of write data in the host-to-target direction (for BDCBKPT breakpoint register)

**Table 17-1. BDC Command Summary**

Command Mnemonic	Active BDM/ Non-intrusive	Coding Structure	Description
SYNC	Non-intrusive	n/a <sup>1</sup>	Request a timed reference pulse to determine target BDC communication speed
ACK_ENABLE	Non-intrusive	D5/d	Enable acknowledge protocol. Refer to Freescale document order no. HCS08RMv1/D.
ACK_DISABLE	Non-intrusive	D6/d	Disable acknowledge protocol. Refer to Freescale document order no. HCS08RMv1/D.
BACKGROUND	Non-intrusive	90/d	Enter active background mode if enabled (ignore if ENBDM bit equals 0)
READ_STATUS	Non-intrusive	E4/SS	Read BDC status from BDCSCR
WRITE_CONTROL	Non-intrusive	C4/CC	Write BDC controls in BDCSCR
READ_BYTE	Non-intrusive	E0/AAAA/d/RD	Read a byte from target memory
READ_BYTE_WS	Non-intrusive	E1/AAAA/d/SS/RD	Read a byte and report status
READ_LAST	Non-intrusive	E8/SS/RD	Re-read byte from address just read and report status
WRITE_BYTE	Non-intrusive	C0/AAAA/WD/d	Write a byte to target memory
WRITE_BYTE_WS	Non-intrusive	C1/AAAA/WD/d/SS	Write a byte and report status
READ_BKPT	Non-intrusive	E2/RBKP	Read BDCBKPT breakpoint register
WRITE_BKPT	Non-intrusive	C2/WBKP	Write BDCBKPT breakpoint register
GO	Active BDM	08/d	Go to execute the user application program starting at the address currently in the PC
TRACE1	Active BDM	10/d	Trace 1 user instruction at the address in the PC, then return to active background mode
TAGGO	Active BDM	18/d	Same as GO but enable external tagging (HCS08 devices have no external tagging pin)
READ_A	Active BDM	68/d/RD	Read accumulator (A)
READ_CCR	Active BDM	69/d/RD	Read condition code register (CCR)
READ_PC	Active BDM	6B/d/RD16	Read program counter (PC)
READ_HX	Active BDM	6C/d/RD16	Read H and X register pair (H:X)
READ_SP	Active BDM	6F/d/RD16	Read stack pointer (SP)
READ_NEXT	Active BDM	70/d/RD	Increment H:X by one then read memory byte located at H:X
READ_NEXT_WS	Active BDM	71/d/SS/RD	Increment H:X by one then read memory byte located at H:X. Report status and data.
WRITE_A	Active BDM	48/WD/d	Write accumulator (A)
WRITE_CCR	Active BDM	49/WD/d	Write condition code register (CCR)
WRITE_PC	Active BDM	4B/WD16/d	Write program counter (PC)
WRITE_HX	Active BDM	4C/WD16/d	Write H and X register pair (H:X)
WRITE_SP	Active BDM	4F/WD16/d	Write stack pointer (SP)
WRITE_NEXT	Active BDM	50/WD/d	Increment H:X by one, then write memory byte located at H:X
WRITE_NEXT_WS	Active BDM	51/WD/d/SS	Increment H:X by one, then write memory byte located at H:X. Also report status.

<sup>1</sup> The SYNC command is a special operation that does not have a command code.

The SYNC command is unlike other BDC commands because the host does not necessarily know the correct communications speed to use for BDC communications until after it has analyzed the response to the SYNC command.

To issue a SYNC command, the host:

- Drives the BKGD pin low for at least 128 cycles of the slowest possible BDC clock (The slowest clock is normally the reference oscillator/64 or the self-clocked rate/64.)
- Drives BKGD high for a brief speedup pulse to get a fast rise time (This speedup pulse is typically one cycle of the fastest clock in the system.)
- Removes all drive to the BKGD pin so it reverts to high impedance
- Monitors the BKGD pin for the sync response pulse

The target, upon detecting the SYNC request from the host (which is a much longer low time than would ever occur during normal BDC communications):

- Waits for BKGD to return to a logic high
- Delays 16 cycles to allow the host to stop driving the high speedup pulse
- Drives BKGD low for 128 BDC clock cycles
- Drives a 1-cycle high speedup pulse to force a fast rise time on BKGD
- Removes all drive to the BKGD pin so it reverts to high impedance

The host measures the low time of this 128-cycle sync response pulse and determines the correct speed for subsequent BDC communications. Typically, the host can determine the correct communication speed within a few percent of the actual target speed and the communication protocol can easily tolerate speed errors of several percent.

## 17.2.4 BDC Hardware Breakpoint

The BDC includes one relatively simple hardware breakpoint that compares the CPU address bus to a 16-bit match value in the BDCBKPT register. This breakpoint can generate a forced breakpoint or a tagged breakpoint. A forced breakpoint causes the CPU to enter active background mode at the first instruction boundary following any access to the breakpoint address. The tagged breakpoint causes the instruction opcode at the breakpoint address to be tagged so that the CPU will enter active background mode rather than executing that instruction if and when it reaches the end of the instruction queue. This implies that tagged breakpoints can only be placed at the address of an instruction opcode while forced breakpoints can be set at any address.

The breakpoint enable (BKPTEN) control bit in the BDC status and control register (BDCSCR) is used to enable the breakpoint logic (BKPTEN = 1). When BKPTEN = 0, its default value after reset, the breakpoint logic is disabled and no BDC breakpoints are requested regardless of the values in other BDC breakpoint registers and control bits. The force/tag select (FTS) control bit in BDCSCR is used to select forced (FTS = 1) or tagged (FTS = 0) type breakpoints.

## 17.3 Register Definition

This section contains the descriptions of the BDC registers and control bits.

This section refers to registers and control bits only by their names. A Freescale-provided equate or header file is used to translate these names into the appropriate absolute addresses.

### 17.3.1 BDC Registers and Control Bits

The BDC has two registers:

- The BDC status and control register (BDCSCR) is an 8-bit register containing control and status bits for the background debug controller.
- The BDC breakpoint match register (BDCBKPT) holds a 16-bit breakpoint match address.

These registers are accessed with dedicated serial BDC commands and are not located in the memory space of the target MCU (so they do not have addresses and cannot be accessed by user programs).

Some of the bits in the BDCSCR have write limitations; otherwise, these registers may be read or written at any time. For example, the ENBDM control bit may not be written while the MCU is in active background mode. (This prevents the ambiguous condition of the control bit forbidding active background mode while the MCU is already in active background mode.) Also, the four status bits (BDMACT, WS, WSF, and DVF) are read-only status indicators and can never be written by the WRITE\_CONTROL serial BDC command. The clock switch (CLKSW) control bit may be read or written at any time.

### 17.3.1.1 BDC Status and Control Register (BDCSCR)

This register can be read or written by serial BDC commands (READ\_STATUS and WRITE\_CONTROL) but is not accessible to user programs because it is not located in the normal memory map of the MCU.

	7	6	5	4	3	2	1	0
R	ENBDM	BDMACT	BKPTEN	FTS	CLKSW	WS	WSF	DVF
W								
Normal Reset	0	0	0	0	0	0	0	0
Reset in Active BDM:	1	1	0	0	1	0	0	0

= Unimplemented or Reserved

Figure 17-5. BDC Status and Control Register (BDCSCR)

Table 17-2. BDCSCR Register Field Descriptions

Field	Description
7 ENBDM	<b>Enable BDM (Permit Active Background Mode)</b> — Typically, this bit is written to 1 by the debug host shortly after the beginning of a debug session or whenever the debug host resets the target and remains 1 until a normal reset clears it. 0 BDM cannot be made active (non-intrusive commands still allowed) 1 BDM can be made active to allow active background mode commands
6 BDMACT	<b>Background Mode Active Status</b> — This is a read-only status bit. 0 BDM not active (user application program running) 1 BDM active and waiting for serial commands
5 BKPTEN	<b>BDC Breakpoint Enable</b> — If this bit is clear, the BDC breakpoint is disabled and the FTS (force tag select) control bit and BDCBKPT match register are ignored. 0 BDC breakpoint disabled 1 BDC breakpoint enabled
4 FTS	<b>Force/Tag Select</b> — When FTS = 1, a breakpoint is requested whenever the CPU address bus matches the BDCBKPT match register. When FTS = 0, a match between the CPU address bus and the BDCBKPT register causes the fetched opcode to be tagged. If this tagged opcode ever reaches the end of the instruction queue, the CPU enters active background mode rather than executing the tagged opcode. 0 Tag opcode at breakpoint address and enter active background mode if CPU attempts to execute that instruction 1 Breakpoint match forces active background mode at next instruction boundary (address need not be an opcode)
3 CLKSW	<b>Select Source for BDC Communications Clock</b> — CLKSW defaults to 0, which selects the alternate BDC clock source. 0 Alternate BDC clock source 1 MCU bus clock

**Table 17-2. BDCSCR Register Field Descriptions (continued)**

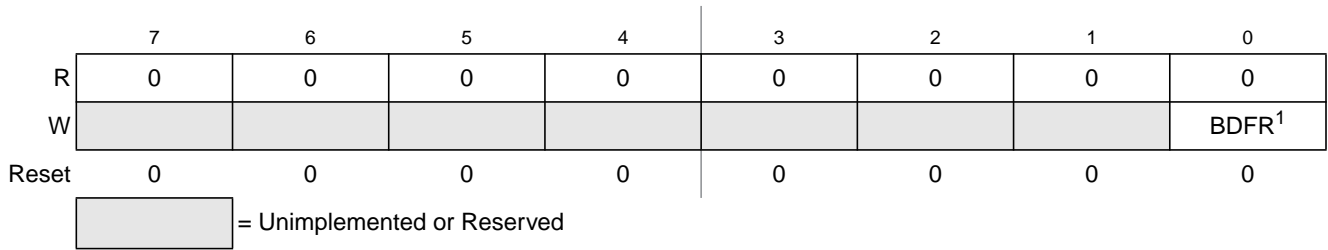
Field	Description
2 WS	<p><b>Wait or Stop Status</b> — When the target CPU is in wait or stop mode, most BDC commands cannot function. However, the BACKGROUND command can be used to force the target CPU out of wait or stop and into active background mode where all BDC commands work. Whenever the host forces the target MCU into active background mode, the host should issue a READ_STATUS command to check that BDMACT = 1 before attempting other BDC commands.</p> <p>0 Target CPU is running user application code or in active background mode (was not in wait or stop mode when background became active)</p> <p>1 Target CPU is in wait or stop mode, or a BACKGROUND command was used to change from wait or stop to active background mode</p>
1 WSF	<p><b>Wait or Stop Failure Status</b> — This status bit is set if a memory access command failed due to the target CPU executing a wait or stop instruction at or about the same time. The usual recovery strategy is to issue a BACKGROUND command to get out of wait or stop mode into active background mode, repeat the command that failed, then return to the user program. (Typically, the host would restore CPU registers and stack values and re-execute the wait or stop instruction.)</p> <p>0 Memory access did not conflict with a wait or stop instruction</p> <p>1 Memory access command failed because the CPU entered wait or stop mode</p>
0 DVF	<p><b>Data Valid Failure Status</b> — This status bit is not used in the MC9S08QE128 Series because it does not have any slow access memory.</p> <p>0 Memory access did not conflict with a slow memory access</p> <p>1 Memory access command failed because CPU was not finished with a slow memory access</p>

### 17.3.1.2 BDC Breakpoint Match Register (BDCBKPT)

This 16-bit register holds the address for the hardware breakpoint in the BDC. The BKPTEN and FTS control bits in BDCSCR are used to enable and configure the breakpoint logic. Dedicated serial BDC commands (READ\_BKPT and WRITE\_BKPT) are used to read and write the BDCBKPT register but is not accessible to user programs because it is not located in the normal memory map of the MCU. Breakpoints are normally set while the target MCU is in active background mode before running the user application program. For additional information about setup and use of the hardware breakpoint logic in the BDC, refer to [Section 17.2.4, “BDC Hardware Breakpoint.”](#)

### 17.3.2 System Background Debug Force Reset Register (SBDFR)

This register contains a single write-only control bit. A serial background mode command such as WRITE\_BYTE must be used to write to SBDFR. Attempts to write this register from a user program are ignored. Reads always return 0x00.



<sup>1</sup> BDFR is writable only through serial background mode debug commands, not from user programs.

**Figure 17-6. System Background Debug Force Reset Register (SBDFR)**

**Table 17-3. SBDFR Register Field Description**

Field	Description
0 BDFR	<b>Background Debug Force Reset</b> — A serial active background mode command such as WRITE_BYTE allows an external debug host to force a target system reset. Writing 1 to this bit forces an MCU reset. This bit cannot be written from a user program.





# Chapter 18

## Debug Module (DBG) (128K)

### 18.1 Introduction

The DBG module implements an on-chip ICE (in-circuit emulation) system and allows non-intrusive debug of application software by providing an on-chip trace buffer with flexible triggering capability. The trigger also can provide extended breakpoint capacity. The on-chip ICE system is optimized for the HCS08 8-bit architecture and supports 64K bytes or 128K bytes of memory space.

#### 18.1.1 Features

The on-chip ICE system includes these distinctive features:

- Three comparators (A, B, and C) with ability to match addresses in 128K space
  - Dual mode, Comparators A and B used to compare addresses
  - Full mode, Comparator A compares address and Comparator B compares data
  - Can be used as triggers and/or breakpoints
  - Comparator C can be used as a normal hardware breakpoint
  - Loop1 capture mode, Comparator C is used to track most recent COF event captured into FIFO
- Tag and Force type breakpoints
- Nine trigger modes
  - A
  - A Or B
  - A Then B
  - A And B, where B is data (Full mode)
  - A And Not B, where B is data (Full mode)
  - Event Only B, store data
  - A Then Event Only B, store data
  - Inside Range,  $A \leq \text{Address} \leq B$
  - Outside Range,  $\text{Address} < A$  or  $\text{Address} > B$
- FIFO for storing change of flow information and event only data
  - Source address of conditional branches taken
  - Destination address of indirect JMP and JSR instruction
  - Destination address of interrupts, RTI, RTC, and RTS instruction
  - Data associated with Event B trigger modes

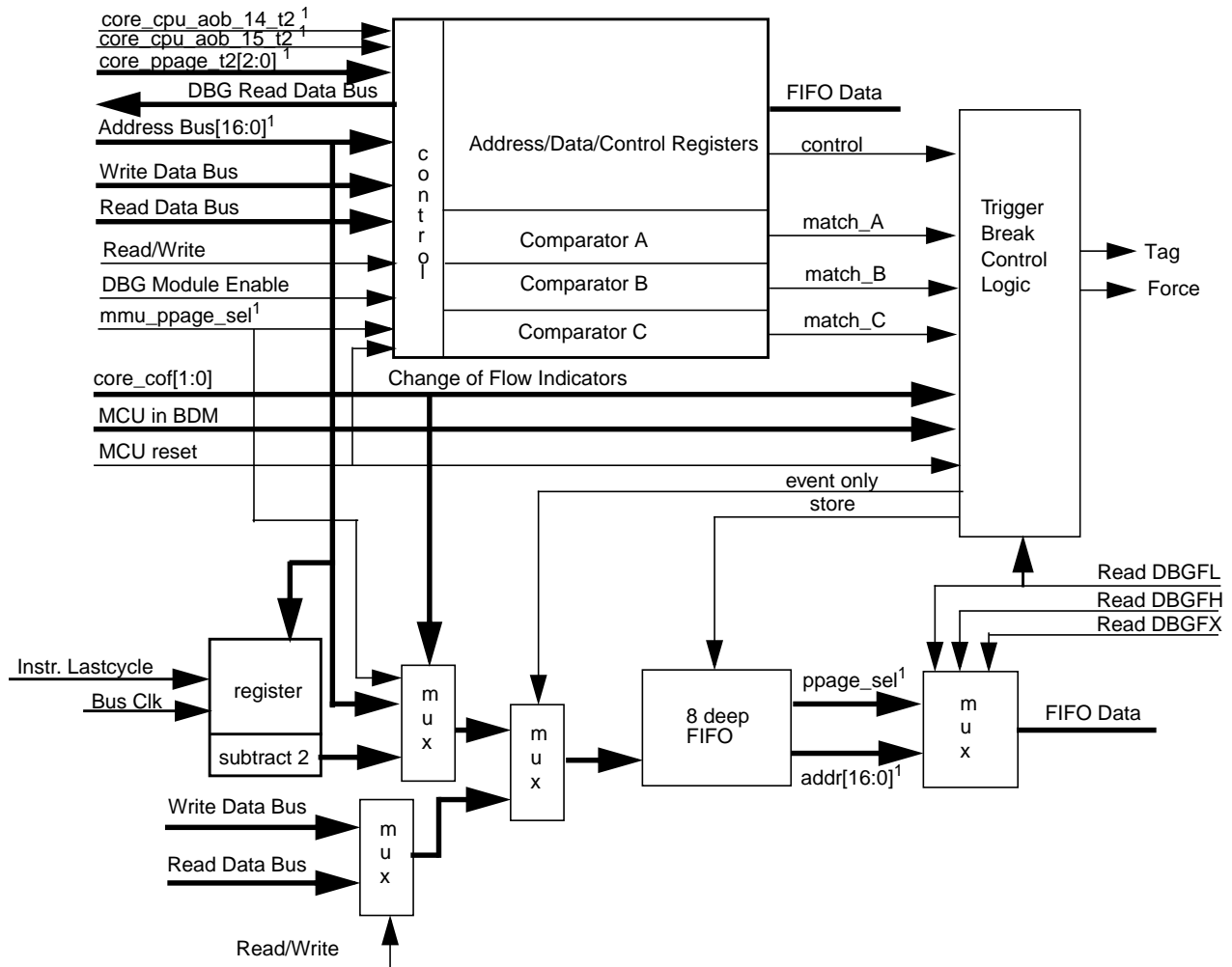
- Ability to End-trace until reset and Begin-trace from reset

## 18.1.2 Modes of Operation

The on-chip ICE system can be enabled in all MCU functional modes. The DBG module is disabled if the MCU is secure. The DBG module comparators are disabled when executing a Background Debug Mode (BDM) command.

## 18.1.3 Block Diagram

Figure 18-1 shows the structure of the DBG module.



1. In 64K versions of this module there are only 16 address lines [15:0], there are no core\_cpu\_aob\_14\_t2, core\_cpu\_aob\_15\_t2, core\_ppage\_t2[2:0], and ppage\_sel signals.

Figure 18-1. DBG Block Diagram

## 18.2 Signal Description

The DBG module contains no external signals.

## 18.3 Memory Map and Registers

This section provides a detailed description of all DBG registers accessible to the end user.

### 18.3.1 Module Memory Map

Table 18-1 shows the registers contained in the DBG module.

**Table 18-1. Module Memory Map**

Address	Use	Access
Base + \$0000	Debug Comparator A High Register (DBGCAH)	Read/write
Base + \$0001	Debug Comparator A Low Register (DBGCAL)	Read/write
Base + \$0002	Debug Comparator B High Register (DBGCBH)	Read/write
Base + \$0003	Debug Comparator B Low Register (DBGCBL)	Read/write
Base + \$0004	Debug Comparator C High Register (DBGCCH)	Read/write
Base + \$0005	Debug Comparator C Low Register (DBGCCL)	Read/write
Base + \$0006	Debug FIFO High Register (DBGFH)	Read only
Base + \$0007	Debug FIFO Low Register (DBGFL)	Read only
Base + \$0008	Debug Comparator A Extension Register (DBGCAE)	Read/write
Base + \$0009	Debug Comparator B Extension Register (DBGCBX)	Read/write
Base + \$000A	Debug Comparator C Extension Register (DBGCCX)	Read/write
Base + \$000B	Debug FIFO Extended Information Register (DBGFX)	Read only
Base + \$000C	Debug Control Register (DBGCR)	Read/write
Base + \$000D	Debug Trigger Register (DBGTR)	Read/write
Base + \$000E	Debug Status Register (DBGSR)	Read only
Base + \$000F	Debug FIFO Count Register (DBGFCR)	Read only

### 18.3.2

**Table 18-2. Register Bit Summary**

	7	6	5	4	3	2	1	0
<b>DBGCAH</b>	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
<b>DBGCAL</b>	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
<b>DBGCBH</b>	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
<b>DBGCBL</b>	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
<b>DBGCCH</b>	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
<b>DBGCCL</b>	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
<b>DBGFH</b>	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
<b>DBGFL</b>	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
<b>DBGCAx</b>	RWAEN	RWA	PAGSEL	0	0	0	0	bit-16
<b>DBGCBx</b>	RWBEN	RWB	PAGSEL	0	0	0	0	bit-16
<b>DBGCCx</b>	RWCEN	RWC	PAGSEL	0	0	0	0	bit-16
<b>DBGFX</b>	PPACC	0	0	0	0	0	0	bit-16
<b>DBGC</b>	DBGEN	ARM	TAG	BRKEN	-	-	-	LOOP1
<b>DBGT</b>	TRGSEL	BEGIN	0	0	TRG[3:0]			
<b>DBGS</b>	AF	BF	CF	0	0	0	0	ARMF
<b>DBGCNT</b>	0	0	0	0	CNT[3:0]			

### 18.3.3 Register Descriptions

This section consists of the DBG register descriptions in address order.

Note: For all registers below, consider: U = Unchanged, bit maintain its value after reset.

#### 18.3.3.1 Debug Comparator A High Register (DBGCAH)

Module Base + 0x0000

	7	6	5	4	3	2	1	0
R								
W	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
POR or non- end-run	1	1	1	1	1	1	1	1
Reset end-run <sup>1</sup>	U	U	U	U	U	U	U	U

**Figure 18-2. Debug Comparator A High Register (DBGCAH)**

<sup>1</sup> In the case of an end-trace to reset where DBGEN=1 and BEGIN=0, the bits in this register do not change after reset.

**Table 18-3. DBGCAH Field Descriptions**

Field	Description
Bits 15–8	<b>Comparator A High Compare Bits</b> — The Comparator A High compare bits control whether Comparator A will compare the address bus bits [15:8] to a logic 1 or logic 0. 0 Compare corresponding address bit to a logic 0 1 Compare corresponding address bit to a logic 1

#### 18.3.3.2 Debug Comparator A Low Register (DBGCAL)

Module Base + 0x0001

	7	6	5	4	3	2	1	0
R								
W	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
POR or non- end-run	1	1	1	1	1	1	1	0
Reset end-run <sup>1</sup>	U	U	U	U	U	U	U	U

**Figure 18-3. Debug Comparator A Low Register (DBGCAL)**

<sup>1</sup> In the case of an end-trace to reset where DBGEN=1 and BEGIN=0, the bits in this register do not change after reset.

**Table 18-4. DBGCAL Field Descriptions**

Field	Description
Bits 7–0	<b>Comparator A Low Compare Bits</b> — The Comparator A Low compare bits control whether Comparator A will compare the address bus bits [7:0] to a logic 1 or logic 0. 0 Compare corresponding address bit to a logic 0 1 Compare corresponding address bit to a logic 1

### 18.3.3.3 Debug Comparator B High Register (DBGCBH)

Module Base + 0x0002

	7	6	5	4	3	2	1	0
R								
W	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
POR or non-end-run	0	0	0	0	0	0	0	0
Reset end-run <sup>1</sup>	U	U	U	U	U	U	U	U

**Figure 18-4. Debug Comparator B High Register (DBGCBH)**

<sup>1</sup> In the case of an end-trace to reset where DBGEN=1 and BEGIN=0, the bits in this register do not change after reset.

**Table 18-5. DBGCBH Field Descriptions**

Field	Description
Bits 15–8	<b>Comparator B High Compare Bits</b> — The Comparator B High compare bits control whether Comparator B will compare the address bus bits [15:8] to a logic 1 or logic 0. Not used in Full mode. 0 Compare corresponding address bit to a logic 0 1 Compare corresponding address bit to a logic 1

### 18.3.3.4 Debug Comparator B Low Register (DBGCBL)

Module Base + 0x0003

	7	6	5	4	3	2	1	0
R								
W	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
POR or non-end-run	0	0	0	0	0	0	0	0
Reset end-run <sup>1</sup>	U	U	U	U	U	U	U	U

**Figure 18-5. Debug Comparator B Low Register (DBGCBL)**

<sup>1</sup> In the case of an end-trace to reset where DBGEN=1 and BEGIN=0, the bits in this register do not change after reset.

**Table 18-6. DBGCBL Field Descriptions**

Field	Description
Bits 7–0	<b>Comparator B Low Compare Bits</b> — The Comparator B Low compare bits control whether Comparator B will compare the address bus or data bus bits [7:0] to a logic 1 or logic 0. 0 Compare corresponding address bit to a logic 0, compares to data if in Full mode 1 Compare corresponding address bit to a logic 1, compares to data if in Full mode

### 18.3.3.5 Debug Comparator C High Register (DBGCCH)

Module Base + 0x0004

	7	6	5	4	3	2	1	0
R								
W								
	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
POR or non-end-run	0	0	0	0	0	0	0	0
Reset end-run <sup>1</sup>	U	U	U	U	U	U	U	U

**Figure 18-6. Debug Comparator C High Register (DBGCCH)**

<sup>1</sup> In the case of an end-trace to reset where DBGEN=1 and BEGIN=0, the bits in this register do not change after reset.

**Table 18-7. DBGCCH Field Descriptions**

Field	Description
Bits 15–8	<b>Comparator C High Compare Bits</b> — The Comparator C High compare bits control whether Comparator C will compare the address bus bits [15:8] to a logic 1 or logic 0. 0 Compare corresponding address bit to a logic 0 1 Compare corresponding address bit to a logic 1

### 18.3.3.6 Debug Comparator C Low Register (DBGCCCL)

Module Base + 0x0005

	7	6	5	4	3	2	1	0
R	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
W								
POR or non- end-run	0	0	0	0	0	0	0	0
Reset end-run <sup>1</sup>	U	U	U	U	U	U	U	U

**Figure 18-7. Debug Comparator C Low Register (DBGCCCL)**

<sup>1</sup> In the case of an end-trace to reset where DBGGEN=1 and BEGIN=0, the bits in this register do not change after reset.

**Table 18-8. DBGCCCL Field Descriptions**

Field	Description
Bits 7–0	<b>Comparator C Low Compare Bits</b> — The Comparator C Low compare bits control whether Comparator C will compare the address bus bits [7:0] to a logic 1 or logic 0. 0 Compare corresponding address bit to a logic 0 1 Compare corresponding address bit to a logic 1

### 18.3.3.7 Debug FIFO High Register (DBGFHF)

Module Base + 0x0006

	7	6	5	4	3	2	1	0
R	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
W								
POR or non- end-run	0	0	0	0	0	0	0	0
Reset end-run <sup>1</sup>	U	U	U	U	U	U	U	U

= Unimplemented or Reserved

**Figure 18-8. Debug FIFO High Register (DBGFHF)**

<sup>1</sup> In the case of an end-trace to reset where DBGGEN=1 and BEGIN=0, the bits in this register do not change after reset.



**Table 18-9. DBGFH Field Descriptions**

Field	Description
Bits 15–8	<b>FIFO High Data Bits</b> — The FIFO High data bits provide access to bits [15:8] of data in the FIFO. This register is not used in event only modes and will read a \$00 for valid FIFO words.

### 18.3.3.8 Debug FIFO Low Register (DBGFL)

Module Base + 0x0007

	7	6	5	4	3	2	1	0
R	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
W								
POR or non- end-run	0	0	0	0	0	0	0	0
Reset end-run <sup>1</sup>	U	U	U	U	U	U	U	U

= Unimplemented or Reserved

**Figure 18-9. Debug FIFO Low Register (DBGFL)**

<sup>1</sup> In the case of an end-trace to reset where DBGGEN=1 and BEGIN=0, the bits in this register do not change after reset.

**Table 18-10. DBGFL Field Descriptions**

Field	Description
Bits 7–0	<b>FIFO Low Data Bits</b> — The FIFO Low data bits contain the least significant byte of data in the FIFO. When reading FIFO words, read DBGFX and DBGFH before reading DBGFL because reading DBGFL causes the FIFO pointers to advance to the next FIFO location. In event-only modes, there is no useful information in DBGFX and DBGFH so it is not necessary to read them before reading DBGFL.

### 18.3.3.9 Debug Comparator A Extension Register (DBGCAx)

Module Base + 0x0008

	7	6	5	4	3	2	1	0
R	RWAEN	RWA	PAGSEL	0	0	0	0	Bit 16
W								
POR or non-end-run	0	0	0	0	0	0	0	0
Reset end-run <sup>1</sup>	U	U	U	0	0	0	0	U

= Unimplemented or Reserved

**Figure 18-10. Debug Comparator A Extension Register (DBGCAx)**

<sup>1</sup> In the case of an end-trace to reset where DBGEN=1 and BEGIN=0, the bits in this register do not change after reset.

**Table 18-11. DBGCAx Field Descriptions**

Field	Description
7 RWAEN	<b>Read/Write Comparator A Enable Bit</b> — The RWAEN bit controls whether read or write comparison is enabled for Comparator A. 0 Read/Write is not used in comparison 1 Read/Write is used in comparison
6 RWA	<b>Read/Write Comparator A Value Bit</b> — The RWA bit controls whether read or write is used in compare for Comparator A. The RWA bit is not used if RWAEN = 0. 0 Write cycle will be matched 1 Read cycle will be matched
5 PAGSEL	<b>Comparator A Page Select Bit</b> — This PAGSEL bit controls whether Comparator A will be qualified with the internal signal (mmu_ppage_sel) that indicates an extended access through the PPAGE mechanism. When mmu_ppage_sel = 1, the 17-bit core address is a paged program access, and the 17-bit core address is made up of PPAGE[2:0]:addr[13:0]. When mmu_ppage_sel = 0, the 17-bit core address is either a 16-bit CPU address with a leading 0 in bit 16, or a 17-bit linear address pointer value. 0 Match qualified by mmu_ppage_sel = 0 so address bits [16:0] correspond to a 17-bit CPU address with a leading zero at bit 16, or a 17-bit linear address pointer address 1 Match qualified by mmu_ppage_sel = 1 so address bits [16:0] compare to flash memory address made up of PPAGE[2:0]:addr[13:0]
0 Bit 16	<b>Comparator A Extended Address Bit 16 Compare Bit</b> — The Comparator A bit 16 compare bit controls whether Comparator A will compare the core address bus bit 16 to a logic 1 or logic 0. 0 Compare corresponding address bit to a logic 0 1 Compare corresponding address bit to a logic 1

### 18.3.3.10 Debug Comparator B Extension Register (DBGCBX)

Module Base + 0x0009

	7	6	5	4	3	2	1	0
R	RWBEN	RWB	PAGSEL	0	0	0	0	Bit 16
W								
POR or non-end-run	0	0	0	0	0	0	0	0
Reset end-run <sup>1</sup>	U	U	U	0	0	0	0	U

= Unimplemented or Reserved

**Figure 18-11. Debug Comparator B Extension Register (DBGCBX)**

<sup>1</sup> In the case of an end-trace to reset where DBGGEN=1 and BEGIN=0, the bits in this register do not change after reset.

**Table 18-12. DBGCBX Field Descriptions**

Field	Description
7 RWBEN	<b>Read/Write Comparator B Enable Bit</b> — The RWBEN bit controls whether read or write comparison is enabled for Comparator B. In full modes, RWAEN and RWA are used to control comparison of R/W and RWBEN is ignored. 0 Read/Write is not used in comparison 1 Read/Write is used in comparison
6 RWB	<b>Read/Write Comparator B Value Bit</b> — The RWB bit controls whether read or write is used in compare for Comparator B. The RWB bit is not used if RWBEN = 0. In full modes, RWAEN and RWA are used to control comparison of R/W and RWB is ignored. 0 Write cycle will be matched 1 Read cycle will be matched
5 PAGSEL	<b>Comparator B Page Select Bit</b> — This PAGSEL bit controls whether Comparator B will be qualified with the internal signal (mmu_ppage_sel) that indicates an extended access through the PPAGE mechanism. When mmu_ppage_sel = 1, the 17-bit core address is a paged program access, and the 17-bit core address is made up of PPAGE[2:0]:addr[13:0]. When mmu_ppage_sel = 0, the 17-bit core address is either a 16-bit CPU address with a leading 0 in bit 16, or a 17-bit linear address pointer value. This bit is not used in full modes where comparator B is used to match the data value. 0 Match qualified by mmu_ppage_sel = 0 so address bits [16:0] correspond to a 17-bit CPU address with a leading zero at bit 16, or a 17-bit linear address pointer address 1 Match qualified by mmu_ppage_sel = 1 so address bits [16:0] compare to flash memory address made up of PPAGE[2:0]:addr[13:0]
0 Bit 16	<b>Comparator B Extended Address Bit 16 Compare Bit</b> — The Comparator B bit 16 compare bit controls whether Comparator B will compare the core address bus bit 16 to a logic 1 or logic 0. This bit is not used in full modes where comparator B is used to match the data value. 0 Compare corresponding address bit to a logic 0 1 Compare corresponding address bit to a logic 1

### 18.3.3.11 Debug Comparator C Extension Register (DBGCCX)

Module Base + 0x000A

	7	6	5	4	3	2	1	0
R	RWCEN	RWC	PAGSEL	0	0	0	0	Bit 16
W								
POR or non-end-run	0	0	0	0	0	0	0	0
Reset end-run <sup>1</sup>	U	U	U	0	0	0	0	U

= Unimplemented or Reserved

**Figure 18-12. Debug Comparator C Extension Register (DBGCCX)**

<sup>1</sup> In the case of an end-trace to reset where DBGGEN=1 and BEGIN=0, the bits in this register do not change after reset.

**Table 18-13. DBGCCX Field Descriptions**

Field	Description
7 RWCEN	<b>Read/Write Comparator C Enable Bit</b> — The RWCEN bit controls whether read or write comparison is enabled for Comparator C. 0 Read/Write is not used in comparison 1 Read/Write is used in comparison
6 RWC	<b>Read/Write Comparator C Value Bit</b> — The RWC bit controls whether read or write is used in compare for Comparator C. The RWC bit is not used if RWCEN = 0. 0 Write cycle will be matched 1 Read cycle will be matched
5 PAGSEL	<b>Comparator C Page Select Bit</b> — This PAGSEL bit controls whether Comparator C will be qualified with the internal signal (mmu_ppage_sel) that indicates an extended access through the PPAGE mechanism. When mmu_ppage_sel = 1, the 17-bit core address is a paged program access, and the 17-bit core address is made up of PPAGE[2:0]:addr[13:0]. When mmu_ppage_sel = 0, the 17-bit core address is either a 16-bit CPU address with a leading 0 in bit 16, or a 17-bit linear address pointer value. 0 Match qualified by mmu_ppage_sel = 0 so address bits [16:0] correspond to a 17-bit CPU address with a leading zero at bit 16, or a 17-bit linear address pointer address 1 Match qualified by mmu_ppage_sel = 1 so address bits [16:0] compare to flash memory address made up of PPAGE[2:0]:addr[13:0]
0 Bit 16	<b>Comparator C Extended Address Bit 16 Compare Bit</b> — The Comparator C bit 16 compare bit controls whether Comparator C will compare the core address bus bit 16 to a logic 1 or logic 0. 0 Compare corresponding address bit to a logic 0 1 Compare corresponding address bit to a logic 1

### 18.3.3.12 Debug FIFO Extended Information Register (DBGFX)

Module Base + 0x000B

	7	6	5	4	3	2	1	0
R	PPACC	0	0	0	0	0	0	Bit 16
W								
POR or non-end-run	0	0	0	0	0	0	0	0
Reset end-run <sup>1</sup>	U	0	0	0	0	0	0	U

= Unimplemented or Reserved

**Figure 18-13. Debug FIFO Extended Information Register (DBGFX)**

<sup>1</sup> In the case of an end-trace to reset where DBGGEN=1 and BEGIN=0, the bits in this register do not change after reset.

**Table 18-14. DBGFX Field Descriptions**

Field	Description
7 PPACC	<b>PPAGE Access Indicator Bit</b> — This bit indicates whether the captured information in the current FIFO word is associated with an extended access through the PPAGE mechanism or not. This is indicated by the internal signal <code>mmu_ppage_sel</code> which is 1 when the access is through the PPAGE mechanism. 0 The information in the corresponding FIFO word is event-only data or an unpagged 17-bit CPU address with bit-16 = 0 1 The information in the corresponding FIFO word is a 17-bit flash address with PPAGE[2:0] in the three most significant bits and CPU address[13:0] in the 14 least significant bits
0 Bit 16	<b>Extended Address Bit 16</b> — This bit is the most significant bit of the 17-bit core address.

### 18.3.3.13 Debug Control Register (DBGC)

Module Base + 0x000C

	7	6	5	4	3	2	1	0
R	DBGEN	ARM	TAG	BRKEN	0	0	0	LOOP1
W								
POR or non-end-run	1	1	0	0	0	0	0	0
Reset end-run <sup>1</sup>	U	0	U	0	0	0	0	U

= Unimplemented or Reserved

**Figure 18-14. Debug Control Register (DBGC)**

<sup>1</sup> In the case of an end-trace to reset where DBGEN=1 and BEGIN=0, the ARM and BRKEN bits are cleared but the remaining control bits in this register do not change after reset.

**Table 18-15. DBGC Field Descriptions**

Field	Description
7 DBGEN	<b>DBG Module Enable Bit</b> — The DBGEN bit enables the DBG module. The DBGEN bit is forced to zero and cannot be set if the MCU is secure. 0 DBG not enabled 1 DBG enabled
6 ARM	<b>Arm Bit</b> — The ARM bit controls whether the debugger is comparing and storing data in FIFO. See <a href="#">Section 18.4.4.2, “Arming the DBG Module”</a> for more information. 0 Debugger not armed 1 Debugger armed
5 TAG	<b>Tag or Force Bit</b> — The TAG bit controls whether a debugger or comparator C breakpoint will be requested as a tag or force breakpoint to the CPU. The TAG bit is not used if BRKEN = 0. 0 Force request selected 1 Tag request selected
4 BRKEN	<b>Break Enable Bit</b> — The BRKEN bit controls whether the debugger will request a breakpoint to the CPU at the end of a trace run, and whether comparator C will request a breakpoint to the CPU. 0 CPU break request not enabled 1 CPU break request enabled
0 LOOP1	<b>Select LOOP1 Capture Mode</b> — This bit selects either normal capture mode or LOOP1 capture mode. LOOP1 is not used in event-only modes. 0 Normal operation - capture COF events into the capture buffer FIFO 1 LOOP1 capture mode enabled. When the conditions are met to store a COF value into the FIFO, compare the current COF address with the address in comparator C. If these addresses match, override the FIFO capture and do not increment the FIFO count. If the address does not match comparator C, capture the COF address, including the PPACC indicator, into the FIFO and into comparator C.

### 18.3.3.14 Debug Trigger Register (DBGT)

Module Base + 0x000D

	7	6	5	4	3	2	1	0
R	TRGSEL	BEGIN	0	0	TRG			
W <sup>2</sup>								
POR or non-end-run	0	1	0	0	0	0	0	0
Reset end-run <sup>1</sup>	U	U	0	0	U	U	U	U

= Unimplemented or Reserved

**Figure 18-15. Debug Trigger Register (DBGT)**

<sup>1</sup> In the case of an end-trace to reset where DBGEN=1 and BEGIN=0, the control bits in this register do not change after reset.

<sup>2</sup> The DBG trigger register (DBGT) can not be changed unless ARM=0.

**Table 18-16. DBGT Field Descriptions**

Field	Description
7 TRGSEL	<b>Trigger Selection Bit</b> — The TRGSEL bit controls the triggering condition for the comparators. See <a href="#">Section 18.4.4, “Trigger Break Control (TBC)”</a> for more information. 0 Trigger on any compare address access 1 Trigger if opcode at compare address is executed
6 BEGIN	<b>Begin/End Trigger Bit</b> — The BEGIN bit controls whether the trigger begins or ends storing of data in FIFO. 0 Trigger at end of stored data 1 Trigger before storing data
3–0 TRG	<b>Trigger Mode Bits</b> — The TRG bits select the trigger mode of the DBG module as shown in <a href="#">Table 18-17</a> .

**Table 18-17. Trigger Mode Encoding**

TRG Value	Meaning
0000	A Only
0001	A Or B
0010	A Then B
0011	Event Only B
0100	A Then Event Only B
0101	A And B (Full Mode)
0110	A And Not B (Full mode)
0111	Inside Range
1000	Outside Range

**Table 18-17. Trigger Mode Encoding**

TRG Value	Meaning
1001 ↓ 1111	No Trigger

**NOTE**

The DBG trigger register (DBGT) can not be changed unless ARM=0.

**18.3.3.15 Debug Status Register (DBGS)**

Module Base + 0x000E

	7	6	5	4	3	2	1	0
R	AF	BF	CF	0	0	0	0	ARMF
W								
POR or non-end-run	0	0	0	0	0	0	0	1
Reset end-run <sup>1</sup>	U	U	U	0	0	0	0	0

= Unimplemented or Reserved

**Figure 18-16. Debug Status Register (DBGS)**

<sup>1</sup> In the case of an end-trace to reset where DBGEN=1 and BEGIN=0, ARMF gets cleared by reset but AF, BF, and CF do not change after reset.

**Table 18-18. DBGS Field Descriptions**

Field	Description
7 AF	<b>Trigger A Match Bit</b> — The AF bit indicates if Trigger A match condition was met since arming. 0 Comparator A did not match 1 Comparator A match
6 BF	<b>Trigger B Match Bit</b> — The BF bit indicates if Trigger B match condition was met since arming. 0 Comparator B did not match 1 Comparator B match
5 CF	<b>Trigger C Match Bit</b> — The CF bit indicates if Trigger C match condition was met since arming. 0 Comparator C did not match 1 Comparator C match
0 ARMF	<b>Arm Flag Bit</b> — The ARMF bit indicates whether the debugger is waiting for trigger or waiting for the FIFO to fill. While DBGEN = 1, this status bit is a read-only image of the ARM bit in DBGCR. See <a href="#">Section 18.4.4.2, “Arming the DBG Module”</a> for more information. 0 Debugger not armed 1 Debugger armed



### 18.3.3.16 Debug Count Status Register (DBGCNT)

Module Base + 0x000F

	7	6	5	4	3	2	1	0
R	0	0	0	0	CNT			
W								
POR or non-end-run	0	0	0	0	0	0	0	0
Reset end-run <sup>1</sup>	0	0	0	0	U	U	U	U

= Unimplemented or Reserved

**Figure 18-17. Debug Count Status Register (DBGCNT)**

<sup>1</sup> In the case of an end-trace to reset where DBGEN=1 and BEGIN=0, the CNT[3:0] bits do not change after reset.

**Table 18-19. DBGS Field Descriptions**

Field	Description
3–0 CNT	<b>FIFO Valid Count Bits</b> — The CNT bits indicate the amount of valid data stored in the FIFO. Table 18-20 shows the correlation between the CNT bits and the amount of valid data in FIFO. The CNT will stop after a count to eight even if more data is being stored in the FIFO. The CNT bits are cleared when the DBG module is armed, and the count is incremented each time a new word is captured into the FIFO. The host development system is responsible for checking the value in CNT[3:0] and reading the correct number of words from the FIFO because the count does not decrement as data is read out of the FIFO at the end of a trace run.

**Table 18-20. CNT Bits**

CNT Value	Meaning
0000	No data valid
0001	1 word valid
0010	2 words valid
0011	3 words valid
0100	4 words valid
0101	5 words valid
0110	6 words valid
0111	7 words valid
1000	8 words valid

## 18.4 Functional Description

This section provides a complete functional description of the on-chip ICE system. The DBG module is enabled by setting the DBGGEN bit in the DBGCR register. Enabling the module allows the arming, triggering and storing of data in the FIFO. The DBG module is made up of three main blocks, the Comparators, Trigger Break Control logic and the FIFO.

### 18.4.1 Comparator

The DBG module contains three comparators, A, B, and C. Comparator A compares the core address bus with the address stored in the DBGCRAX, DBGCAH, and DBGCRAL registers. Comparator B compares the core address bus with the address stored in the DBGCBX, DBGCBH, and DBGCRBL registers except in full mode, where it compares the data buses to the data stored in the DBGCRBL register. Comparator C compares the core address bus with the address stored in the DBGCCX, DBGCCCH, and DBGCCCL registers. Matches on Comparators A, B, and C are signaled to the Trigger Break Control (TBC) block.

#### 18.4.1.1 RWA and RWAEN in Full Modes

In full modes ("A And B" and "A And Not B") RWAEN and RWA are used to select read or write comparisons for both comparators A and B. To select write comparisons and the write data bus in Full Modes set RWAEN=1 and RWA=0, otherwise read comparisons and the read data bus will be selected. The RWBEN and RWB bits are not used and will be ignored in Full Modes.

#### 18.4.1.2 Comparator C in LOOP1 Capture Mode

Normally comparator C is used as a third hardware breakpoint and is not involved in the trigger logic for the on-chip ICE system. In this mode, it compares the core address bus with the address stored in the DBGCCX, DBGCCCH, and DBGCCCL registers. However, in LOOP1 capture mode, comparator C is managed by logic in the DBG module to track the address of the most recent change-of-flow event that was captured into the FIFO buffer. In LOOP1 capture mode, comparator C is not available for use as a normal hardware breakpoint.

When the ARM and DBGGEN bits are set to one in LOOP1 capture mode, comparator C value registers are cleared to prevent the previous contents of these registers from interfering with the LOOP1 capture mode operation. When a COF event is detected, the address of the event is compared to the contents of the DBGCCX, DBGCCCH, and DBGCCCL registers to determine whether it is the same as the previous COF entry in the capture FIFO. If the values match, the capture is inhibited to prevent the FIFO from filling up with duplicate entries. If the values do not match, the COF event is captured into the FIFO and the DBGCCX, DBGCCCH, and DBGCCCL registers are updated to reflect the address of the captured COF event. When comparator C is updated, the PAGSEL bit (bit-7 of DBGCCX) is updated with the PPACC value that is captured into the FIFO. This bit indicates whether the COF address was a paged 17-bit program address using the PPAGE mechanism (PPACC=1) or a 17-bit CPU address that resulted from an unpagged CPU access.

## 18.4.2 Breakpoints

A breakpoint request to the CPU at the end of a trace run can be created if the BRKEN bit in the DBGCR register is set. The value of the BEGIN bit in DBGTR register determines when the breakpoint request to the CPU will occur. If the BEGIN bit is set, begin-trigger is selected and the breakpoint request will not occur until the FIFO is filled with 8 words. If the BEGIN bit is cleared, end-trigger is selected and the breakpoint request will occur immediately at the trigger cycle.

When traditional hardware breakpoints from comparators A or B are desired, set BEGIN=0 to select an end-trace run and set the trigger mode to either 0x0 (A-only) or 0x1 (A OR B) mode.

There are two types of breakpoint requests supported by the DBG module, tag-type and force-type. Tagged breakpoints are associated with opcode addresses and allow breaking just before a specific instruction executes. Force breakpoints are not associated with opcode addresses and allow breaking at the next instruction boundary. The TAG bit in the DBGCR register determines whether CPU breakpoint requests will be a tag-type or force-type breakpoints. When TAG=0, a force-type breakpoint is requested and it will take effect at the next instruction boundary after the request. When TAG=1, a tag-type breakpoint is registered into the instruction queue and the CPU will break if/when this tag reaches the head of the instruction queue and the tagged instruction is about to be executed.

### 18.4.2.1 Hardware Breakpoints

Comparators A, B, and C can be used as three traditional hardware breakpoints whether the on-chip ICE real-time capture function is required or not. To use any breakpoint or trace run capture functions set DBGGEN=1. BRKEN and TAG affect all three comparators. When BRKEN=0, no CPU breakpoints are enabled. When BRKEN=1, CPU breakpoints are enabled and the TAG bit determines whether the breakpoints will be tag-type or force-type breakpoints. To use comparators A and B as hardware breakpoints, set DBGTR=0x81 for tag-type breakpoints and 0x01 for force-type breakpoints. This sets up an end-type trace with trigger mode “A OR B”.

Comparator C is not involved in the trigger logic for the on-chip ICE system.

## 18.4.3 Trigger Selection

The TRGSEL bit in the DBGTR register is used to determine the triggering condition of the on-chip ICE system. TRGSEL applies to both trigger A and B except in the event only trigger modes. By setting the TRGSEL bit, the comparators will qualify a match with the output of opcode tracking logic. The opcode tracking logic is internal to each comparator and determines whether the CPU executed the opcode at the compare address. With the TRGSEL bit cleared a comparator match is all that is necessary for a trigger condition to be met.

### NOTE

If the TRGSEL is set, the address stored in the comparator match address registers must be an opcode address for the trigger to occur.

## 18.4.4 Trigger Break Control (TBC)

The TBC is the main controller for the DBG module. Its function is to decide whether data should be stored in the FIFO based on the trigger mode and the match signals from the comparator. The TBC also determines whether a request to break the CPU should occur.

The TAG bit in DBGCR controls whether CPU breakpoints are treated as tag-type or force-type breakpoints. The TRGSEL bit in DBGTR controls whether a comparator A or B match is further qualified by opcode tracking logic. Each comparator has a separate circuit to track opcodes because the comparators could correspond to separate instructions that could be propagating through the instruction queue at the same time.

In end-type trace runs (BEGIN=0), when the comparator registers match, including the optional R/W match, this signal goes to the CPU break logic where BRKEN determines whether a CPU break is requested and the TAG control bit determines whether the CPU break will be a tag-type or force-type breakpoint. When TRGSEL is set, the R/W qualified comparator match signal also passes through the opcode tracking logic. If/when it propagates through this logic, it will cause a trigger to the ICE logic to begin or end capturing information into the FIFO. In the case of an end-type (BEGIN=0) trace run, the qualified comparator signal stops the FIFO from capturing any more information.

If a CPU breakpoint is also enabled, you would want TAG and TRGSEL to agree so that the CPU break occurs at the same place in the application program as the FIFO stopped capturing information. If TRGSEL was 0 and TAG was 1 in an end-type trace run, the FIFO would stop capturing as soon as the comparator address matched, but the CPU would continue running until a TAG signal could propagate through the CPU's instruction queue which could take a long time in the case where changes of flow caused the instruction queue to be flushed. If TRGSEL was one and TAG was zero in an end-type trace run, the CPU would break before the comparator match signal could propagate through the opcode tracking logic to end the trace run.

In begin-type trace runs (BEGIN=1), the start of FIFO capturing is triggered by the qualified comparator signals, and the CPU breakpoint (if enabled by BRKEN=1) is triggered when the FIFO becomes full. Since this FIFO full condition does not correspond to the execution of a tagged instruction, it would not make sense to use TAG=1 for a begin-type trace run.

### 18.4.4.1 Begin- and End-Trigger

The definition of begin- and end-trigger as used in the DBG module are as follows:

- Begin-trigger: Storage in FIFO occurs after the trigger and continues until 8 locations are filled.
- End-trigger: Storage in FIFO occurs until the trigger with the least recent data falling out of the FIFO if more than 8 words are collected.

### 18.4.4.2 Arming the DBG Module

Arming occurs by enabling the DBG module by setting the DBGEN bit and by setting the ARM bit in the DBGCR register. The ARM bit in the DBGCR register and the ARMF bit in the DBGSR register are cleared when the trigger condition is met in end-trigger mode or when the FIFO is filled in begin-trigger mode. In the case of an end-trace where DBGEN=1 and BEGIN=0, ARM and ARMF are cleared by any reset to

end the trace run that was in progress. The ARMF bit is also cleared if ARM is written to zero or when the DBGEN bit is low. The TBC logic determines whether a trigger condition has been met based on the trigger mode and the trigger selection.

### 18.4.4.3 Trigger Modes

The on-chip ICE system supports nine trigger modes. The trigger modes are encoded as shown in Table 18-17. The trigger mode is used as a qualifier for either starting or ending the storing of data in the FIFO. When the match condition is met, the appropriate flag AF or BF is set in DBGS register. Arming the DBG module clears the AF, BF, and CF flags in the DBGS register. In all trigger modes except for the event only modes change of flow addresses are stored in the FIFO. In the event only modes only the value on the data bus at the trigger event B comparator match address will be stored.

#### 18.4.4.3.1 A Only

In the A Only trigger mode, if the match condition for A is met, the AF flag in the DBGS register is set.

#### 18.4.4.3.2 A Or B

In the A Or B trigger mode, if the match condition for A or B is met, the corresponding flag(s) in the DBGS register are set.

#### 18.4.4.3.3 A Then B

In the A Then B trigger mode, the match condition for A must be met before the match condition for B is compared. When the match condition for A or B is met, the corresponding flag in the DBGS register is set.

#### 18.4.4.3.4 Event Only B

In the Event Only B trigger mode, if the match condition for B is met, the BF flag in the DBGS register is set. The Event Only B trigger mode is considered a begin-trigger type and the BEGIN bit in the DBGT register is ignored.

#### 18.4.4.3.5 A Then Event Only B

In the A Then Event Only B trigger mode, the match condition for A must be met before the match condition for B is compared. When the match condition for A or B is met, the corresponding flag in the DBGS register is set. The A Then Event Only B trigger mode is considered a begin-trigger type and the BEGIN bit in the DBGT register is ignored.

#### 18.4.4.3.6 A And B (Full Mode)

In the A And B trigger mode, Comparator A compares to the address bus and Comparator B compares to the data bus. In the A and B trigger mode, if the match condition for A and B happen on the same bus cycle, both the AF and BF flags in the DBGS register are set. If a match condition on only A or only B happens, no flags are set.

For Breakpoint tagging operation with an end-trigger type trace, only matches from Comparator A will be used to determine if the Breakpoint conditions are met and Comparator B matches will be ignored.

### 18.4.4.3.7 A And Not B (Full Mode)

In the A And Not B trigger mode, comparator A compares to the address bus and comparator B compares to the data bus. In the A And Not B trigger mode, if the match condition for A and Not B happen on the same bus cycle, both the AF and BF flags in the DBGS register are set. If a match condition on only A or only Not B occur no flags are set.

For Breakpoint tagging operation with an end-trigger type trace, only matches from Comparator A will be used to determine if the Breakpoint conditions are met and Comparator B matches will be ignored.

### 18.4.4.3.8 Inside Range, $A \leq \text{address} \leq B$

In the Inside Range trigger mode, if the match condition for A and B happen on the same bus cycle, both the AF and BF flags in the DBGS register are set. If a match condition on only A or only B occur no flags are set.

### 18.4.4.3.9 Outside Range, $\text{address} < A$ or $\text{address} > B$

In the Outside Range trigger mode, if the match condition for A or B is met, the corresponding flag in the DBGS register is set.

The four control bits BEGIN and TRGSEL in DBGTT, and BRKEN and TAG in DBGTC, determine the basic type of debug run as shown in Table 1.21. Some of the 16 possible combinations are not used (refer to the notes at the end of the table).

**Table 18-21. Basic Types of Debug Runs**

BEGIN	TRGSEL	BRKEN	TAG	Type of Debug Run
0	0	0	x <sup>(1)</sup>	Fill FIFO until trigger address (No CPU breakpoint - keep running)
0	0	1	0	Fill FIFO until trigger address, then force CPU breakpoint
0	0	1	1	Do not use <sup>(2)</sup>
0	1	0	x <sup>(1)</sup>	Fill FIFO until trigger opcode about to execute (No CPU breakpoint - keep running)
0	1	1	0	Do not use <sup>(3)</sup>
0	1	1	1	Fill FIFO until trigger opcode about to execute (trigger causes CPU breakpoint)
1	0	0	x <sup>(1)</sup>	Start FIFO at trigger address (No CPU breakpoint - keep running)
1	0	1	0	Start FIFO at trigger address, force CPU breakpoint when FIFO full
1	0	1	1	Do not use <sup>(4)</sup>
1	1	0	x <sup>(1)</sup>	Start FIFO at trigger opcode (No CPU breakpoint - keep running)
1	1	1	0	Start FIFO at trigger opcode, force CPU breakpoint when FIFO full
1	1	1	1	Do not use <sup>(4)</sup>

<sup>1</sup> When BRKEN = 0, TAG is do not care (x in the table).

<sup>2</sup> In end trace configurations (BEGIN = 0) where a CPU breakpoint is enabled (BRKEN = 1), TRGSEL should agree with TAG. In this case, where TRGSEL = 0 to select no opcode tracking qualification and TAG = 1 to specify a tag-type CPU breakpoint, the CPU breakpoint would not take effect until sometime after the FIFO stopped storing values. Depending on program loops or interrupts, the delay could be very long.

<sup>3</sup> In end trace configurations (BEGIN = 0) where a CPU breakpoint is enabled (BRKEN = 1), TRGSEL should agree with TAG. In this case, where TRGSEL = 1 to select opcode tracking qualification and TAG = 0 to specify a force-type CPU breakpoint, the CPU breakpoint would erroneously take effect before the FIFO stopped storing values and the debug run would not complete normally.

<sup>4</sup> In begin trace configurations (BEGIN = 1) where a CPU breakpoint is enabled (BRKEN = 1), TAG should not be set to 1. In begin trace debug runs, the CPU breakpoint corresponds to the FIFO full condition which does not correspond to a taggable instruction fetch.

## 18.4.5 FIFO

The FIFO is an eight word deep FIFO. In all trigger modes except for event only, the data stored in the FIFO will be change of flow addresses. In the event only trigger modes only the data bus value corresponding to the event is stored. In event only trigger modes, the high byte of the valid data from the FIFO will always read a 0x00 and the extended information byte in DBGFX will always read 0x00.

### 18.4.5.1 Storing Data in FIFO

In all trigger modes except for the event only modes, the address stored in the FIFO will be determined by the change of flow indicators from the core. The signal `core_cof[1]` indicates the current core address is the destination address of an indirect JSR or JMP instruction, or a RTS, RTC, or RTI instruction or interrupt vector and the destination address should be stored. The signal `core_cof[0]` indicates that a conditional branch was taken and that the source address of the conditional branch should be stored.

### 18.4.5.2 Storing with Begin-Trigger

Storing with Begin-Trigger can be used in all trigger modes. Once the DBG module is enabled and armed in the begin-trigger mode, data is not stored in the FIFO until the trigger condition is met. Once the trigger condition is met the DBG module will remain armed until 8 words are stored in the FIFO. If the `core_cof[1]` signal becomes asserted, the current address is stored in the FIFO. If the `core_cof[0]` signal becomes asserted, the address registered during the previous last cycle is decremented by two and stored in the FIFO.

### 18.4.5.3 Storing with End-Trigger

Storing with End-Trigger cannot be used in event-only trigger modes. Once the DBG module is enabled and armed in the end-trigger mode, data is stored in the FIFO until the trigger condition is met. If the `core_cof[1]` signal becomes asserted, the current address is stored in the FIFO. If the `core_cof[0]` signal becomes asserted, the address registered during the previous last cycle is decremented by two and stored in the FIFO. When the trigger condition is met, the ARM and ARMF will be cleared and no more data will be stored. In non-event only end-trigger modes, if the trigger is at a change of flow address the trigger event will be stored in the FIFO.

### 18.4.5.4 Reading Data from FIFO

The data stored in the FIFO can be read using BDM commands provided the DBG module is enabled and not armed (DBGEN=1 and ARM=0). The FIFO data is read out first-in-first-out. By reading the CNT bits

in the DBGCNT register at the end of a trace run, the number of valid words can be determined. The FIFO data is read by optionally reading the DBGFX and DBGFH registers followed by the DBGFL register. Each time the DBGFL register is read the FIFO is shifted to allow reading of the next word however the count does not decrement. In event-only trigger modes where the FIFO will contain only the data bus values stored, to read the FIFO only DBGFL needs to be accessed.

The FIFO is normally only read while ARM and ARMF=0, however reading the FIFO while the DBG module is armed will return the data value in the oldest location of the FIFO and the TBC will not allow the FIFO to shift. This action could cause a valid entry to be lost because the unexpected read blocked the FIFO advance.

If the DBG module is not armed and the DBGFL register is read, the TBC will store the current opcode address. Through periodic reads of the DBGFX, DBGFH, and DBGFL registers while the DBG module is not armed, host software can provide a histogram of program execution. This is called profile mode. Since the full 17-bit address and the signal that indicates whether an address is in paged extended memory are captured on each FIFO store, profile mode works correctly over the entire extended memory map.

### 18.4.6 Interrupt Priority

When TRGSEL is set and the DBG module is armed to trigger on begin- or end-trigger types, a trigger is not detected in the condition where a pending interrupt occurs at the same time that a target address reaches the top of the instruction pipe. In these conditions, the pending interrupt has higher priority and code execution switches to the interrupt service routine.

When TRGSEL is clear and the DBG module is armed to trigger on end-trigger types, the trigger event is detected on a program fetch of the target address, even when an interrupt becomes pending on the same cycle. In these conditions, the pending interrupt has higher priority, the exception is processed by the core and the interrupt vector is fetched. Code execution is halted before the first instruction of the interrupt service routine is executed. In this scenario, the DBG module will have cleared ARM without having recorded the change-of-flow that occurred as part of the interrupt exception. Note that the stack will hold the return addresses and can be used to reconstruct execution flow in this scenario.

When TRGSEL is clear and the DBG module is armed to trigger on begin-trigger types, the trigger event is detected on a program fetch of the target address, even when an interrupt becomes pending on the same cycle. In this scenario, the FIFO captures the change of flow event. Because the system is configured for begin-trigger, the DBG remains armed and does not break until the FIFO has been filled by subsequent change of flow events.

## 18.5 Resets

The DBG module cannot cause an MCU reset.

There are two different ways this module will respond to reset depending upon the conditions before the reset event. If the DBG module was setup for an end trace run with DBGGEN=1 and BEGIN=0, ARM, ARMF, and BRKEN are cleared but the reset function on most DBG control and status bits is overridden so a host development system can read out the results of the trace run after the MCU has been reset. In all other cases including POR, the DBG module controls are initialized to start a begin trace run starting from when the reset vector is fetched. The conditions for the default begin trace run are:



- DBGCAX=0x00, DBGCAH=0xFF, DBGCAL=0xFE so comparator A is set to match when the 16-bit CPU address 0xFFFFE appears during the reset vector fetch
- DBGC=0xC0 to enable and arm the DBG module
- DBGT=0x40 to select a force-type trigger, a BEGIN trigger, and A-only trigger mode

## 18.6 Interrupts

The DBG contains no interrupt source.

## 18.7 Electrical Specifications

The DBG module contain no electrical specifications.

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